

General Description

The SLG47004 provides a small, low power component for commonly used analog signal processing and mixed-signal functions. Individual, tunable, analog components used in conjunction with configurable logic provide a way to solve a wide variety of tasks with minimal costs. The user creates their circuit design by programming the multiple time Non-Volatile Memory (NVM) to configure the interconnect logic, the analog and digital macrocell, and the IO Pins of the SLG47004.

Key Features

- Two Programmable Bandwidth Op Amps
 - 3-Op Amp Instrumentation Amplifier Function (including Additional Internal Op Amp)
 - Rail to Rail Input
 - Low Quiescent Current
 - Low Offset Voltage
 - Analog Comparator Mode
 - Optional Vref Voltage Connection for Input Pins
- Two 1024 Position Digital Rheostats
 - User Defined Auto-Trim Option
 - Manual Control Option
 - I²C Control Option
 - Potentiometer Mode
- Two Single-Pole/Single-Throw Analog Switches
 - Voltage or Current Source/Sink Mode
- One Low Offset Chopper Comparator
- Two Low Power General Purpose ACMPs
 - ACMP Sampling Mode
 - Hysteresis with Independently-Selectable Thresholds
- Three Voltage References
 - Two ACMP Vref Output Buffers
 - One High Drive Buffer
- Thirteen Combination Function Macrocells
 - Three Selectable DFF/LATCH or 2-bit LUTs
 - One Selectable Programmable Pattern Generator or 2-bit LUT
 - Seven Selectable DFF/LATCH or 3-bit LUTs
 - One Selectable Pipe Delay or Ripple Counter or 3-bit LUT
 - One Selectable DFF/LATCH or 4-bit LUT
- Seven Multi-Function Macrocells
 - Six Selectable DFF/LATCH or 3-bit LUTs + 8-bit Delay/Counters
 - One Selectable DFF/LATCH or 4-bit LUT + 16-bit Delay/Counter
- Serial Communications
 - I²C Protocol Interface
- 2-kbit (256 x 8) I²C-Compatible (2-Wire) Serial EEPROM Emulation with Software Write Protection
- Programmable Delay with Edge Detector Output
- Deglitch Filter or Edge Detector
- Three Oscillators
 - 2.048 kHz Oscillator
 - 2.048 MHz Oscillator
 - 25 MHz Oscillator
- Analog Temperature Sensor
- Power-On Reset
- In-System Programmability
- Multiple Time Programmable Memory
- Wide Range Power Supply
 - 2.5 V (±4 %) to 5 V (±10 %) V_{DD}
- Operating Temperature Range: -40 °C to +85 °C
- RoHS Compliant/Halogen-Free
- Package Available
 - 24-pin STQFN: 3 mm x 3 mm x 0.55 mm, 0.4 mm pitch

Applications

- Adjust Precision Threshold
- Sensor Offset Trimming/Calibration
- Tunable Analog Filters
- Operational Amplifier Adjustable Gain and Offset
- Adjustable Voltage-to-Current Conversions
- Personal Computers and Servers
- PC Peripherals
- Consumer Electronics
- Data Communications Equipment
- Handheld and Portable Electronics
- Smartphones and Fitness Bands
- Notebook and Tablet PCs

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1 Block Diagram

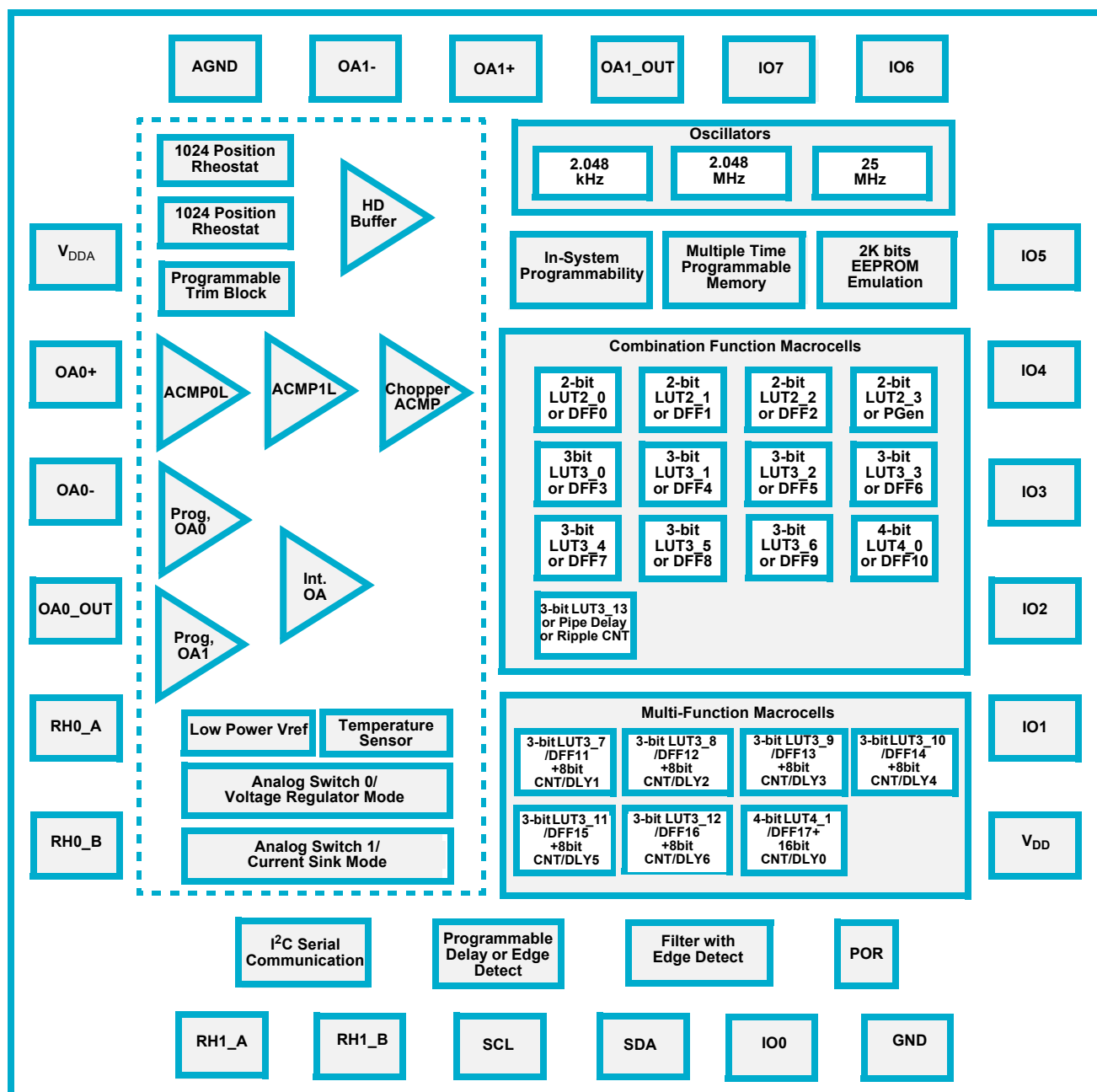
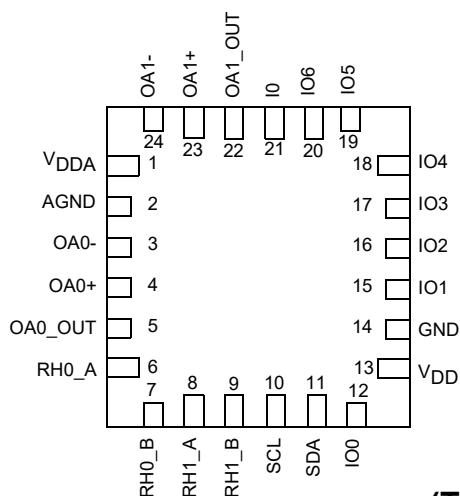


Figure 1: Block Diagram

2 Pinout

2.1 PIN CONFIGURATION - STQFN-24L



(Top View)
STQFN-24

Pin #	Signal Name	Pin Functions
1	V _{DDA}	Analog Power Supply
2	AGND	Analog Ground
3	OA0-	Op Amp0 Inverting Input
4	OA0+	Op Amp0 Non-Inverting Input
5	OA0_OUT	Op Amp0_OUT/ACMP0L+ /
6	RH0_A	Digital Rheostat 0 Terminal A
7	RH0_B	Digital Rheostat 0 Terminal B
8	RH1_A	Digital Rheostat 1 Terminal A
9	RH1_B	Digital Rheostat 1 Terminal B
10	SCL	I ² C_SCL
11	SDA	I ² C_SDA
12	IO0	GPIO, ACMP0L-, ACMP1L-, EXT_OSC0_IN, Vref0_Out or Temp_Sens_Out
13	V _{DD}	Digital Power Supply
14	GND	Digital Ground
15	IO1	GPIO, Chop_ACMP+, Vref1_OUT or Temp_Sens_Out, EXT_OSC1_IN or SLA_0
16	IO2	GPIO, ACMP0L+, EXT_OSC2_IN, SLA_1
17	IO3	GPIO, AS_1_A, ACMP1L+ or SLA_2
18	IO4	GPIO, AS_1_B, Chop_ACMP- or SLA_3
19	IO5	GPIO, AS_0_B
20	IO6	GPIO, AS_0_A, HD_Buff_Out, In Amp_Vref
21	IO	GPI, In Amp_OUT
22	OA1_OUT	Op Amp1_OUT, ACMP1L+
23	OA1+	Op Amp1 Non-inverting Input
24	OA1-	Op Amp1 Inverting Input

Legend:

ACMPx+: ACMPx Positive Input
ACMPx-: ACMPx Negative Input
SCL: I²C Clock Input
SDA: I²C Data Input/Output
Vrefx: Voltage Reference Output
SLA: Slave Address

Table 1: Functional Pin Description

Pin No.	Pin Name	Signal Name	Function	Input Options	Output Options
STQFN 24L					
1	V _{DDA}	V _{DDA}	Analog Power Supply	--	--
2	AGND	AGND	Analog Ground	--	--
3	OA0-	OA0-	Op Amp0 Inverting Input	Analog	--
4	OA0+	OA0+	Op Amp0 Non-Inverting Input	Analog	--
5	OA0_OUT	OA0_OUT	Op Amp0 Output	--	Analog
		ACMP0L+	Analog Comparator 0 Positive Input	Analog	--
6	RH0_A	RH0_A	Digital Rheostat 0 Terminal A	--	--

Table 1: Functional Pin Description(Continued)

Pin No. STQFN 24L	Pin Name	Signal Name	Function	Input Options	Output Options
7	RH0_B	RH0_B	Digital Rheostat 0 Terminal B	--	--
8	RH1_A	RH1_A	Digital Rheostat 1 Terminal A	--	--
9	RH1_B	RH1_B	Digital Rheostat 1 Terminal B	--	--
10	SCL	SCL	I ² C Serial Clock	--	--
11	SDA	SDA	I ² C Serial Data	--	--
12	IO0	IO0	General Purpose IO	--	--
		ACMP0L-	Analog Comparator 0 Negative Input	Analog	--
		ACMP1L-	Analog Comparator 1 Negative Input	Analog	--
		EXT_OSC0_IN	External Clock Connection	--	--
		Vref0_Out	Voltage Reference 0 Output	--	Analog
13	V _{DD}	V _{DD}	Digital Power Supply	--	--
14	GND	GND	Digital Ground	--	--
15	IO1	IO1	General Purpose IO	--	--
		CHOP_ACMP+	Chopper ACMP Positive Input	Analog	--
		Temp_Sens_Out	Temperature Sensor Output	--	Analog
		EXT_OSC1_IN	External Clock Connection	--	--
		SLA_0	Slave Address 0	--	--
16	IO2	IO2	General Purpose IO	--	--
		ACMP0L+	Analog Comparator 0 Positive Input	Analog	--
		EXT_OSC2_IN	External Clock Connection	--	--
		SLA_1	Slave Address 1	--	--
17	IO3	IO3	General Purpose IO	--	--
		AS_1_A	Analog Switch 1 Input A	Analog	Analog
		ACMP1L+	Analog Comparator 1 Positive Input	--	--
		SLA_2	Slave Address 2	--	--
18	IO4	IO4	General Purpose IO	--	--
		AS_1_B	Analog Switch 1 Input B	Analog	Analog
			Chopper ACMP Negative Input	Analog	--
		SLA_3	Slave Address 3	--	--

Table 1: Functional Pin Description(Continued)

Pin No.	Pin Name	Signal Name	Function	Input Options	Output Options
STQFN 24L					
19	IO5	IO5	General Purpose IO	--	--
		AS_0_B	Analog Switch 0 Input B	Analog	Analog
20	IO6	IO6	General Purpose IO	--	--
		AS_0_A	Analog Switch 0 Input A	Analog	Analog
		HD_Buffer_Out	High Drive Buffer Out put	--	Analog
		In Amp_Vref	Instrumentation Amplifier Voltage Reference	Analog	--
21	IO	IO	General Purpose Input	--	--
		In Amp Out	Instrumentation Amplifier Output	Analog	--
22	OA1_OUT	OA1_OUT	Op Amp1 Output	--	Analog
		ACMP1L+	Analog Comparator 1 Positive Input	Analog	--
23	OA1+	OA1+	Op Amp1 Non-inverting Input	Analog	--
24	OA1-	OA1-	Op Amp1 Inverting Input	Analog	--

Table 2: Pin Type Definitions

Pin Type	Description
V _{DDA}	Analog Power Supply
AGND	Analog Ground
OA-	Op Amp Inverting Input
OA+	Op Amp Non-Inverting Input
OA_OUT	Op Amp Output
RH_A	Digital Rheostat Terminal A
RH_B	Digital Rheostat Terminal B
SCL	I ² C Serial Clock
SDA	I ² C Serial Data
IO	General Purpose Input/Output
V _{DD}	Digital Power Supply
GND	Digital Ground
I	General Purpose Input

3 Characteristics

3.1 ABSOLUTE MAXIMUM RATINGS

Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, so functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specification are not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

Analog and digital grounds must be connected together on the PCB board. The place of connection depends on users schematic. For application cases with low digital current of SLG47004, both AGND and GND should be connected to analog ground plane.

Table 3: Absolute Maximum Ratings

Parameter		Min	Max	Unit
V_{DD} to GND, V_{DDA} to AGND (Note 1)		-0.3	7	V
Maximum Slew Rate of V_{DDA}		--	1	V/ μ s
Voltage at Input Pin		GND-0.3	$V_{DD}+0.3$	V
Current at Input Pin		-1.0	1.0	mA
Maximum Average or DC Current through V_{DDA} or AGND Pin (Per chip side)	$T_J = 85^\circ\text{C}$	--	110	mA
	$T_J = 110^\circ\text{C}$	--	50	mA
Maximum Average or DC Current through V_{DD} or GND Pin (Per chip side)	$T_J = 85^\circ\text{C}$	--	100	mA
	$T_J = 110^\circ\text{C}$	--	50	mA
Input leakage (Absolute Value)		--	1000	nA
Storage Temperature Range		-65	150	$^\circ\text{C}$
Junction Temperature		--	150	$^\circ\text{C}$
Moisture Sensitivity Level		1		

Note 1: V_{DDA} must be equal to V_{DD}

3.2 ELECTROSTATIC DISCHARGE RATINGS

Table 4: Electrostatic Discharge Ratings

Parameter	Min	Max	Unit
ESD Protection (Human Body Model)	2000	--	V
ESD Protection (Charged Device Model)	1300	--	V

3.3 RECOMMENDED OPERATING CONDITIONS

Table 5: Recommended Operating Conditions

Parameter	Condition	Min	Max	Unit
Supply Voltage (V_{DDA})		2.4	5.5	V
	During NVM Write and Erase commands	2.5	5.5	V
Operating Temperature		-40	85	$^\circ\text{C}$
Capacitor Value at V_{DD}		0.1	--	μF
Analog Input Common Mode Range	Allowable Input Voltage at Analog Pins	-0.2	$V_{DDA}+0.2$	V

3.4 ELECTRICAL CHARACTERISTICS

Table 6: EC at T = -40 °C to +85 °C, V_{DD} = 2.4 V to 5.5 V Unless Otherwise Noted

Parameter	Description	Condition	Min	Typ	Max	Unit
V _{IH}	HIGH-Level Input Voltage	Logic Input (Note 1)	0.7x V _{DD}	--	V _{DD} + 0.3	V
		Logic Input with Schmitt Trigger	0.8x V _{DD}	--	V _{DD} + 0.3	V
		Low-Level Logic Input (Note 1)	1.25	--	V _{DD} + 0.3	V
V _{IL}	LOW-Level Input Voltage	Logic Input (Note 1)	GND- 0.3	--	0.3x V _{DD}	V
		Logic Input with Schmitt Trigger	GND- 0.3	--	0.2x V _{DD}	V
		Low-Level Logic Input (Note 1)	GND- 0.3	--	0.5	V
V _{HYS}	Schmitt Trigger Hysteresis Voltage	V _{DD} = 2.5 V +/- 8 % (Note 1)	0.28	0.43	0.54	V
		V _{DD} = 3.3 V +/- 10 % (Note 1)	0.34	0.46	0.56	V
		V _{DD} = 5 V +/- 10 % (Note 1)	0.50	0.63	0.74	V
V _O	Maximal Voltage Applied to any PIN in High Impedance State		--	--	V _{DD} + 0.3	V

Table 6: EC at T = -40 °C to +85 °C, V_{DD} = 2.4 V to 5.5 V Unless Otherwise Noted(Continued)

Parameter	Description	Condition	Min	Typ	Max	Unit
V _{OH}	HIGH-Level Output Voltage	Push-Pull, 1x Drive, I _{OH} = 1 mA, V _{DD} = 2.4 V (Note 1)	2.178	--	--	V
		Push-Pull, 1x Drive, I _{OH} = 1 mA, V _{DD} = 2.5 V (Note 1)	2.389	--	--	V
		Push-Pull, 1x Drive, I _{OH} = 1 mA, V _{DD} = 2.7 V (Note 1)	2.598	--	--	V
		Push-Pull, 1x Drive, I _{OH} = 3 mA, V _{DD} = 3.0 V (Note 1)	2.712	--	--	V
		Push-Pull, 1x Drive, I _{OH} = 3 mA, V _{DD} = 3.3 V (Note 1)	3.039	--	--	V
		Push-Pull, 1x Drive, I _{OH} = 3 mA, V _{DD} = 3.6 V (Note 1)	3.36	--	--	V
		Push-Pull, 1x Drive, I _{OH} = 5 mA, V _{DD} = 4.5 V (Note 1)	4.157	--	--	V
		Push-Pull, 1x Drive, I _{OH} = 5 mA, V _{DD} = 5.0 V (Note 1)	4.678	--	--	V
		Push-Pull, 1x Drive, I _{OH} = 5 mA, V _{DD} = 5.5 V (Note 1)	5.201	--	--	V
		Push-Pull, 2x Drive, I _{OH} = 1 mA, V _{DD} = 2.4 V (Note 1)	2.239	--	--	V
		Push-Pull, 2x Drive, I _{OH} = 1 mA, V _{DD} = 2.5 V (Note 1)	2.443	--	--	V
		Push-Pull, 2x Drive, I _{OH} = 1 mA, V _{DD} = 2.7 V (Note 1)	2.648	--	--	V
		Push-Pull, 2x Drive, I _{OH} = 3 mA, V _{DD} = 3.0 V (Note 1)	2.854	--	--	V
		Push-Pull, 2x Drive, I _{OH} = 3 mA, V _{DD} = 3.3 V (Note 1)	3.165	--	--	V
		Push-Pull, 2x Drive, I _{OH} = 3 mA, V _{DD} = 3.6 V (Note 1)	3.474	--	--	V
		Push-Pull, 2x Drive, I _{OH} = 5 mA, V _{DD} = 4.5 V (Note 1)	4.314	--	--	V
		Push-Pull, 2x Drive, I _{OH} = 5 mA, V _{DD} = 5.0 V (Note 1)	4.821	--	--	V
		Push-Pull, 2x Drive, I _{OH} = 5 mA, V _{DD} = 5.5 V (Note 1)	5.329	--	--	V

Table 6: EC at T = -40 °C to +85 °C, V_{DD} = 2.4 V to 5.5 V Unless Otherwise Noted(Continued)

Parameter	Description	Condition	Min	Typ	Max	Unit
V _{OL}	LOW-Level Output Voltage	Push-Pull, 1x Drive, I _{OL} = 1 mA, V _{DD} = 2.4 V (Note 1)	--	--	0.085	V
		Push-Pull, 1x Drive, I _{OL} = 1 mA, V _{DD} = 2.5 V (Note 1)	--	--	0.079	V
		Push-Pull, 1x Drive, I _{OL} = 1 mA, V _{DD} = 2.7 V (Note 1)	--	--	0.074	V
		Push-Pull, 1x Drive, I _{OL} = 3 mA, V _{DD} = 3.0 V (Note 1)	--	--	0.210	V
		Push-Pull, 1x Drive, I _{OL} = 3 mA, V _{DD} = 3.3 V (Note 1)	--	--	0.195	V
		Push-Pull, 1x Drive, I _{OL} = 3 mA, V _{DD} = 3.6 V (Note 1)	--	--	0.183	V
		Push-Pull, 1x Drive, I _{OL} = 5 mA, V _{DD} = 4.5 V (Note 1)	--	--	0.271	V
		Push-Pull, 1x Drive, I _{OL} = 5 mA, V _{DD} = 5.0 V (Note 1)	--	--	0.256	V
		Push-Pull, 1x Drive, I _{OL} = 5 mA, V _{DD} = 5.5 V (Note 1)	--	--	0.246	V
		Push-Pull, 2x Drive, I _{OL} = 1 mA, V _{DD} = 2.4 V (Note 1)	--	--	0.046	V
		Push-Pull, 2x Drive, I _{OL} = 1 mA, V _{DD} = 2.5 V (Note 1)	--	--	0.043	V
		Push-Pull, 2x Drive, I _{OL} = 1 mA, V _{DD} = 2.7 V (Note 1)	--	--	0.040	V
		Push-Pull, 2x Drive, I _{OL} = 3 mA, V _{DD} = 3.0 V (Note 1)	--	--	0.114	V
		Push-Pull, 2x Drive, I _{OL} = 3 mA, V _{DD} = 3.3 V (Note 1)	--	--	0.107	V
		Push-Pull, 2x Drive, I _{OL} = 3 mA, V _{DD} = 3.6 V (Note 1)	--	--	0.102	V
		Push-Pull, 2x Drive, I _{OL} = 5 mA, V _{DD} = 4.5 V (Note 1)	--	--	0.152	V
		Push-Pull, 2x Drive, I _{OL} = 5 mA, V _{DD} = 5.0 V (Note 1)	--	--	0.145	V
		Push-Pull, 2x Drive, I _{OL} = 5 mA, V _{DD} = 5.5 V (Note 1)	--	--	0.140	V
		NMOS OD, 1x Drive, I _{OL} = 1 mA, V _{DD} = 2.4 V (Note 1)	--	--	0.038	V
		NMOS OD, 1x Drive, I _{OL} = 1 mA, V _{DD} = 2.5 V (Note 1)	--	--	0.035	V
		NMOS OD, 1x Drive, I _{OL} = 1 mA, V _{DD} = 2.7 V (Note 1)	--	--	0.033	V
		NMOS OD, 1x Drive, I _{OL} = 3 mA, V _{DD} = 3.0 V (Note 1)	--	--	0.094	V
		NMOS OD, 1x Drive, I _{OL} = 3 mA, V _{DD} = 3.3 V (Note 1)	--	--	0.088	V
		NMOS OD, 1x Drive, I _{OL} = 3 mA, V _{DD} = 3.6 V (Note 1)	--	--	0.084	V

Table 6: EC at T = -40 °C to +85 °C, V_{DD} = 2.4 V to 5.5 V Unless Otherwise Noted(Continued)

Parameter	Description	Condition	Min	Typ	Max	Unit
V _{OL}	LOW-Level Output Voltage	NMOS OD, 1x Drive, I _{OL} = 5 mA, V _{DD} = 4.5 V (Note 1)	--	--	0.127	V
		NMOS OD, 1x Drive, I _{OL} = 5 mA, V _{DD} = 5.0 V (Note 1)	--	--	0.121	V
		NMOS OD, 1x Drive, I _{OL} = 5 mA, V _{DD} = 5.5 V (Note 1)	--	--	0.117	V
		NMOS OD, 2x Drive, I _{OL} = 1 mA, V _{DD2} = 2.4 V (Note 1)	--	--	0.032	V
		NMOS OD, 2x Drive, I _{OL} = 1 mA, V _{DD} = 2.5 V (Note 1)	--	--	0.03	V
		NMOS OD, 2x Drive, I _{OL} = 1 mA, V _{DD} = 2.7 V (Note 1)	--	--	0.029	V
		NMOS OD, 2x Drive, I _{OL} = 3 mA, V _{DD} = 3.0 V (Note 1)	--	--	0.064	V
		NMOS OD, 2x Drive, I _{OL} = 3 mA, V _{DD} = 3.3 V (Note 1)	--	--	0.062	V
		NMOS OD, 2x Drive, I _{OL} = 3 mA, V _{DD} = 3.6 V (Note 1)	--	--	0.059	V
		NMOS OD, 2x Drive, I _{OL} = 5 mA, V _{DD} = 4.5 V (Note 1)	--	--	0.085	V
		NMOS OD, 2x Drive, I _{OL} = 5 mA, V _{DD} = 5.0 V (Note 1)	--	--	0.081	V
		NMOS OD, 2x Drive, I _{OL} = 5 mA, V _{DD} = 5.5 V (Note 1)	--	--	0.08	V
I _{OH}	HIGH-Level Output Current (Note 2)	Push-Pull, 1x Drive, V _{OH} = V _{DD} - 0.2 V _{DD} = 2.4 V (Note 1)	1.60	--	--	mA
		Push-Pull, 1x Drive, V _{OH} = V _{DD} - 0.2 V _{DD} = 2.5 V (Note 1)	1.76	--	--	mA
		Push-Pull, 1x Drive, V _{OH} = V _{DD} - 0.2 V _{DD} = 2.7 V (Note 1)	1.92	--	--	mA
		Push-Pull, 1x Drive, V _{OH} = 2.4 V, V _{DD} = 3.0 V (Note 1)	5.64	--	--	mA
		Push-Pull, 1x Drive, V _{OH} = 2.4 V, V _{DD} = 3.3 V (Note 1)	8.56	--	--	mA
		Push-Pull, 1x Drive, V _{OH} = 2.4 V, V _{DD} = 3.6 V (Note 1)	11.51	--	--	mA
		Push-Pull, 1x Drive, V _{OH} = 2.4 V, V _{DD} = 4.5 V (Note 1)	20.46	--	--	mA
		Push-Pull, 1x Drive, V _{OH} = 2.4 V, V _{DD} = 5.0 V (Note 1)	25.12	--	--	mA
		Push-Pull, 1x Drive, V _{OH} = 2.4 V, V _{DD} = 5.5 V (Note 1)	29.34	--	--	mA
		Push-Pull, 2x Drive, V _{OH} = V _{DD} - 0.2 V _{DD} = 2.4 V (Note 1)	3.10	--	--	mA
		Push-Pull, 2x Drive, V _{OH} = V _{DD} - 0.2 V _{DD} = 2.5 V (Note 1)	3.40	--	--	mA

Table 6: EC at T = -40 °C to +85 °C, V_{DD} = 2.4 V to 5.5 V Unless Otherwise Noted(Continued)

Parameter	Description	Condition	Min	Typ	Max	Unit
I _{OH}	HIGH-Level Output Current (Note 2)	Push-Pull, 2x Drive, V _{OH} = V _{DD} - 0.2 V _{DD} = 2.7 V (Note 1)	3.69	--	--	mA
		Push-Pull, 2x Drive, V _{OH} = 2.4 V, V _{DD} = 3.0 V (Note 1)	10.89	--	--	mA
		Push-Pull, 2x Drive, V _{OH} = 2.4 V, V _{DD} = 3.3 V (Note 1)	16.54	--	--	mA
		Push-Pull, 2x Drive, V _{OH} = 2.4 V, V _{DD} = 3.6 V (Note 1)	22.28	--	--	mA
		Push-Pull, 2x Drive, V _{OH} = 2.4 V, V _{DD} = 4.5 V (Note 1)	39.61	--	--	mA
		Push-Pull, 2x Drive, V _{OH} = 2.4 V, V _{DD} = 5.0 V (Note 1)	48.49	--	--	mA
		Push-Pull, 2x Drive, V _{OH} = 2.4 V, V _{DD} = 5.5 V (Note 1)	56.39	--	--	mA
I _{OL}	LOW-Level Output Current (Note 2)	Push-Pull, 1x Drive, V _{OL} = 0.15 V, V _{DD} = 2.4 V (Note 1)	1.73	--	--	mA
		Push-Pull, 1x Drive, V _{OL} = 0.15 V, V _{DD} = 2.5 V (Note 1)	1.87	--	--	mA
		Push-Pull, 1x Drive, V _{OL} = 0.15 V, V _{DD} = 2.7 V (Note 1)	2.00	--	--	mA
		Push-Pull, 1x Drive, V _{OL} = 0.4 V, V _{DD} = 3.0 V (Note 1)	5.45	--	--	mA
		Push-Pull, 1x Drive, V _{OL} = 0.4 V, V _{DD} = 3.3 V (Note 1)	5.90	--	--	mA
		Push-Pull, 1x Drive, V _{OL} = 0.4 V, V _{DD} = 3.6 V (Note 1)	6.29	--	--	mA
		Push-Pull, 1x Drive, V _{OL} = 0.4 V, V _{DD} = 4.5 V (Note 1)	7.25	--	--	mA
		Push-Pull, 1x Drive, V _{OL} = 0.4 V, V _{DD} = 5.0 V (Note 1)	7.67	--	--	mA
		Push-Pull, 1x Drive, V _{OL} = 0.4 V, V _{DD} = 5.5 V (Note 1)	8.01	--	--	mA
		Push-Pull, 2x Drive, V _{OL} = 0.15 V, V _{DD} = 2.4 V (Note 1)	3.20	--	--	mA
		Push-Pull, 2x Drive, V _{OL} = 0.15 V, V _{DD} = 2.5 V (Note 1)	3.44	--	--	mA
		Push-Pull, 2x Drive, V _{OL} = 0.15 V, V _{DD} = 2.7 V (Note 1)	3.65	--	--	mA
		Push-Pull, 2x Drive, V _{OL} = 0.4 V, V _{DD} = 3.0 V (Note 1)	10.01	--	--	mA
		Push-Pull, 2x Drive, V _{OL} = 0.4 V, V _{DD} = 3.3 V (Note 1)	10.73	--	--	mA
		Push-Pull, 2x Drive, V _{OL} = 0.4 V, V _{DD} = 3.6 V (Note 1)	11.36	--	--	mA
		Push-Pull, 2x Drive, V _{OL} = 0.4 V, V _{DD} = 4.5 V (Note 1)	12.85	--	--	mA
		Push-Pull, 2x Drive, V _{OL} = 0.4 V, V _{DD} = 5.0 V (Note 1)	13.52	--	--	mA

Table 6: EC at T = -40 °C to +85 °C, V_{DD} = 2.4 V to 5.5 V Unless Otherwise Noted(Continued)

Parameter	Description	Condition	Min	Typ	Max	Unit
I _{OL}	LOW-Level Output Current (Note 2)	Push-Pull, 2x Drive, V _{OL} = 0.4 V, V _{DD} = 5.5 V (Note 1)	14.05	--	--	mA
		NMOS OD, 1x Drive, V _{OL} = 0.15 V, V _{DD} = 2.4 V (Note 1)	3.91	--	--	mA
		NMOS OD, 1x Drive, V _{OL} = 0.15 V, V _{DD} = V _{DD2} = 2.5 V (Note 1)	4.19	--	--	mA
		NMOS OD, 1x Drive, V _{OL} = 0.15 V, V _{DD} = 2.7 V (Note 1)	4.44	--	--	mA
		NMOS OD, 1x Drive, V _{OL} = 0.4 V, V _{DD} = 3.0 V (Note 1)	12.18	--	--	mA
		NMOS OD, 1x Drive, V _{OL} = 0.4 V, V _{DD} = 3.3 V (Note 1)	13.02	--	--	mA
		NMOS OD, 1x Drive, V _{OL} = 0.4 V, V _{DD} = 3.6 V (Note 1)	13.75	--	--	mA
		NMOS OD, 1x Drive, V _{OL} = 0.4 V, V _{DD} = 4.5 V (Note 1)	15.47	--	--	mA
		NMOS OD, 1x Drive, V _{OL} = 0.4 V, V _{DD} = 5.0 V (Note 1)	16.19	--	--	mA
		NMOS OD, 1x Drive, V _{OL} = 0.4 V, V _{DD} = 5.5 V (Note 1)	16.80	--	--	mA
		NMOS OD, 2x Drive, V _{OL} = 0.15 V, V _{DD} = 2.4 V (Note 1)	6.28	--	--	mA
		NMOS OD, 2x Drive, V _{OL} = 0.15 V, V _{DD} = 2.5 V (Note 1)	6.68	--	--	mA
		NMOS OD, 2x Drive, V _{OL} = 0.15 V, V _{DD} = 2.7 V (Note 1)	7.02	--	--	mA
		NMOS OD, 2x Drive, V _{OL} = 0.4 V, V _{DD} = 3.0 V (Note 1)	20.14	--	--	mA
		NMOS OD, 2x Drive, V _{OL} = 0.4 V, V _{DD} = 3.3 V (Note 1)	21.23	--	--	mA
		NMOS OD, 2x Drive, V _{OL} = 0.4 V, V _{DD} = 3.6 V (Note 1)	22.12	--	--	mA
		NMOS OD, 2x Drive, V _{OL} = 0.4 V, V _{DD} = 4.5 V (Note 1)	24.84	--	--	mA
		NMOS OD, 2x Drive, V _{OL} = 0.4 V, V _{DD} = 5.0 V (Note 1)	26.08	--	--	mA
		NMOS OD, 2x Drive, V _{OL} = 0.4 V, V _{DD} = 5.5 V (Note 1)	26.72	--	--	mA
T _{SU}	Startup Time	From V _{DD} rising past PON _{THR}	--	1.904	2.651	ms
T _{WR}	NVM Page Write Time	V _{DD} = 2.5 V to 5.5 V	--	--	20	ms
T _{ER}	NVM Page Erase Time	V _{DD} = 2.5 V to 5.5 V	--	--	20	ms
PON _{THR}	Power-On Threshold	V _{DD} Level Required to Start Up the Chip	1.60	--	2.07	V
POFF _{THR}	Power-Off Threshold	V _{DD} Level Required to Switch Off the Chip	0.97	--	1.531	V

Table 6: EC at T = -40 °C to +85 °C, V_{DD} = 2.4 V to 5.5 V Unless Otherwise Noted(Continued)

Parameter	Description	Condition	Min	Typ	Max	Unit
R _{PULL}	Pull-up or Pull-down Resistance	1 M for Pull-up: V _{IN} = GND; for Pull-down: V _{IN} = V _{DD} (Note 1)	0.72	1.12	1.4	MΩ
		100 k for Pull-up: V _{IN} = GND; for Pull-down: V _{IN} = V _{DD} (Note 1)	72	110	134.4	kΩ
		10 k For Pull-up: V _{IN} = GND; for Pull-down: V _{IN} = V _{DD} (Note 1)	6.32	10	13.5	kΩ
C _{IN}	Input Capacitance	PINs 10, 11	--	2.905	--	pF
		PIN 12	--	3.476	--	pF
		PINs 15, 16	--	3.677	--	pF
		PINs 17, 18, 19	--	10.228	--	pF
		PIN 20	--	27.964	--	pF
		PIN 21	--	5.671	--	pF
Note 1 No hysteresis.						
Note 2 DC or average current through any pin should not exceed value given in Absolute Maximum Conditions.						

Table 7: EC of the I²C Pins at T = -40 °C to +85 °C, V_{DD} = 2.4 V to 5.5 V Unless Otherwise Noted

Parameter	Description	Condition	Fast-Mode		Fast-Mode Plus		Unit
			Min	Max	Min	Max	
V _{IL}	LOW-level Input Voltage		-0.5	0.3xV _{DD}	-0.5	0.3xV _{DD}	V
V _{IH}	HIGH-level Input Voltage		0.7xV _{DD}	5.5	0.7xV _{DD}	5.5	V
V _{HYS}	Hysteresis of Schmitt Trigger Inputs		0.05xV _{DD}	--	0.05xV _{DD}	--	V
V _{OL1}	LOW-Level Output Voltage 1	(Open-Drain) at 3 mA sink current V _{DD} > 2 V	0	0.4	0	0.4	V
V _{OL2}	LOW-Level Output Voltage 2	(Open-Drain) at 2 mA sink current V _{DD} ≤ 2 V	0	0.2xV _{DD}	0	0.2xV _{DD}	V
I _{OL}	LOW-Level Output Current (Note 1)	V _{OL} = 0.4 V, V _{DD} = 2.4 V	3	--	16.75	--	mA
		V _{OL} = 0.4 V, V _{DD} = 3.0 V	3	--	20	--	mA
		V _{OL} = 0.4 V, V _{DD} = 4.5 V	3	--	20	--	mA
		V _{OL} = 0.6 V	6	--	--	--	mA
t _{of}	Output Fall Time from V _{IHmin} to V _{ILmax} (Note 1)		14x (V _{DD} /5.5 V)	250	10x (V _{DD} /5.5 V)	120	ns
t _{SP}	Pulse Width of Spikes that must be suppressed by the Input Filter		0	50	0	50	ns
I _i	Input Current (each IO Pin)	0.1xV _{DD} < V _I < 0.9xV _{DDmax}	-10	+10	-10	+10	μA
C _i	Capacitance (each IO Pin)		--	10	--	10	pF
Note 1 Does not meet standard I ² C specifications: t _{of} = 20x(V _{DD} /5.5 V) (min); For Fast-mode Plus I _{OL} = 20 mA (min) at V _{OL} = 0.4 V. Note 2 For Fast-mode Plus SDA pin must be configured as NMOS 2x Open-Drain, see register [1155] in Section 21.							

Table 8: I²C Pins Timing Characteristics at T = -40 °C to +85 °C, V_{DD} = 2.4 V to 5.5 V Unless Otherwise Noted

Parameter	Description	Condition	Fast-Mode		Fast-Mode Plus		Unit
			Min	Max	Min	Max	
F _{SCL}	Clock Frequency, SCL		--	400	--	1000	kHz
t _{LOW}	Clock Pulse Width Low		1300	--	500	--	ns
t _{HIGH}	Clock Pulse Width High		600	--	260	--	ns
t _I	Input Filter Spike Suppression (SCL, SDA)		--	50	--	50	ns
t _{AA}	Clock Low to Data Out Valid		--	900	--	450	ns
t _{BUF}	Bus Free Time between Stop and Start		1300	--	500	--	ns
t _{HD_STA}	Start Hold Time		600	--	260	--	ns
t _{SU_STA}	Start Set-up Time		600	--	260	--	ns
t _{HD_DAT}	Data Hold Time		0	--	0	--	ns
t _{SU_DAT}	Data Set-up Time		100	--	50	--	ns
t _R	Inputs Rise Time		--	300	--	120	ns
t _F	Inputs Fall Time		--	300	--	120	ns
t _{SU_STD}	Stop Set-up Time		600	--	260	--	ns
t _{DH}	Data Out Hold Time		50	--	50	--	ns

Note 1 Timing diagram can be found in [Figure 129](#).

Table 9: Typical Current Estimated for Each Macrocell at T = 25°C

Parameter	Description	Note	V _{DD} = 2.5 V	V _{DD} = 3.3 V	V _{DD} = 5.0 V	Unit
I	Current	Chip Quiescent, BG disabled	0.056	0.079	0.13	μA
		Chip Quiescent, BG enabled	0.357	0.391	0.472	μA
		OSC2 25 MHz, pre-divider = 1	40.954	49.907	71.075	μA
		OSC2 25 MHz, pre-divider = 4	31.716	37.448	51.515	μA
		OSC2 25 MHz, pre-divider = 8	29.897	34.998	47.664	μA
		OSC1 2.048 MHz, pre-divider = 1	18.951	19.751	21.507	μA
		OSC1 2.048 MHz, pre-divider = 4	18.255	18.809	20.023	μA
		OSC1 2.048 MHz, pre-divider = 8	18.116	18.622	19.730	μA
		OS00 2.048 kHz, pre-divider = 1	0.330	0.363	0.443	μA
		OSC0 2.048 kHz, pre-divider = 4	0.327	0.359	0.437	μA
		OSC0 2.048 kHz, pre-divider = 8	0.326	0.359	0.436	μA
		Push-Pull 1x + 4 pF @ 2.048 kHz	0.384	0.436	0.554	μA
		Push-Pull 1x + 4 pF @ 2.048 MHz	66.582	82.354	115.785	μA
		Temperature Sensor, range 1	11.001	11.050	11.356	μA
		Temperature Sensor, range 2	11.140	11.188	11.493	μA
		One ACMPx_L (includes internal Vref)	6.198	6.260	6.484	μA

Table 9: Typical Current Estimated for Each Macrocell at T = 25°C(Continued)

Parameter	Description	Note	V _{DD} = 2.5 V	V _{DD} = 3.3 V	V _{DD} = 5.0 V	Unit
I	Current	Two ACMPx_L (includes internal Vref)	8.530	8.616	8.954	μA
		Op AmpX Quiescent Current (128 kHz bandwidth)	31.663	32.227	33.005	μA
		Op AmpX Quiescent Current (8.192 MHz bandwidth)	604.144	607.979	609.342	μA
		In Amp Quiescent Current (three Op Amps are ON, Rf1 = Rf2 = 50 kΩ, Rg = 1 kΩ, 128 kHz bandwidth, Charge Pump - Disabled)	95.33	97.105	99.895	μA
		In Amp Quiescent Current (three Op Amps are ON, Rf1 = Rf2 = 50 kΩ, Rg = 1 kΩ, 128 kHz bandwidth, Charge Pump - Enabled)	72.352	73.973	76.688	μA
		In Amp Quiescent Current (three Op Amps are ON, Rf1 = Rf2 = 50 kΩ, Rg = 1 kΩ, 8.192 MHz bandwidth, Charge Pump - Disabled)	1810.631	1821.938	1826.541	μA
		In Amp Quiescent Current (three Op Amps are ON, Rf1 = Rf2 = 50 kΩ, Rg = 1 kΩ, 8.192 MHz bandwidth, Charge Pump - Enabled)	1229.011	1236.282	1241.784	μA
		Chopper ACMP (with 2.048 kHz clock)	31.719	33.940	38.717	μA

3.5 TIMING CHARACTERISTICS

Table 10: Typical Delay Estimated for Each Macrocell at T = 25 °C

Parameter	Description	Conditions	V _{DD} = 2.5 V		V _{DD} = 3.3 V		V _{DD} = 5.0 V		Unit
			Rising	Falling	Rising	Falling	Rising	Falling	
tpd	Delay	Digital Input to PP 1x	26	27	18	20	13	15	ns
tpd	Delay	Digital Input with Schmitt Trigger to PP 1x	27	28	19	21	15	15	ns
tpd	Delay	Digital Input to PP 2x	24	25	17	18	12	14	ns
tpd	Delay	Low Voltage Digital input to PP 1x	28	246	20	163	15	95	ns
tpd	Delay	Digital input to NMOS output	--	24	--	18	--	13	ns
tpd	Delay	Output enable from Pin, OE Hi-Z to 1	26	--	19	--	13	--	ns
tpd	Delay	Output enable from Pin, OE Hi-Z to 0	--	26	--	19	--	14	ns
tpd	Delay	Digital input to 1x3-State (Z to 1)	26	--	19	--	13	--	ns
tpd	Delay	Digital input to x3-State (Z to 0)	--	26	--	17	--	14	ns
tpd	Delay	Digital input to 2x3-State (Z to 1)	24	--	17	--	13	--	ns
tpd	Delay	Digital input to 2x3-State (Z to 0)	--	24	--	19	--	12	ns
tpd	Delay	LUT2bt	17	17	12	12	8	8	ns

Table 10: Typical Delay Estimated for Each Macrocell at T = 25 °C(Continued)

Parameter	Description	Conditions	V _{DD} = 2.5 V		V _{DD} = 3.3 V		V _{DD} = 5.0 V		Unit
			Rising	Falling	Rising	Falling	Rising	Falling	
tpd	Delay	LUT3bit	19	20	13	14	9	10	ns
tpd	Delay	LUT4bit	20	21	15	14	9	10	ns
tpd	Delay	LATCH	25	25	17	18	12	12	ns
tpd	Delay	DFF	24	25	16	18	11	12	ns
tpd	Delay	CNT/DLY	107	107	77	74	48	70	ns
tw	Width	Edge detect	206	205	161	160	116	116	ns
tpd	Delay	Edge detect	19	20	13	13	8	8	ns
tpd	Delay	Edge detect Delayed	241	241	175	175	125	125	ns
tpd	Delay	Ripple Counter	45	60	32	44	22	31	ns
tpd	Delay	PGen	20	20	14	14	9	10	ns
tpd	Delay	Filter	177	177	121	121	77	78	ns
tpd	Delay	Inverter Filter	115	115	83	83	57	57	ns
tpd	Delay	Pipe Delay	36	37	25	26	17	18	ns

Table 11: Programmable Delay Expected Typical Delays and Widths at T = 25 °C

Parameter	Description	Note	V _{DD} = 2.5 V	V _{DD} = 3.3 V	V _{DD} = 5.0 V	Unit
tw	Pulse Width, 1 cell	mode: (any) edge detect, edge detect output	223	163	118	ns
tw	Pulse Width, 2 cell	mode: (any) edge detect, edge detect output	444	324	233	ns
tw	Pulse Width, 3 cell	mode: (any) edge detect, edge detect output	663	484	347	ns
tw	Pulse Width, 4 cell	mode: (any) edge detect, edge detect output	882	643	461	ns
time1	Delay, 1 cell	mode: (any) edge detect, edge detect output	18	12	8	ns
time1	Delay, 2 cell	mode: (any) edge detect, edge detect output	18	12	8	ns
time1	Delay, 3 cell	mode: (any) edge detect, edge detect output	18	12	8	ns
time1	Delay, 4 cell	mode: (any) edge detect, edge detect output	18	12	8	ns
time2	Delay, 1 cell	mode: both edge delay, edge detect output	243	176	126	ns
time2	Delay, 2 cell	mode: both edge delay, edge detect output	464	337	241	ns
time2	Delay, 3 cell	mode: both edge delay, edge detect output	683	497	356	ns
time2	Delay, 4 cell	mode: both edge delay, edge detect output	902	655	470	ns

Table 12: Typical Filter Rejection Pulse Width at T = 25 °C

Parameter	V _{DD} = 2.5 V	V _{DD} = 3.3 V	V _{DD} = 5.0 V	Unit
Filtered Pulse Width	< 177	< 122	< 78	ns

Table 13: Typical Counter/Delay Offset Measurements at T = 25 °C

Parameter	OSC Freq	OSC Power	V _{DD} = 2.5 V	V _{DD} = 3.3 V	V _{DD} = 5.0 V	Unit
Power-On time	25 MHz	auto	<0.04	<0.13	<0.13	μs
Power-On time	2.048 MHz	auto	<0.5	<0.5	<0.5	μs
Power-On time	2.048 kHz	auto	<500	<500	<500	μs
frequency settling time	25 MHz	auto	4	4	4	μs

Table 13: Typical Counter/Delay Offset Measurements at T = 25 °C(Continued)

Parameter	OSC Freq	OSC Power	V _{DD} = 2.5 V	V _{DD} = 3.3 V	V _{DD} = 5.0 V	Unit
frequency settling time	2.048 MHz	auto	0.3	0.4	0.4	μs
frequency settling time	2.048 kHz	auto	660	570	480	μs
variable (CLK period)	25 MHz	forced	0-40	0-40	0-40	μs
variable (CLK period)	2.048 MHz	forced	0-0.5	0-0.5	0-0.5	μs
variable (CLK period)	2.048 kHz	forced	0-488	0-488	0-488	μs
tpd (non-delayed edge)	25 MHz/ 2.048 kHz	either	35	14	10	ns

3.6 OSCILLATOR CHARACTERISTICS

Table 14: Oscillators Frequency Limits, V_{DD} = 2.4 V to 5.5 V

OSC	Temperature Range					
	+25 °C			-40 °C to +85 °C		
	Minimum Value, kHz	Maximum Value, kHz	Error, %	Minimum Value, kHz	Maximum Value, kHz	Error, %
2.048 kHz OSC0	2.007	2.089	+2.00	1.902	2.110	+3.03
			-2.00			-7.13
2.048 MHz OSC1	2007	2089	+2.00	2003.017	2081.296	+1.63
			-2.00			-2.20
25 MHz OSC2	24500	25500	+2.00	23799.64	25900.32	+3.60
			-2.00			-4.80

3.6.1 OSC Power-On Delay

Table 15: Oscillators Power-On Delay at T = 25 °C, OSC Power Setting: "Auto Power-On"

Power Supply Range (V _{DD}) V	OSC0 2.048 kHz		OSC1 2.048 MHz		OSC2 25 MHz		OSC2 25 MHz Start with Delay	
	Typical Value, μs	Maximum Value, μs	Typical Value, ns	Maximum Value, ns	Typical Value, ns	Maximum Value, ns	Typical Value, ns	Maximum Value, ns
2.40	688.658	890.850	521.838	534.426	47.316	52.408	149.854	156.326
2.50	673.305	862.190	511.273	524.612	44.580	49.272	148.574	154.942
3.30	584.854	716.920	461.524	476.126	31.229	34.985	143.901	149.772
5.00	494.549	582.281	417.841	433.196	21.331	24.667	142.340	147.284
5.50	470.605	549.359	410.224	425.767	19.924	23.143	142.158	147.092

3.7 ACMP CHARACTERISTICS

Table 16: ACMP Specifications at T = -40 °C to +85 °C, V_{DD} = 2.4 V to 5.5 V Unless Otherwise Noted

Parameter	Description	Conditions	Note	Min	Typ	Max	Unit
V _{ACMP}	ACMP Input Voltage Range	Positive Input		0	--	V _{DD}	V
		Negative Input		0	--	V _{DD}	V
V _{offset}	ACMP Input Offset	ACMPxL, V _{hys} = 0 mV, Gain = 1, V _{ref} = 32 mV to 2048 mV	T = -40 °C to +85 °C	-6.364	--	3.709	mV
			T = 25 °C	-5.853	-1.025	3.425	mV
	Chopper ACMP Input Offset		T = -40 °C to +85 °C	-4.30	--	2.61	mV
			T = 25 °C	-2.74	-0.79	1.37	mV

Table 16: ACMP Specifications at T = -40 °C to +85 °C, V_{DD} = 2.4 V to 5.5 V Unless Otherwise Noted (Continued)

Parameter	Description	Conditions	Note	Min	Typ	Max	Unit
t _{start}	ACMP Startup Time when BG ON	ACMP Power-On delay, Minimal required wake time for the "Wake and Sleep function", for ACMPxL	T = -40 °C to +85 °C	--	--	91.02	μs
	ACMP Startup Time when BG OFF			--	--	2797.95	μs
R _{sin}	Series Input Resistance	Gain = 1x		--	10	--	GΩ
		Gain = 0.5x		--	1.627	--	MΩ
		Gain = 0.33x		--	1.626	--	MΩ
		Gain = 0.25x		--	1.625	--	MΩ
PROP	Propagation Delay, Response Time	ACMPxL, V _{ref} = 1.024 V, Gain = 1, Overdrive = 100 mV	Low to High	--	2.593	3.647	μs
			High to Low	--	2.829	5.127	μs
		ACMPxL, V _{ref} = 32 mV to 2048 mV, Gain = 1, Overdrive = 100 mV	Low to High	--	2.808	5.143	μs
			High to Low	--	2.937	7.486	μs
G	Gain Error	G = 1		1	1	1	
		G = 0.5		0.496	0.5	0.504	
		G = 0.33		0.331	0.334	0.337	
		G = 0.25		0.248	0.25	0.253	

3.8 INTERNAL VREF CHARACTERISTICS

Table 17: Internal Vref Characteristics

Parameter	Description	Conditions	Note	Min	Typ	Max	Unit
V _{ref} Accuracy and Loading	Internal Vref Accuracy at V _{ref} > 1216 mV	V _{DD} = 2.4 V to 5.5 V, No loading	T = 25 °C	-0.2	--	0.2	%
			T = -40 °C to +85 °C	-0.7	--	0.7	%

3.9 OUTPUT BUFFERS CHARACTERISTICS

Table 18: HD Buffer Electrical Characteristics at T = -40 °C to +85 °C, V_{DD} = 2.4 V to 5.5 V Unless Otherwise Noted

Parameter	Description	Conditions	Min	Typ	Max	Unit
Offset						
V _{OFFSET}	Input Offset Voltage	V _{DDA} = 5 V, V _{OUT} = 0.5 V to 4 V, T = 25 °C	--	0.088	9.936	mV
		V _{DDA} = 5 V, V _{OUT} = 0.5 V to 4 V, T = -40 °C to +85 °C	--	--	10.503	mV
dV _{OFFSET} /dt	Offset Drift with Temperature	V _{OUT} = V _{DDA} /2, T = -40 °C to +85 °C	--	1.033	33.564	μV/°C
Output						
ΔV _{OUT} (I)	Load Regulation	V _{DDA} = 5 V, V _{OUT} = 2.048 V, I _{LOAD} = 0.5 mA to 2 mA, T = 25 °C	--	-0.146	0.718	mV
ΔV _{OUT} (U)	Line Regulation	V _{DDA} = 2.5 V to 5 V, V _{OUT} = 2.048 V, T = 25 °C	--	0.803	3.781	mV

Table 18: HD Buffer Electrical Characteristics at T = -40 °C to +85 °C, V_{DD} = 2.4 V to 5.5 V Unless Otherwise

Parameter	Description	Conditions	Min	Typ	Max	Unit
I _{SC}	Short Circuit Current	V _{DDA} = 2.4 V to 5.5 V, T = -40 °C to +85 °C	--	--	25	mA
Shutdown Characteristics						
t _{on}	Buffer Turn-On Time	R _{LOAD} = 5 kΩ, T = 25 °C,	--	--	42.583	μs
t _{off}	Buffer Turn-Off Time	R _{LOAD} = 5 kΩ, T = 25 °C	--	0.076	--	μs

Table 19: Vref0 Output Buffer at T = -40 °C to +85 °C, V_{DD} = 2.4 V to 5.5 V Unless Otherwise Noted

Parameter	Description	Conditions	Note	Min	Typ	Max	Unit
Vref0 Buffer Accuracy and Loading	Vref0 Buffer Output Accuracy, Vref = 32 mV to 2048 mV, Buffer Enabled		T = 25 °C Loading = 200 μA	-1	--	1	%
			Loading = 1 mA	-5	--	5	%
	Vref0 Buffer Output Capacitance Loading		Load Resistance = 1 MΩ	--	--	5	pF
			Load Resistance = 560 kΩ	--	--	10	pF
			Load Resistance = 100 kΩ	--	--	40	pF
			Load Resistance = 10 kΩ	--	--	80	pF
			Load Resistance = 2 kΩ	--	--	120	pF
			Load Resistance = 1 kΩ, Vref = 32 mV to 1024 mV	--	--	150	pF

3.10 ANALOG TEMPERATURE SENSOR CHARACTERISTICS

Table 20: TS Output vs Temperature (Output Range 1)

T, °C	V _{DD} = 2.5 V		V _{DD} = 3.3 V		V _{DD} = 5.0 V	
	Typical, mV	Accuracy, %	Typical, mV	Accuracy, %	Typical, mV	Accuracy, %
-40	1004	±1.29	999	±1.28	998	±1.25
-30	978	±1.31	976	±1.30	976	±1.28
-20	955	±1.33	954	±1.32	953	±1.29
-10	933	±1.34	931	±1.33	930	±1.31
0	910	±1.34	908	±1.34	907	±1.32
10	886	±1.36	885	±1.36	884	±1.33
20	863	±1.39	862	±1.37	861	±1.36
30	840	±1.43	838	±1.42	838	±1.40
40	817	±1.48	815	±1.46	814	±1.44
50	793	±1.52	792	±1.51	791	±1.48
60	769	±1.58	768	±1.55	767	±1.53
70	746	±1.62	744	±1.61	744	±1.59
80	722	±1.67	721	±1.65	720	±1.63
85	710	±1.69	709	±1.68	708	±1.66

Table 21: TS Output vs Temperature (Output Range 2)

T, °C	V _{DD} = 2.5 V		V _{DD} = 3.3 V		V _{DD} = 5.0 V	
	Typical, mV	Accuracy, %	Typical, mV	Accuracy, %	Typical, mV	Accuracy, %
-40	1208	±1.36	1206	±1.35	1205	±1.32
-30	1181	±1.37	1179	±1.35	1178	±1.33
-20	1153	±1.39	1151	±1.37	1150	±1.35
-10	1126	±1.42	1124	±1.40	1123	±1.38
0	1098	±1.42	1096	±1.40	1095	±1.38
10	1070	±1.44	1068	±1.42	1067	±1.41
20	1042	±1.45	1040	±1.44	1039	±1.42
30	1014	±1.49	1012	±1.48	1011	±1.46
40	986	±1.53	984	±1.52	983	±1.50
50	957	±1.58	956	±1.56	955	±1.54
60	929	±1.63	927	±1.62	926	±1.60
70	900	±1.68	898	±1.66	898	±1.64
80	872	±1.72	870	±1.71	869	±1.69
85	857	±1.76	855	±1.74	855	±1.71

3.11 PROGRAMMABLE OPERATIONAL AMPLIFIER CHARACTERISTICS

Table 22: EC of OA, $V_{DDA} = 2.4 \text{ V to } 5.5 \text{ V}$, $V_{CM} = V_{DDA}/2$, $V_{OUT} \approx V_{DDA}/2$, $R_L = 100 \text{ k}\Omega$ to $V_{DDA}/2$, $C_L = 50 \text{ pF}$, $T = 25 \text{ }^\circ\text{C}$

Parameter	Description	Conditions (Note 1)	Min	Typ	Max	Unit
Input Voltage Offset (without Customers Trimming, Included Factory Block Offset Trim)						
V _{OFFSET}	Input Offset Voltage	V _{CM} = V _{DD} /2	--	500	1000	μV
dV _{OFFSET} /dt	Offset Drift with Temperature	V _{CM} = V _{DD} /2, T = -40 °C to +85 °C	--	1	5	μV/°C
		V _{CM} = GND, T = -40 °C to +85 °C	--	1	5	μV/°C
Trimmed Input Offset (Customer Perspective after Using Digital Rheostats with Gain = 200x) (Note 2)						
V _{OFFSET}	Input Offset Voltage	V _{DD} = 3.3 V, V _{CM} = 0 V to V _{DD}	--	50	--	μV
Input Voltage Range						
V _{CMR}	Input Common-Mode Voltage Range	T = -40 °C to +85 °C	-0.2	--	V _{DD} + 0.2	V
CMRR	Common-Mode Rejection Ratio	GND + 0.8 V < V _{CM} < V _{DD} - 0.8 V, T = -40 °C to +85 °C	80	110	--	dB
		GND < V _{CM} < GND+ 0.8 V or V _{DD} - 0.8 V < V _{CM} < V _{DD}	75	90	--	dB
PSRR	Power Supply Rejection Ratio	V _{CM} = V _{DD} /2, T = -40 °C to +85 °C	85	95	--	dB
		V _{CM} = GND, T = -40 °C to +85 °C	80	90	--	dB
CS	Channel Separation	V _{DD} = 5 V, f = 10 Hz	--	100	--	dB
		V _{DD} = 5 V, f = 1 kHz	--	80	--	dB
Input Current and Impedance						
I _B	Input Bias Current	T = 25 °C	--	--	4	pA
		T = +85 °C	--	--	125	pA
I _{OFFSET}	Input Offset Current	T = 25 °C	--	--	1.804	pA
		T = +85 °C	--	--	32.864	pA
R _{CM}	Common-Mode Input Resistance		--	10^13	--	Ω
R _{DIFF}	Differential Input Resistance		--	10^13	--	Ω
C _{CM}	Input Capacitance Common-Mode		--	5	7	pF
C _{DIFF}	Input Capacitance Differential		--	1.949	2.274	pF
Open-Loop Gain						
A _{OL}	DC Open Loop Gain	R _{LOAD} = 1 MΩ, GND + 0.1 V < V _{OUT} < V _{DD} - 0.1 V, T = -40 °C to +85 °C	100	123.796	--	dB
		R _{LOAD} = 50 kΩ, GND + 0.5 V < V _{OUT} < V _{DD} - 0.5 V T = -40 °C to +85 °C	100	124.093	--	dB
Output						

Table 22: EC of OA, $V_{DDA} = 2.4 \text{ V to } 5.5 \text{ V}$, $V_{CM} = V_{DDA}/2$, $V_{OUT} \approx V_{DDA}/2$, $R_L = 100 \text{ k}\Omega \text{ to } V_{DDA}/2$, $C_L = 50 \text{ pF}$, $T = 25 \text{ }^\circ\text{C}$

Parameter	Description	Conditions (Note 1)		Min	Typ	Max	Unit
V _{OH}	Maximum Voltage Swing	R _{LOAD} = 50 kΩ, T = -40 °C to +85 °C		-6.7	--	--	mV
		BW = 8.192 MHz, R _{LOAD} = 600 Ω, T = -40 °C to +85 °C		-143	--	--	mV
V _{OL}		R _{LOAD} = 50 kΩ, T = -40 °C to +85 °C		--	--	4.8	mV
		BW = 8.192 MHz, R _{LOAD} = 600 Ω, T = -40 °C to +85 °C		--	--	101	mV
V _{OSR}	Linear Output Swing Range	VOVR from Rail R _{LOAD} = 1 MΩ		GND + 100	--	V _{DD} - 100	mV
I _{SC}	Short Circuit Current	ISC to GND	BW = 128 kHz, T = -40 °C to +85 °C	--	10.693	--	mA
			BW = 512 kHz, T = -40 °C to +85 °C	--	14.288	--	mA
			BW = 2.048 MHz, T = -40 °C to +85 °C	--	22.230	--	mA
			BW = 8.192 MHz, T = -40 °C to +85 °C	--	51.489	--	mA
		ISC to V _{DD}	BW = 128 kHz, T = -40 °C to +85 °C		20.010	--	mA
			BW = 512 kHz, T = -40 °C to +85 °C		26.206	--	mA
			BW = 2.048 MHz, T = -40 °C to +85 °C		39.910	--	mA
			BW = 8.192 MHz, T = -40 °C to +85 °C		89.567	--	mA
C _{LOAD}	Capacitive Load Drive			--		--	pF
Power Supply							
V _{DD}	Supply Voltage	Guaranteed by PSRR Test		2.4	--	5.5	V

Table 22: EC of OA, $V_{DDA} = 2.4 \text{ V to } 5.5 \text{ V}$, $V_{CM} = V_{DDA}/2$, $V_{OUT} \approx V_{DDA}/2$, $R_L = 100 \text{ k}\Omega \text{ to } V_{DDA}/2$, $C_L = 50 \text{ pF}$, $T = 25^\circ\text{C}$

Parameter	Description	Conditions (Note 1)		Min	Typ	Max	Unit
I _Q (including charge pump current consumption)	Quiescent Current per Amplifier, BW = 128 kHz	T = 25 °C, V _{DDA} = 2.5 V to 5.5 V		--	32.558	--	μA
		T = -40 °C to +85 °C, V _{DDA} = 2.5 V to 5.5 V		--	32.160	--	μA
	Quiescent Current per Amplifier, BW = 512 kHz	T = 25 °C, V _{DDA} = 2.5 V to 5.5 V		--	87.576	--	μA
		T = -40 °C to +85 °C, V _{DDA} = 2.5 V to 5.5 V		--	86.940	--	μA
	Quiescent Current per Amplifier, BW = 2.048 MHz	T = 25 °C, V _{DDA} = 2.5 V to 5.5 V		--	236.020	--	μA
		T = -40 °C to +85 °C, V _{DDA} = 2.5 V to 5.5 V		--	233.160	--	μA
	Quiescent Current per Amplifier, BW = 8.192 MHz	T = 25 °C, V _{DDA} = 2.5 V to 5.5 V		--	608.094	--	μA
		T = -40 °C to +85 °C, V _{DDA} = 2.5 V to 5.5 V		--	594.150	--	μA
	Full Shutdown	T = -40 °C to +85 °C, V _{DDA} = 2.5 V to 5.5 V		--	103.352	--	nA
	Partial Shutdown (Note 3), BW = 128 kHz	T = 25 °C		--	14.916	--	μA
	Partial Shutdown (Note 3), BW = 8.192 MHz	T = 25 °C		--	14.916	--	μA
	Frequency Response						
GBW	Gain Bandwidth Product	R _{LOAD} = 10 kΩ, C _{LOAD} = 20 pF, G = +1 V/V	BW = 128 kHz	90	128	166	kHz
			BW = 512 kHz	358	512	666	kHz
			BW = 2.048 MHz	1434	2048	2662	kHz
			BW = 8.192 MHz	5734	8192	10650	kHz
PM	Phase Margin	G = +1 V/V, BW = 128 kHz → 8.192 MHz; R _{LOAD} = 10 kΩ, C _{LOAD} = 20 pF		44	70	--	degree
SR	Slew Rate	R _{LOAD} = 50 kΩ, C _{LOAD} = 85 pF	BW = 128 kHz, T = -40 °C to +85 °C	--	0.091	--	V/μs
			BW = 512 kHz, T = -40 °C to +85 °C	--	0.380	--	V/μs
			BW = 2.048 MHz, T = -40 °C to +85 °C	--	1.834	--	V/μs
			BW = 8.192 MHz, T = -40 °C to +85 °C	--	6.310	--	V/μs
t _{OR}	Overload Recovery Time	T = -40 °C to +85 °C R _{LOAD} = 50 kΩ		--	500	--	μs
Noise							

Table 22: EC of OA, $V_{DDA} = 2.4 \text{ V to } 5.5 \text{ V}$, $V_{CM} = V_{DDA}/2$, $V_{OUT} \approx V_{DDA}/2$, $R_L = 100 \text{ k}\Omega \text{ to } V_{DDA}/2$, $C_L = 50 \text{ pF}$, $T = 25^\circ \text{C}$

Parameter	Description	Conditions (Note 1)		Min	Typ	Max	Unit
THD	Total Harmonic Distortion	AV = 1, RLOAD = 50 kΩ, VOUT(PP) = VDD/2	f = 1 kHz, BW = 128 kHz	--	1.3	--	%
			f = 1 kHz, BW = 512 kHz	--	0.2	--	%
			f = 1 kHz, BW = 2.048 MHz	--	0.7	--	%
			f = 1 kHz, BW = 8.192 MHz	--	0.1	--	%
e _n	Input Voltage Noise	f = 0.1 to 10 Hz		--	4	--	μVpp
V _n	Input Voltage Noise Density	f = 1 kHz	BW = 128 kHz	--	--	130	nV/ √Hz
			BW = 512 kHz	--	--	125	
			BW = 2.048 MHz	--	--	120	
			BW = 8.192 MHz	--	--	75	
I _n	Input Current Noise Density	f = 1 kHz		--	1	--	fA/ √Hz
Shutdown Characteristics							
t _{on}	Amplifier Turn-On Time	BW = 8.192 MHz, T = -40 °C to +85 °C	V _{CM} = V _{DDA} /2, R _L = 50 kΩ	--	2.121	5.363	μs
			V _{DDA} > V _{CM} > (V _{DDA} - 1.3)	--	2.145	5.330	μs
		BW = 128 kHz, T = -40 °C to +85 °C	V _{CM} = V _{DDA} /2, R _L = 50 kΩ	--	25.458	43.158	μs
			V _{DDA} > V _{CM} > (V _{DDA} - 1.3)	--	35.134	70.602	μs
t _{off}	Amplifier Turn-Off Time	--		--	0.671	1.015	μs
Comparator Mode							
t _{PHL}	Propagation Delay Output High to Low	V _{ID} = 100 mV, BW = 128 kHz		--	15	--	μs
		V _{ID} = 100 mV, BW = 512 kHz		--	3.5	--	μs
		V _{ID} = 100 mV, BW = 2.048 MHz		--	1.2	--	μs
		V _{ID} = 100 mV, BW = 8.192 MHz		--	4.2	--	μs
t _{PLH}	Propagation Delay Output Low to High	V _{ID} = 100 mV, BW = 128 kHz		--	14	--	μs
		V _{ID} = 100 mV, BW = 512 kHz		--	3.5	--	μs
		V _{ID} = 100 mV, BW = 2.048 MHz		--	1.2	--	μs
		V _{ID} = 100 mV, BW = 8.192 MHz		--	4.2	--	μs
3 Op Amp Instrumentation Amplifier Mode							
R _{INT_TL}	Mismatch Between Internal Resistors (R ₁ , R ₂ , R ₃ , R ₄)			--	--	0.15	%

Table 22: EC of OA, $V_{DDA} = 2.4 \text{ V to } 5.5 \text{ V}$, $V_{CM} = V_{DDA}/2$, $V_{OUT} \approx V_{DDA}/2$, $R_L = 100 \text{ k}\Omega$ to $V_{DDA}/2$, $C_L = 50 \text{ pF}$, $T = 25 \text{ }^\circ\text{C}$

Parameter	Description	Conditions (Note 1)	Min	Typ	Max	Unit
Note 1 AGND = GND, unless otherwise noted Note 2 Equivalent offset voltage of the amplifier after user's trim using digital rheostat. Gain of the amplifier is $G=200$ and the zero output voltage level $V_{zero} = V_{DD}/2$ (See Section 10.2.1) Note 3 Op amps analog supporting blocks are always turned on.						

3.12 100K DIGITAL RHEOSTAT CHARACTERISTICS

Table 23: 100K Digital Rheostat EC at $V_A=V_{DD}$, $V_B=GND$, $T=-40^\circ\text{C}$ to $+85^\circ\text{C}$, $V_{DD}=2.4\text{V}$ to 5.5V Unless Otherwise Noted

Parameter	Description	Conditions	Min	Typ	Max	Unit
V_{DR}	Rheostat Pin Voltage Range	Voltage between any (A or B) pins and AGND	AGND	--	V_{DDA}	V
R_{DR}	Digital Rheostat Resistance	Full resistance with all switches open (Note 1)	80	100	120	k Ω
R_{DR_MIN}	Minimal Rheostat Resistance	Code = 0x00	44.381	--	110	Ω
R_{MATCH}	Mismatch between rheostats	Code = 0x3FF, $T = 25 \text{ }^\circ\text{C}$	--	0.043	--	%
Number of taps					1024	
$BWDT_{DR}$	Digital Rheostat Bandwidth	Frequency applied on one side of resistor chain and -3 dB frequency measured at the other side with full 100 k Ω , assume no additional load	--	50	--	kHz
R_S	Step Resistance		--	98.266	--	Ω
I_{DR_MAX}	Max current through Rheostat	$T = 25 \text{ }^\circ\text{C}$	--	--	2	mA
E_{SW_N}	Resistor Noise Voltage	$R_{AB} = 25 \text{ k}\Omega$, $f = 1 \text{ kHz}$	--	30	--	nV/ $\sqrt{\text{Hz}}$
f_{ChACMP}	Chopper Comparator Switching Frequency		--	--	30	kHz
V_{Ch_offset}	Chopper comparator offset when Auto-Trim process is active		--	100	300	μV
f_{DR_CLK}	Counter Frequency independent from the Rheostat	The counter frequency is determined by user selection	0	--	25	MHz
f_{DR_SWCH}	Rheostat Switch Speed (Note 2)	$V_A = 5 \text{ V}$, $V_B = 0 \text{ V}$, $\pm 1 \text{ LSB}$ error band, Auto-Trim mode	--	--	10	kHz
		$V_A = 5 \text{ V}$, $V_B = 0 \text{ V}$, $\pm 1 \text{ LSB}$ error band, regular mode	--	--	1	kHz
C_{DR}	Maximum Capacitance of A, B pins Measured to AGND	All switches are ON, $f = 200 \text{ kHz}$	--	33.461	--	pF
I_{LKG}	Leakage Current	Including active charge pump current consumption	--	--	1000	nA
Error ZScale	Zero-Scale Error	Code = 0x00	--	--	1.203	LSB
Error FScale	Full-Scale Error	Code = 0x3FF	--	--	61	LSB

Table 23: 100K Digital Rheostat EC at $V_A=V_{DD}$, $V_B=GND$, $T=-40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$, $V_{DD}=2.4\text{V}$ to 5.5V Unless Otherwise Noted

Parameter	Description	Conditions	Min	Typ	Max	Unit
INL	Integral Non-linearity		--	--	± 1	LSB
DNL	Differential Non-linearity		--	--	± 1	LSB
BWDT _{CAP}	Bandwidth -3 dB (Load = 30 pF)	$R_{LOAD} < 12.5\text{ k}\Omega$	--	240	--	kHz
		$R_{LOAD} = 12.5\text{ k}\Omega$ to $25\text{ k}\Omega$	--	120	--	kHz
		$R_{LOAD} = 25\text{ k}\Omega$ to $50\text{ k}\Omega$	--	60	--	kHz
		$R_{LOAD} = 50\text{ k}\Omega$ to $100\text{ k}\Omega$	--	30	--	kHz
$\alpha R(T)$	Resistance Temperature Coefficient	$V_{AB} = \text{const.}$	--	--	110	ppm/ $^{\circ}\text{C}$
Potentiometer Mode						
INL _{POT}	Integral Non-linearity in Potentiometer Mode		--	--	± 1	LSB
DNL _{POT}	Differential Non-linearity in Potentiometer Mode		--	--	± 1	LSB

Note 1 User can calculate actual Digital Rheostat value using calibration data from NVM (see Section 12.2).
Note 2 Includes internal timing. External circuit should be counted separately.

3.13 ANALOG SWITCHES CHARACTERISTICS

Table 24: Analog Switch0/Voltage Regulator EC at $T = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$, $V_{DD} = 2.4\text{V}$ to 5.5V Unless Otherwise Noted

Parameter	Description	Conditions	Min	Typ	Max	Unit
V_{AS}	Maximum Voltage At Pins	Voltage between any Analog Switch pin to AGND	0	--	$V_{DD} + 0.3$	V
f_{MAX}	Maximum Switching Frequency	$R_L = 50\text{ k}\Omega$	3	--	--	MHz
R_{ON}	ON Resistance	$V_{DD} = 3.3\text{V}$; $V_{IN} > 1.2\text{V}$, N-ch FET, $T = 25^{\circ}\text{C}$	--	29.621	--	Ω
		$V_{DD} - 1.2 < V_{IN} < V_{DD}$, P-ch FET, $T = 25^{\circ}\text{C}$	--	3.857	--	Ω
I_{PWROFF}	OFF Leakage Current	Switch OFF; from IN to OUT $V_A = V_{DD}$ or $V_B = V_{DD}$	--	--	7.456	nA
I_{PWRON}	ON Leakage Current (Including Charge Pump Current Consumption)	Switch ON, quiescent current consumption	--	--	0.1	μA
I_{SW_MAX}	Maximum ON-state Switch Current	$V_A = V_{DD}$, load connected to ground, $V_{AB} = 0.4\text{V}$	100	--	--	mA

Table 25: Analog Switch1/Current Sink EC at $T = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$, $V_{DD} = 2.4\text{V}$ to 5.5V Unless Otherwise Noted

Parameter	Description	Conditions	Min	Typ	Max	Unit
V_{AS}	Maximum Voltage At Pins	Voltage between any Analog Switch pin to AGND	0	--	$V_{DD} + 0.3$	V
f_{MAX}	Maximum Switching Frequency	$R_L = 50\text{ k}\Omega$	3	--	--	MHz

Table 25: Analog Switch1/Current Sink EC at T = -40 °C to +85 °C, V_{DD} = 2.4 V to 5.5 V Unless Otherwise Noted

Parameter	Description	Conditions	Min	Typ	Max	Unit
R _{ON}	ON Resistance	V _{DD} = 3.3 V; V _{in} > 1.2 V, N-ch FET, T = 25 °C	--	0.809	--	Ω
		V _{DD} - 1.2 < V _{IN} < V _{DD} , P-ch FET, T = 25 °C	--	95.5	--	Ω
I _{PWROFF}	OFF Leakage Current	Switch OFF; from IN to OUT, V _A = V _{DD} or V _B = V _{DD}	--	--	8.073	nA
I _{PWRON}	ON Leakage Current (including charge pump current consumption)	Switch ON quiescent current consumption	--	--	0.1	μA
I _{SW_MAX}	Maximum ON-state Switch Current	V _A = V _{DD} , load connected to ground, V _{AB} = 0.4 V	100	--	--	mA

4 User Programmability

The SLG47004 is a user programmable device with Multiple-Time-Programmable (MTP) memory elements that are able to configure the connection matrix and macrocells. A programming development kit allows the user the ability to create initial devices. Once the design is finalized, the programming code (.gpx file) is forwarded to Dialog Semiconductor to integrate into a production process.

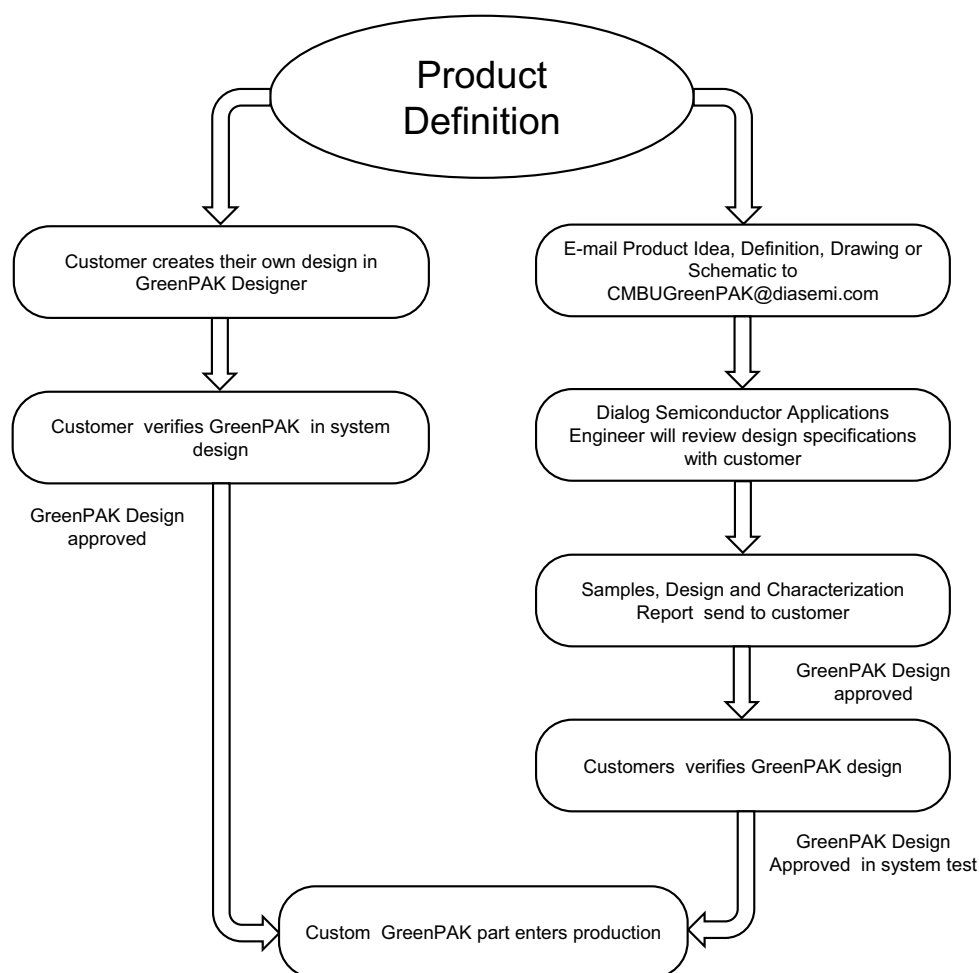


Figure 2: Steps to Create a Custom GreenPAK Device

5 IO Pins

The SLG47004 has a total of 7 GPIO Pins which can function as either a user-defined Input or Output, as well as serve as a special function (such as outputting the voltage reference) and 1 GPI Pin.

5.1 GPIO PINS

IO0, IO1, IO2, IO3, IO4, IO5, and IO6 serve as General Purpose IO Pins.

5.2 GPI PINS

IO serve as General Purpose Input Pin.

5.3 PULL-UP/DOWN RESISTORS

All IO Pins have the option of user-selectable resistors that can be connected to the pin structure. The selectable values on these resistors are 10 k Ω , 100 k Ω , and 1 M Ω . The internal resistors can be configured as either Pull-up or Pull-downs.

5.4 FAST PULL-UP/DOWN DURING POWER-UP

During power-up, IO Pull-up/down resistance will switch to 2.6 k Ω initially and then it will switch to normal setting value. This function is enabled by register [1207].

5.5 I²C MODE IO STRUCTURE

5.5.1 I²C Mode Structure (for SCL and SDA)

Input Mode [1:0]

00: Digital In without Schmitt Trigger, wosmt_en = 1

01: Reserved

10: Low Voltage Digital In mode 1, lv_en = 1

11: Reserved

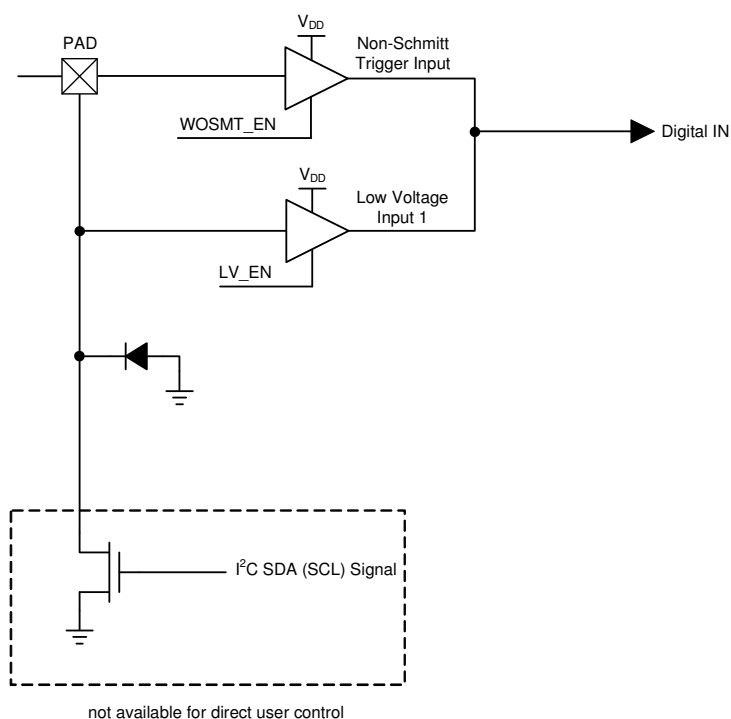


Figure 3: IO with I²C Mode IO Structure Diagram

5.6 MATRIX OE IO STRUCTURE

Input Mode registers [1153:1152]

00: Digital In without Schmitt Trigger, wosmt_en = 1
01: Digital In with Schmitt Trigger, smt_en = 1
10: Low Voltage Digital In mode, lv_en = 1
11: analog IO mode

Output Mode [1:0]

00: Push-Pull 1x mode, pp1x_en = 1
01: Push-Pull 2x mode, pp2x_en = 1, pp1x_en = 1
10: NMOS 1x Open-Drain mode, od1x_en = 1
11: NMOS 2x Open-Drain mode, od2x_en = 1, od1x_en = 1

Note 1: Digital Out and OE are Matrix Output, Digital In is Matrix Input.
Note 2: Can be varied over PVT, for reference only.

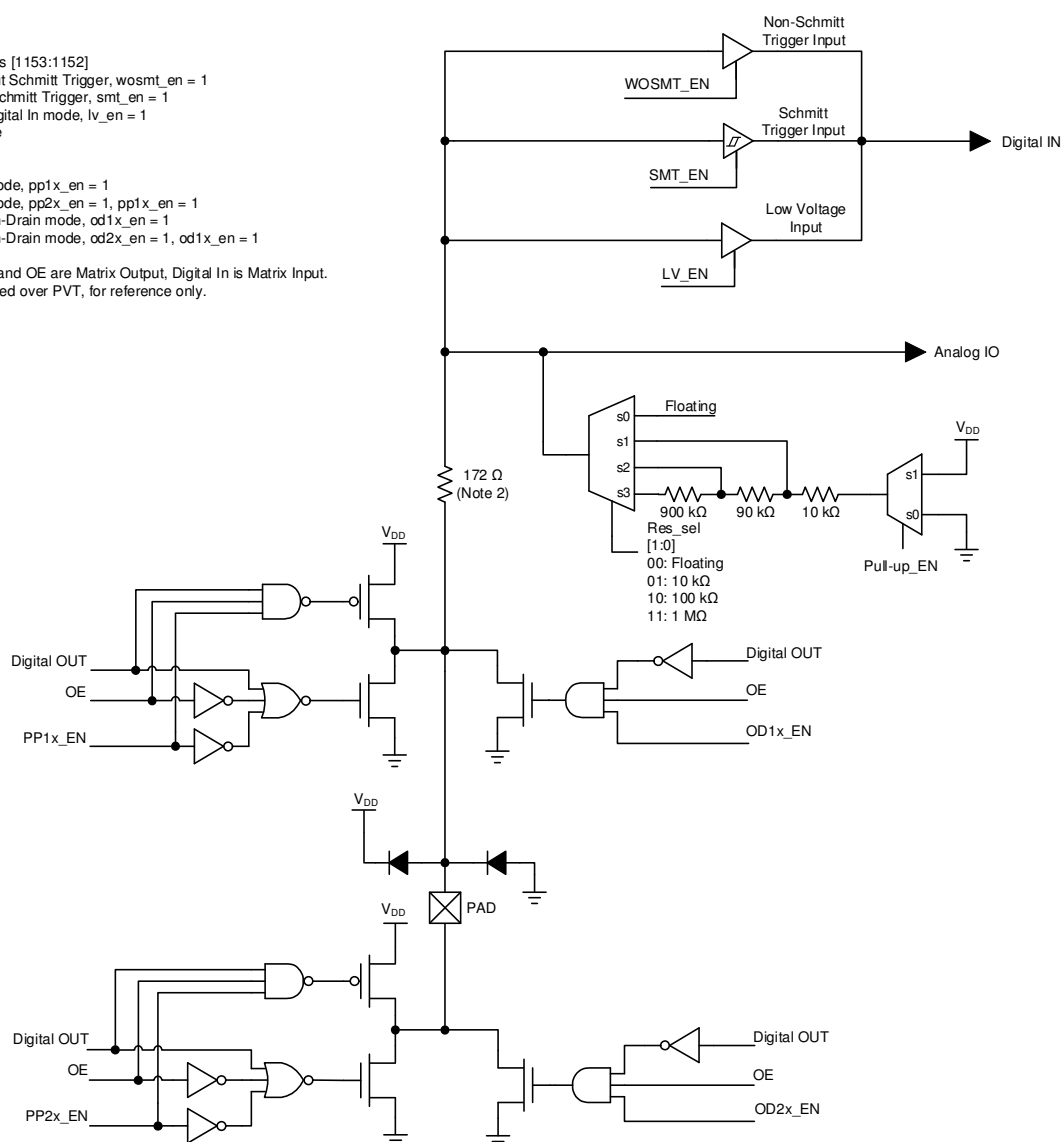


Figure 4: Matrix OE IO Structure Diagram

5.7 GPI STRUCTURE

5.7.1 GPI Structure (for I0)

Input Mode [1:0]

00: Digital In without Schmitt Trigger, wosmt_en = 1, OE=0

01: Digital In with Schmitt Trigger, smt_en = 1, OE = 0

10: Low Voltage Digital In mode, lv_en = 1, OE = 0

11: Reserved

Note 1: OE cannot be selected by user.

Note 2: OE is Matrix output, Digital In is Matrix input.

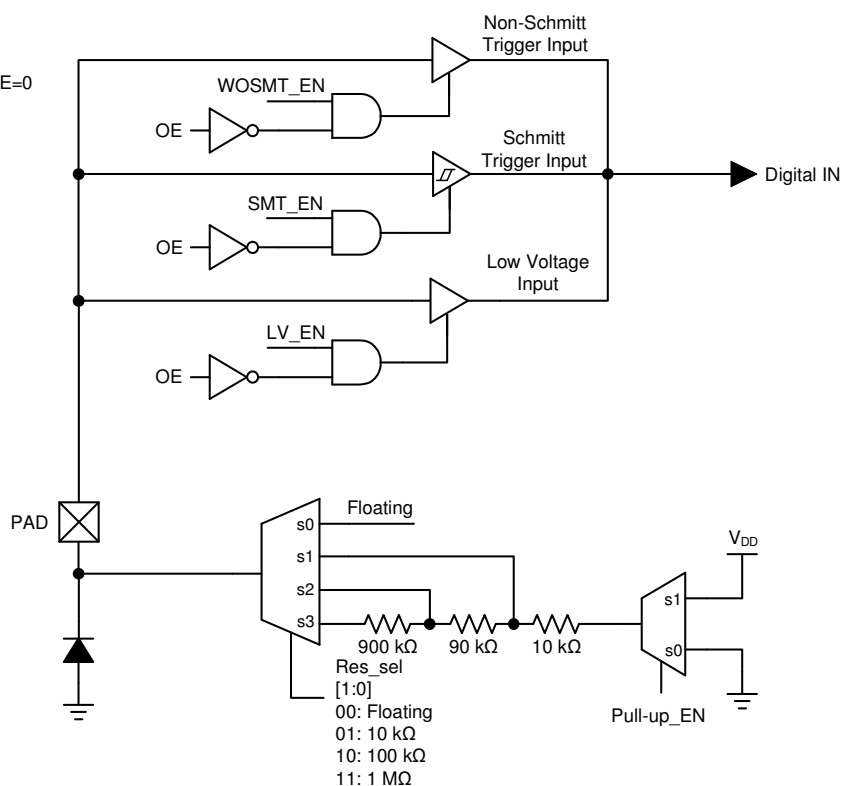


Figure 5: IO0 GPI Structure Diagram

5.8 IO PINS TYPICAL PERFORMANCE

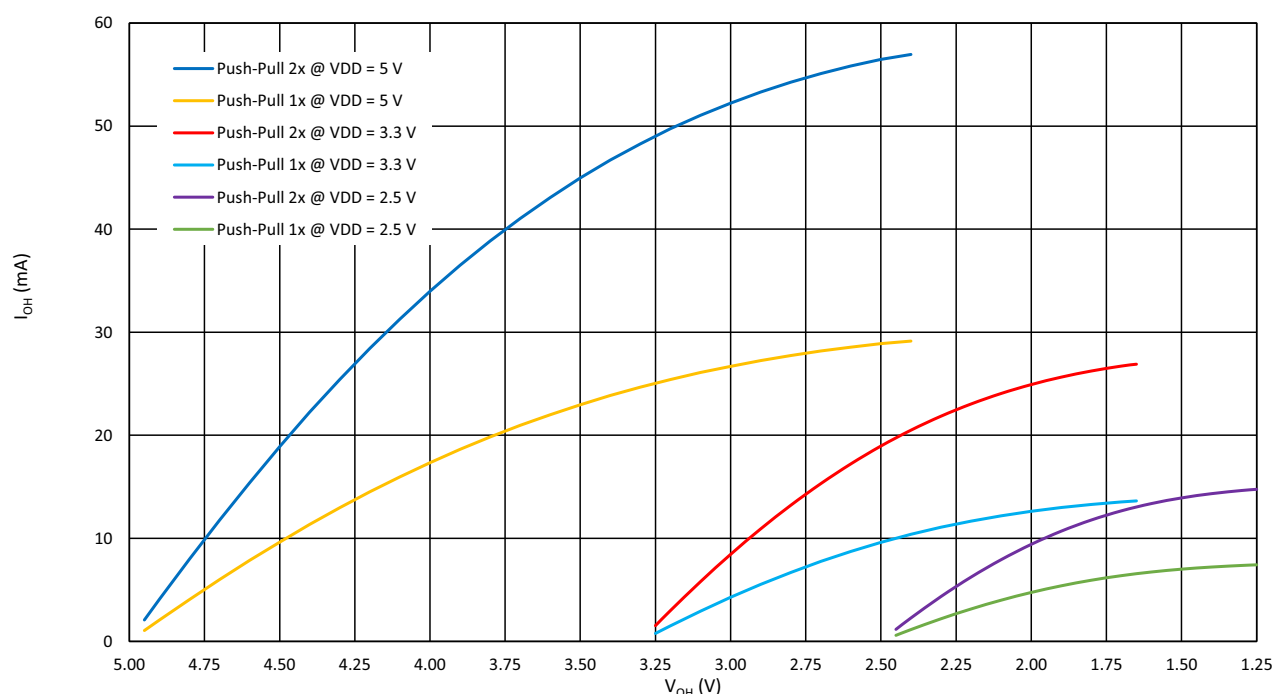


Figure 6: Typical High Level Output Current vs. High Level Output Voltage at T = 25 °C

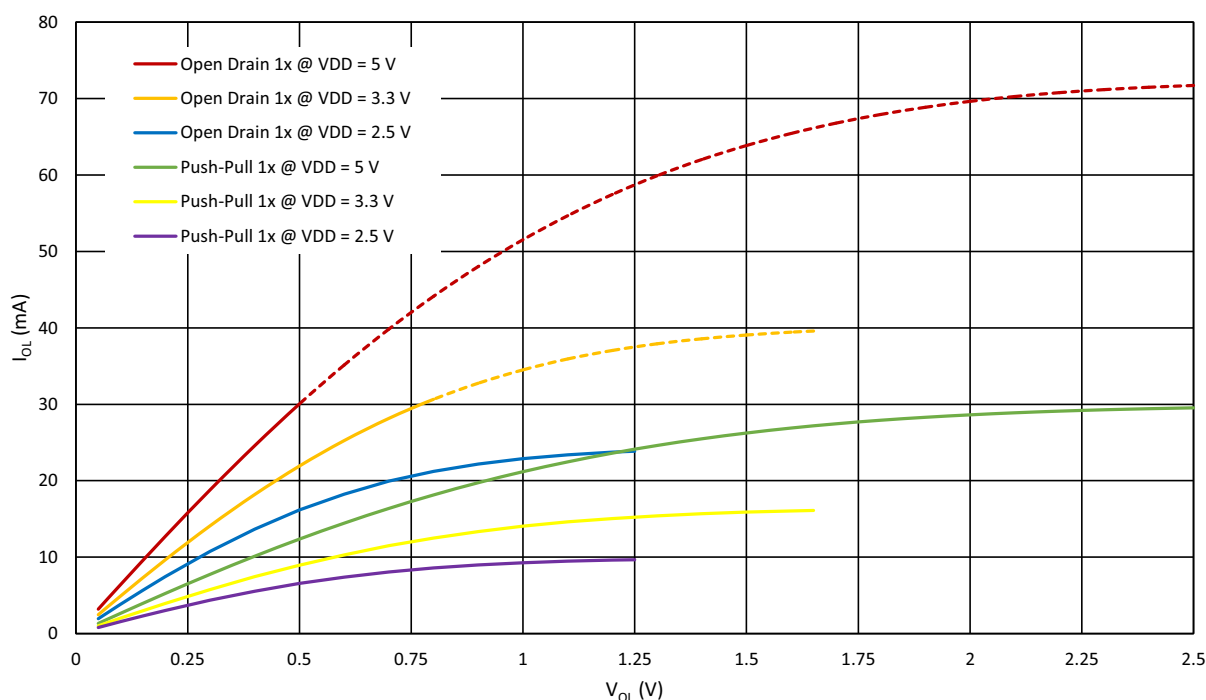


Figure 7: Typical Low Level Output Current vs. Low Level Output Voltage, 1x Drive at T = 25 °C, Full Range

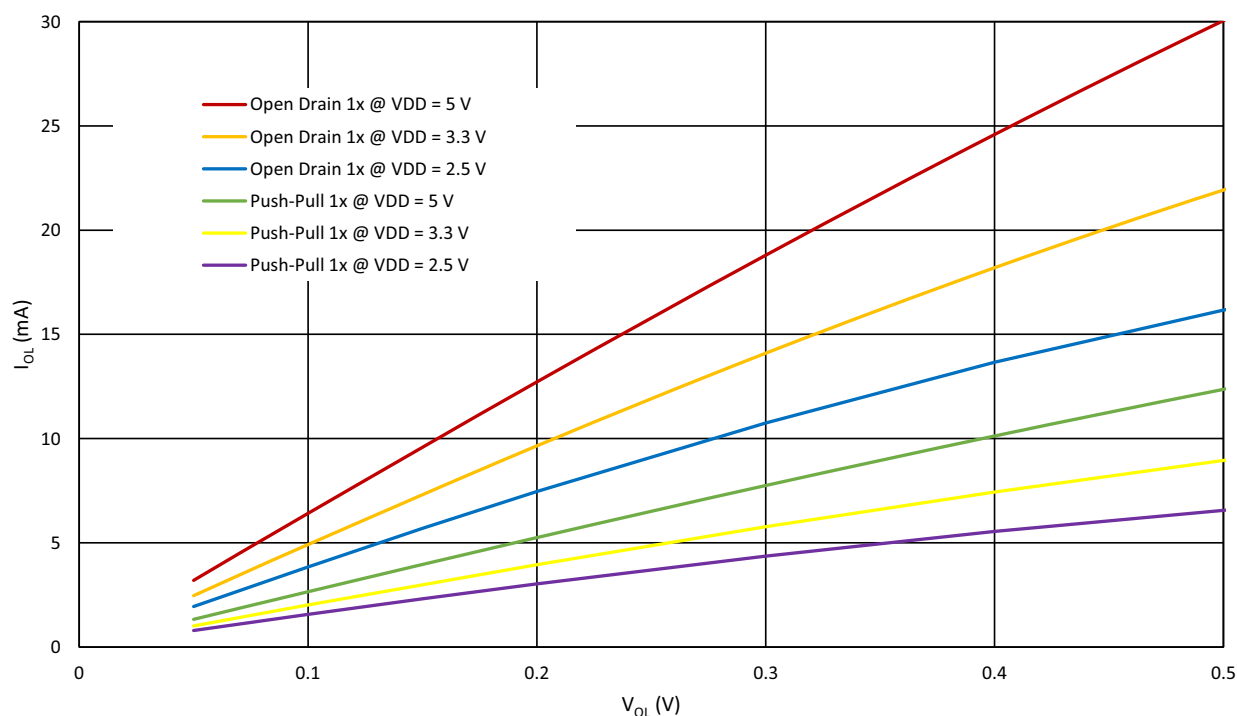


Figure 8: Typical Low Level Output Current vs. Low Level Output Voltage, 1x Drive at T = 25 °C

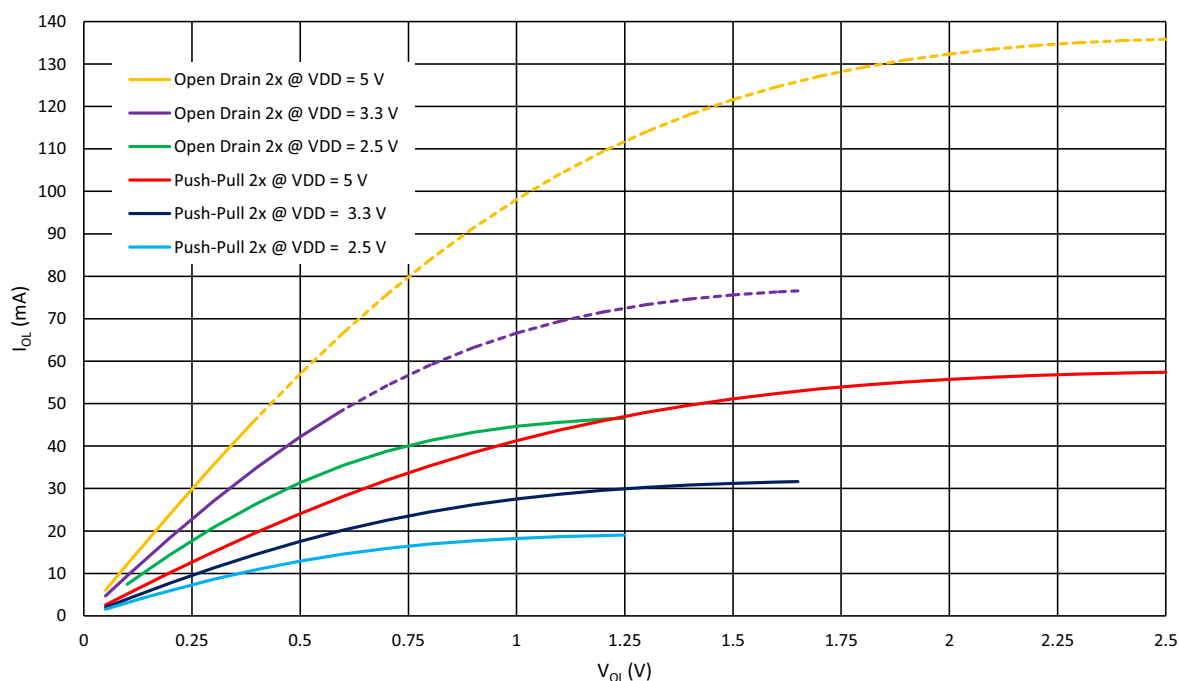


Figure 9: Typical Low Level Output Current vs. Low Level Output Voltage, 2x Drive at T = 25 °C, Full Range

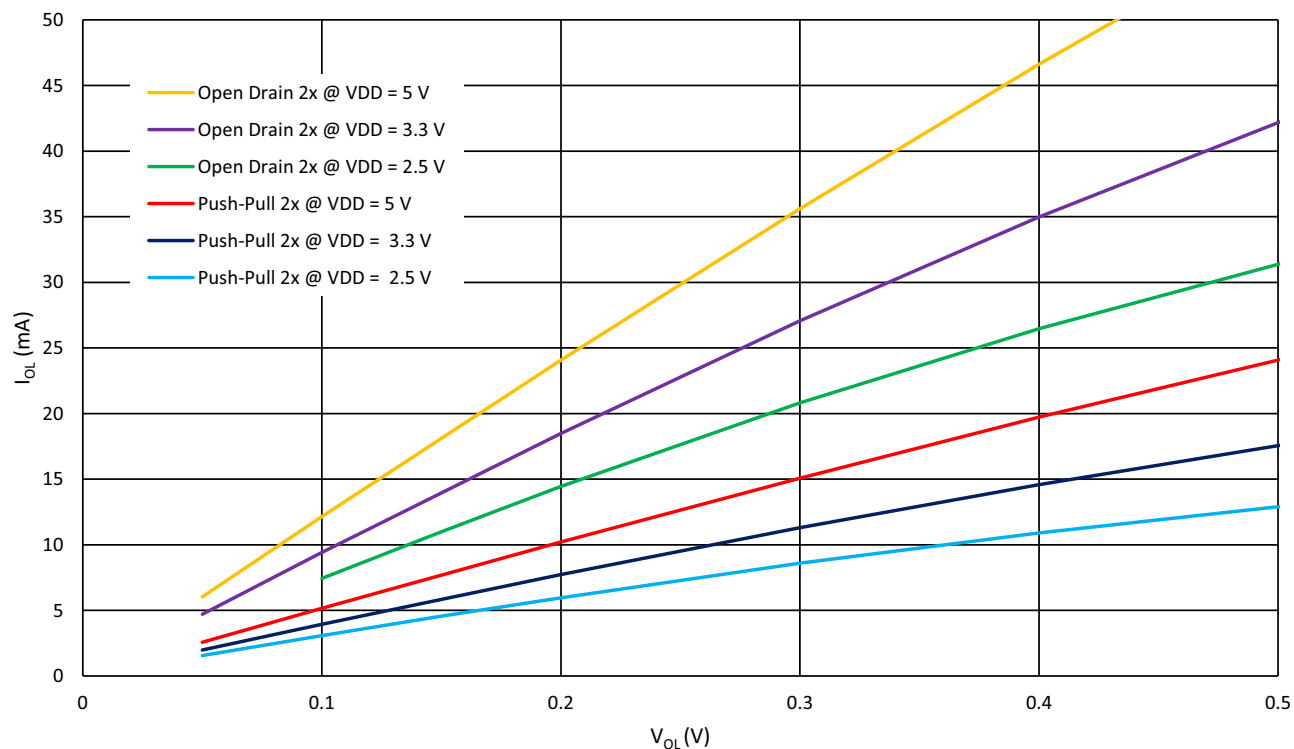


Figure 10: Typical Low Level Output Current vs. Low Level Output Voltage, 2x Drive at $T = 25^\circ\text{C}$

6 Connection Matrix

The Connection Matrix in the SLG47004 is used to create an internal routing for internal functional macrocells of the device once it is programmed. The output of each functional macrocell within the SLG47004 has a specific digital bit code assigned to it, that is either set to active "High" or inactive "Low", based on the design that is created. Once the 2048 register bits within the SLG47004 are programmed, a fully custom circuit will be created.

The Connection Matrix has 64 inputs and 99 outputs. Each of the 64 inputs to the Connection Matrix is hard-wired to the digital output of a particular source macrocell, including IOs, LUTs, analog comparators, other digital resources, such as V_{DD} and GND. The input to a digital macrocell uses a 6-bit register to select one of these 64 input lines.

For a complete list of the SLG47004's register table, see Section 21.

Matrix Input Signal Functions	N						
GND	0						
LUT2_0/DFF0 output	1						
LUT2_1/DFF1 output	2						
LUT2_2/DFF2 output	3						
⋮	⋮						
V _{DD}	62						
V _{DD}	63						
Matrix Inputs	N	0	1	2	-----	99	
		Registers	registers [5:0]	registers [11:6]	registers [17:12]	-----	registers [599:594]
		Function	Matrix OUT: IN0 of LUT2_0 or Clock Input of DFF0	Matrix OUT: IN1 of LUT2_0 or Data Input of DFF0	Matrix Out: IN0 of LUT2_1 or Clock Input of DFF1	-----	OP Vref ENABLE
Matrix Outputs							

Figure 11: Connection Matrix

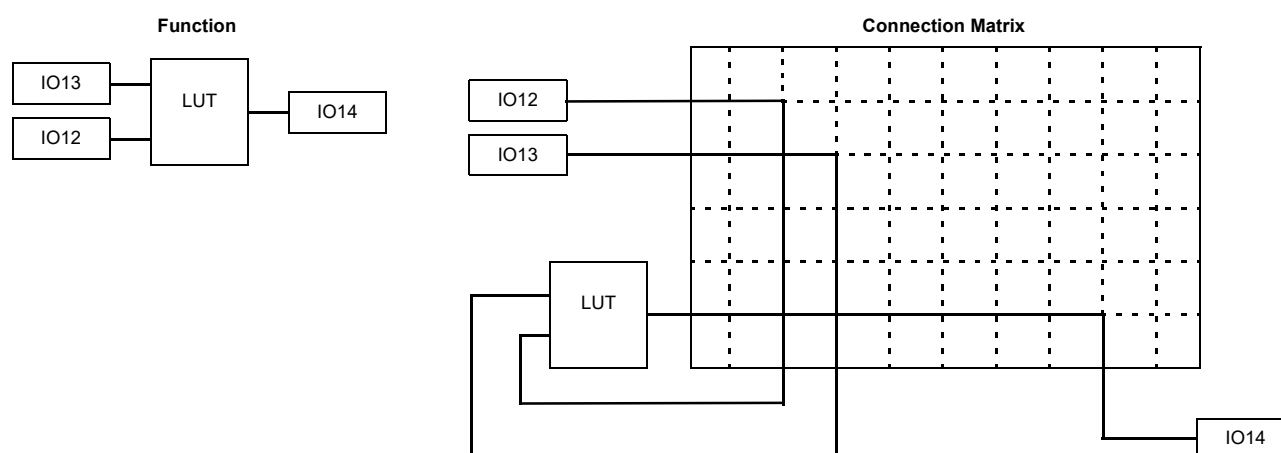


Figure 12: Connection Matrix Example

6.1 MATRIX INPUT TABLE

Table 26: Matrix Input Table

Matrix Input Number	Matrix Input Signal Function	Matrix Decode					
		5	4	3	2	1	0
0	GND	0	0	0	0	0	0
1	LUT2_0/DFF0 output	0	0	0	0	0	1
2	LUT2_1/DFF1 output	0	0	0	0	1	0
3	LUT2_2/DFF2 output	0	0	0	0	1	1
4	LUT2_3/PGen output	0	0	0	1	0	0
5	LUT3_0/DFF3 output	0	0	0	1	0	1
6	LUT3_1/DFF4 output	0	0	0	1	1	0
7	LUT3_2/DFF5 output	0	0	0	1	1	1
8	LUT3_3/DFF6 output	0	0	1	0	0	0
9	LUT3_4/DFF7 output	0	0	1	0	0	1
10	LUT3_5/DFF8 output	0	0	1	0	1	0
11	LUT3_6/DFF9 output	0	0	1	0	1	1
12	CNT_DLY0 output	0	0	1	1	0	0
13	MLT0_LUT4_1/DFF17_OUT	0	0	1	1	0	1
14	CNT_DLY1 output	0	0	1	1	1	0
15	MLT1_LUT3_7/DFF11_OUT	0	0	1	1	1	1
16	CNT_DLY2 output	0	1	0	0	0	0
17	MLT2_LUT3_8/DFF12_OUT	0	1	0	0	0	1
18	CNT_DLY3 output	0	1	0	0	1	0
19	MLT3_LUT3_9/DFF13_OUT	0	1	0	0	1	1
20	CNT_DLY4 output	0	1	0	1	0	0
21	MLT4_LUT3_10/DFF14_OUT	0	1	0	1	0	1
22	CNT_DLY5 output	0	1	0	1	1	0
23	MLT5_LUT3_11/DFF15_OUT	0	1	0	1	1	1
24	CNT_DLY6 output	0	1	1	0	0	0
25	MLT6_LUT3_12/DFF16_OUT	0	1	1	0	0	1
26	LUT3_13/Pipe Delay/RippleCNT_out0	0	1	1	0	1	0
27	Pipe Delay/RippleCNT_out1	0	1	1	0	1	1
28	Pipe Delay/RippleCNT_out2	0	1	1	1	0	0
29	LUT4_0/DFF10 output	0	1	1	1	0	1
30	Programmable Delay Edge Detect Output	0	1	1	1	1	0
31	Edge Detect Filter Output	0	1	1	1	1	1
32	I ² C_virtual_0 Input	1	0	0	0	0	0
33	I ² C_virtual_1 Input	1	0	0	0	0	1
34	I ² C_virtual_2 Input	1	0	0	0	1	0
35	I ² C_virtual_3 Input	1	0	0	0	1	1
36	I ² C_virtual_4 Input	1	0	0	1	0	0
37	I ² C_virtual_5 Input	1	0	0	1	0	1

Table 26: Matrix Input Table(Continued)

Matrix Input Number	Matrix Input Signal Function	Matrix Decode					
		5	4	3	2	1	0
38	I ² C_virtual_6 Input	1	0	0	1	1	0
39	I ² C_virtual_7 Input	1	0	0	1	1	1
40	RH0 Idle/Active	1	0	1	0	0	0
41	RH1 Idle/Active	1	0	1	0	0	1
42	Output of Op Amp0 in ACMP mode	1	0	1	0	1	0
43	Output of Op Amp1 in ACMP mode	1	0	1	0	1	1
44	IO0 Digital Input	1	0	1	1	0	0
45	IO1 Digital Input	1	0	1	1	0	1
46	IO2 Digital Input	1	0	1	1	1	0
47	IO3 Digital Input	1	0	1	1	1	1
48	IO4 Digital Input	1	1	0	0	0	0
49	IO5 Digital Input	1	1	0	0	0	1
50	IO6 Digital Input	1	1	0	0	1	0
51	IO Digital Input	1	1	0	0	1	1
52	Oscillator0 output 0	1	1	0	1	0	0
53	Oscillator1 output 0	1	1	0	1	0	1
54	Oscillator2 output	1	1	0	1	1	0
55	Chopper ACMP Out	1	1	0	1	1	1
56	ACMP0 Output (low speed)	1	1	1	0	0	0
57	ACMP1 Output (low speed)	1	1	1	0	0	1
58	Oscillator0 output 1	1	1	1	0	1	0
59	Oscillator1 output 1	1	1	1	0	1	1
60	POR OUT	1	1	1	1	0	0
61	V _{DD}	1	1	1	1	0	1
62	V _{DD}	1	1	1	1	1	0
63	V _{DD}	1	1	1	1	1	1

6.2 MATRIX OUTPUT TABLE

Table 27: Matrix Output Table

Register Bit Address	Matrix Output Signal Function	Matrix Output Number
[5:0]	IN0 of LUT2_0 or Clock Input of DFF0	0
[11:6]	IN1 of LUT2_0 or Data Input of DFF0	1
[17:12]	IN0 of LUT2_1 or Clock Input of DFF1	2
[23:18]	IN1 of LUT2_1 or Data Input of DFF1	3
[29:24]	IN0 of LUT2_2 or Clock Input of DFF2	4
[35:30]	IN1 of LUT2_2 or Data Input of DFF2	5
[41:36]	IN0 of LUT2_3 or Clock Input of PGen	6
[47:42]	IN1 of LUT2_3 or nRST of PGen	7
[53:48]	IN0 of LUT3_0 or CLK Input of DFF3	8

Table 27: Matrix Output Table(Continued)

Register Bit Address	Matrix Output Signal Function	Matrix Output Number
[59:54]	IN1 of LUT3_0 or Data of DFF3	9
[65:60]	IN2 of LUT3_0 or nRST (nSET) of DFF3	10
[71:66]	IN0 of LUT3_1 or CLK Input of DFF4	11
[77:72]	IN1 of LUT3_1 or Data of DFF4	12
[83:78]	IN2 of LUT3_1 or nRST (nSET) of DFF4	13
[89:84]	IN0 of LUT3_2 or CLK Input of DFF5	14
[95:90]	IN1 of LUT3_2 or Data of DFF5	15
[101:96]	IN2 of LUT3_2 or nRST(nSET) of DFF5	16
[107:102]	IN0 of LUT3_3 or CLK Input of DFF6	17
[113:108]	IN1 of LUT3_3 or Data of DFF6	18
[119:114]	IN2 of LUT3_3 or nRST (nSET) of DFF6	19
[125:120]	IN0 of LUT3_4 or CLK Input of DFF7	20
[131:126]	IN1 of LUT3_4 or Data of DFF7	21
[137:132]	IN2 of LUT3_4 or nRST (nSET) of DFF7	22
[143:138]	IN0 of LUT3_5 or CLK Input of DFF8	23
[149:144]	IN1 of LUT3_5 or Data of DFF8	24
[155:150]	IN2 of LUT3_5 or nRST (nSET) of DFF8	25
[161:156]	IN0 of LUT3_6 or CLK Input of DFF9	26
[167:162]	IN1 of LUT3_6 or CLK Input of DFF9	27
[173:168]	IN2 of LUT3_6 or nRST (nSET) of DFF9	28
[179:174]	IN0 of LUT3_7 or CLK Input of DFF11 Delay1 Input (or Counter1 nRST Input)	29
[185:180]	IN1 of LUT3_7 or nRST (nSET) of DFF11 Delay1 Input (or Counter1 nRST Input)	30
[191:186]	IN2 of LUT3_7 or Data of DFF11 Delay1 Input (or Counter1 nRST Input)	31
[197:192]	IN0 of LUT3_8 or CLK Input of DFF12 Delay2 Input (or Counter2 nRST Input)	32
[203:198]	IN1 of LUT3_8 or nRST (nSET) of DFF12 Delay2 Input (or Counter2 nRST Input)	33
[209:204]	IN2 of LUT3_8 or Data of DFF12 Delay2 Input (or Counter2 nRST Input)	34
[215:210]	IN0 of LUT3_9 or CLK Input of DFF13 Delay3 Input (or Counter3 nRST Input)	35
[221:216]	IN1 of LUT3_9 or nRST (nSET) of DFF13 Delay3 Input (or Counter3 nRST Input)	36
[227:222]	IN2 of LUT3_9 or Data of DFF13 Delay3 Input (or Counter3 nRST Input)	37
[233:228]	IN0 of LUT3_10 or CLK Input of DFF14 Delay4 Input (or Counter4 nRST Input)	38
[239:234]	IN1 of LUT3_10 or nRST (nSET) of DFF14 Delay4 Input (or Counter4 nRST Input)	39

Table 27: Matrix Output Table(Continued)

Register Bit Address	Matrix Output Signal Function	Matrix Output Number
[245:240]	IN2 of LUT3_10 or Data of DFF14 Delay4 Input (or Counter4 nRST Input)	40
[251:246]	IN0 of LUT3_11 or CLK Input of DFF15 Delay5 Input (or Counter5 nRST Input)	41
[257:252]	IN1 of LUT3_11 or nRST (nSET) of DFF15 Delay5 Input (or Counter5 nRST Input)	42
[263:258]	IN2 of LUT3_11 or nRST (nSET) of DFF15 Delay5 Input (or Counter5 nRST Input)	43
[269:264]	IN0 of LUT3_12 or CLK Input of DFF16 Delay6 Input (or Counter6 nRST Input)	44
[275:270]	IN1 of LUT3_12 or nRST (nSET) of DFF16 Delay6 Input (or Counter6 nRST Input)	45
[281:276]	IN2 of LUT3_12 or Data of DFF16 Delay6 Input (or Counter6 nRST Input)	46
[287:282]	IN0 of LUT3_13 or Input of Pipe Delay or UP signal of RIPP CNT	47
[293:288]	IN1 of LUT3_13 or nRST of Pipe Delay or nSet of RIPP CNT	48
[299:294]	IN2 of LUT3_13 or CLK of Pipe Delay_RIPP CNT	49
[305:300]	IN0 of LUT4_0 or CLK of DFF10	50
[311:306]	IN1 of LUT4_0 or Data of DFF10	51
[317:312]	IN2 of LUT4_0 or nRST (nSET) of DFF10	52
[323:318]	IN3 of LUT4_0	53
[329:324]	IN0 of LUT4_1 or CLK Input of DFF17 Delay0 Input (or Counter0 nRST Input)	54
[335:330]	IN1 of LUT4_1 or nRST of DFF17 Delay0 Input (or Counter0 nRST Input) Delay/Counter0 External CLK source	55
[341:336]	IN2 of LUT4_1 or nSet of DFF17 Delay0 Input (or Counter0 nRST Input) Delay/Counter0 External CLK source KEEP Input of FSM0	56
[347:342]	IN3 of LUT4_1 or Data of DFF17 Delay0 Input (or Counter0 nRST Input) UP Input of FSM0	57
[353:348]	Programmable delay/edge detect input	58
[359:354]	Filter/Edge detect input	59
[365:360]	IO0 DOUT	60
[371:366]	IO0 DOUT OE	61
[377:372]	IO1 DOUT	62
[383:378]	IO1 DOUT OE	63
[389:384]	IO2 DOUT	64
[395:390]	IO2 DOUT OE	65
[401:396]	IO3 DOUT	66
[407:402]	IO3 DOUT OE	67
[413:408]	IO4 DOUT	68

Table 27: Matrix Output Table(Continued)

Register Bit Address	Matrix Output Signal Function	Matrix Output Number
[419:414]	IO4 DOUT OE	69
[425:420]	IO5 DOUT	70
[431:426]	IO5 DOUT OE	71
[437:432]	IO6 DOUT	72
[443:438]	IO6 DOUT OE	73
[449:444]	Set of PT0 block	74
[455:450]	Clock of PT0 block	75
[461:456]	Reload of PT0 block	76
[467:462]	Program of PT0 block	77
[473:468]	Up/Down of PT0 block	78
[479:474]	Set of PT1 block	79
[485:480]	Clock of PT1 block	80
[491:486]	Reload of PT1 block	81
[497:492]	Program of PT1 block	82
[503:498]	Up/Down of PT1 block	83
[509:504]	FIFO Reset of PT blocks	84
[515:510]	Power Up of Chopper ACMP	85
[521:516]	Rheostats Charge Pump Enable	86
[527:522]	ASW0 enable/Half bridge Enable	87
[533:528]	ASW1 enable/Half bridge data	88
[539:534]	ACMP0 Power Up	89
[545:540]	ACMP1 Power Up	90
[551:546]	Oscillator0 Enable	91
[557:552]	Oscillator1 Enable	92
[563:558]	Oscillator2 Enable	93
[569:564]	VrefO, Temp sensor, VrefO Power Up	94
[575:570]	HDBUF Enable	95
[581:576]	Op Amp0 Power Up	96
[587:582]	Op Amp1 Power Up	97
[593:588]	Op Amp2 Power Up	98
[599:594]	Op amps Vref Enable	99

Note 1 For each Address, the two most significant bits are unused.

6.3 CONNECTION MATRIX VIRTUAL INPUTS

As mentioned previously, the Connection Matrix inputs come from the outputs of various digital macrocells on the device. Eight of the Connection Matrix inputs have the special characteristic that the state of these signal lines comes from a corresponding data bit written as a register value via I²C. This gives the user the ability to write data via the serial channel, and have this information translated into signals that can be driven into the Connection Matrix and from the Connection Matrix to the digital inputs of other macrocells on the device. The I²C address for reading and writing these register values is at 0x7C (124).

An I²C write command to these register bits will set the signal values going into the Connection Matrix to the desired state. A read command to these register bits will read either the original data values coming from the NVM memory bits (that were

loaded during the initial device startup), or the values from a previous write command (if that has happened).

See [Table 28](#).

Table 28: Connection Matrix Virtual Inputs

Matrix Input Number	Matrix Input Signal Function	Register Bit Addresses (d)
32	I ² C_virtual_0 Input	[992]
33	I ² C_virtual_1 Input	[993]
34	I ² C_virtual_2 Input	[994]
35	I ² C_virtual_3 Input	[995]
36	I ² C_virtual_4 Input	[996]
37	I ² C_virtual_5 Input	[997]
38	I ² C_virtual_6 Input	[998]
39	I ² C_virtual_7 Input	[999]

6.4 CONNECTION MATRIX VIRTUAL OUTPUTS

The digital outputs of the various macrocells are routed to the Connection Matrix to enable interconnections to the inputs of other macrocells in the device. At the same time, it is possible to read the state of each of the macrocell outputs as a register value via I²C. This option, called Connection Matrix Virtual Outputs, allows the user to remotely read the values of each macrocell output. The I²C addresses for reading these register values are bytes 0xC4 (196) to 0xCA (202). Write commands to these same register values will be ignored (with the exception of the Virtual Input register bits at byte 0x7C (124)).

7 Combination Function Macrocells

The SLG47004 has 13 combination function macrocells that can serve as more than one logic or timing function. In each case, they can serve as a Look Up Table (LUT), or as another logic or timing function. See the list below for the functions that can be implemented in these macrocells:

- Three macrocells that can serve as either 2-bit LUT or as D Flip-Flop
- Seven macrocells that can serve as either 3-bit LUTs or as D Flip-Flops with Set/Reset Input
- One macrocell that can serve as either 3-bit LUT or as Pipe Delay/Ripple Counter
- One macrocell that can serve as either 2-bit LUT or as Programmable Pattern Generator (PGen)
- One macrocell that can serve as either 4-bit LUT or as D Flip-Flop with Set/Reset Input

Inputs/Outputs for the 13 combination function macrocells are configured from the connection matrix with specific logic functions being defined by the state of configuration bits.

When used as a LUT to implement combinatorial logic functions, the outputs of the LUTs can be configured to any user-defined function, including the following standard digital logic devices (AND, NAND, OR, NOR, XOR, XNOR).

7.1 2-BIT LUT OR D FLIP-FLOP MACROCELLS

There is one macrocell that can serve as either 2-bit LUT or as D Flip-Flop. When used to implement LUT functions, the 2-bit LUT takes in two input signals from the connection matrix and produces a single output, which goes back into the connection matrix. When used to implement D Flip-Flop function, the two input signals from the connection matrix go to the data (D) and clock (CLK) inputs for the Flip-Flop, with the output going back to the connection matrix.

The operation of the D Flip-Flop and LATCH will follow the functional descriptions below:

DFF: CLK is rising edge triggered, then $Q = D$; otherwise Q will not change.

LATCH: when CLK is Low, then Q = D; otherwise Q remains its previous value (input D has no effect on the output, when CLK is High).

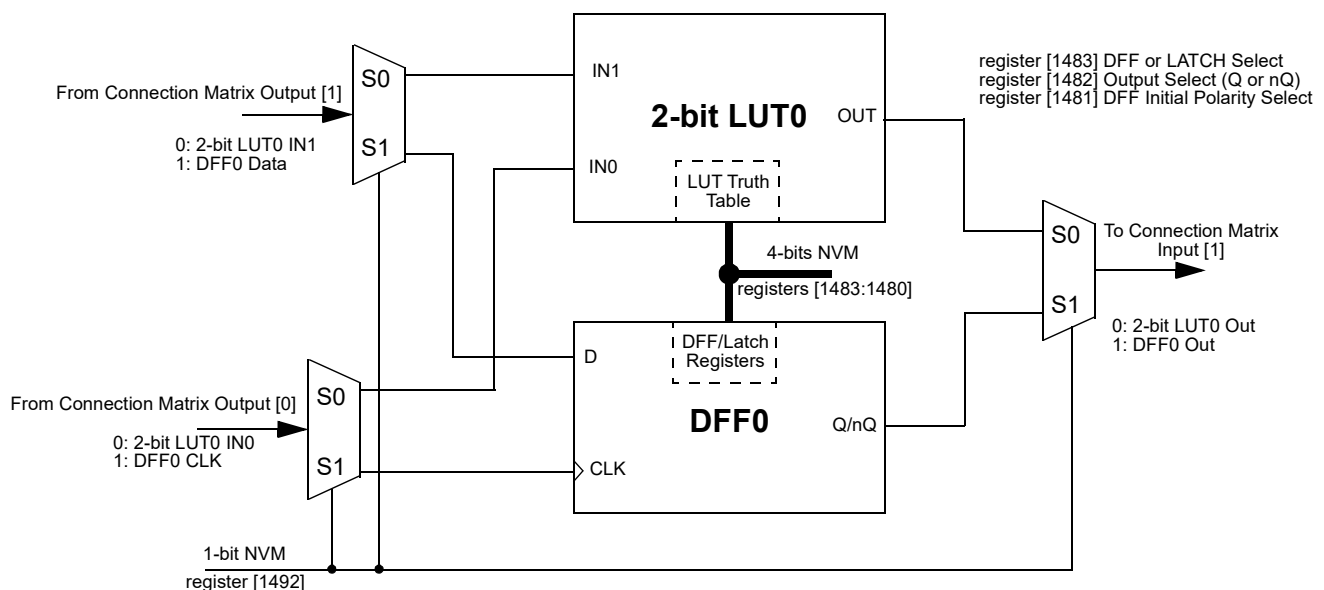


Figure 13: 2-bit LUT0 or DFF0

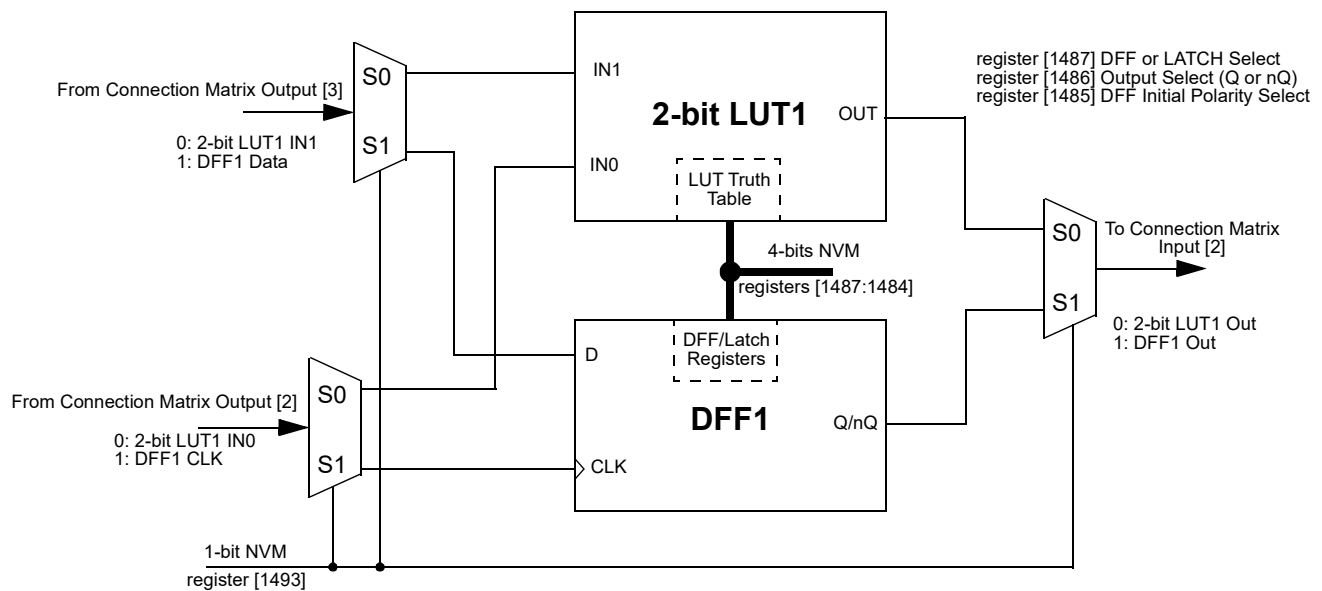


Figure 14: 2-bit LUT1 or DFF1

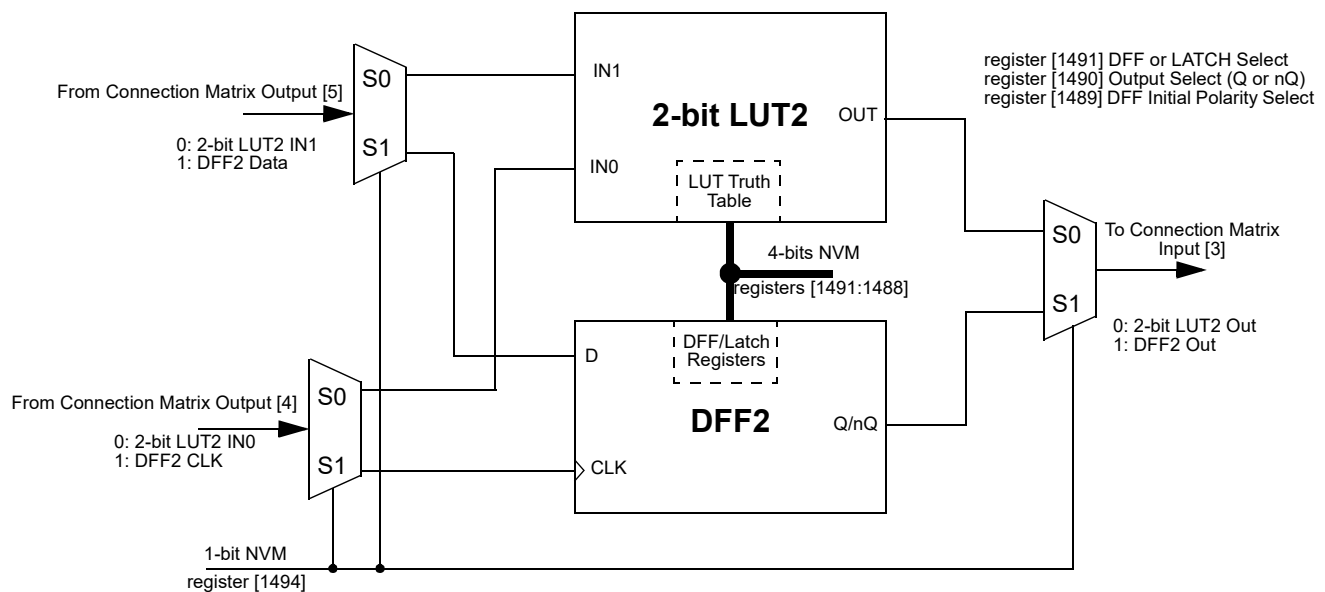


Figure 15: 2-bit LUT2 or DFF2

7.1.1 2-Bit LUT or D Flip-Flop Macrocell Used as 2-Bit LUT

Table 29: 2-bit LUT0 Truth Table

IN1	IN0	OUT	
0	0	register [1480]	LSB
0	1	register [1481]	
1	0	register [1482]	
1	1	register [1483]	MSB

Table 30: 2-bit LUT1 Truth Table

IN1	IN0	OUT	
0	0	register [1484]	LSB
0	1	register [1485]	
1	0	register [1486]	
1	1	register [1487]	MSB

Table 31: 2-bit LUT2 Truth Table

IN1	IN0	OUT	
0	0	register [1488]	LSB
0	1	register [1489]	
1	0	register [1490]	
1	1	register [1491]	MSB

This macrocell, when programmed for a LUT function, uses a 4-bit register to define their output function:

2-Bit LUT0 is defined by registers [1483:1480]

2-Bit LUT1 is defined by registers [1487:1484]

2-Bit LUT2 is defined by registers [1491:1488]

Table 32 shows the register bits for the standard digital logic devices (AND, NAND, OR, NOR, XOR, XNOR) that can be created within each of the 2-bit LUT logic cells.

Table 32: 2-bit LUT Standard Digital Functions

Function	MSB			LSB
AND-2	1	0	0	0
NAND-2	0	1	1	1
OR-2	1	1	1	0
NOR-2	0	0	0	1
XOR-2	0	1	1	0
XNOR-2	1	0	0	1

7.1.2 Initial Polarity Operations

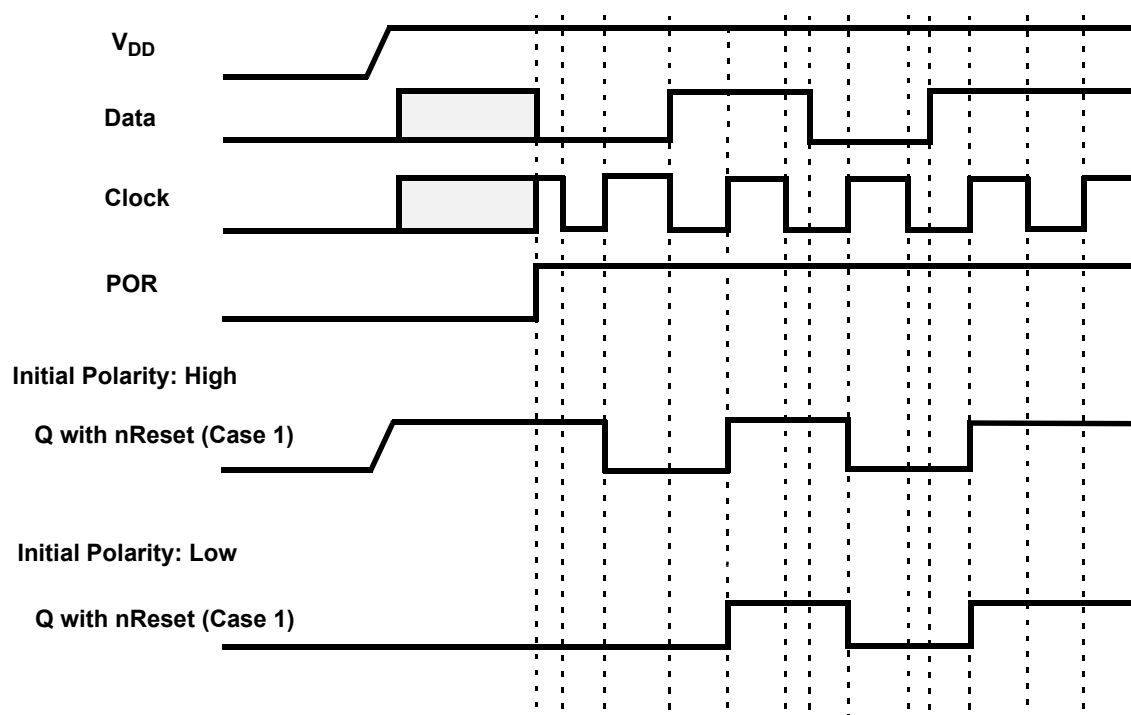


Figure 16: DFF Polarity Operations

7.2 2-BIT LUT OR PROGRAMMABLE PATTERN GENERATOR

The SLG47004 has one combination function macrocell that can serve as a logic or a timing function. This macrocell can serve as a Look Up Table (LUT), or a Programmable Pattern Generator (PGen).

When used to implement LUT functions, the 2-bit LUT takes in two input signals from the connection matrix and produces a single output, which goes back into the connection matrix. When used as a LUT to implement combinatorial logic functions, the outputs of the LUT can be configured to any user defined function, including the following standard digital logic devices (AND, NAND, OR, NOR, XOR, XNOR). The user can also define the combinatorial relationship between inputs and outputs to be any selectable function.

It is possible to define the RST level for the PGen macrocell. There are both high level reset (RST) and a low level reset (nRST) options available, which are selected by register [1517]. When operating as the Programmable Pattern Generator, the output of the macrocell will clock out a sequence of two to sixteen bits that are user selectable in their bit values, and user selectable in the number of bits (up to sixteen) that are output before the pattern repeats.

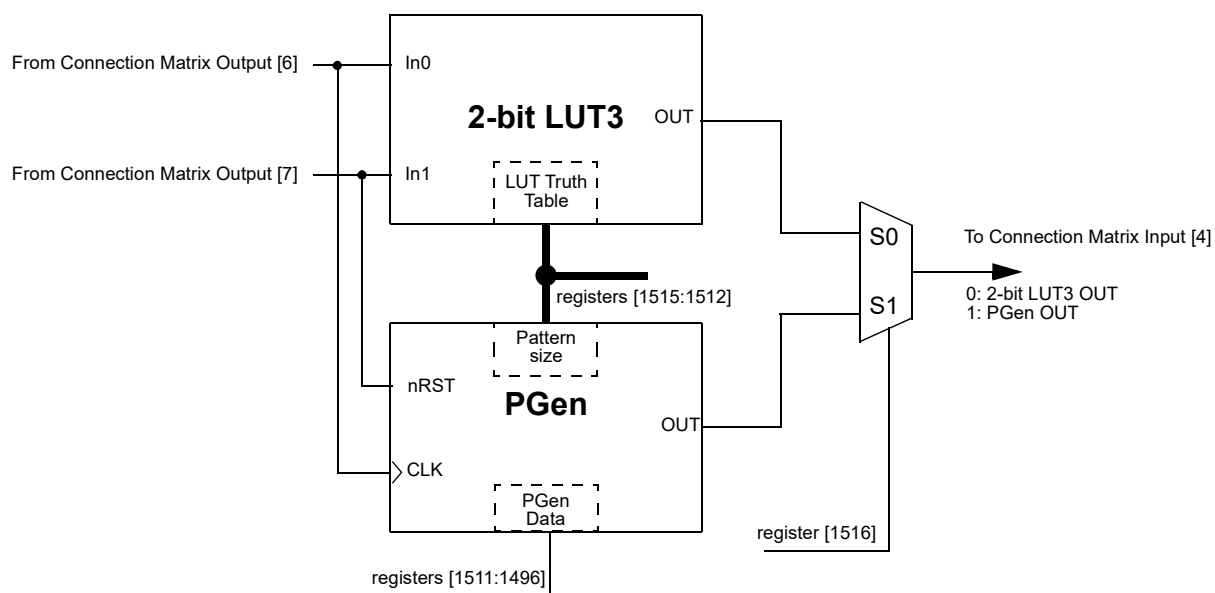


Figure 17: 2-bit LUT3 or PGen

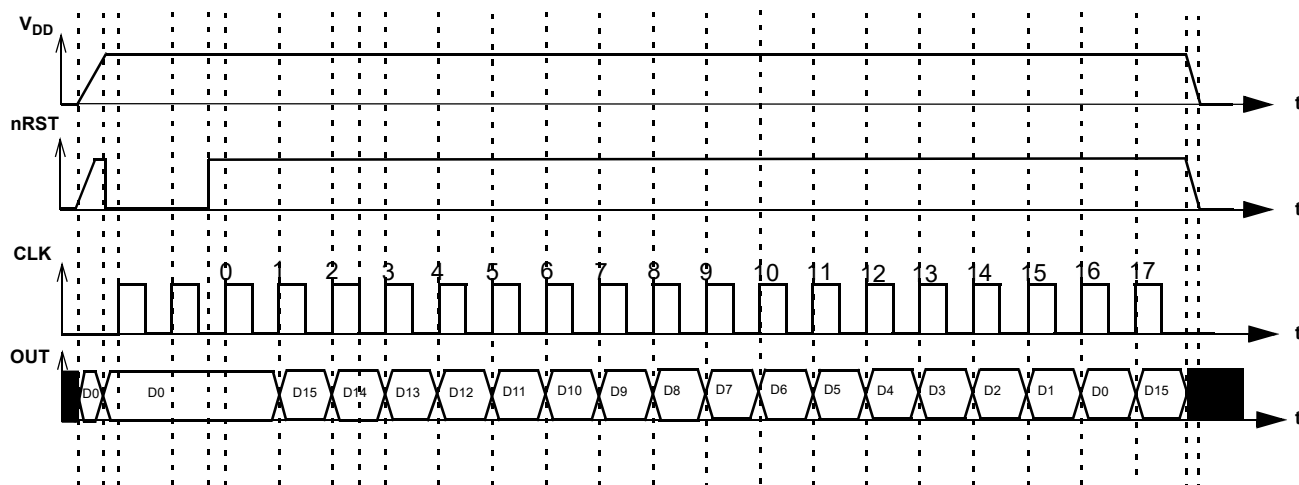


Figure 18: PGen Timing Diagram

7.2.1 2-Bit LUT or PGen Macrocell Used as 2-Bit LUT

Table 33: 2-bit LUT1 Truth Table

IN1	IN0	OUT	
0	0	register [1512]	LSB
0	1	register [1513]	
1	0	register [1514]	
1	1	register [1515]	MSB

This macrocell, when programmed for a LUT function, uses a 4-bit register to define their output function:

2-Bit LUT3 is defined by [1515:1512]

Table 34 shows the register bits for the standard digital logic devices (AND, NAND, OR, NOR, XOR, XNOR) that can be created within each of the 2-bit LUT logic cells.

Table 34: 2-bit LUT Standard Digital Functions

Function	MSB			LSB
AND-2	1	0	0	0
NAND-2	0	1	1	1
OR-2	1	1	1	0
NOR-2	0	0	0	1
XOR-2	0	1	1	0
XNOR-2	1	0	0	1

7.3 3-BIT LUT OR D FLIP-FLOP WITH SET/RESET MACROCELLS

There are seven macrocells that can serve as either 3-bit LUTs or as D Flip-Flops with Set/Reset inputs. When used to implement LUT functions, the 3-bit LUTs each takes in three input signals from the connection matrix and produces a single output, which goes back into the connection matrix. When used to implement D Flip-Flop function, the three input signals from the connection matrix go to the data (D) and clock (CLK), and Reset/Set (nRST/nSET) inputs for the Flip-Flop, with the output going back to the connection matrix. It is possible to define the active level for the reset/set input of DFF/LATCH macrocell. There are both active high level reset/set (RST/SET) and active low level reset/set (nRST/nSET) options available, which are selected by register [1523].

The DFF3 operation will flow the functional description:

- If register [1522] = 0, and the CLK is rising edge triggered, then Q = D, otherwise Q will not change.
- If register [1522] = 1, then data from D is written into the DFF by the rising edge on CLK and output to Q by the falling edge on CLK.









7.3.1 3-Bit LUT or D Flip-Flop Macrocells Used as 3-Bit LUTs

Table 35: 3-bit LUT0 Truth Table

IN2	IN1	IN0	OUT	
0	0	0	register [1520]	LSB
0	0	1	register [1521]	
0	1	0	register [1522]	
0	1	1	register [1523]	
1	0	0	register [1524]	
1	0	1	register [1525]	
1	1	0	register [1526]	
1	1	1	register [1527]	MSB

Table 36: 3-bit LUT1 Truth Table

IN2	IN1	IN0	OUT	
0	0	0	register [1528]	LSB
0	0	1	register [1529]	
0	1	0	register [1530]	
0	1	1	register [1531]	
1	0	0	register [1532]	
1	0	1	register [1533]	
1	1	0	register [1534]	
1	1	1	register [1535]	MSB

Table 37: 3-bit LUT2 Truth Table

IN2	IN1	IN0	OUT	
0	0	0	register [784]	LSB
0	0	1	register [785]	
0	1	0	register [786]	
0	1	1	register [787]	
1	0	0	register [788]	
1	0	1	register [789]	
1	1	0	register [790]	
1	1	1	register [791]	MSB

Table 38: 3-bit LUT3 Truth Table

IN2	IN1	IN0	OUT	
0	0	0	register [792]	LSB
0	0	1	register [793]	
0	1	0	register [794]	
0	1	1	register [795]	
1	0	0	register [796]	
1	0	1	register [797]	
1	1	0	register [798]	
1	1	1	register [799]	MSB

Table 39: 3-bit LUT4 Truth Table

IN2	IN1	IN0	OUT	
0	0	0	register [800]	LSB
0	0	1	register [801]	
0	1	0	register [802]	
0	1	1	register [803]	
1	0	0	register [804]	
1	0	1	register [805]	
1	1	0	register [806]	
1	1	1	register [807]	MSB

Table 40: 3-bit LUT5 Truth Table

IN2	IN1	IN0	OUT	
0	0	0	register [808]	LSB
0	0	1	register [809]	
0	1	0	register [810]	
0	1	1	register [811]	
1	0	0	register [812]	
1	0	1	register [813]	
1	1	0	register [814]	
1	1	1	register [815]	MSB

Table 41: 3-bit LUT6 Truth Table

IN2	IN1	IN0	OUT	
0	0	0	register [816]	LSB
0	0	1	register [817]	
0	1	0	register [818]	
0	1	1	register [819]	
1	0	0	register [820]	
1	0	1	register [821]	
1	1	0	register [822]	
1	1	1	register [823]	MSB

Each macrocell, when programmed for a LUT function, uses an 8-bit register to define their output function:

3-Bit LUT0 is defined by registers [1527:1520]

3-Bit LUT1 is defined by registers [1535:1528]

3-Bit LUT2 is defined by registers [791:784]

3-Bit LUT3 is defined by registers [799:792]

3-Bit LUT4 is defined by registers [807:800]

3-Bit LUT5 is defined by registers [815:808]

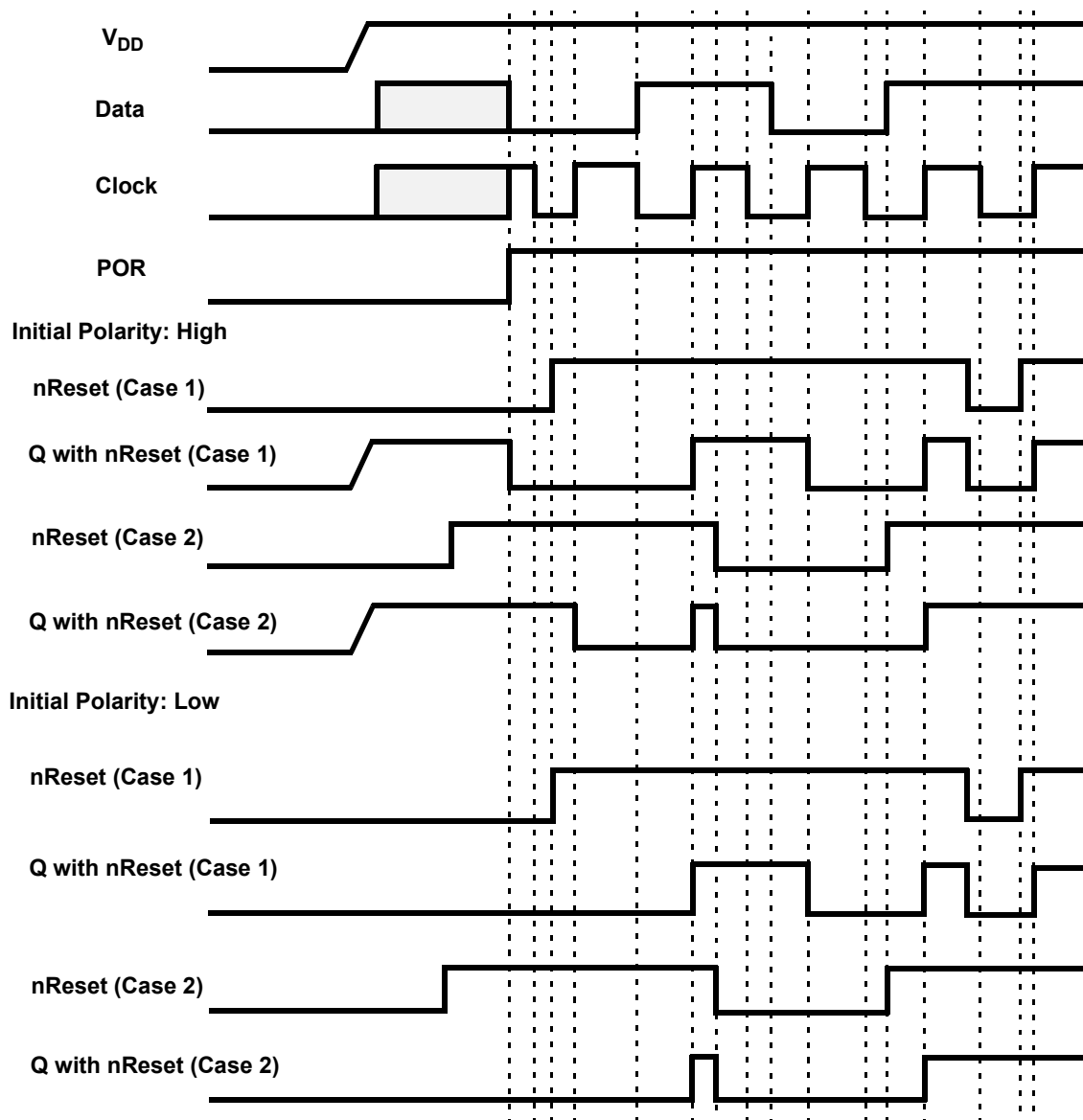
3-Bit LUT6 is defined by registers [823:816]

Table 42 shows the register bits for the standard digital logic devices (AND, NAND, OR, NOR, XOR, XNOR) that can be created within each of the four 3-bit LUT logic cells.

Table 42: 3-bit LUT Standard Digital Functions

Function	MSB							LSB
AND-3	1	0	0	0	0	0	0	0
NAND-3	0	1	1	1	1	1	1	1
OR-3	1	1	1	1	1	1	1	0
NOR-3	0	0	0	0	0	0	0	1
XOR-3	1	0	0	1	0	1	1	0
XNOR-3	0	1	1	0	1	0	0	1

7.3.2 Initial Polarity Operations

Figure 26: DFF Polarity Operations with $n\text{Reset}$

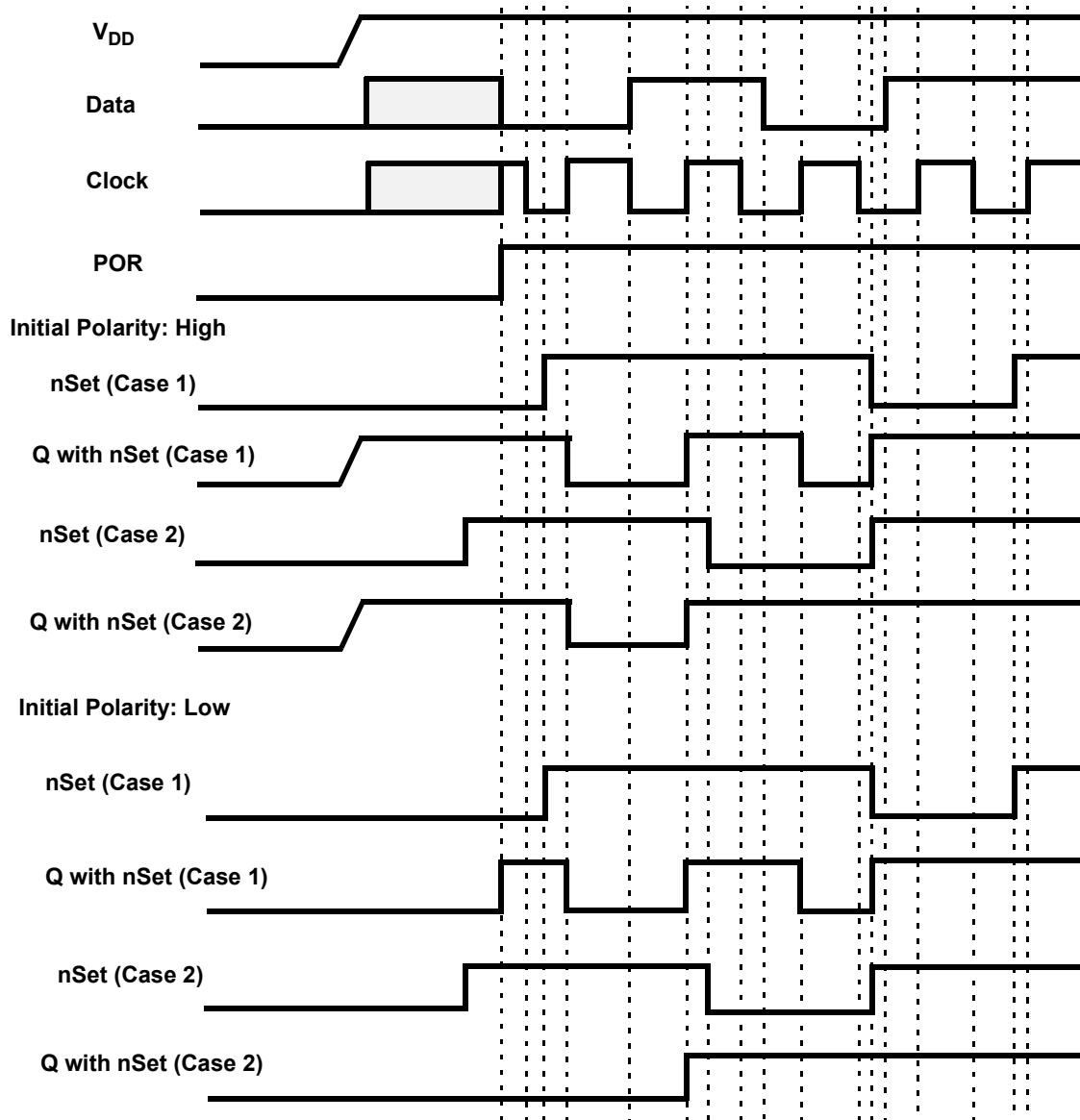


Figure 27: DFF Polarity Operations with nSet

7.4 4-BIT LUT OR D FLIP-FLOP WITH SET/RESET MACROCELL

There is one macrocell that can serve as either a 4-bit LUT or as a D Flip-Flop with Set/Reset inputs. When used to implement LUT functions, the 4-bit LUT takes in four input signals from the connection matrix and produces a single output, which goes back into the connection matrix. When used to implement D Flip-Flop function, the input signals from the connection matrix go to the data (D) and clock (CLK), and Reset/Set (nRST/nSET) inputs for the Flip-Flop, with the output going back to the connection matrix.

If register [842] = 0, and the CLK is rising edge triggered, then $Q = D$, otherwise Q will not change.

If register [842] = 1, then data from D is written into the DFF by the rising edge on CLK and output to Q by the falling edge on CLK. It is possible to define the active level for the reset/set input of DFF/LATCH macrocell. There are both active high level reset/set (RST/SET) and active low level reset/set (nRST/nSET) options available, which are selected by register [843].

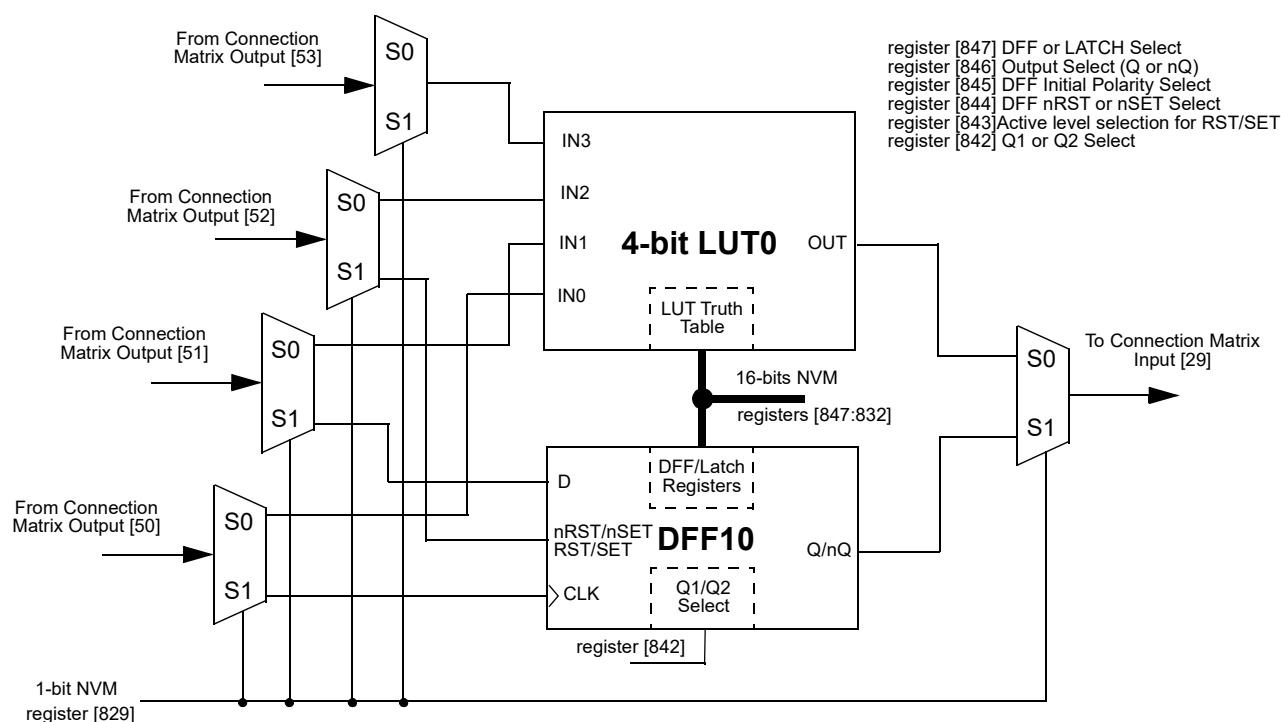


Figure 28: 4-bit LUT0 or DFF10

7.4.1 4-Bit LUT Macrocell Used as 4-Bit LUT

Table 43: 4-bit LUT0 Truth Table

IN3	IN2	IN1	IN0	OUT	
0	0	0	0	register [832]	LSB
0	0	0	1	register [833]	
0	0	1	0	register [834]	
0	0	1	1	register [835]	
0	1	0	0	register [836]	
0	1	0	1	register [837]	
0	1	1	0	register [838]	
0	1	1	1	register [839]	
1	0	0	0	register [840]	
1	0	0	1	register [841]	
1	0	1	0	register [842]	
1	0	1	1	register [843]	
1	1	0	0	register [844]	
1	1	0	1	register [845]	
1	1	1	0	register [846]	
1	1	1	1	register [847]	MSB

This macrocell, when programmed for a LUT function, uses a 16-bit register to define their output function:

4-Bit LUT0 is defined by registers [847:832]

Table 44: 4-bit LUT Standard Digital Functions

Function	MSB															LSB
AND-4	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
NAND-4	0	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
OR-4	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	0
NOR-4	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1
XOR-4	0	1	1	0	1	0	0	1	1	0	0	1	0	1	1	0
XNOR-4	1	0	0	1	0	1	1	0	0	1	1	0	1	0	0	1

7.5 3-BIT LUT OR PIPE DELAY/RIPPLE COUNTER MACROCELL

There is one macrocell that can serve as either a 3-bit LUT or as a Pipe Delay/Ripple Counter.

When used to implement LUT functions, the 3-bit LUT takes in three input signals from the connection matrix and produces a single output, which goes back into the connection matrix.

When used as a Pipe Delay, there are three inputs signals from the matrix, Input (IN), Clock (CLK), and Reset (nRST). The Pipe Delay cell is built from 16 D Flip-Flop logic cells that provide the three delay options, two of which are user selectable. The DFF cells are tied in series where the output (Q) of each delay cell goes to the next DFF cell input (IN). Both of the two outputs (OUT0 and OUT1) provide user selectable options for 1 to 16 stages of delay. There are delay output points for each set of the OUT0 and OUT1 outputs to a 4-input mux that is controlled by registers [851:848] for OUT0 and registers [855:852] for OUT1. The 4-input MUX is used to control the selection of the amount of delay.

The overall time of the delay is based on the clock used in the SLG47004 design. Each DFF cell has a time delay of the inverse of the clock time (either external clock or the internal Oscillator within the SLG47004). The sum of the number of DFF cells used will be the total time delay of the Pipe Delay logic cell. OUT1 Output can be inverted (as selected by register [859]).

In the Ripple Counter mode, there are 3 options for setting, which use 7 bits. There are 3 bits to set **nSET value (SV)** in range from 0 to 7. It is a value, which will be set into the Ripple Counter outputs when nSET input goes LOW. **End value (EV)** will use 3 bits for setting outputs code, which will be last code in the cycle. After reaching the EV, the Ripple Counter goes to the first code by the rising edge on CLK input. The **Functionality mode** option uses 1 bit. This setting defines how exactly Ripple Counter will operate.

The user can select one of the functionality modes by register: RANGE or FULL. If the RANGE option is selected, the count starts from SV. If UP input is LOW the count goes down: SV→EV→EV-1 to SV+1→SV, and others (if SV is smaller than EV), or SV→SV-1 to EV+1→EV→SV (if SV is bigger than EV). If UP input is HIGH, count starts from SV up to EV, and others.

In the FULL range configuration the Ripple Counter functions as follows. If UP input is LOW, the count starts from SV and goes down to 0. Then current counter value jumps to EV and goes down to 0, and others.

If UP input is HIGH, count goes up starting from SV. Then current counter value jumps to 0 and counts up to EV, and others. See Ripple Counter functionality example in [Figure 30](#).

Every step is executed by the rising edge on CLK input.

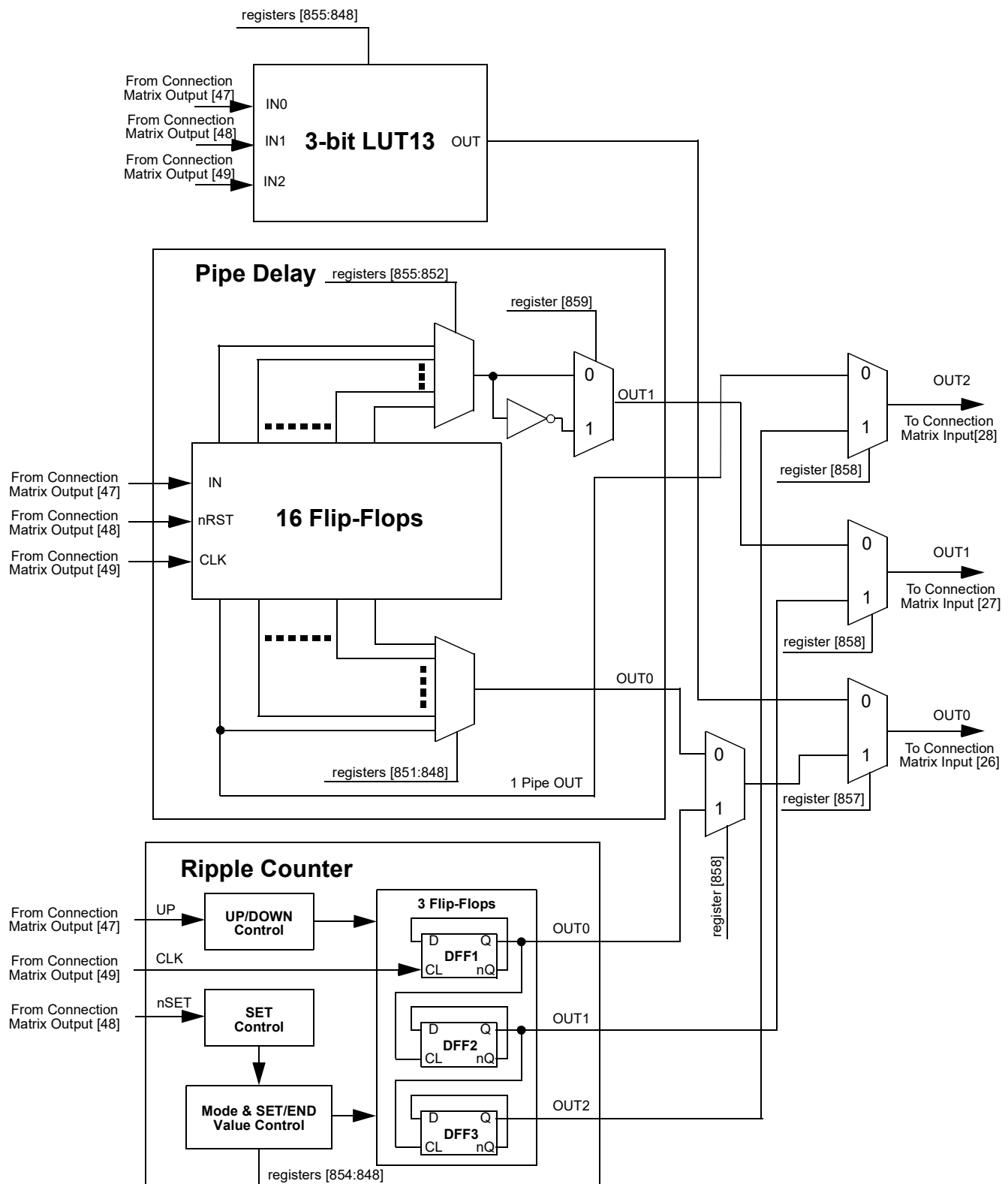


Figure 29: 3-bit LUT13/Pipe Delay/Ripple Counter

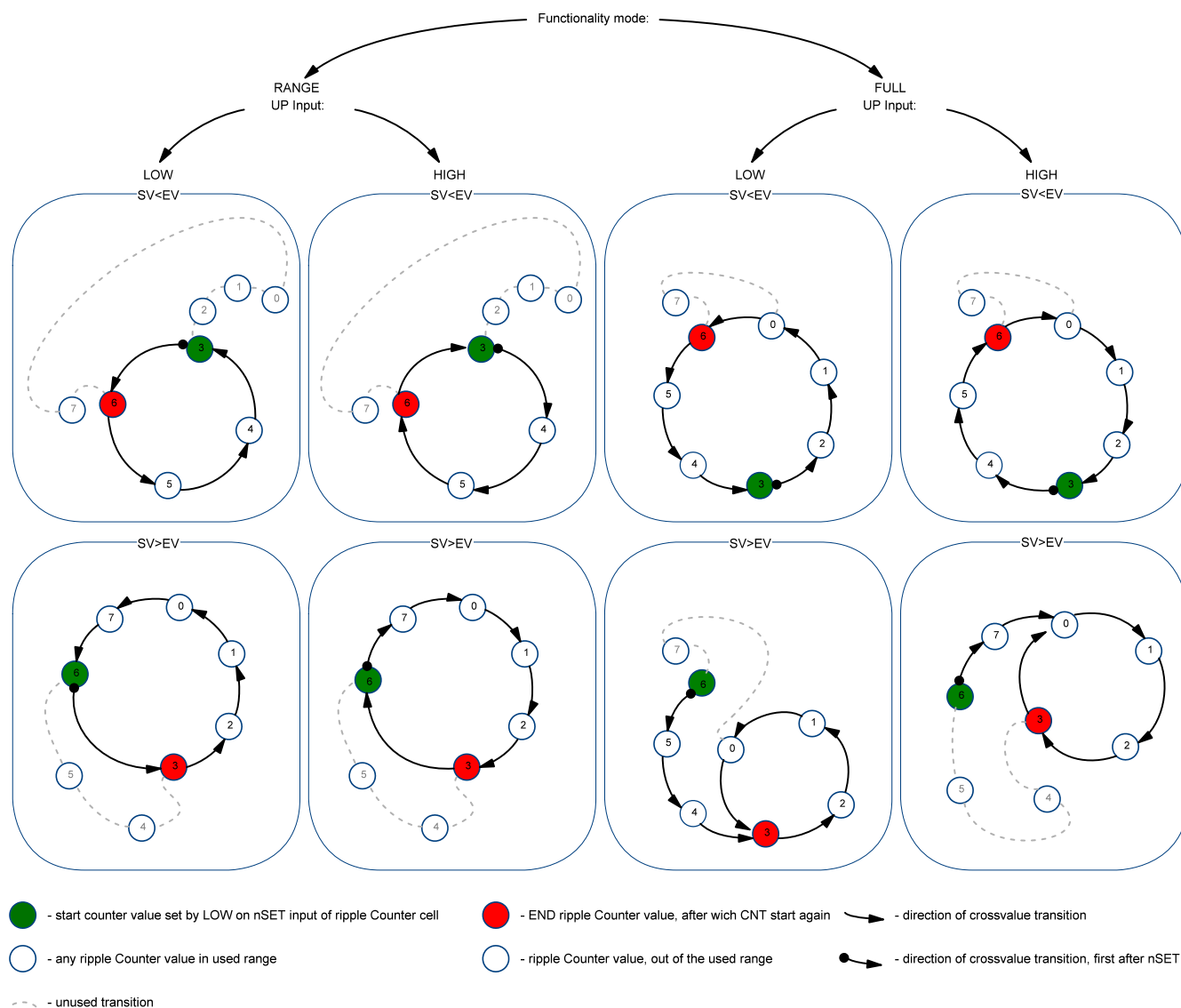


Figure 30: Example: Ripple Counter Functionality

7.5.1 3-Bit LUT or Pipe Delay Macrocells Used as 3-Bit LUT

Table 45: 3-bit LUT13 Truth Table

IN2	IN1	IN0	OUT
0	0	0	register [848]
0	0	1	register [849]
0	1	0	register [850]
0	1	1	register [851]
1	0	0	register [852]
1	0	1	register [853]
1	1	0	register [854]
1	1	1	register [855]

Each macrocell, when programmed for a LUT function, uses an 8-bit register to define their output function:

3-Bit LUT13 is defined by registers [855:848]

8 Multi-Function Macrocells

The SLG47004 has seven Multi-Function macrocells that can serve as more than one logic or timing function. In each case, they can serve as a LUT, DFF with flexible settings, or as CNT/DLY with multiple modes such as One Shot, Frequency Detect, Edge Detect, and others. Also, the macrocell is capable to combine those functions: LUT/DFF connected to CNT/DLY or CNT/DLY connected to LUT/DFF, see Figure 31.

See the list below for the functions that can be implemented in these macrocells:

- Six macrocells that can serve as 3-bit LUTs/D Flip-Flops and as 8-Bit Counter/Delays
- One macrocell that can serve as a 4-bit LUT/D Flip-Flop and as 16-Bit Counter/Delay/FSM

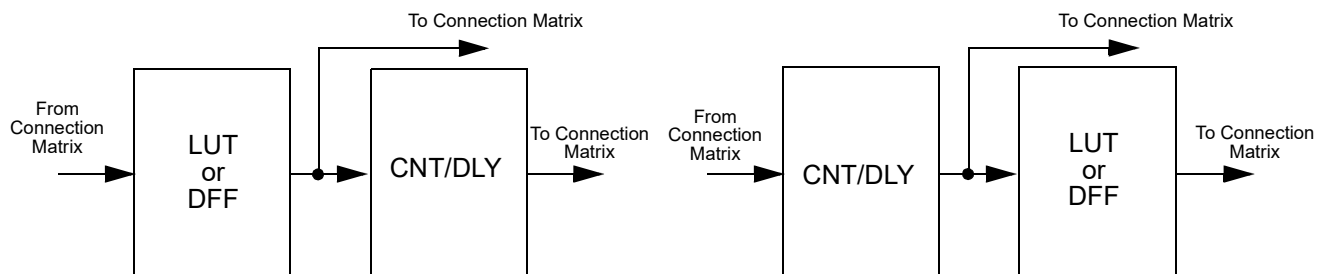


Figure 31: Possible Connections Inside Multi-Function Macrocell

Inputs/Outputs for the seven Multi-Function macrocells are configured from the connection matrix with specific logic functions being defined by the state of NVM bits.

When used as a LUT to implement combinatorial logic functions, the outputs of the LUTs can be configured to any user defined function, including the following standard digital logic devices (AND, NAND, OR, NOR, XOR, XNOR).

8.1 3-BIT LUT OR DFF/LATCH WITH 8-BIT COUNTER/DELAY MACROCELLS

There are six macrocells that can serve as 3-bit LUTs/D Flip-Flops and as 8-Bit Counter/Delays.

When used to implement LUT functions, the 3-bit LUTs each takes in three input signals from the connection matrix and produces a single output, which goes back into the connection matrix or can be connected to CNT/DLY's input.

When used to implement D Flip-Flop function, the three input signals from the connection matrix go to the data (D), clock (CLK), and Reset/Set (nRST/nSET) inputs of the Flip-Flop, with the output going back to the connection matrix or to the CNT/DLY's input.

When used to implement Counter/Delays, each macrocell has a dedicated matrix input connection. For flexibility, each of these macrocells has a large selection of internal and external clock sources, as well as the option to chain from the output of the previous (N-1) CNT/DLY macrocell, to implement longer count/delay circuits. These macrocells can also operate in a One-Shot mode, which will generate an output pulse of user-defined width. They can also operate in a Frequency Detection or Edge Detection mode.

Counter/Delay macrocell has an initial value, which defines its initial value after SLG47004 is powered up. It is possible to select initial Low or initial High, as well as initial value defined by a Delay In signal.

For example, in case initial LOW option is used, the rising edge delay will start operation.

For timing diagrams refer to Section 8.3.

Note: After two DFF – counters initialize with counter data = 0 after POR.
Initial state = 1 – counters initialize with counter data = 0 after POR.
Initial state = 0 And After two DFF is bypass – counters initialize with counter data after POR.

CNT5 and CNT6 current count value can be read via I²C. However, it is possible to change the counter data (value counter starts operating from) for any macrocell using I²C write commands. In this mode, it is possible to load count data immediately (after two DFF) or after counter ends counting. See Section 18.7.1 for further details.

8.1.1 3-Bit LUT or 8-Bit CNT/DLY Block Diagrams

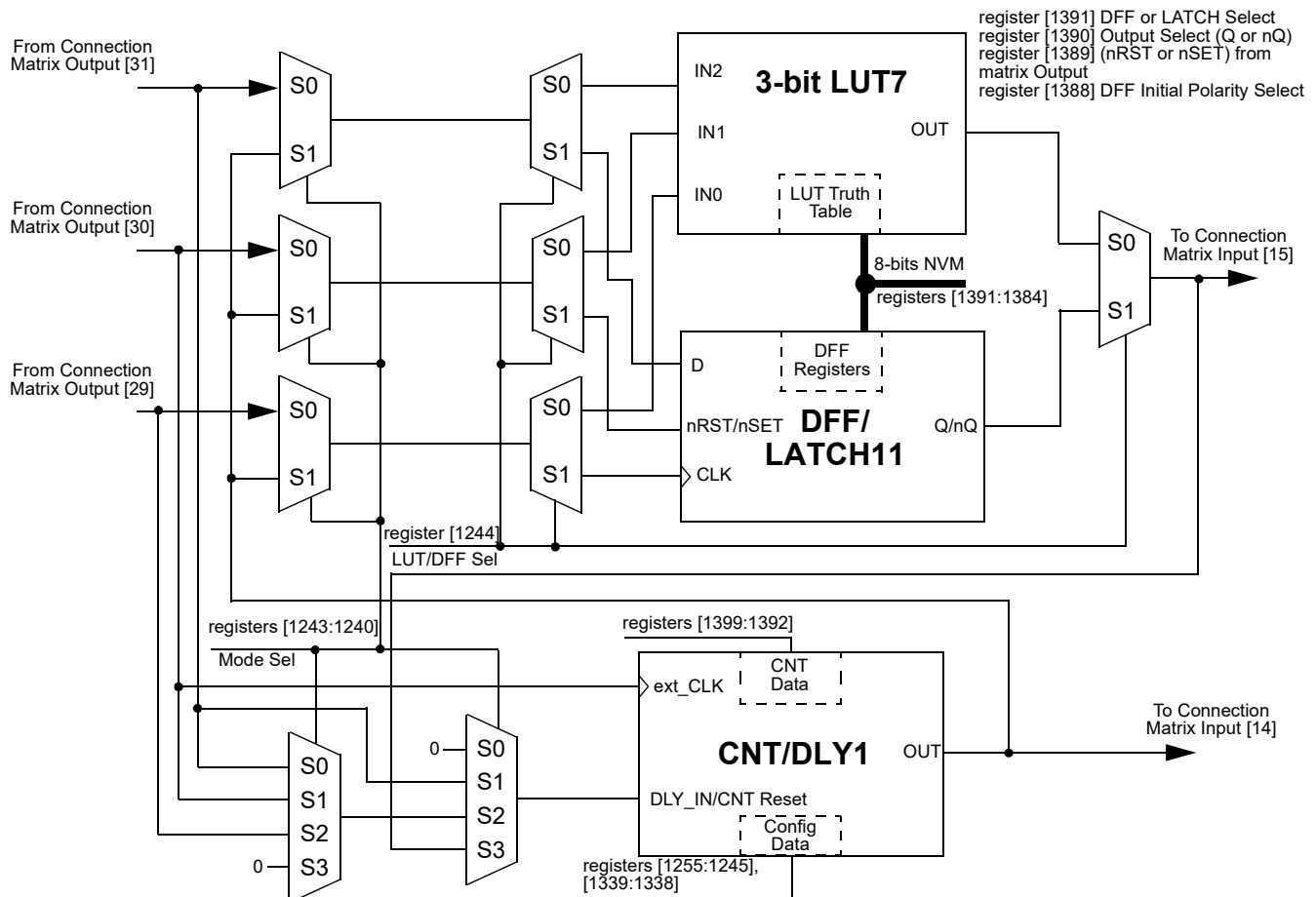


Figure 32: 8-bit Multi-Function Macrocells Block Diagram (3-bit LUT7/DFF11, CNT/DLY1)

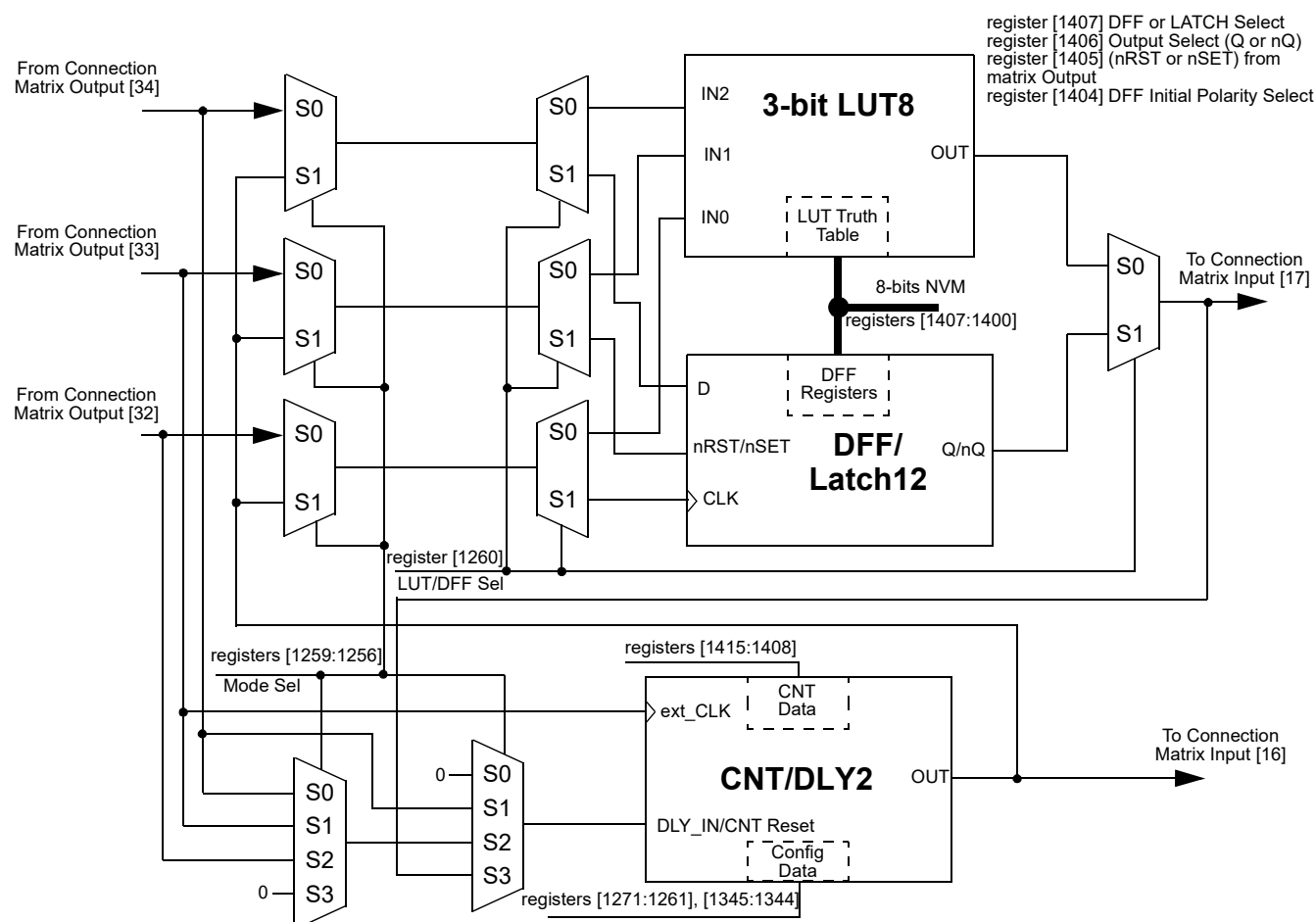


Figure 33: 8-bit Multi-Function Macrocells Block Diagram (3-bit LUT8/DFF12, CNT/DLY2)

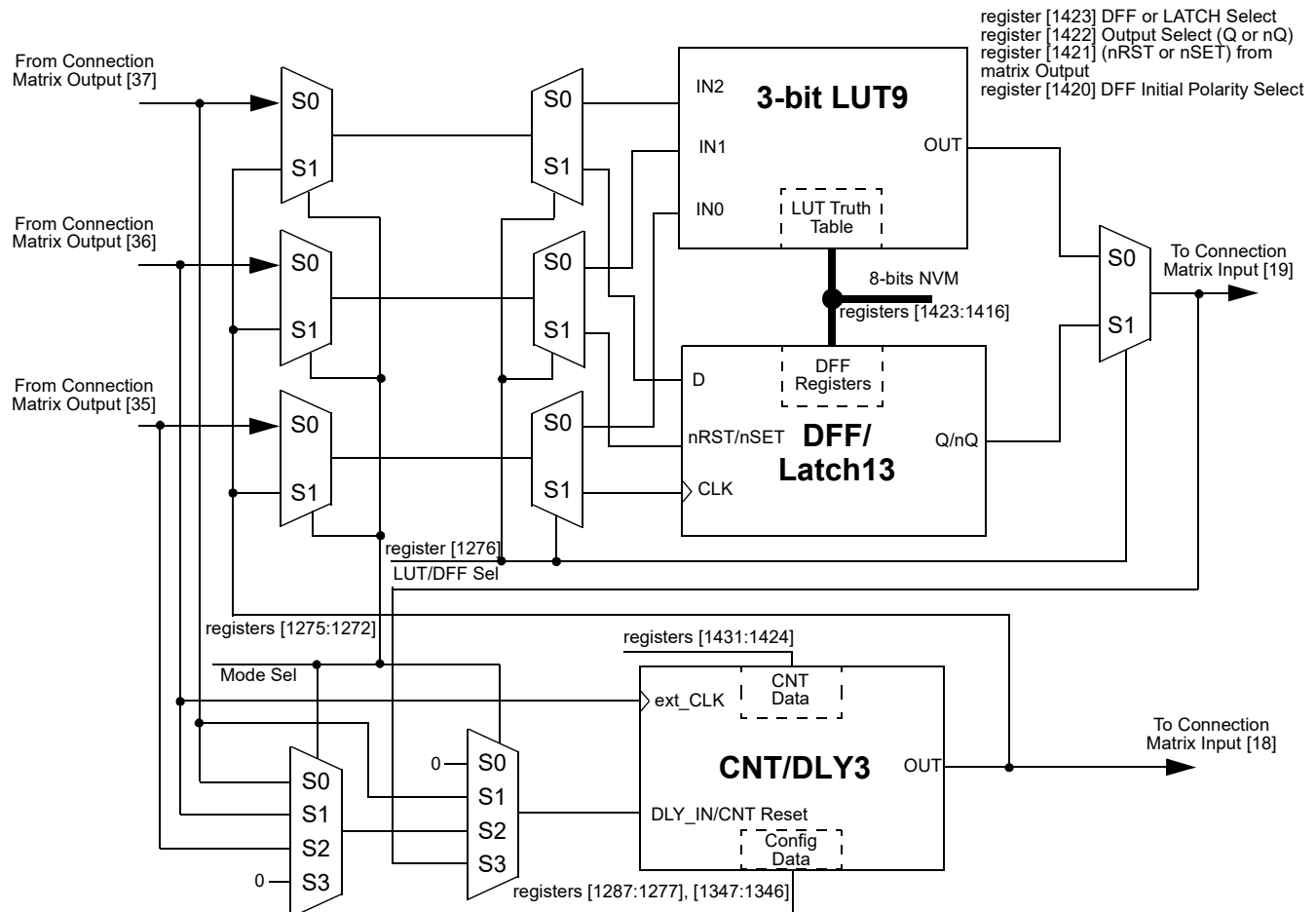


Figure 34: 8-bit Multi-Function Macrocells Block Diagram (3-bit LUT9/DFF13, CNT/DLY3)

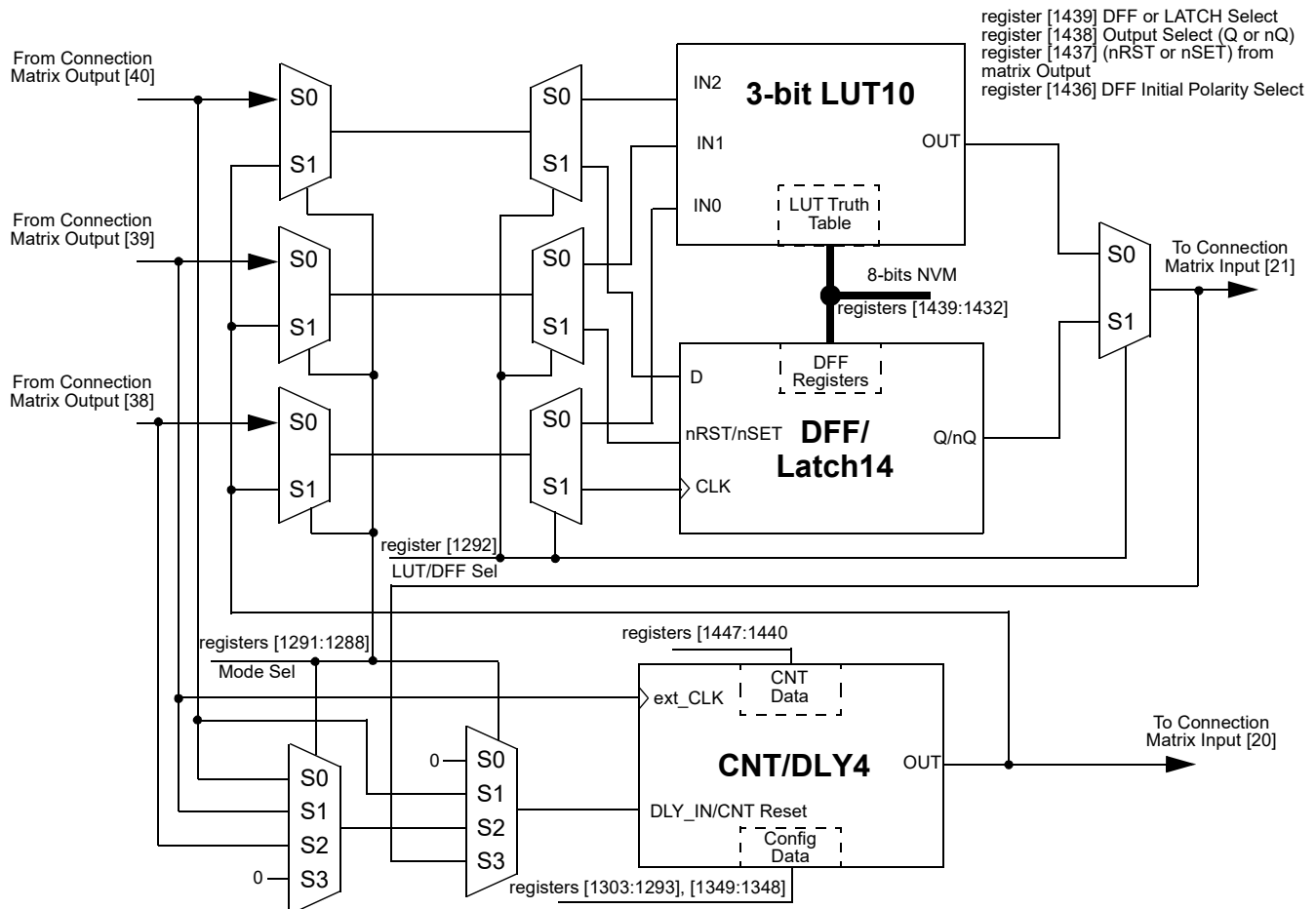
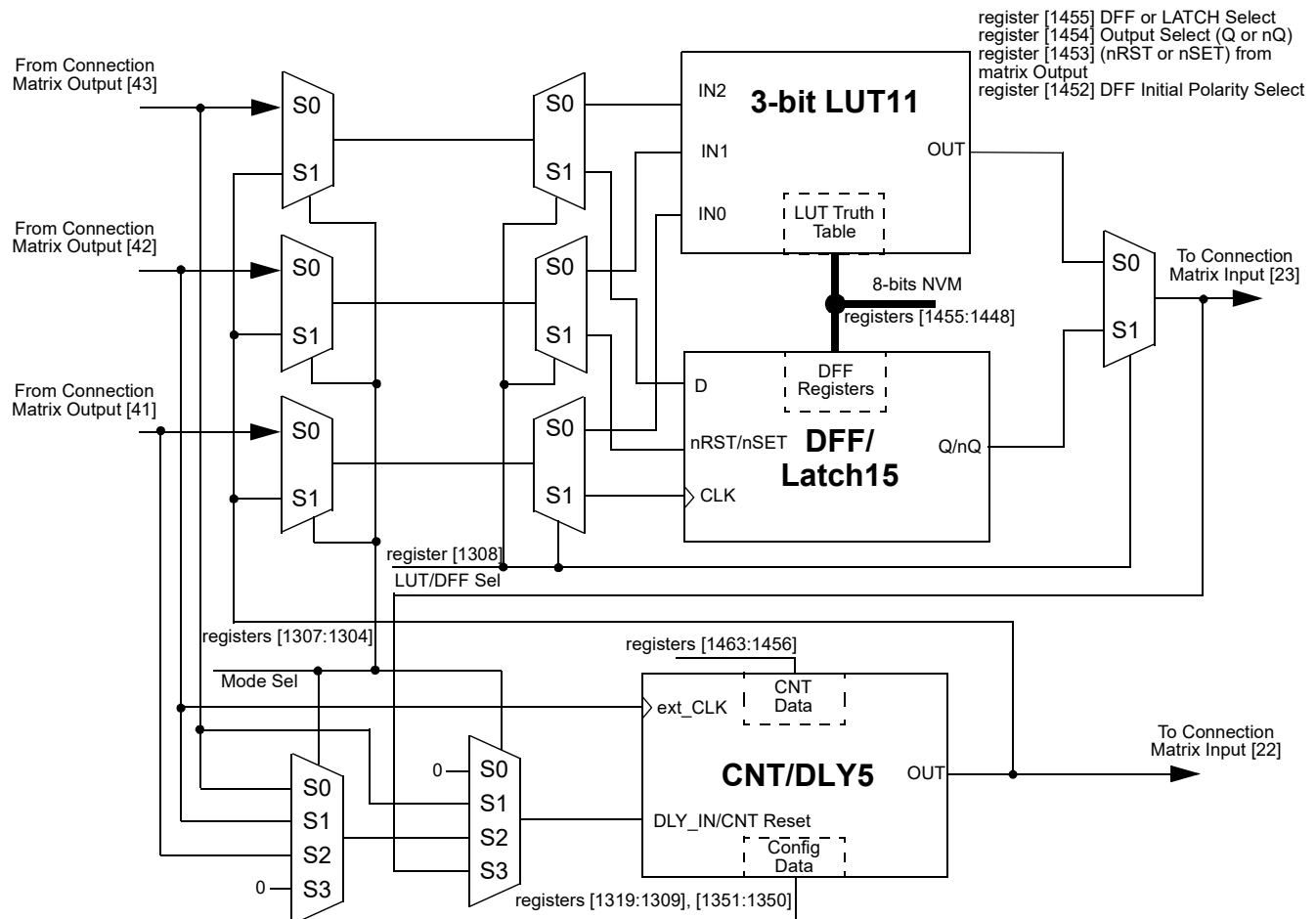


Figure 35: 8-bit Multi-Function Macrocells Block Diagram (3-bit LUT10/DFF14, CNT/DLY4)



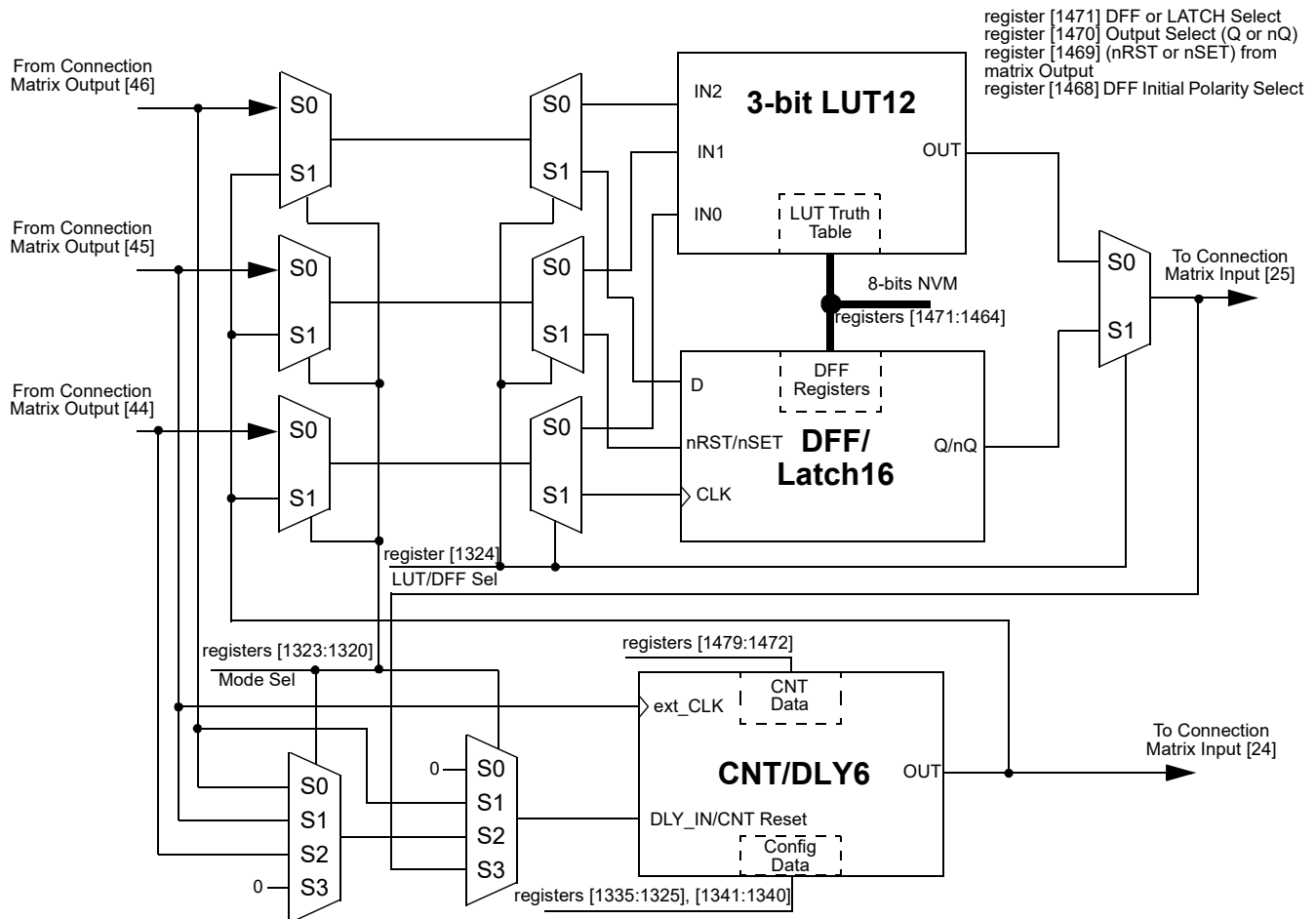


Figure 37: 8-bit Multi-Function Macrocells Block Diagram (3-bit LUT12/DFF16, CNT/DLY6)

As shown in Figure 32 to Figure 37 there is a possibility to use LUT/DFF and CNT/DLY simultaneously.

Note: It is not possible to use LUT and DFF at once, one of these macrocells must be selected.

- Case 1. LUT/DFF in front of CNT/DLY. Three input signals from the connection matrix go to previously selected LUT or DFF's inputs and produce a single output which goes to a CNT/DLY input. In its turn Counter/Delay's output goes back to the matrix.
- Case 2. CNT/DLY in front of LUT/DFF. Two input signals from the connection matrix go to CNT/DLY's inputs (IN and CLK). Its output signal can be connected to any input of previously selected LUT or DFF, after which the signal goes back to the matrix.
- Case 3. Single LUT/DFF or CNT/DLY. Also, it is possible to use a standalone LUT/DFF or CNT/DLY. In this case, all inputs and output of the macrocell are connected to the matrix.

8.1.2 3-Bit LUT or CNT/DLYs Used as 3-Bit LUTs

Table 46: 3-bit LUT7 Truth Table

IN2	IN1	IN0	OUT	
0	0	0	register [1384]	LSB
0	0	1	register [1385]	
0	1	0	register [1386]	
0	1	1	register [1387]	
1	0	0	register [1388]	
1	0	1	register [1389]	
1	1	0	register [1390]	
1	1	1	register [1391]	MSB

Table 47: 3-bit LUT8 Truth Table

IN2	IN1	IN0	OUT	
0	0	0	register [1400]	LSB
0	0	1	register [1401]	
0	1	0	register [1402]	
0	1	1	register [1403]	
1	0	0	register [1404]	
1	0	1	register [1405]	
1	1	0	register [1406]	
1	1	1	register [1407]	MSB

Table 48: 3-bit LUT9 Truth Table

IN2	IN1	IN0	OUT	
0	0	0	register [1416]	LSB
0	0	1	register [1417]	
0	1	0	register [1418]	
0	1	1	register [1419]	
1	0	0	register [1420]	
1	0	1	register [1421]	
1	1	0	register [1422]	
1	1	1	register [1423]	MSB

Table 49: 3-bit LUT10 Truth Table

IN2	IN1	IN0	OUT	
0	0	0	register [1432]	LSB
0	0	1	register [1433]	
0	1	0	register [1434]	
0	1	1	register [1435]	
1	0	0	register [1436]	
1	0	1	register [1437]	
1	1	0	register [1438]	
1	1	1	register [1439]	MSB

Table 50: 3-bit LUT11 Truth Table

IN2	IN1	IN0	OUT	
0	0	0	register [1448]	LSB
0	0	1	register [1449]	
0	1	0	register [1450]	
0	1	1	register [1451]	
1	0	0	register [1452]	
1	0	1	register [1453]	
1	1	0	register [1454]	
1	1	1	register [1455]	MSB

Table 51: 3-bit LUT12 Truth Table

IN2	IN1	IN0	OUT	
0	0	0	register [1464]	LSB
0	0	1	register [1465]	
0	1	0	register [1466]	
0	1	1	register [1467]	
1	0	0	register [1468]	
1	0	1	register [1469]	
1	1	0	register [1470]	
1	1	1	register [1471]	MSB

Each macrocell, when programmed for a LUT function, uses an 8-bit register to define their output function:

3-Bit LUT7 is defined by registers [1391:1384]

3-Bit LUT8 is defined by registers [1407:1400]

3-Bit LUT9 is defined by registers [1423:1416]

3-Bit LUT10 is defined by registers [1439:1432]

3-Bit LUT11 is defined by registers [1455:1448]

3-Bit LUT12 is defined by registers [1471:1464]

8.2 4-BIT LUT OR DFF/LATCH WITH 16-BIT COUNTER/DELAY MACROCELL

There is one macrocell that can serve as either 4-bit LUT/D Flip-Flops or as 16-bit Counter/Delay.

When used to implement LUT function, the 4-bit LUT takes in four input signals from the Connection Matrix and produces a single output, which goes back into the Connection Matrix.

When used to implement D Flip-Flop function, the two input signals from the connection matrix go to the data (D) and clock (CLK) inputs for the Flip-Flop, with the output going back to the connection matrix.

When used to implement 16-Bit Counter/Delay function, two of the four input signals from the connection matrix go to the external clock (EXT_CLK) and reset (DLY_IN/CNT Reset) for the Counter/Delay, with the output going back to the connection matrix.

This macrocell has an optional Finite State Machine (FSM) function. There are two additional matrix inputs for Up and Keep to support FSM functionality

This macrocell can also operate in a one-shot mode, which will generate an output pulse of user-defined width.

This macrocell can also operate in a frequency detection or edge detection mode.

This macrocell can have its active count value read via I²C. See Section 18.7.1 for further details.

Note: After two DFF – counters initialize with counter data = 0 after POR.

Initial state = 1 – counters initialize with counter data = 0 after POR.

Initial state = 0 And After two DFF is bypass – counters initialize with counter data after POR.

8.2.1 4-Bit LUT or DFF/LATCH with 16-Bit CNT/DLY Block Diagram

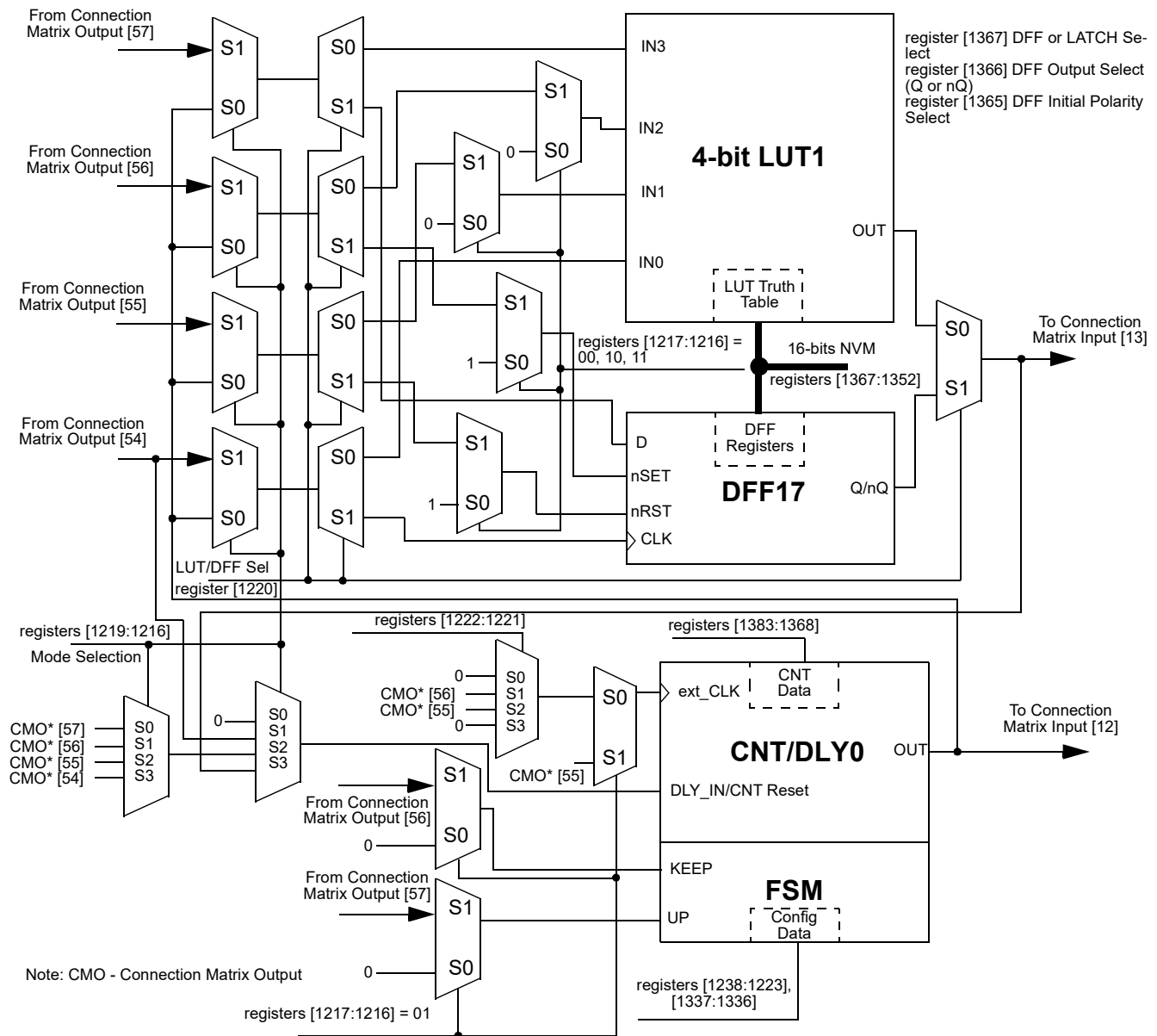


Figure 38: 4-bit LUT1 or CNT/DLY0

8.2.2 4-Bit LUT or 16-Bit Counter/Delay Macrocells Used as 4-Bit LUTs

Table 52: 4-bit LUT1 Truth Table

IN3	IN2	IN1	IN0	OUT	
0	0	0	0	register [1352]	LSB
0	0	0	1	register [1353]	
0	0	1	0	register [1354]	
0	0	1	1	register [1355]	
0	1	0	0	register [1356]	
0	1	0	1	register [1357]	
0	1	1	0	register [1358]	
0	1	1	1	register [1359]	
1	0	0	0	register [1360]	
1	0	0	1	register [1361]	
1	0	1	0	register [1362]	
1	0	1	1	register [1363]	
1	1	0	0	register [1364]	
1	1	0	1	register [1365]	
1	1	1	0	register [1366]	
1	1	1	1	register [1367]	MSB

This macrocell, when programmed for a LUT function, uses a 16-bit register to define their output function:

4-Bit LUT1 is defined by registers [1367:1352]

Table 53: 4-bit LUT Standard Digital Functions

Function	MSB															LSB
AND-4	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
NAND-4	0	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
OR-4	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	0
NOR-4	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1
XOR-4	0	1	1	0	1	0	0	1	1	1	0	0	1	1	1	0
XNOR-4	1	0	0	1	0	1	1	0	0	0	1	1	0	0	0	1

8.3 CNT/DLY/FSM TIMING DIAGRAMS

8.3.1 Delay Mode CNT/DLY0 to CNT/DLY6

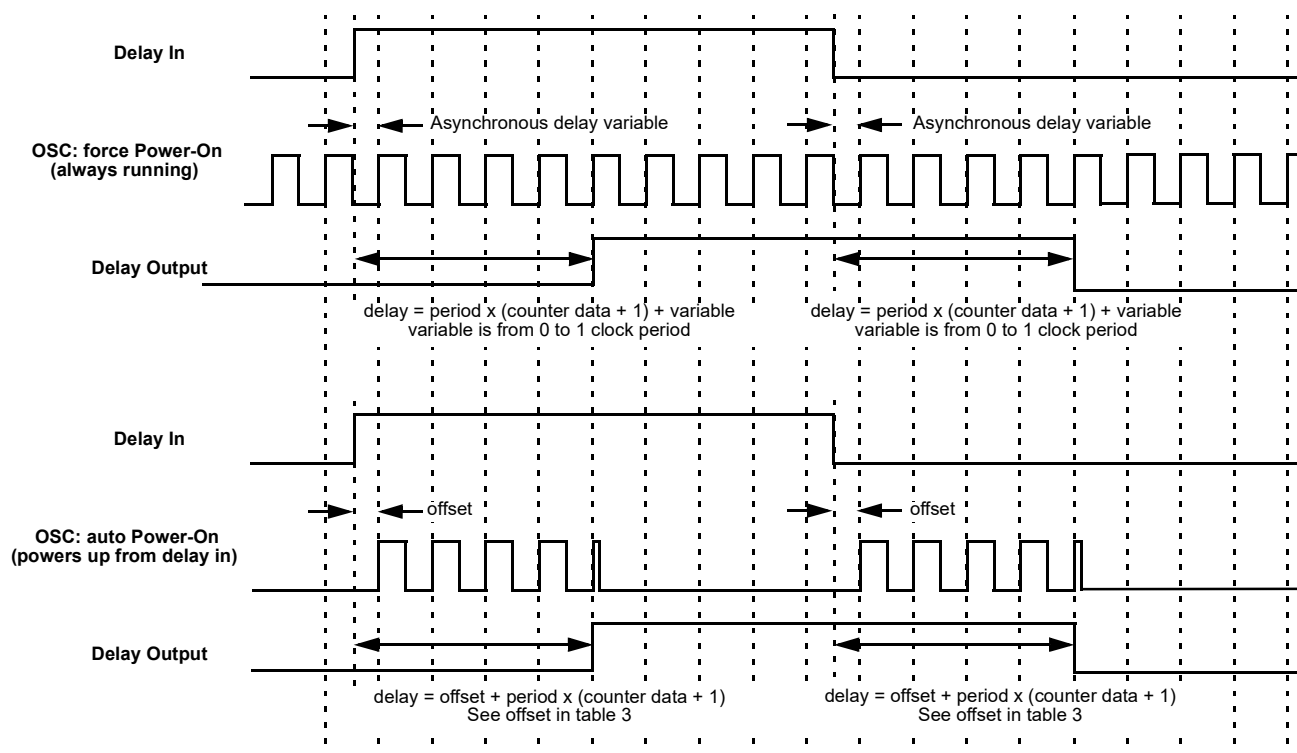


Figure 39: Delay Mode Timing Diagram, Edge Select: Both, Counter Data: 3

The macrocell shifts the respective edge to a set time and restarts by appropriate edge. It works as a filter if the input signal is shorter than the delay time.

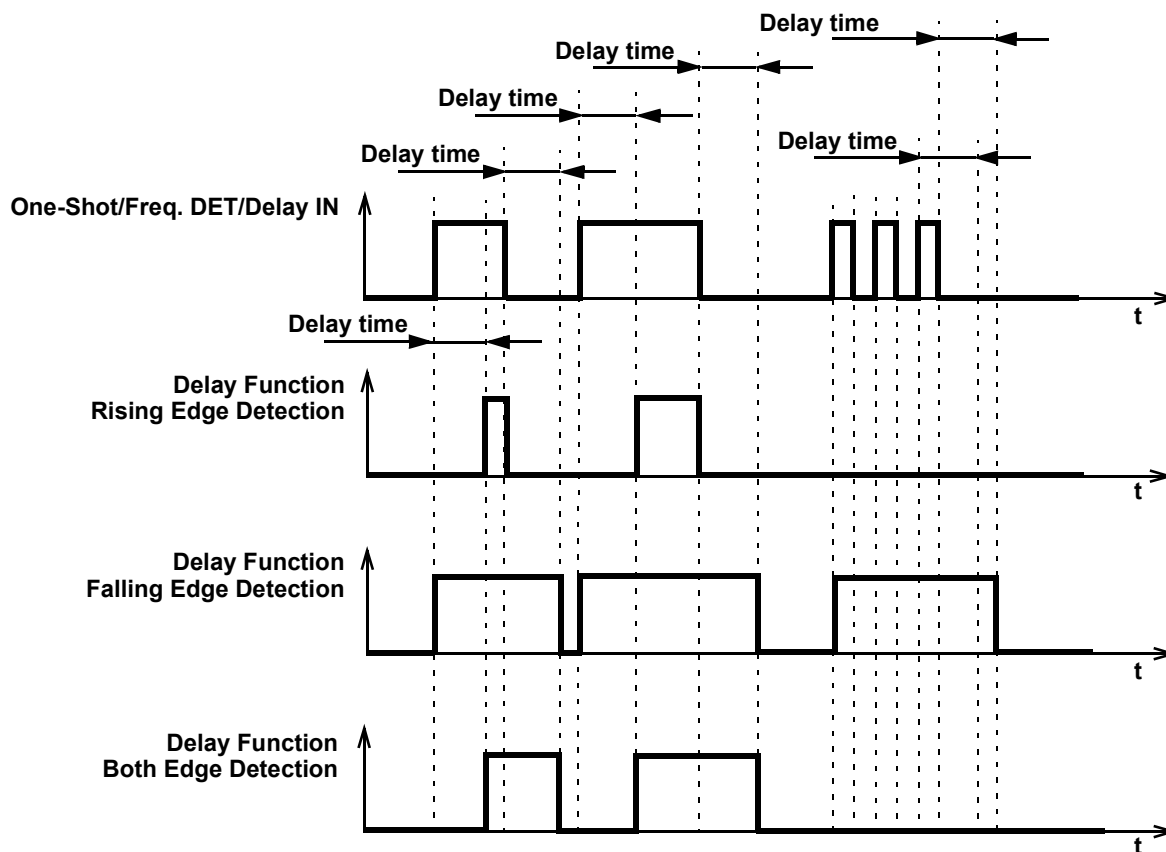


Figure 40: Delay Mode Timing Diagram for Different Edge Select Modes

8.3.2 Count Mode (Count Data: 3), Counter Reset (Rising Edge Detect) CNT/DLY0 to CNT/DLY6

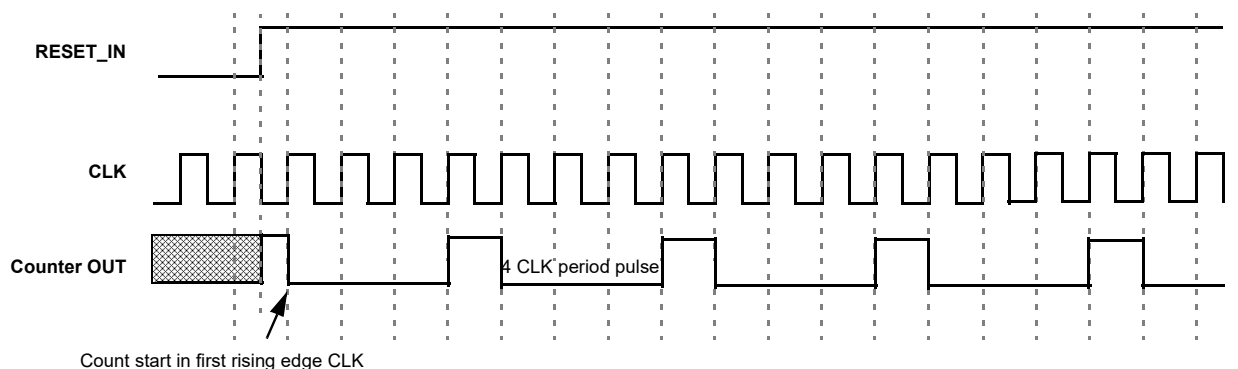
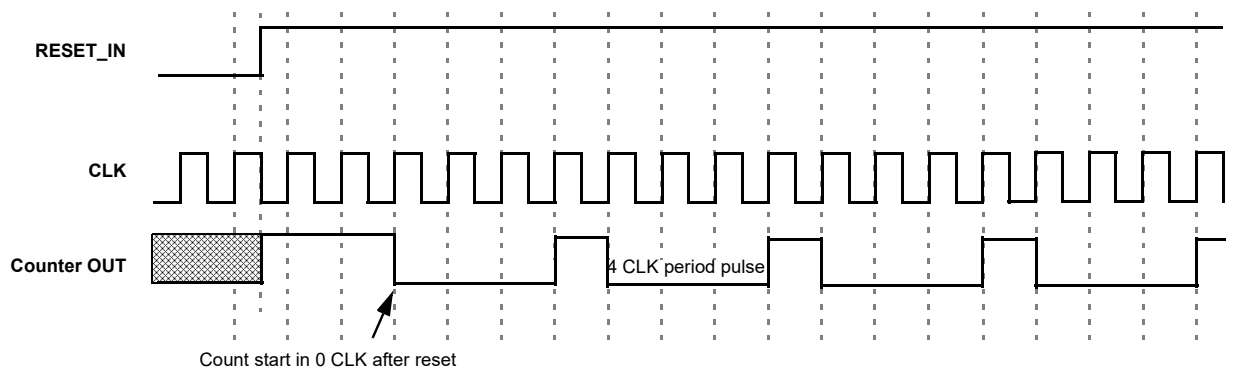


Figure 41: Counter Mode Timing Diagram without Two DFFs Synced Up

**Figure 42: Counter Mode Timing Diagram with Two DFFs Synced Up**

8.3.3 One-Shot Mode CNT/DLY0 to CNT/DLY6

This macrocell will generate a pulse whenever a selected edge is detected on its input. Register bits set the edge selection. The pulse width is determined by counter data and clock selection properties.

The output pulse polarity (non-inverted or inverted) is selected by register bit. Any incoming edges will be ignored during the pulse width generation. The following diagram shows one-shot function for non-inverted output.

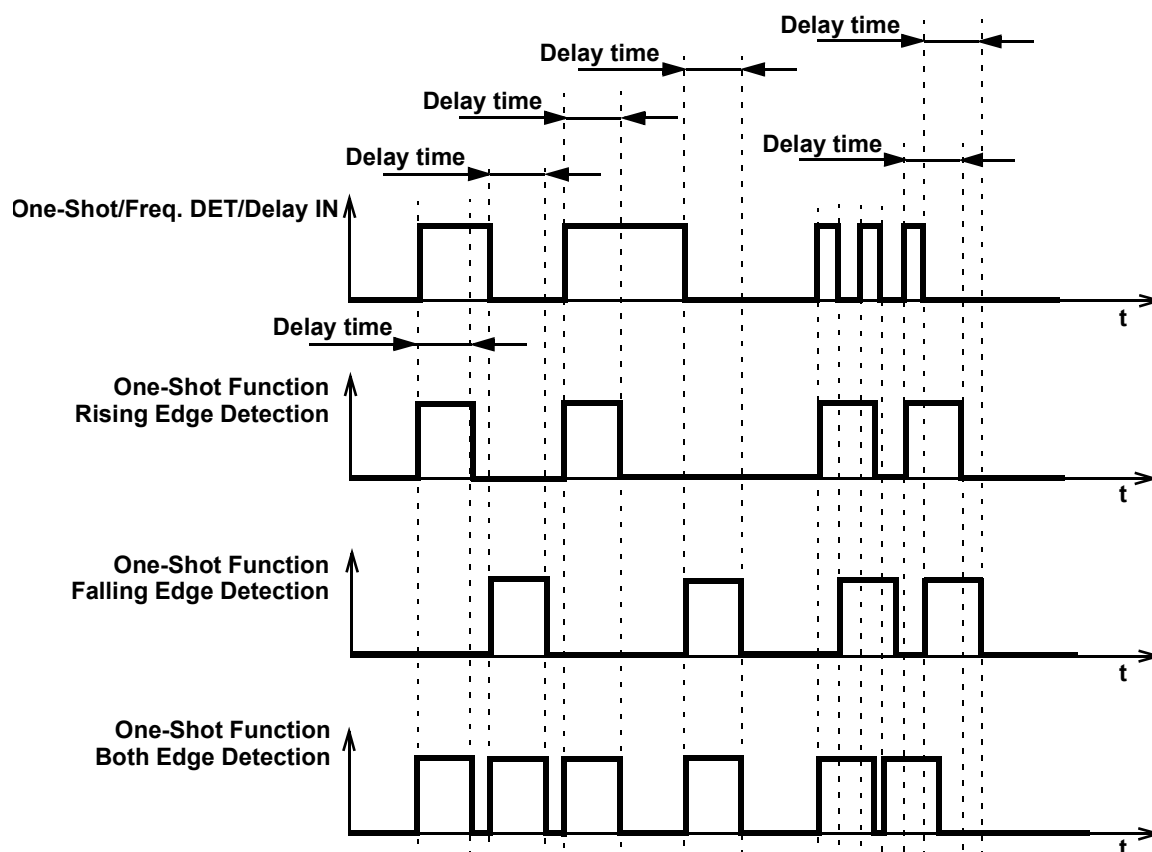


Figure 43: One-Shot Function Timing Diagram

This macrocell generates a high level pulse with a set width (defined by counter data) when detecting the respective edge. It does not restart while pulse is high.

8.3.4 Frequency Detection Mode CNT/DLY0 to CNT/DLY6

Rising Edge: The output goes high if the time between two successive edges is less than the delay. The output goes low if the second rising edge has not come after the last rising edge in specified time.

Falling Edge: The output goes high if the time between two falling edges is less than the set time. The output goes low if the second falling edge has not come after the last falling edge in specified time.

Both Edge: The output goes high if the time between the rising and falling edges is less than the set time, which is equivalent to the length of the pulse. The output goes low if after the last rising/falling edge and specified time, the second edge has not come.

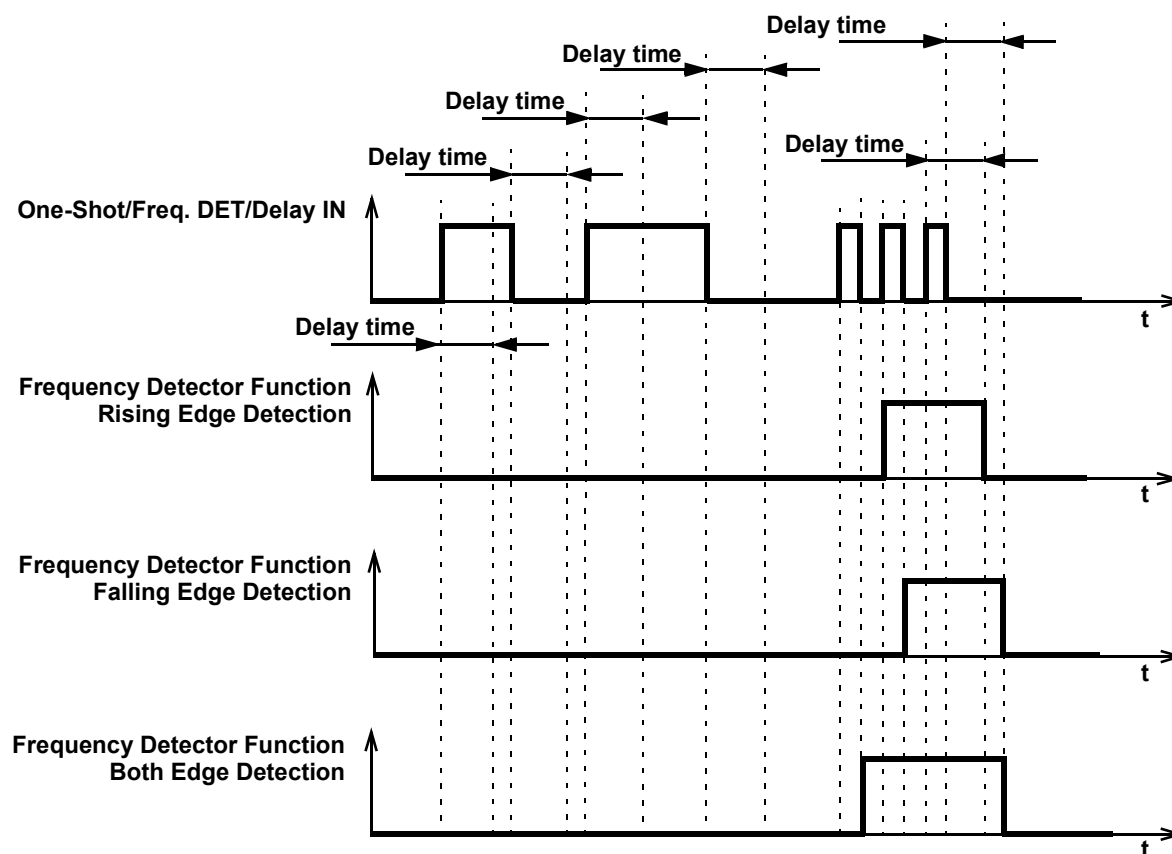


Figure 44: Frequency Detection Mode Timing Diagram

8.3.5 Edge Detection Mode CNT/DLY1 to CNT/DLY6

The macrocell generates high level short pulse when detecting the respective edge. See [Table 10](#).

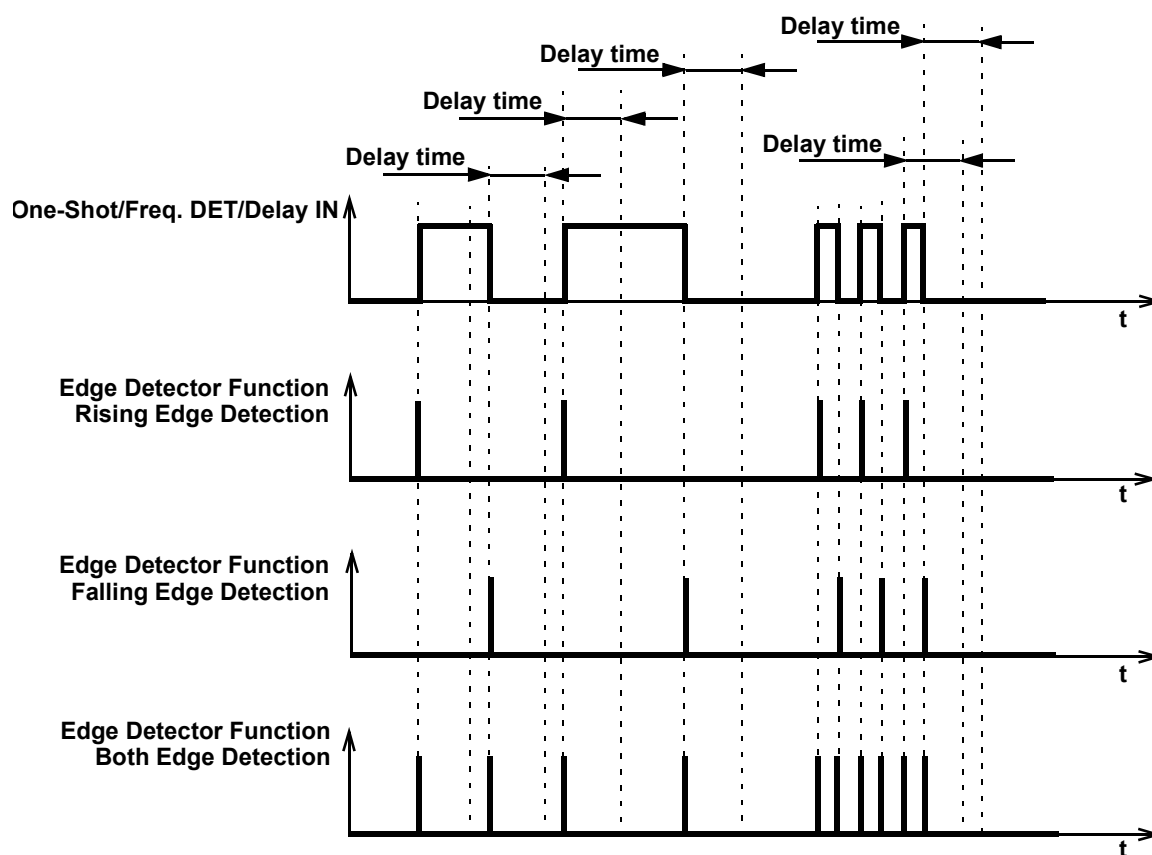


Figure 45: Edge Detection Mode Timing Diagram

8.3.6 Delayed Edge Detection Mode CNT/DLY0 to CNT/DLY6

In Delayed Edge Detection Mode, High-level short pulses are generated on the macrocell output after the configured delay time, if the corresponding edge was detected on the input.

If the input signal is changed during the set delay time, the pulse will not be generated.

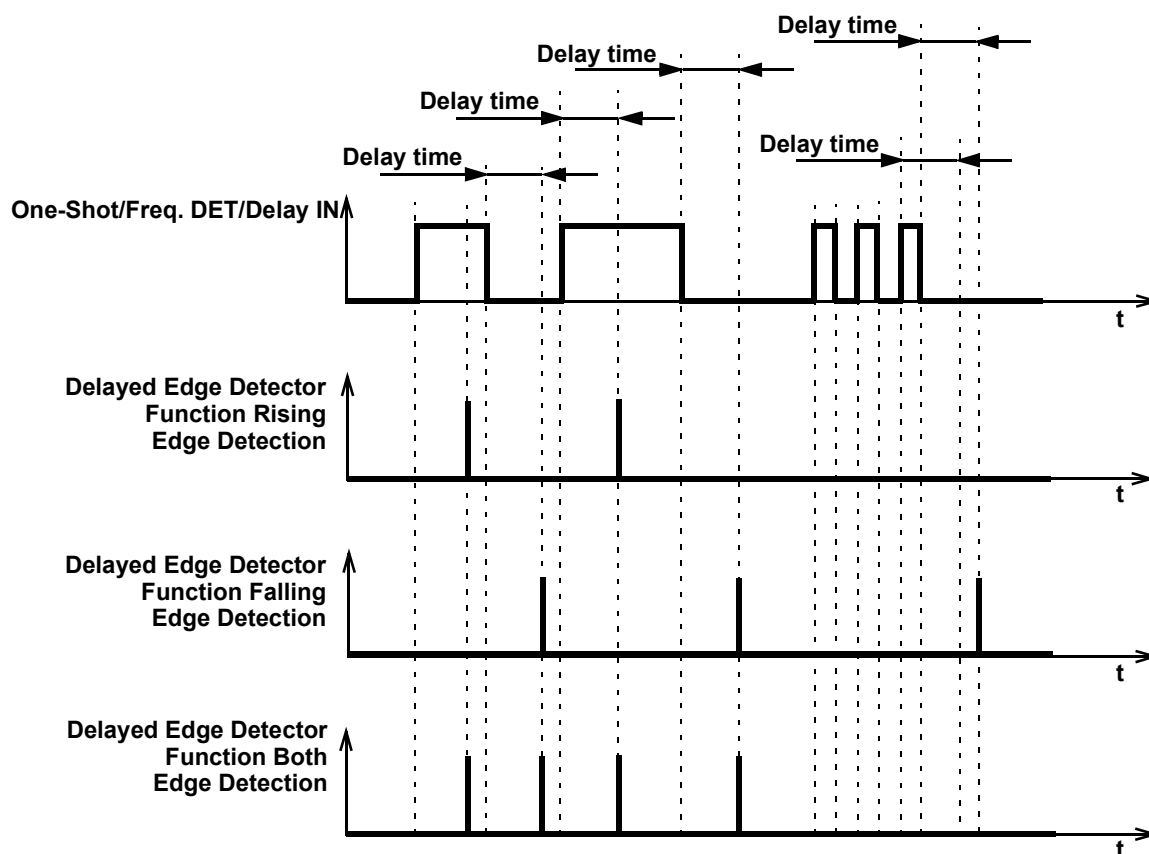


Figure 46: Delayed Edge Detection Mode Timing Diagram

8.3.7 CNT/FSM Mode CNT/DLY0

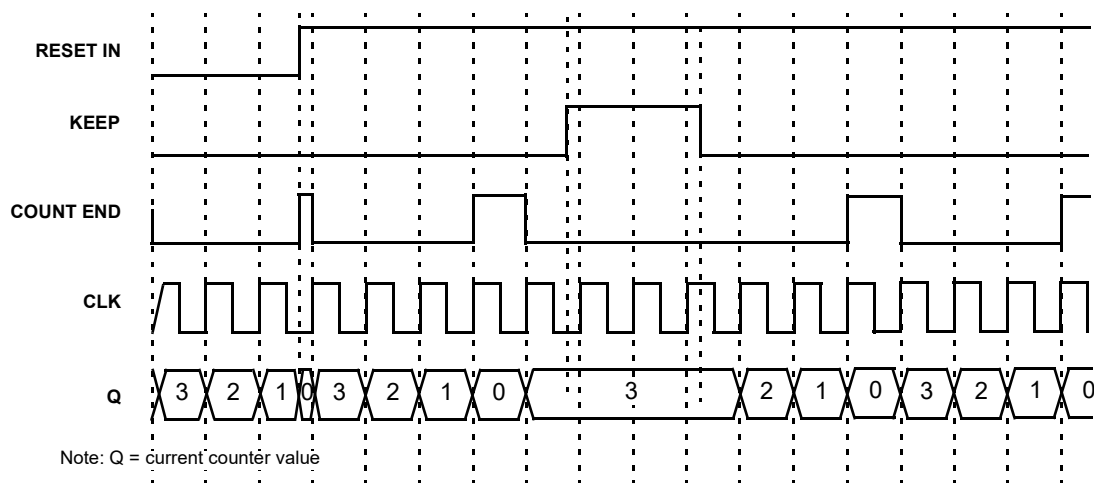


Figure 47: CNT/FSM Timing Diagram (Reset Rising Edge Mode, Oscillator is Forced On, UP = 0) for Counter Data = 3

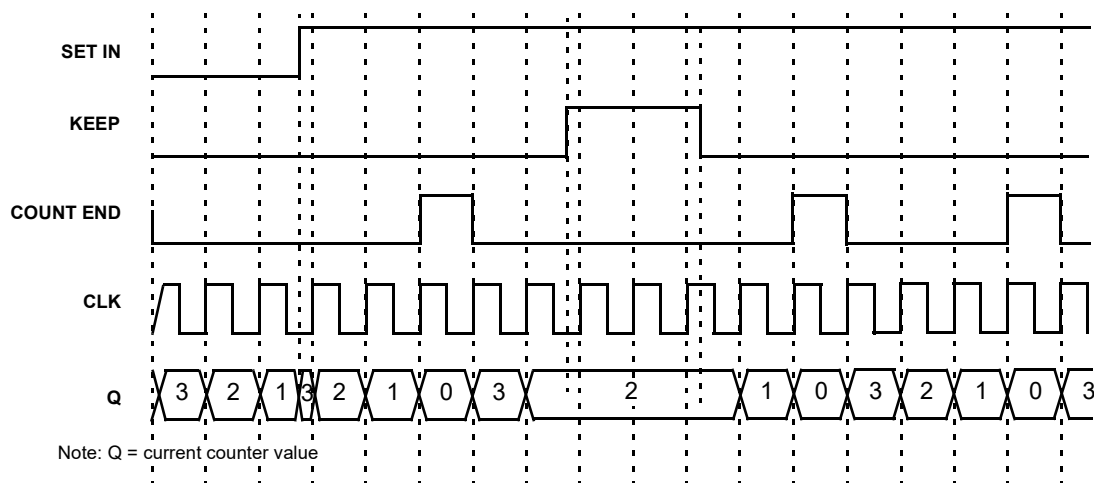


Figure 48: CNT/FSM Timing Diagram (Set Rising Edge Mode, Oscillator is Forced On, UP = 0) for Counter Data = 3

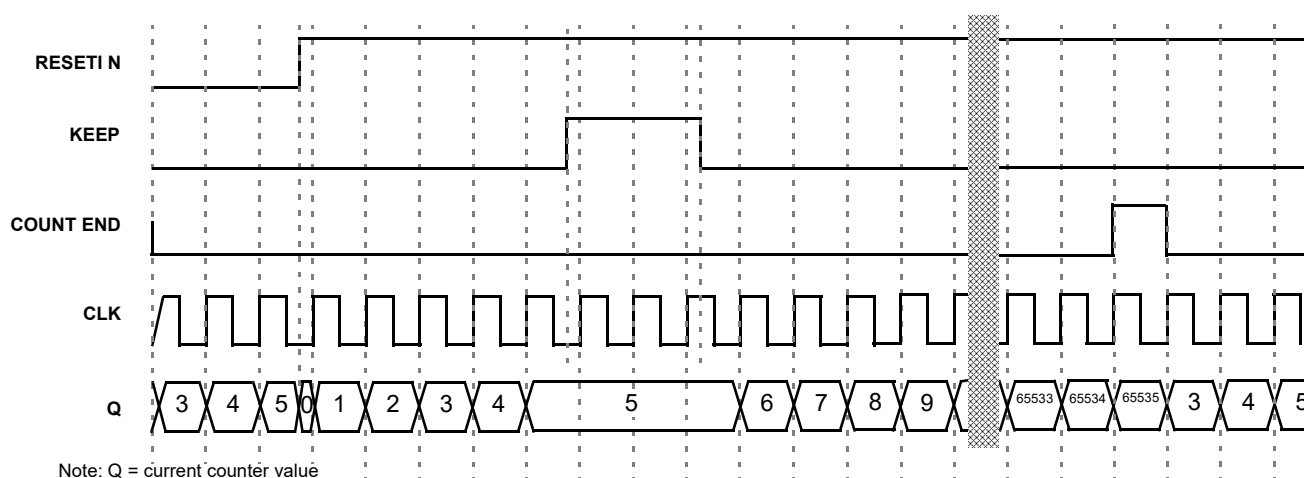
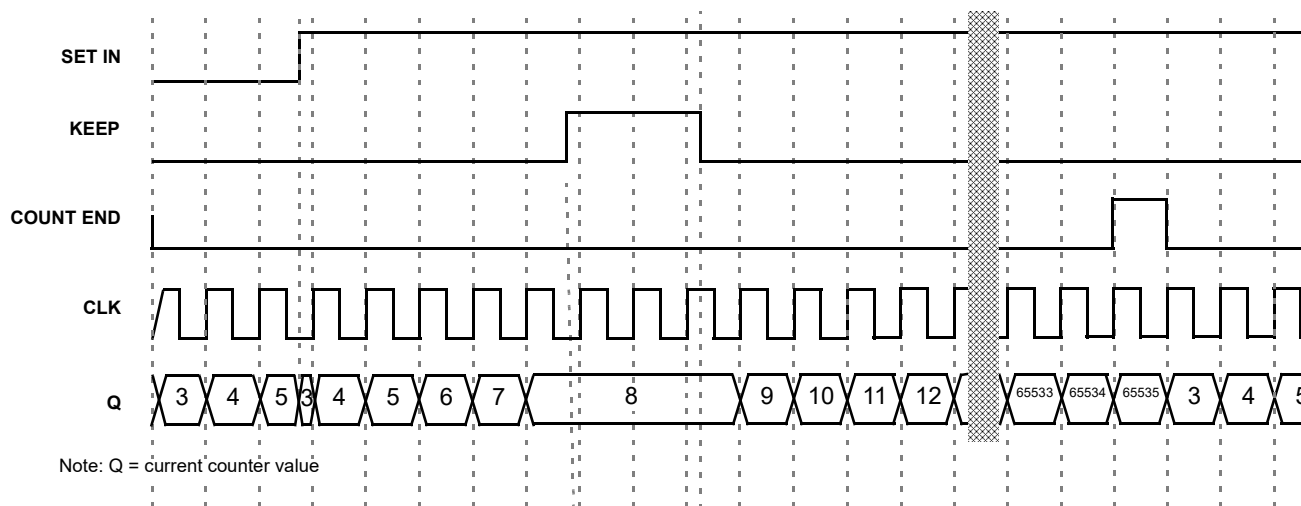
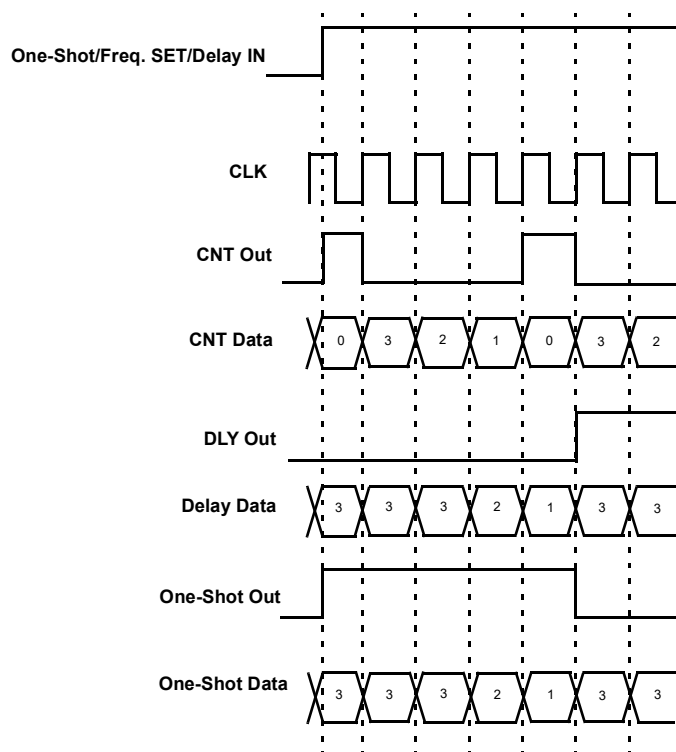


Figure 49: CNT/FSM Timing Diagram (Reset Rising Edge Mode, Oscillator is Forced On, UP = 1) for Counter Data = 3


Figure 50: CNT/FSM Timing Diagram (Set Rising Edge Mode, Oscillator is Forced On, UP = 1) for Counter Data = 3

8.3.8 Difference in Counter Value for Counter, Delay, One-Shot, and Frequency Detect Modes

There is a difference in counter value for Counter and Delay/One-Shot/Frequency Detect modes. Compared to Counter mode, in Delay/One-Shot/Frequency Detect modes the counter value is shifted for two rising edges of the clock signal. See [Figure 51](#).


Figure 51: Counter Value, Counter Data = 3

8.4 WAKE AND SLEEP CONTROLLER

The SLG47004 has a Wake and Sleep (WS) function for ACMP. The macrocell CNT/DLY0 can be reconfigured for this purpose registers [1224:1223] = 11 and register [1232] = 1. The WS serves for power saving, it allows to switch on and off selected ACMPs on selected bit of 16-bit counter.

Note 1: BG/Analog_Good time is long and should be considered in the wake and sleep timing in case it dynamically powers on/off.

Note 2: Wake time should be long enough to make sure ACMP and Vref have enough time to get a sample before going to sleep.

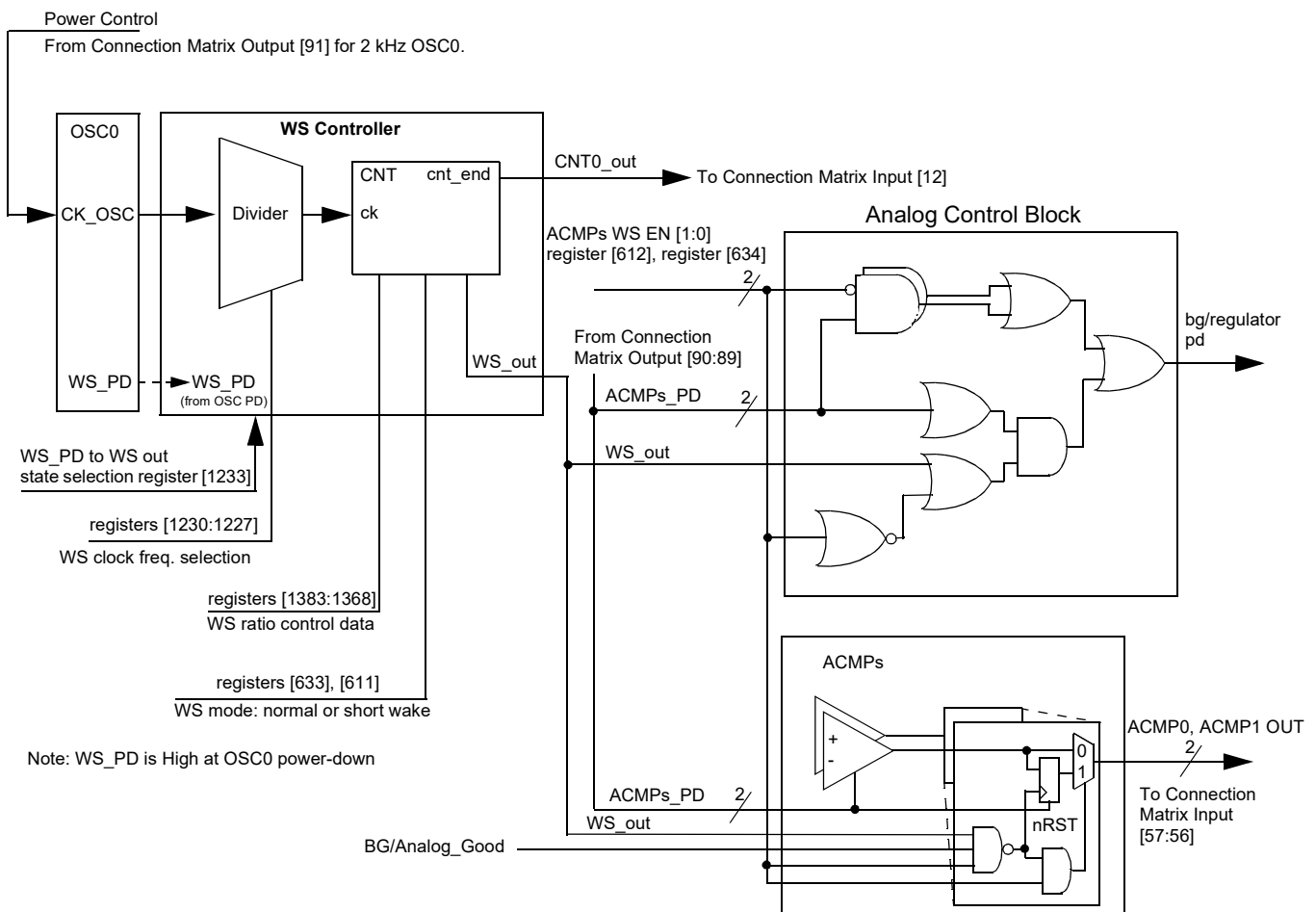
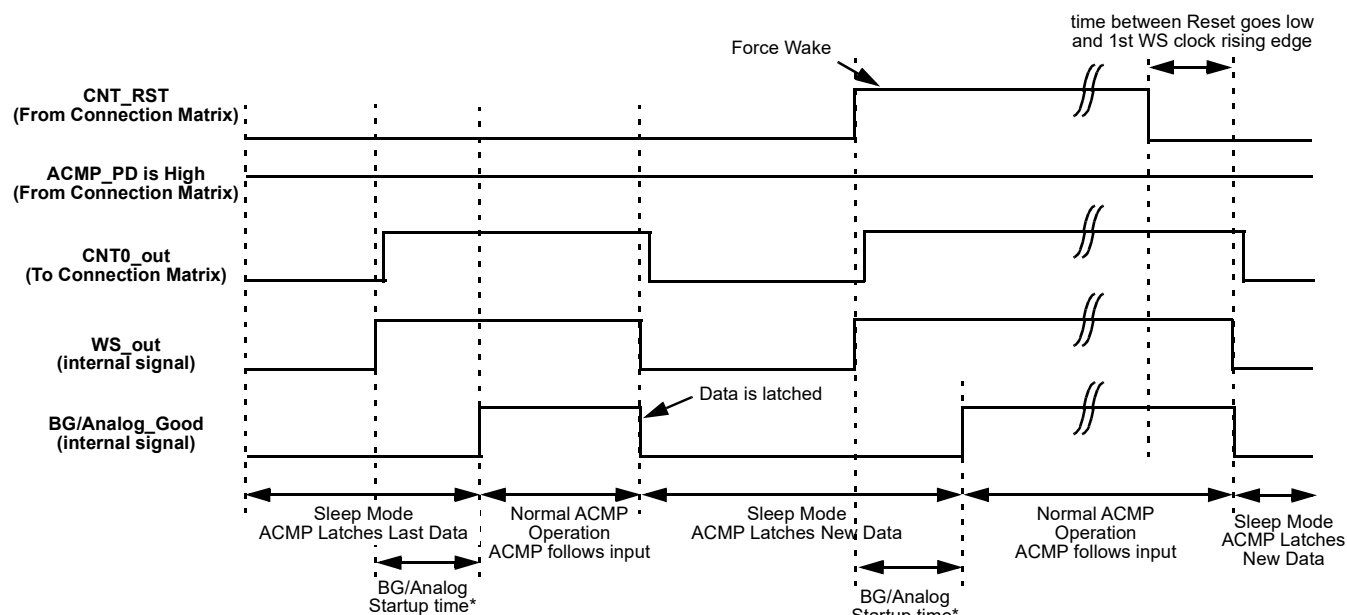
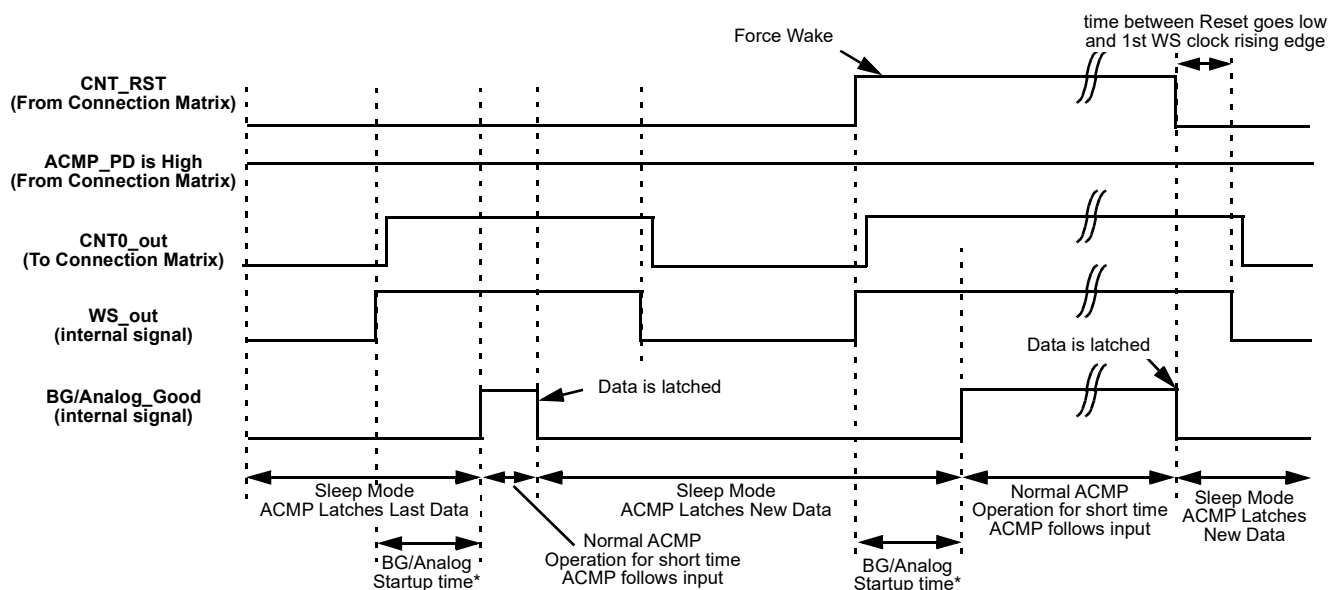


Figure 52: Wake and Sleep Controller



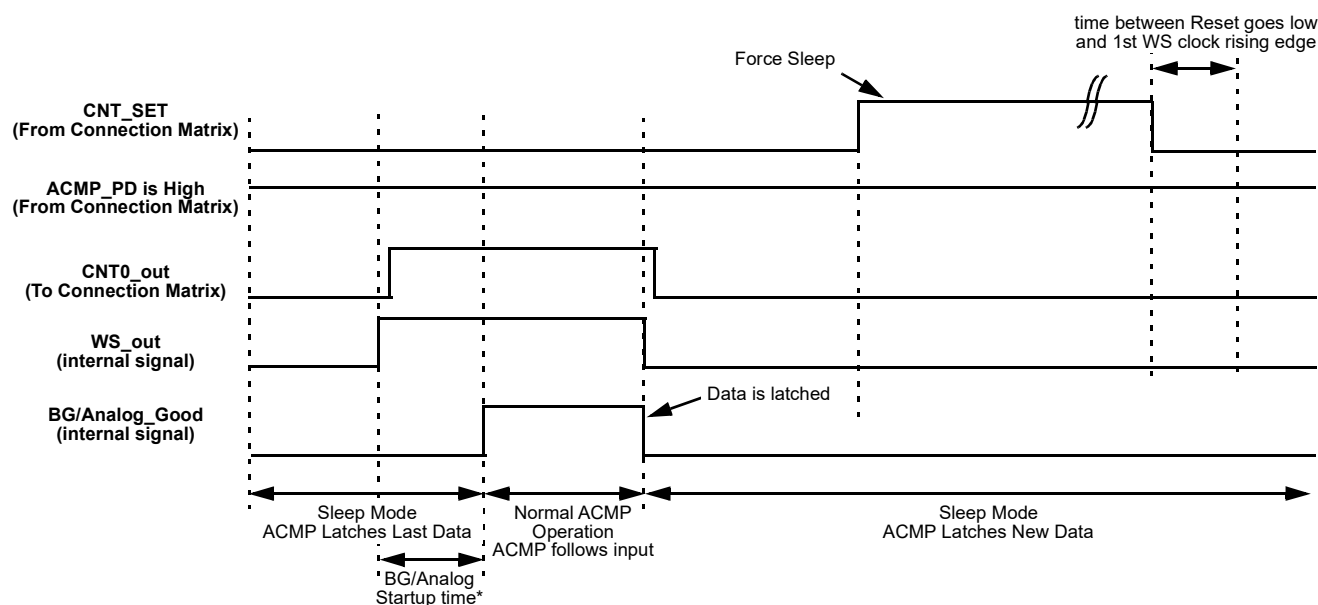
Note: CNT0_out is a delayed WS_out signal for 1us to make sure the data is correct during LATCH.

Figure 53: Wake and Sleep Timing Diagram, Normal Wake Mode, Counter Reset is Used



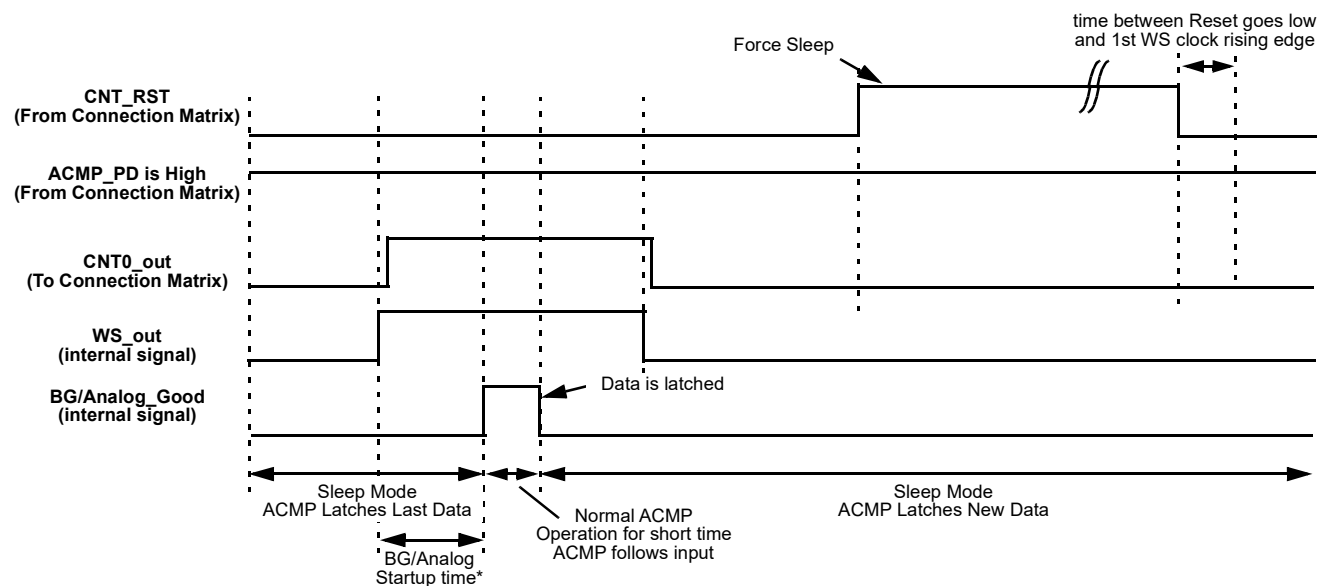
Note: CNT0_out is a delayed WS_out signal for 1us to make sure the data is correct during LATCH.

Figure 54: Wake and Sleep Timing Diagram, Short Wake Mode, Counter Reset is Used



Note: CNT0_out is a delayed WS_out signal for 1 us to make sure the data is correct during LATCH.

Figure 55: Wake and Sleep Timing Diagram, Normal Wake Mode, Counter Set is Used



Note: CNT0_out is a delayed WS_out signal for 1us to make sure the data is correct during LATCH.

Figure 56: Wake and Sleep Timing Diagram, Short Wake Mode, Counter Set is Used

Note: If low power BG is powered on/off by WS, the wake time should be longer than 2.1 ms. The BG/analog start up time will take maximal 2 ms. If low power BG is always on, OSC0 period is longer than required wake time. The short wake mode can be used to reduce the current consumption. The short wake mode is edge triggered, when the wake signal is latched by rising edge and released the Power-On signal after the ACMP output data is latched. This allows to have a valid ACMP data for any type of wake signal and have the optimized current consumption.

GreenPAK Programmable Mixed-Signal Matrix with In-System Programmability and Advanced Analog Features

Preliminary

To use any ACMP under WS controller, the following settings must be done:

- CNT/DLY0 must be set to Wake and Sleep Controller function (for all ACMPs);
- Register WS => enable (for each ACMP separately);
- CNT/DLY0 set/reset input = 0 (for all ACMPs).

As the OSC any oscillator with any pre-divider can be used. The user can select a period of time while the ACMP is sleeping in a range of 1 - 65535 clock cycles. Before they are sent to sleep their outputs are latched, so the ACMPs remain their state (High or Low) while sleeping.

WS controller has the following settings:

- Wake and Sleep Output State (High/Low)
 - If OSC is powered off (Power-down option is selected; Power-down input = 1) and Wake and Sleep Output State = High, the ACMP is continuously on.
 - If OSC is powered off (Power-down option is selected; Power-down input = 1) and Wake and Sleep Output State = Low, the ACMP is continuously off.
 - Both cases WS function is turned off.
- Counter Data (Range: 1 to 65535)
 - User can select wake and sleep ratio of the ACMP; counter data = sleep time, one clock = wake time.
- Q mode - defines the state of WS counter data when Set/Reset signal appears
 - Reset - when active signal appears, the WS counter will reset to zero and High level signal on its output will turn on the ACMPs. When Reset signal goes out, the WS counter will go Low and turn off the ACMPs until the counter counts up to the end.
 - Set - when active signal appears, the WS counter will stop and Low level signal on its output will turn off the ACMPs. When Set signal goes out, the WS counter will go on counting and High level signal will turn on the ACMPs while counter is counting up to the end.

Note: The OSC0 matrix power down to control ACMP WS is not supported for short wait time option.

- Edge Select defines the edge for Q mode
 - High level Set/Reset - switches mode Set/Reset when level is High

Note: Q mode operates only in case of "High Level Set/Reset".

- Wake time selection - time required for wake signal to turn the ACMPs on

Normal Wake Time - when WS signal is High, it takes BG/analog start up time to turn the ACMPs on. They will stay on until WS signal is Low again. Wake time is one clock period. It should be longer than BG turn on time and minimal required comparing time of the ACMP.

Short Wake Time - when WS signal is High, it takes BG/analog start up time to turn the ACMPs on. They will stay on for 1 μ s and turn off regardless of WS signal. The WS signal width does not matter.

- Keep - pauses counting while Keep = 1
- Up - reverses counting
 - If Up = 1, CNT is counting up from user selected value to 65535.
 - If Up = 0, CNT is counting down from user selected value to 0.

9 Analog Comparators

9.1 ANALOG COMPARATORS OVERVIEW

There are two Low Power Rail-to-Rail General Purpose Analog Comparators (ACMP) macrocells in the SLG47004. For the ACMP macrocells to be used in a GreenPAK design, the power-up signals (ACMP0_L_pdb and ACMP1_L_pdb) need to be active. By connecting to signals coming from the Connection Matrix, it is possible to have each ACMP be ON continuously, OFF continuously, or switched on periodically, based on a digital signal coming from the Connection Matrix. When ACMP is powered down, its output is low. Two General Purpose Analog Comparators are optimized for low power operation.

Each of the General Purpose ACMP cells has a positive input signal that can be provided by a variety of external sources, and can also have a selectable gain stage (1x, 0.5x, 0.33x, 0.25x) before connection to the analog comparator. The gain divider is unbuffered and has an input resistance of 2 M Ω (typ) for 0.5x, 0.33x, 0.25x, and 10 G Ω for 1x. Each of the General Purpose ACMP macrocells has a negative input signal that is either created from an internal Vref or provided by any external source (from external pins). Note that the external Vref signal is filtered with a 2nd order low pass filter with 8 kHz typical bandwidth, see in [Figure 57](#) and [Figure 58](#).

Input bias current < 1 nA (typ).

PWR UP = 1 => ACMP is powered up.

PWR UP = 0 => ACMP is powered down.

Both General Purpose Analog Comparators have "Low Energy Power Up" setting (register [608] - ACMP0, register [630] - ACMP1). When enabled, it allows reducing average power consumption during ACMP power up process. This setting changes power up sequence of analog macrocells:

Low Energy Power Up register [608], register [630] = 0 - all analog macrocells associated with ACMP turns on simultaneously.

Low Energy Power Up register [608], register [630] = 1 - the first macrocell that begins to turn on is Bandgap. Other analog macrocells begin to turn on only after BG_OK signal is valid. This option slightly increases general ACMP Power-On time, while reducing the average current consumption.

During power-up, the ACMP output will remain LOW, and then becomes valid after power up signal goes high for ACMP0_L and ACMP1_L (see parameter t_{start} in [Table 16](#)).

Each cell also has a flexible hysteresis selection, to offer hysteresis of 32 steps, but not more than Vref voltage. It means that there are 6-bits to select Vref and independent 6-bits to select the hysteresis (no need to have an adder logic).

It's possible to enable low pass filter at the Vref input. But it's highly recommended to enable this LPF only when hysteresis $V_{hys} > 196$ mV.

ACMP0_L IN+ options are OA0_out, GPIOx (PIN), V_{DD} .

ACMP1_L IN+ options are OA1, GPIOx (PIN), ACMP0L_IN+, Temp Sensor OUT.

9.1.1 ACMP0L Block Diagram

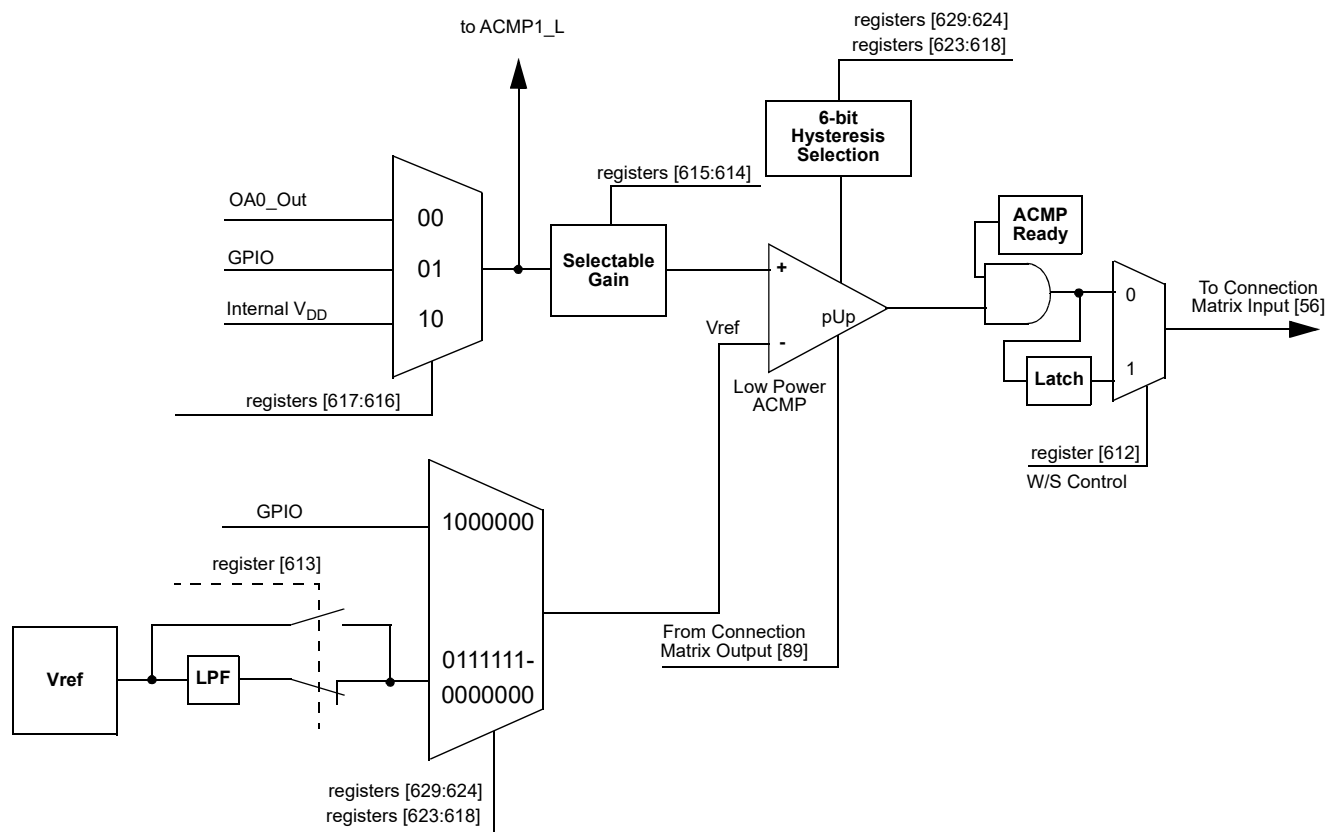


Figure 57: ACMP0L Block Diagram

9.1.2 ACMP1L Block Diagram

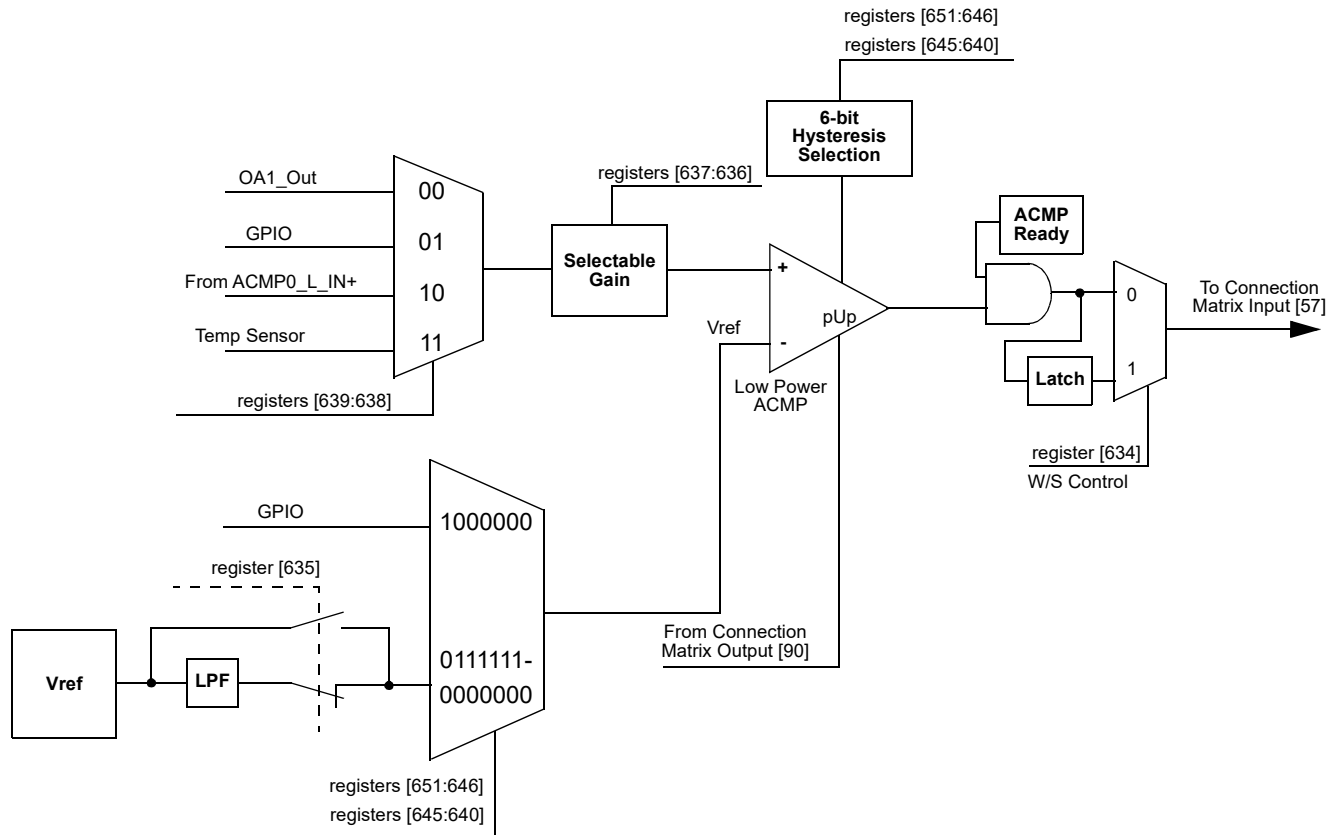


Figure 58: ACMP1L Block Diagram

9.2 CHOPPER ANALOG COMPARATOR

There is one Chopper Rail-to-Rail Analog Comparator (ACMP) macrocells in the SLG47004. It is possible to use Chopper ACMP to do in system trim by changing the Rheostat resistance in Auto-Trim mode. It is also possible to use a Chopper ACMP as a general purpose analog comparator.

The chopper ACMP power up signal is controlled either by internal Auto-Trim logic (Set 0/1 of Digital Rheostat 0/1) or by matrix input.

The chopper ACMP is automatically powered on during the calibration time to control the up/down signal of the counter/rheostat, when the Auto-Trim is enabled (register [909] = 0).

In order to use Chopper ACMP as a standalone comparator (Auto-Trim mode is disabled, register [909] = 1) user should provide the clock signal to this macrocell. Clock source can be internal oscillators or any pulses from the connection matrix.

Note that clock frequency for the Chopper ACMP shouldn't be greater than f_{ChACMP} . Please refer to [Table 23](#).

Output of Chopper ACMP can be optionally inverted by register [882].

The matrix output [85] is used to control chopper ACMP power up signal for the general purpose usage, see [Figure 59](#). It is possible to use the chopper ACMP as a general purpose ACMP after Auto-Trim procedure is completed, since the power up signal is a logic OR of the latched Set (Digital Rheostat 0/1) signal and matrix signal. If Auto-Trim (Set 0/1 of Digital Rheostat 0/1) is disabled and chopper ACMP channel is set to Auto (Channel 0/1), then ACMP output defaults to Channel 0 while Channel 1 is ignored.

The power-up signals need to be active high in order to use the Chopper ACMP. By connecting to signals coming from the Connection Matrix, it is possible to have ACMP be ON continuously, OFF continuously, or switched on periodically based on a

digital signal coming from the Connection Matrix. When ACMP is powered down, its output is low.

There are no Gain and Hysteresis selection for chopper ACMP compared to the ACMP0L and ACMP1L.

It's possible to select different reference sources for Chopper ACMP. It can be:

- external voltage from pin;
- divided internal voltage from internal reference source (from 32 mV to 2048 mV);
- divided internal reference voltage from HD Buffer (64 steps);
- divided V_{DDA} voltage (64 steps).

For more information see Section 15.

The positive input of the Chopper ACMP can be connected to the Op Amp0 out or Op Amp1 out, or to the external PIN.

The inputs of Chopper ACMP can be reconfigured while operating in AutoTrim mode. There is one configuration of inputs (Figure 59) for case when Set0 (Digital Rheostat 0) signal is latched, and another configuration of Chopper ACMP inputs when Set1 (Digital Rheostat 1) signal is latched. For example, M1 MUX can be configured to operate with In Amp out when Set0 (Digital Rheostat 0) is latched and Chopper_ACMP+ pin when Set1 (Digital Rheostat 1) is latched. The same way, “-” input of Chopper ACMP can be configured to work with any of possible inputs when Set0 (Digital Rheostat 0) or Set1 (Digital Rheostat 1) are latched.

Note that the default configuration is the configuration for Set0 (Digital Rheostat 0) signal. When Chopper ACMP operates as separate ACMP and AutoTrim function is disabled, inputs of Chopper ACMP are defined by registers [893:892].

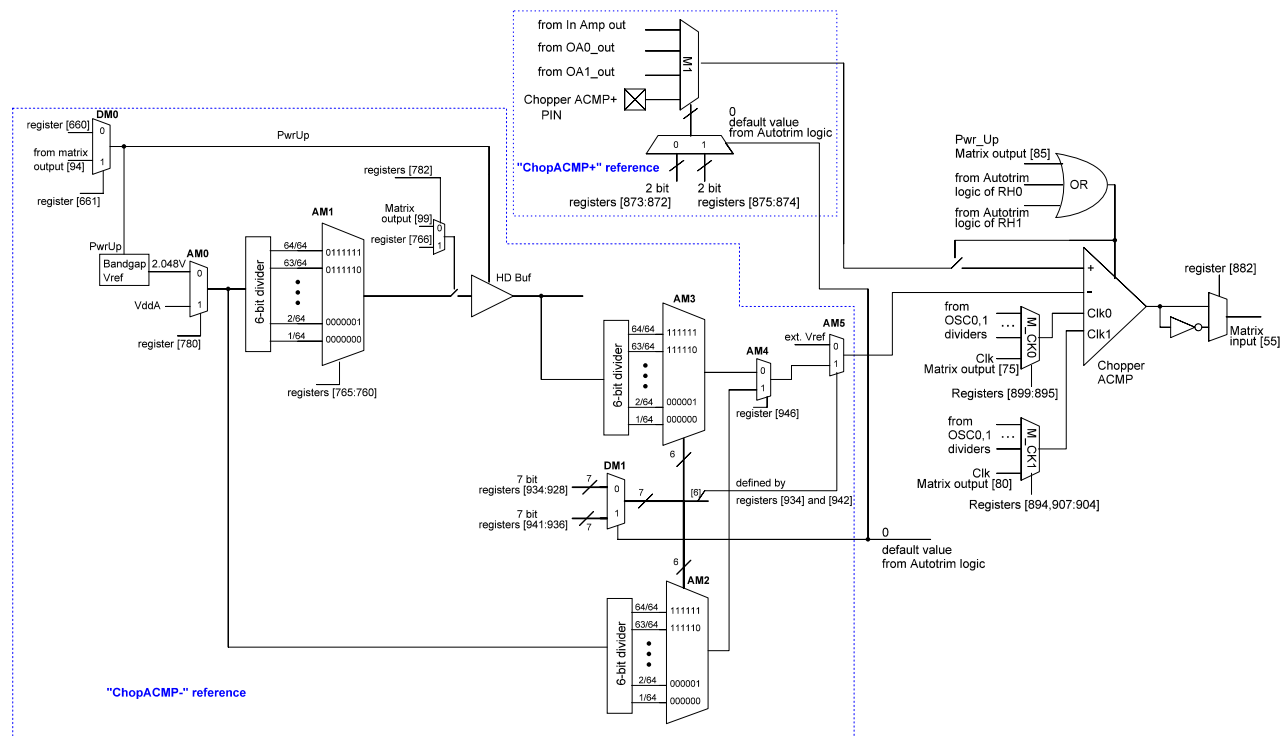


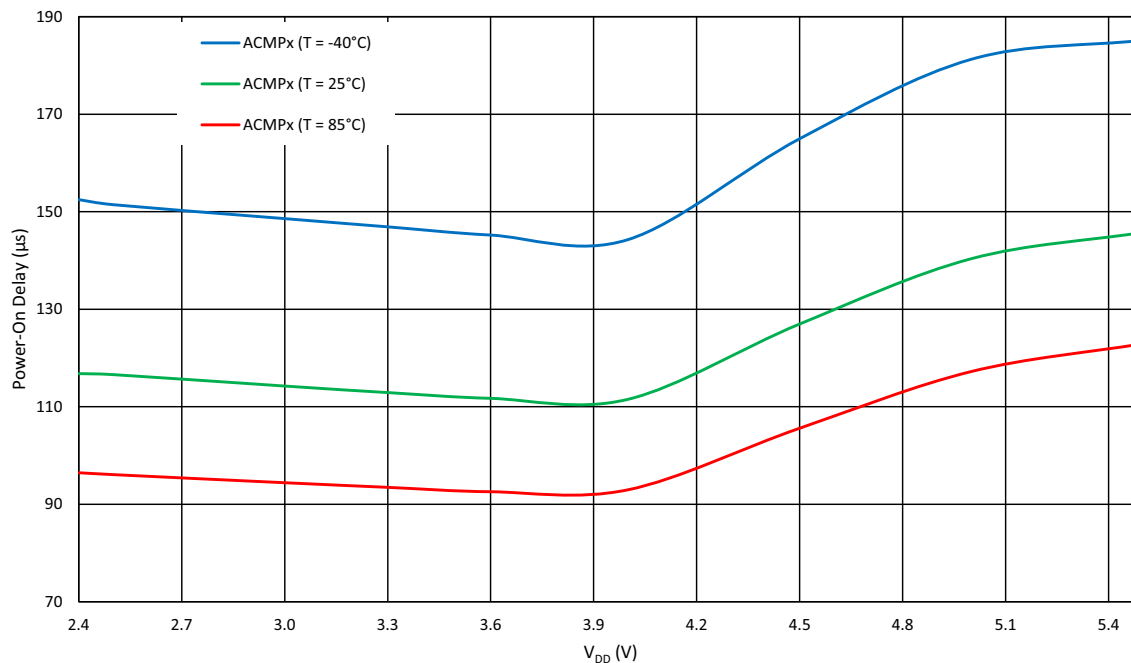
Figure 59: Chopper ACMP Block Diagram

9.3 ACMP SAMPLING MODE

Both General Purpose Analog Comparators (ACMPL0 and ACMPL1) have an optional sampling mode. In this mode, ACMP is enabled for the shortest amount of time after rising edge at Power Up input to get a valid data. Then ACMP latches its value and goes sleep again.

Registers [610], [632] enable sampling mode for two comparators.

9.4 ACMP TYPICAL PERFORMANCE

Figure 60: ACMPx Power-On Delay vs. V_{DD}

10 Programmable Operational Amplifiers

10.1 GENERAL DESCRIPTION

The SLG47004 contains three operational amplifiers with rail-to-rail input and output. Two of them (Programmable Op Amps) have the additional functions of driving internal analog FETs (Voltage Regulator and Current Sink modes) and Comparator mode. The third Internal Op Amp is an amplifier with internal resistors, and can be configured as a difference amplifier with Gain = 1. All three op amps can function as instrumentation amplifiers. The structures of the op amps are shown in Figure 61 and Figure 62.

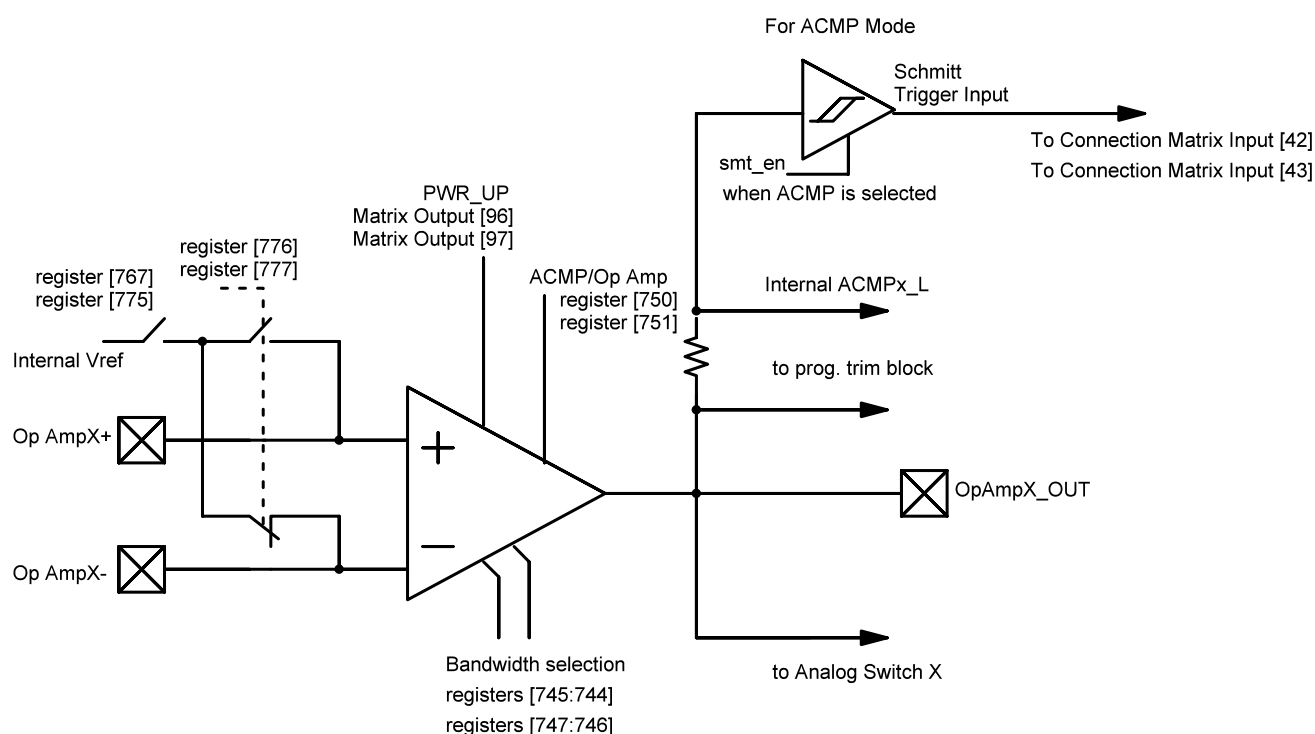


Figure 61: Programmable Operational Amplifier OA0, OA1 Internal Circuit

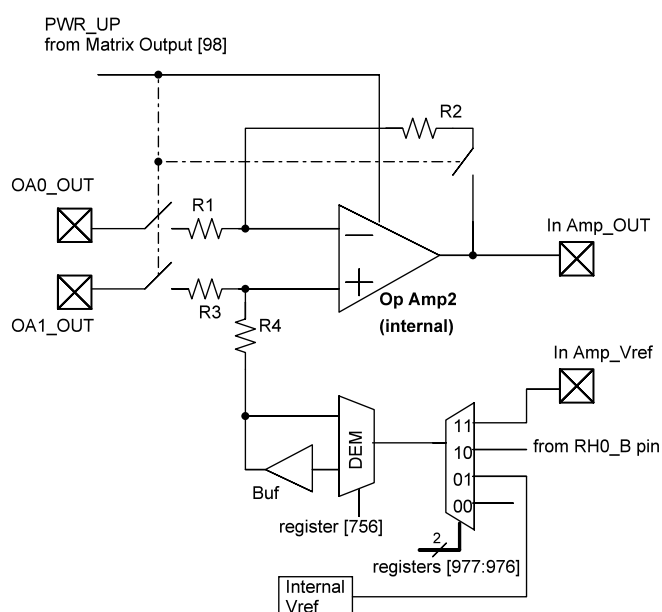


Figure 62: Internal Operational Amplifier Circuit

Each of the two Programmable Op Amp inputs has a hardware connection to the external pin and an optional connection to the internal voltage reference source, which makes it possible to create precise voltage or current source. For more detailed description of op amp Vref sources see Section 15. The output of the operational amplifier is hardwired to an external pin. This output can also be connected to the Programmable Trim block of rheostat macrocell, ACMP non-inverting input (ACMP0_L+ for OA0, ACMP1_L+ for OA1), or control the corresponding Analog Switch, depending on the mode of operation. Each Programmable Op Amp can also be configured as an analog comparator, in which case its output signal is connected to the Connection Matrix through a dedicated buffer.

Each Programmable Op Amp has a programmable bandwidth that can be set by two register bits. In addition, internal charge pump setting for each Op Amp must be changed according to bandwidth selection, see Table 54.

The bandwidths may vary up to $\pm 30\%$ over PVT. Each operational amplifier is factory trimmed. This trimming is independent of the trimming associated with the onboard digital rheostat (system calibration).

The Internal operational amplifier shares its inputs with the Programmable Op Amps outputs. The voltage reference for the internal amplifier can be sourced from either the internal or external Vref. Note that if the internal Vref is used as a source for the instrumentation amplifier Vref, the user can optionally connect this Vref to the output pin, or disconnect the Vref from output pin and use this pin as GPIO.

Also, if the Internal Op Amp is inactive (In Amp Mode is disabled), the user can use the In Amp_Vref pin as GPIO. The In Amp_Out pin can be configured as GPI.

Table 54: Op Amp Bandwidth Settings

Op Amp Bandwidth Selection	Op Amp0				Op Amp1				Op Amp2 (Internal)			
	Bandwidth Selection		Charge Pump Frequency		Bandwidth Selection		Charge Pump Frequency		Bandwidth Selection		Charge Pump Frequency	
Register Bit →	745	744	955	954	747	746	963	962	749	748	971	970
128 kHz	0	0	0	0	0	0	0	0	0	0	0	0
512 kHz	0	1	0	1	0	1	0	1	0	1	0	1
2.048 MHz	1	0	1	0	1	0	1	0	1	0	1	0
8.192 MHz	1	1	1	1	1	1	1	0	1	1	1	0

10.2 MODES OF OPERATION

In order to use any of the op amp macrocells in the GreenPAK Designer, the power up signal (PWR_UP) must be set to logic High. By default, all op amp macrocells are turned off after SLG47004 startup. During power-up, outputs of all op amps will remain in a Hi-Z state and then become valid (see parameter t_{on} in Table 22).

Operational amplifiers turn-on time can be decreased by setting register bits [759:757] to 1. In this case op amps analog supporting blocks are always turned on. Note that current consumption of op amp will be increased when op amp is powered down and bits [759:757] is 1 (see Section 3.11).

See the list below for the op amp operation modes:

- Operational Amplifier mode;
- Instrumentation Amplifier mode;
- Analog Comparator mode;
- Voltage Regulator mode;
- Current Sink mode.

10.2.1 Operational Amplifier Mode

In this mode, the Programmable Op Amp operates as a conventional operational amplifier. Also, the Programmable Op Amp can source the corresponding non-inverting ACMP input (see ACMP macrocell settings). The output of the Programmable Op Amp macrocell is in a Hi-Z state while the macrocell is turned off.

Figure 63 shows the example of differential amplifier with input offset voltage compensation with help of digital rheostat and programmable trim block. Zero input voltage equal to output voltage $V_{OUT} = V_{DD}/2$.

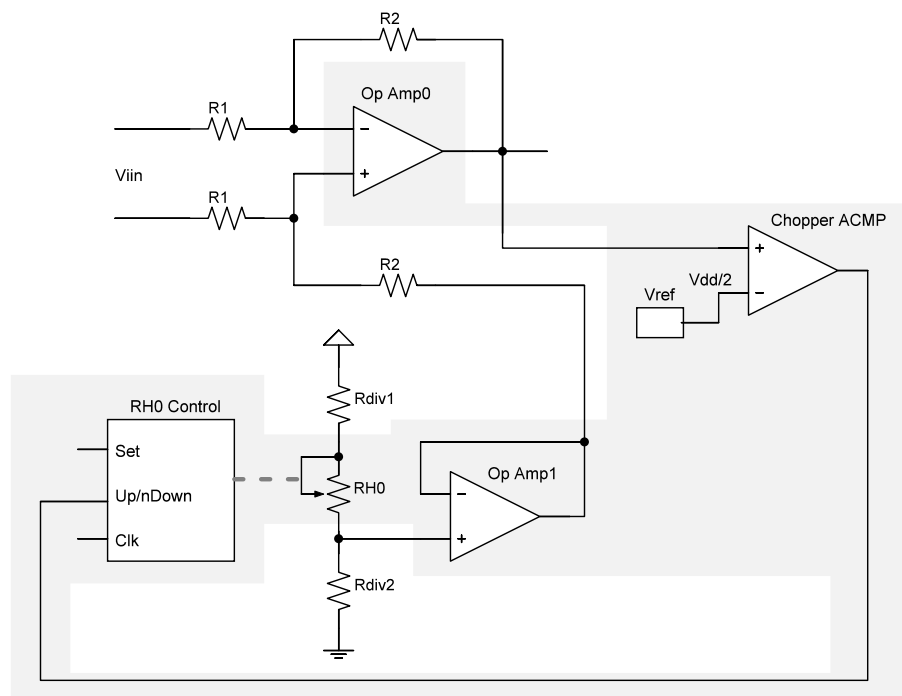
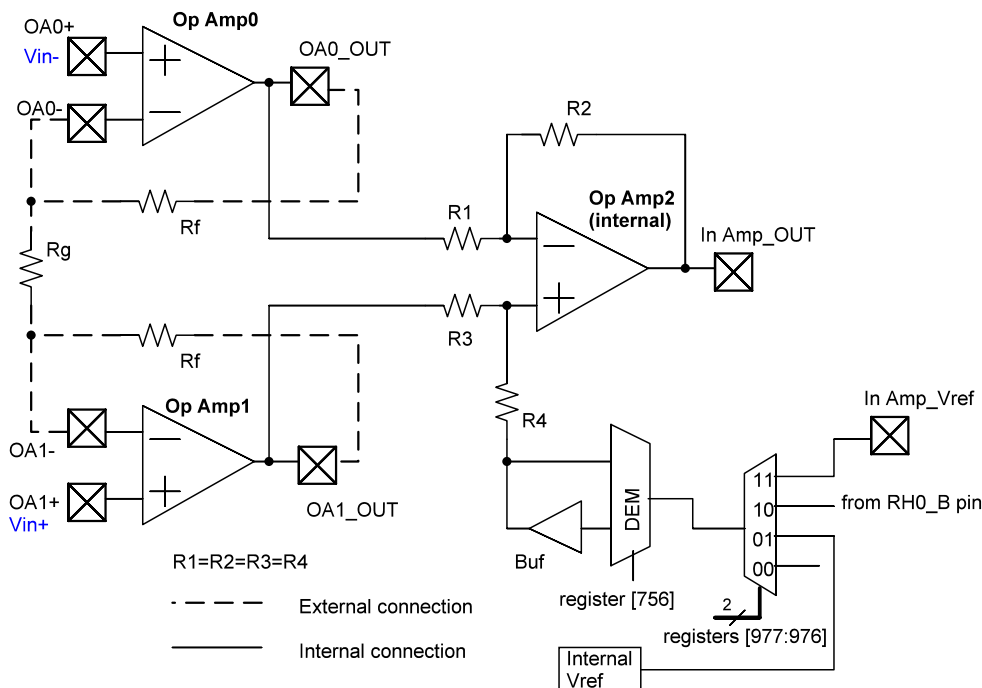


Figure 63: Example of Input Offset Voltage Compensation

10.2.2 Instrumentation Amplifier Mode

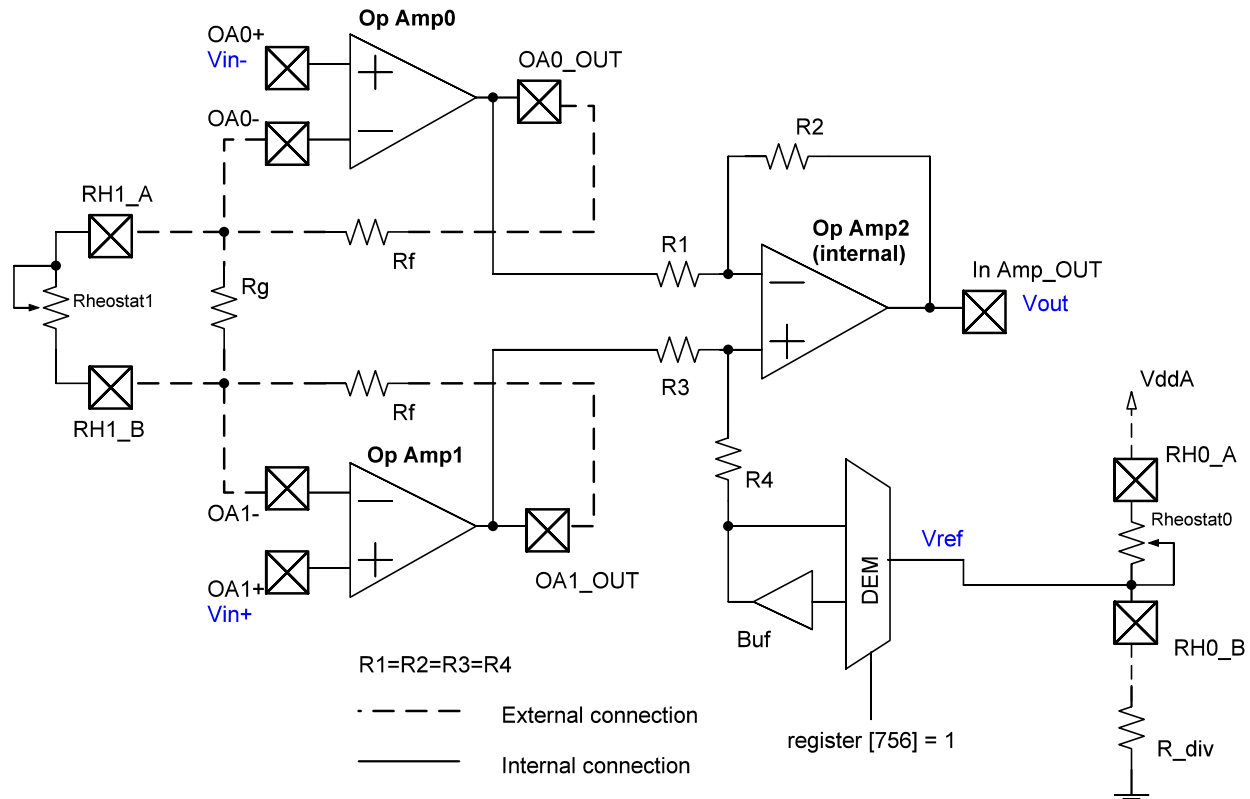
If this mode is active (Matrix Output [98] is High level), the two Programmable Op Amps and the single Internal Op Amp work together in Instrumentation Amplifier configuration, shown in Figure 64. When power up signal is logic LOW the output of In Amp is in Hi-Z state.


Figure 64: Instrumentation Amplifier Structure

The absolute value of internal resistors R_1 , R_2 , R_3 , R_4 is $\langle R_{INT} \rangle$ k Ω ± 20 %. The mismatch between resistors in one IC is $\langle R_{INT_TL} \rangle$ %. The resistors R_f and R_g are user defined external resistors. The output voltage V_{OUT} of the instrumentation amplifier shown in Figure 64 is

$$V_{OUT} = (1 + 2R_f/R_g)(V_{IN+} - V_{IN-}) + V_{REF}$$

The user can trim both the gain and the offset error of the instrumentation amplifier using two of the Rheostats from the SLG47004. Figure 65 shows the configuration of the instrumentation amplifier in this scenario.


Figure 65: Instrumentation Operational Amplifier Configuration for Users Trim

Note that in [Figure 65](#), the Demux connects to the Vref external input with an internal buffer (register [756] = 1). This allows us to eliminate the influence of resistor divider R_{div} and Rheostat0 on instrumentation amplifier.

It is possible to use a built-in Auto-Trim function for either setting the zero point of the Wheatstone bridge sensor using the In Amp or tuning a system output voltage to the desired level. However, the following limitations exist for using the built-in Auto-Trim function to trim both total system offset and system gain errors:

- The Auto-Trim procedures of total offset compensation and system gain error must be done iteratively starting and finishing with the total offset compensation: 1st iteration - offset compensation, 2nd iteration - gain trim, 3rd iteration - offset compensation. Extra iterations can be added to achieve a better accuracy. The last iteration should be an offset compensation.
- Total system offset (sensor offset + Op Amp1 offset + Op Amp2 offset) must not be greater than $V_{sensor_output_range}/2$.

It's possible to power external components like bridge or ADC from internal HD Buffer of SLG47004 to improve accuracy of system.

10.2.3 Analog Comparator Mode

Both operational amplifiers have an Analog Comparator mode in which they work as conventional rail-to-rail comparators.

10.2.4 Voltage Regulator Mode

In this mode, the op amp output drives P-FET (part of Analog Switch). Note that FETs of Analog Switches have different resistances. Analog Switch 0 has $R_{ds_PMOS} \ll R_{ds_NMOS}$, while Analog Switch 1 has $R_{ds_NMOS} \ll R_{ds_PMOS}$. That's why it is recommended to implement voltage regulator mode using Analog Switch 0. In this mode the op amp output is High when the macrocell is turned off. [Figure 66 \(A\)](#) shows the typical implementation of the voltage source function. Optionally, the

user can use this mode to implement a constant current source with load connected to ground (Figure 66, B, C). Note that op amp must operate in operational amplifier mode (register 750 = 0 for Op Amp0, register 751 = 0 for Op Amp1).

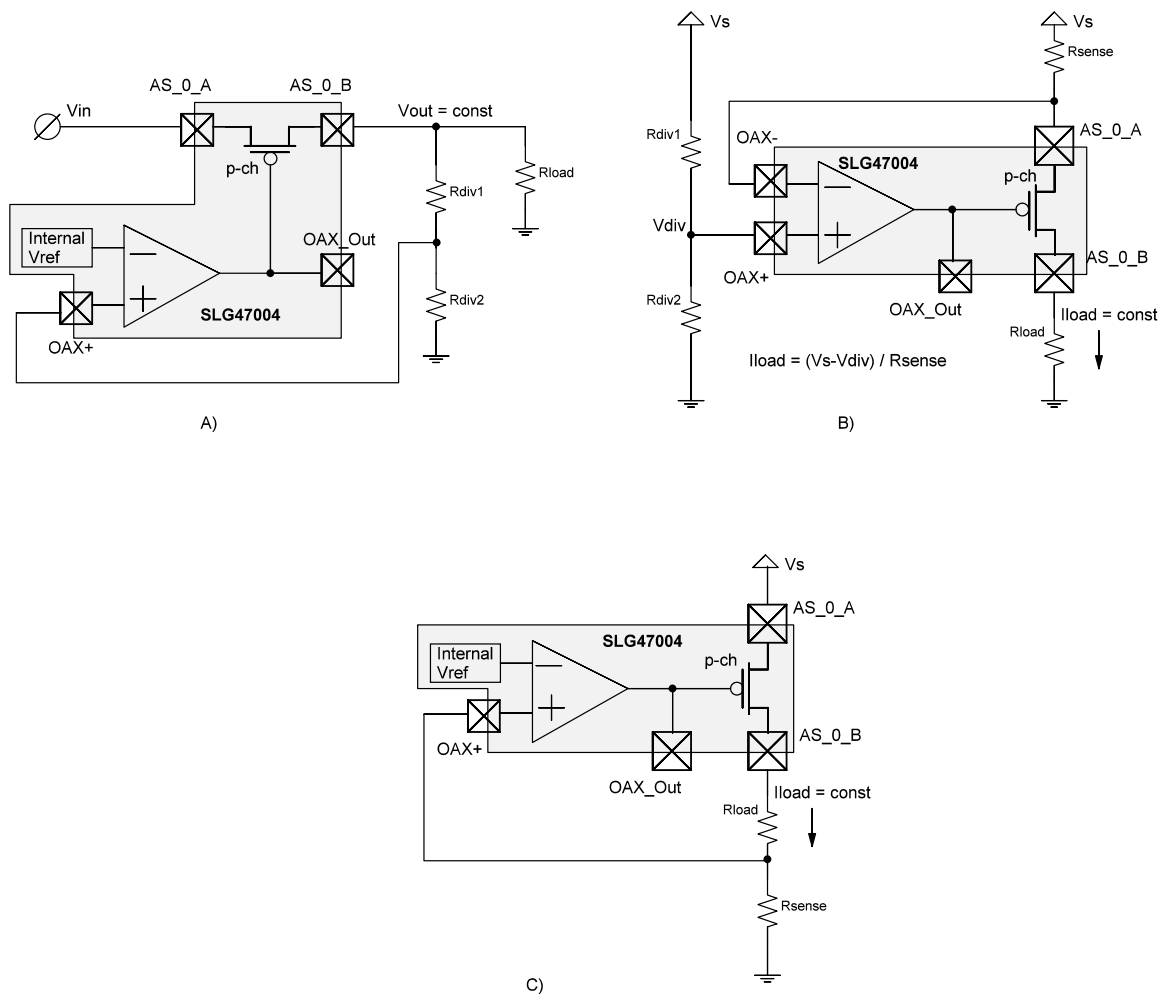


Figure 66: Typical Implementation of Voltage Regulator (A) and Current Sources (B, C)

Note that in this mode only an enhanced P channel FET of An_Sw_0 is used.

10.2.5 Current Sink Mode

Also, the op amp output can drive the N-FET (part of the Analog Switch) in order to implement a constant current sink. Note that FETs of Analog Switches have different resistances. Analog Switch 0 has $R_{ds_PMOS} \ll R_{ds_NMOS}$, while Analog Switch 1 has $R_{ds_NMOS} \ll R_{ds_PMOS}$. That's why it is recommended to implement current sink mode using Analog Switch 1. In this mode, the op amp output is LOW when the macrocell is turned off. Figure 67 (A) shows a typical implementation of this Current Sink Function. Note that op amp must operate in operational amplifier mode (register 750 = 0 for Op Amp0, register 751 = 0 for Op Amp1).

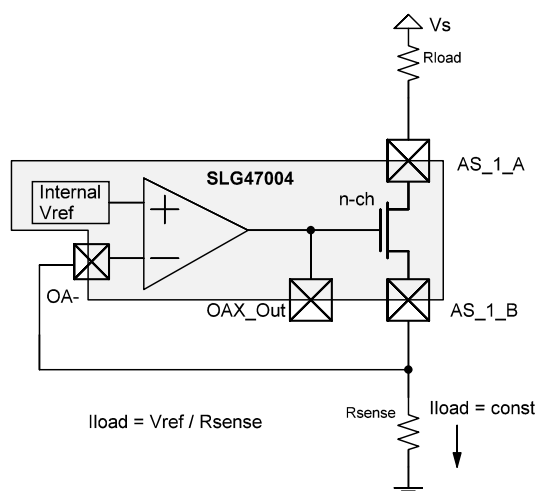
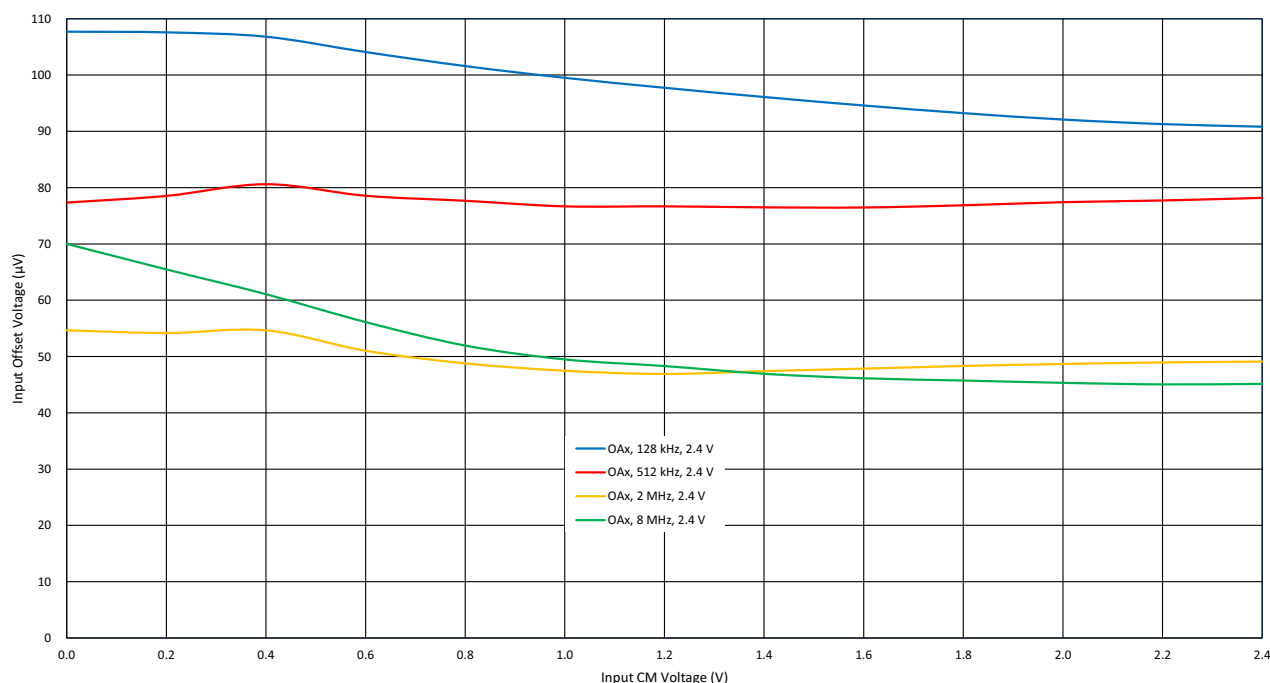


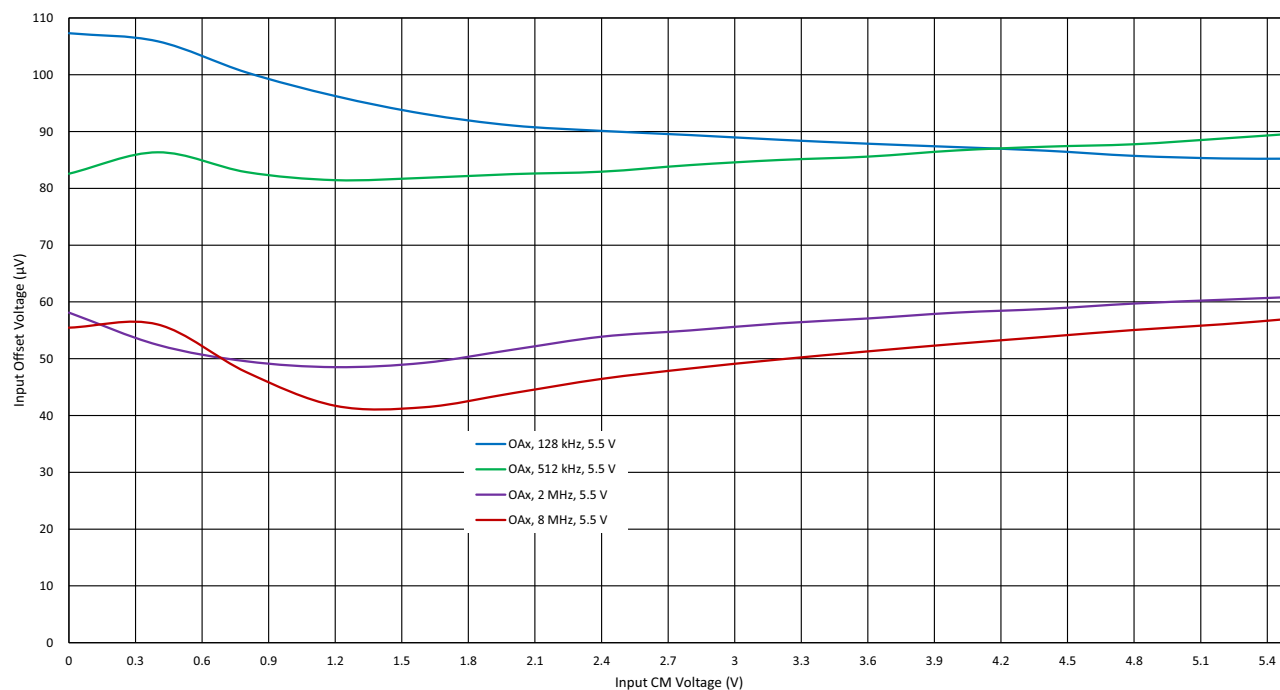
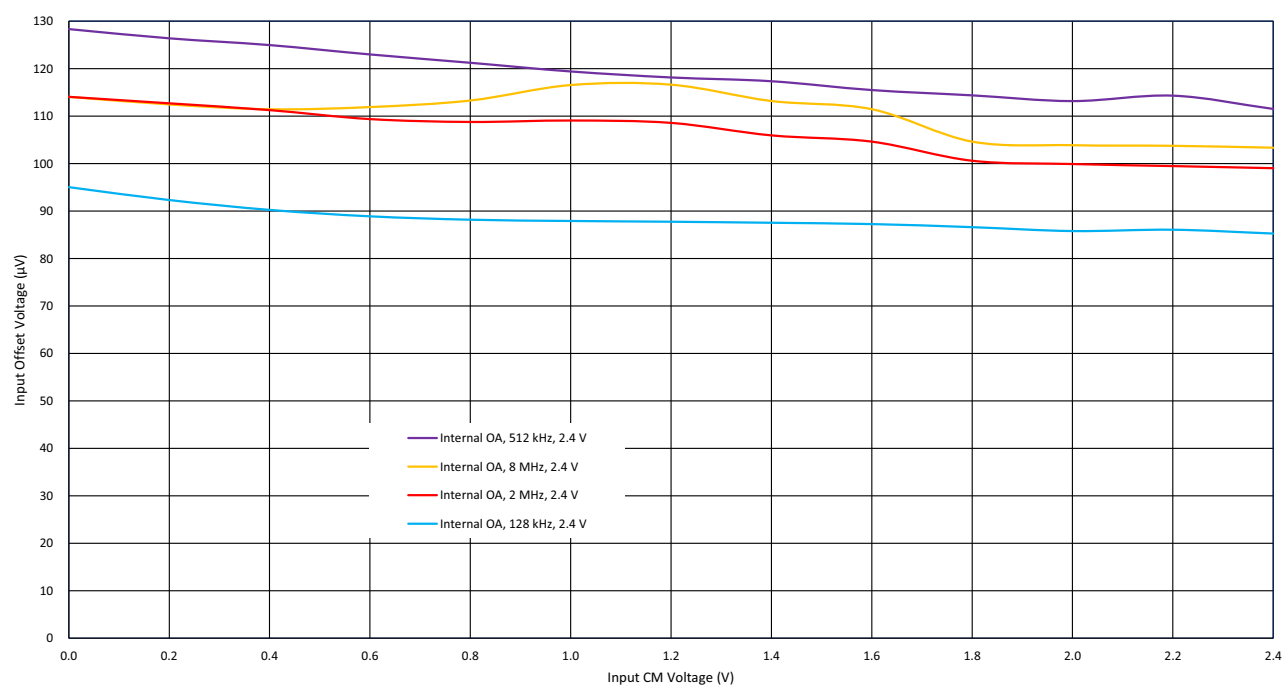
Figure 67: Constant Current Sink

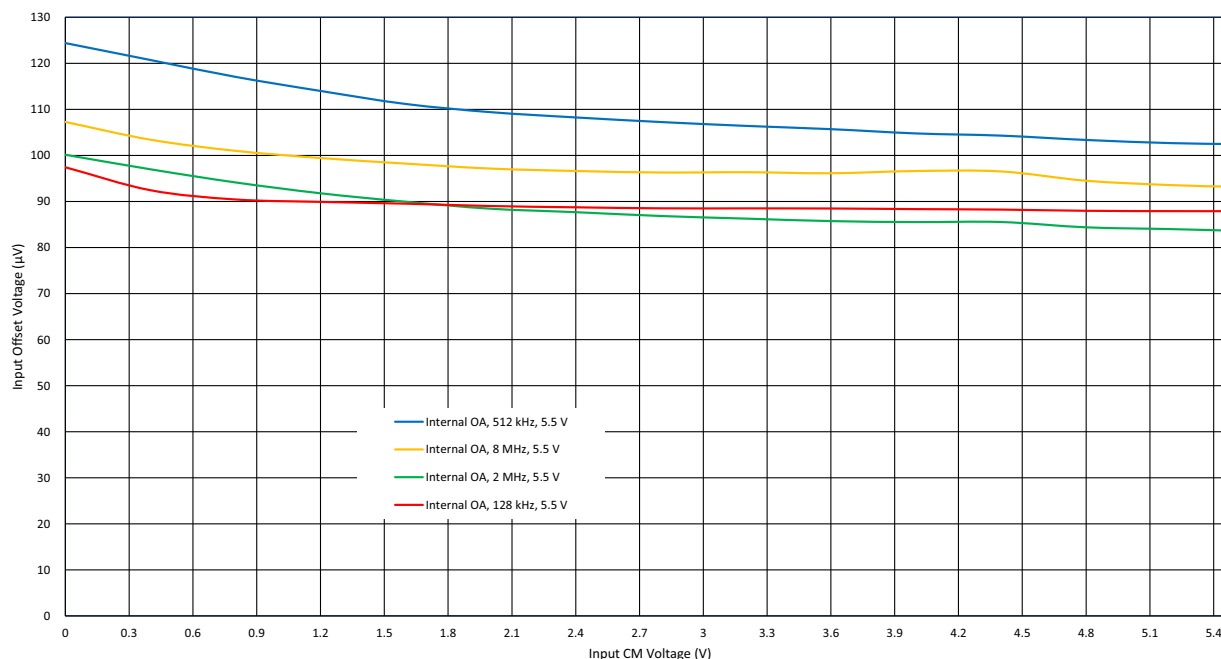
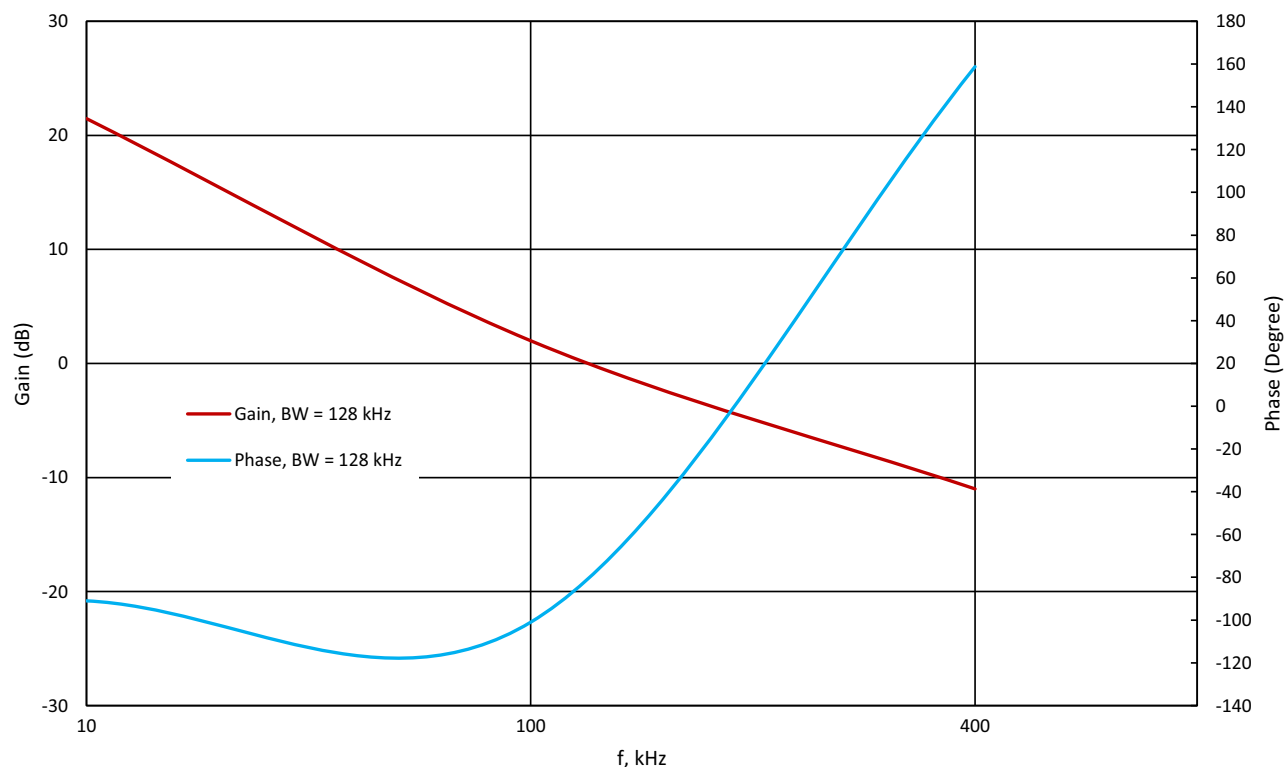
Note that in this mode only an enhanced N channel FET of An_Sw_1 is used.

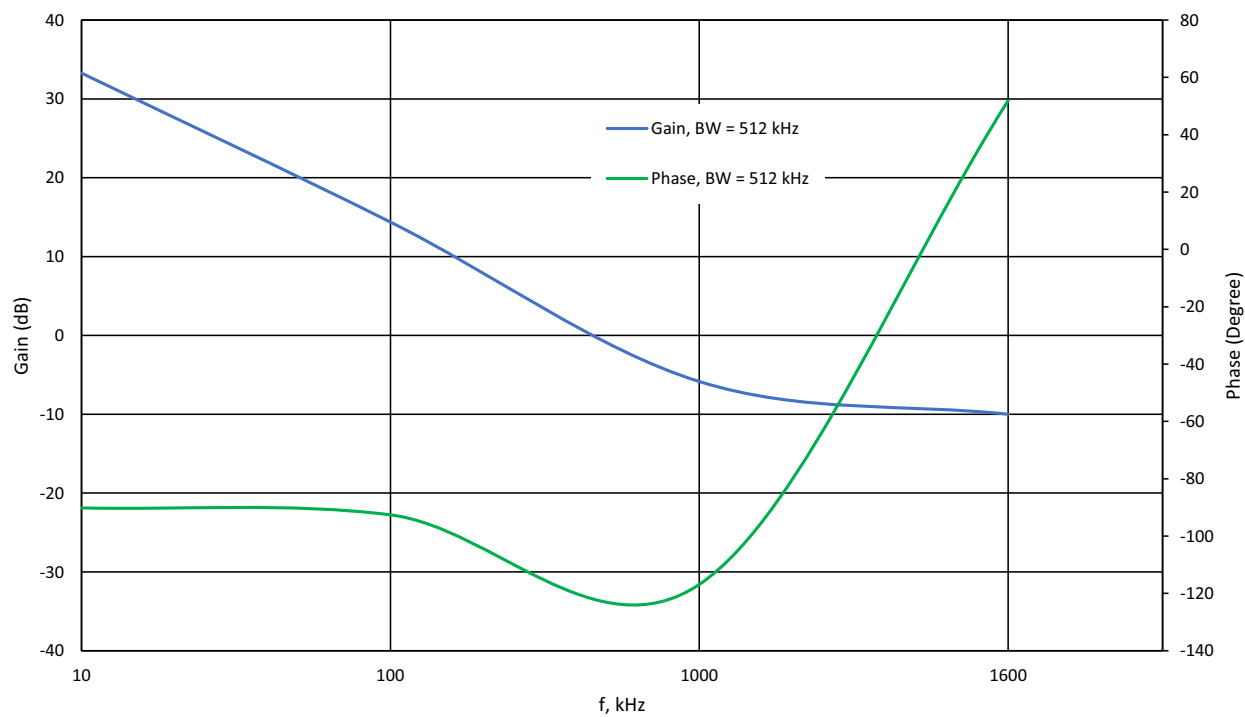
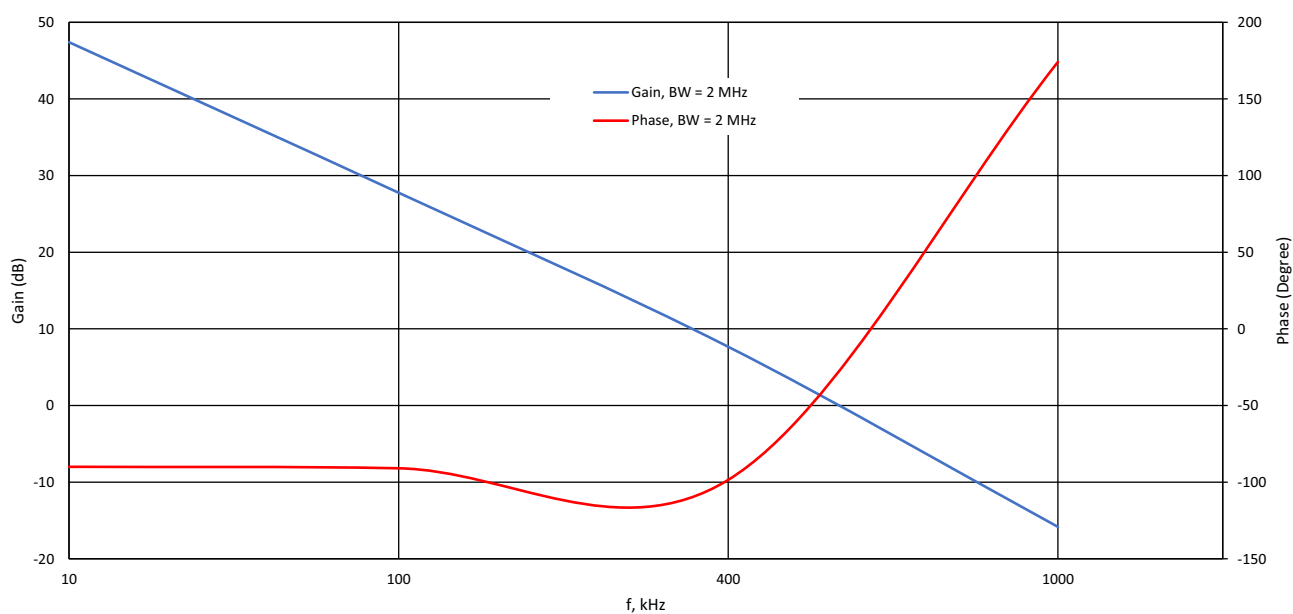
10.3 OP AMP TYPICAL PERFORMANCE

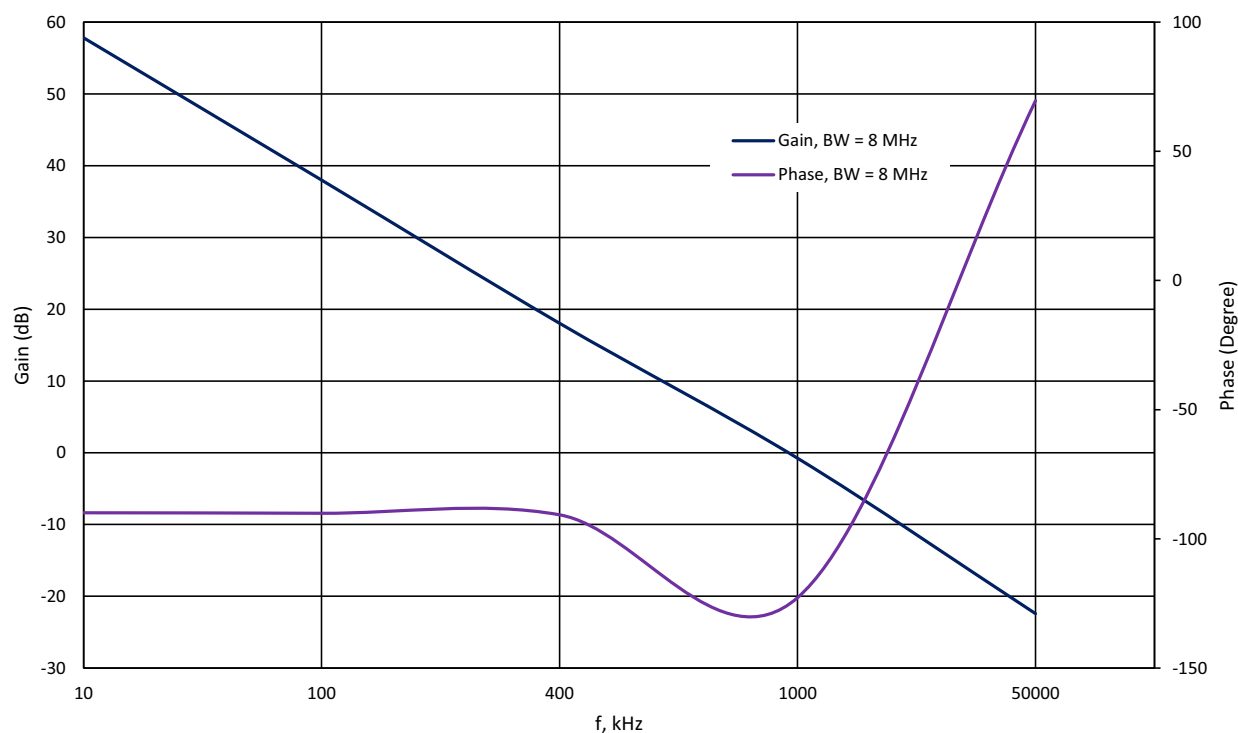
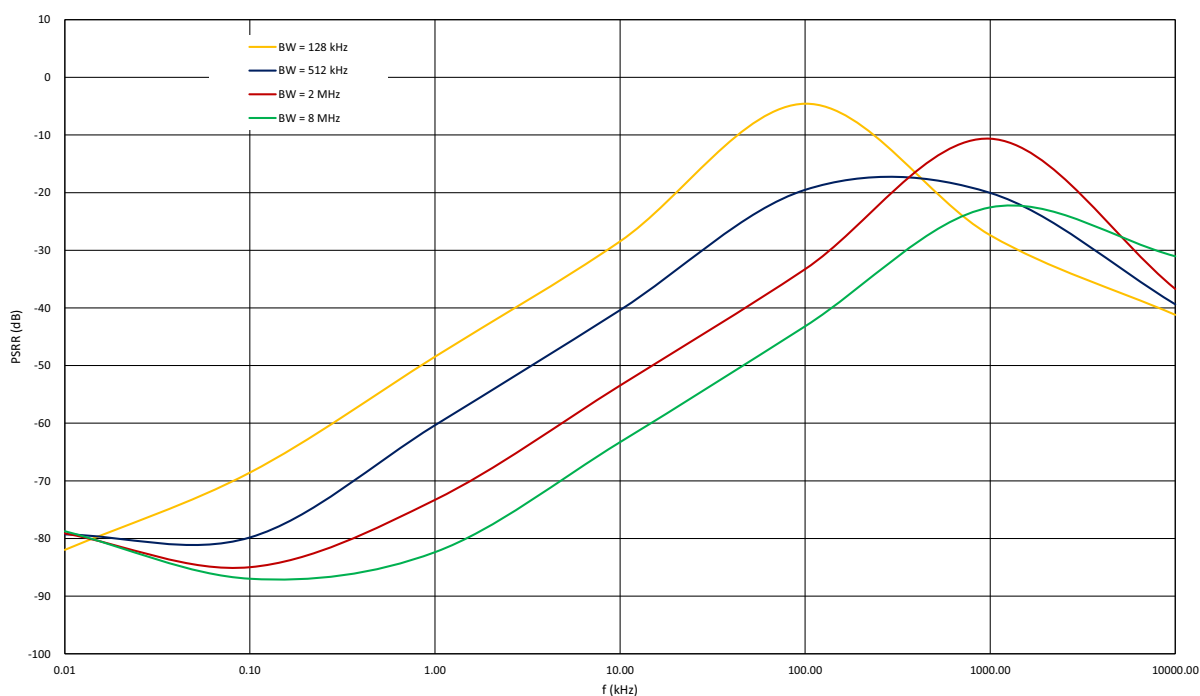
$T_A = 25^\circ\text{C}$, $V_{DDA} = 5.0\text{ V}$, $V_{SS} = \text{GND}$, $V_{CM} = V_{DD}/2$, $V_{OUT} = V_{DD}/2$, $V_L = V_{DD}/2$, $R_L = 1\text{ M}\Omega$ to V_L , $C_L = 80\text{ pF}$, unless otherwise stated.

Figure 68: OpAmp0, 1 Input Offset Voltage vs. Input CM Voltage at $T = 25^\circ\text{C}$, $V_{DDA} = 2.4\text{ V}$


 Figure 69: OpAmp0, 1 Input Offset Voltage vs. Input CM Voltage at $T = 25\text{ }^{\circ}\text{C}$, $V_{DDA} = 5.5\text{ V}$

 Figure 70: Internal OpAmp Input Offset Voltage vs. Input CM Voltage at $T = 25\text{ }^{\circ}\text{C}$, $V_{DDA} = 2.4\text{ V}$


 Figure 71: Internal OpAmp Input Offset Voltage vs. Input CM Voltage at $T = 25\text{ }^{\circ}\text{C}$, $V_{DDA} = 5.5\text{ V}$

 Figure 72: Open Loop Gain and Phase vs. Frequency $V_{DD} = 3.3\text{ V}$ for $BW = 128\text{ kHz}$


Figure 73: Open Loop Gain and Phase vs. Frequency $V_{DD} = 3.3$ V for BW = 512 kHz

Figure 74: Open Loop Gain and Phase vs. Frequency $V_{DD} = 3.3$ V for BW = 2 MHz


 Figure 75: Open Loop Gain and Phase vs. Frequency $V_{DD} = 3.3\text{ V}$ for BW = 8 MHz

 Figure 76: PSRR vs. Frequency $V_{DD} = 2.4\text{ V to }5.5\text{ V}$

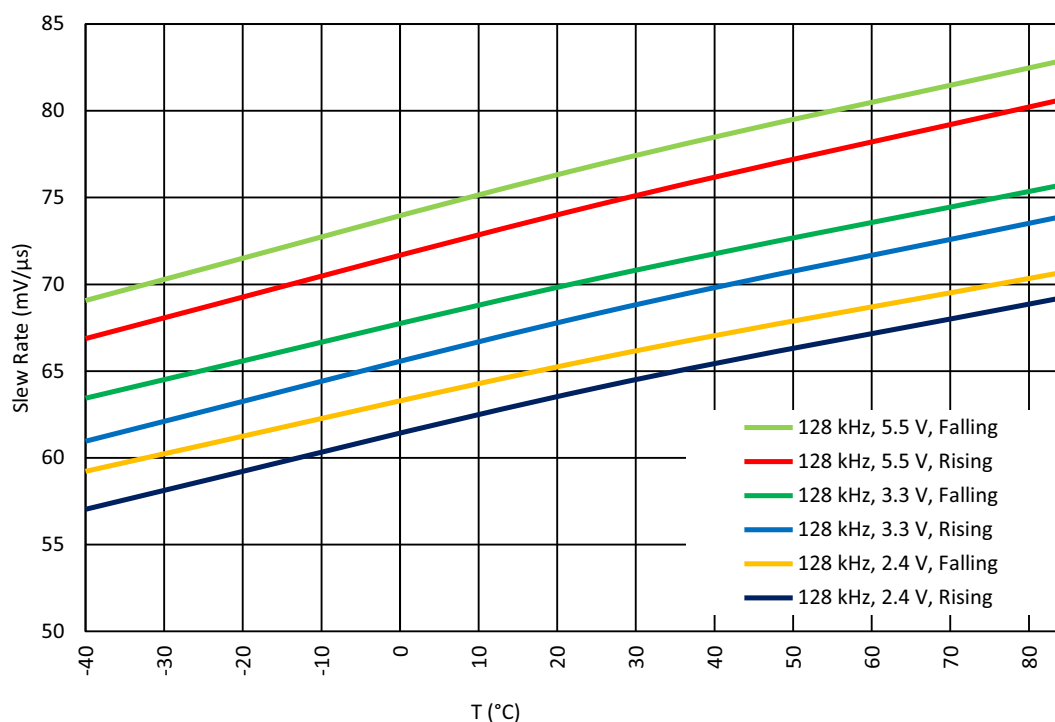


Figure 77: Slew Rate vs. Ambient Temperature $G = 1 \text{ V/V}$; $R_L = 50 \text{ k}\Omega$ for $BW = 128 \text{ kHz}$

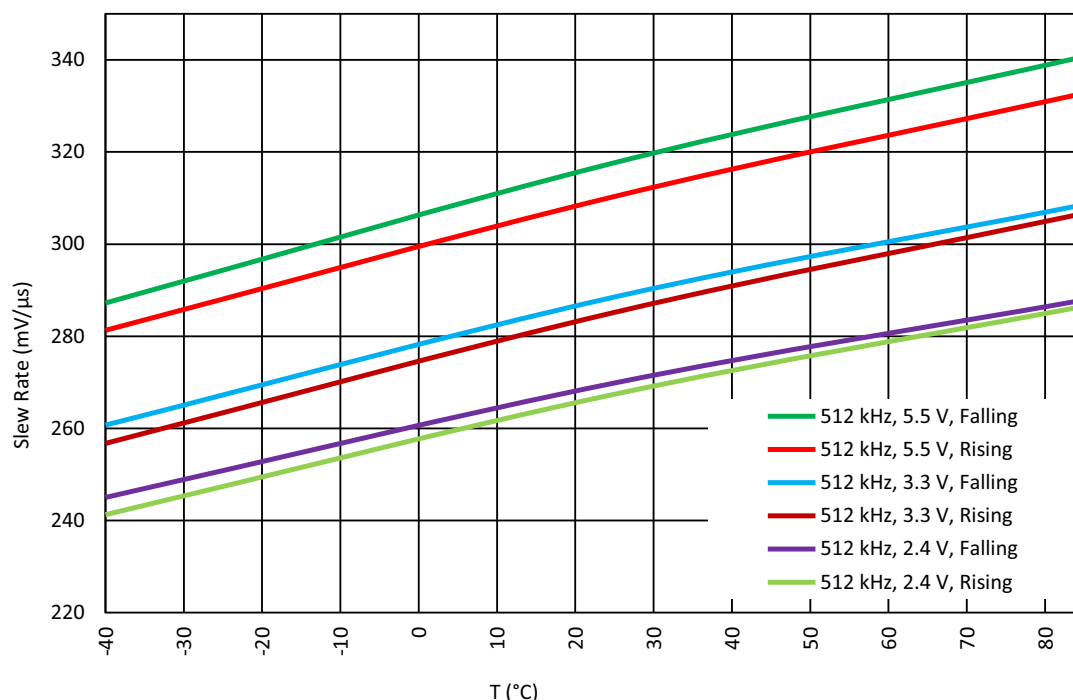


Figure 78: Slew Rate vs. Ambient Temperature $G = 1 \text{ V/V}$; $R_L = 50 \text{ k}\Omega$ for $BW = 512 \text{ kHz}$

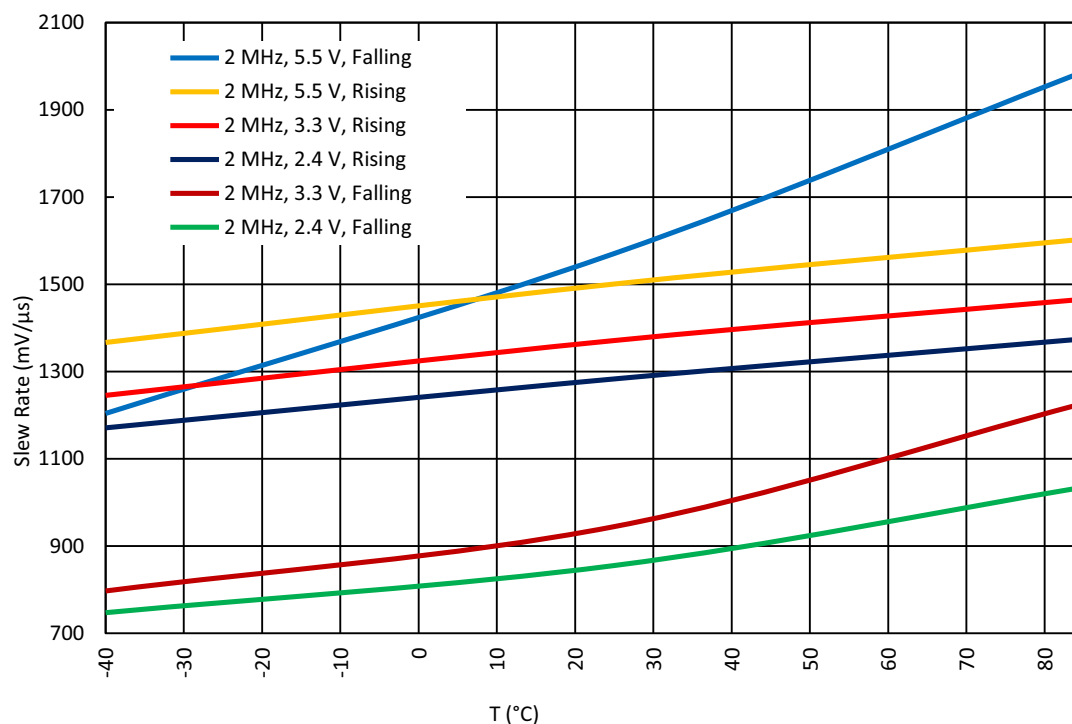


Figure 79: Slew Rate vs. Ambient Temperature $G = 1 \text{ V/V}$; $R_L = 50 \text{ k}\Omega$ for $BW = 2 \text{ MHz}$

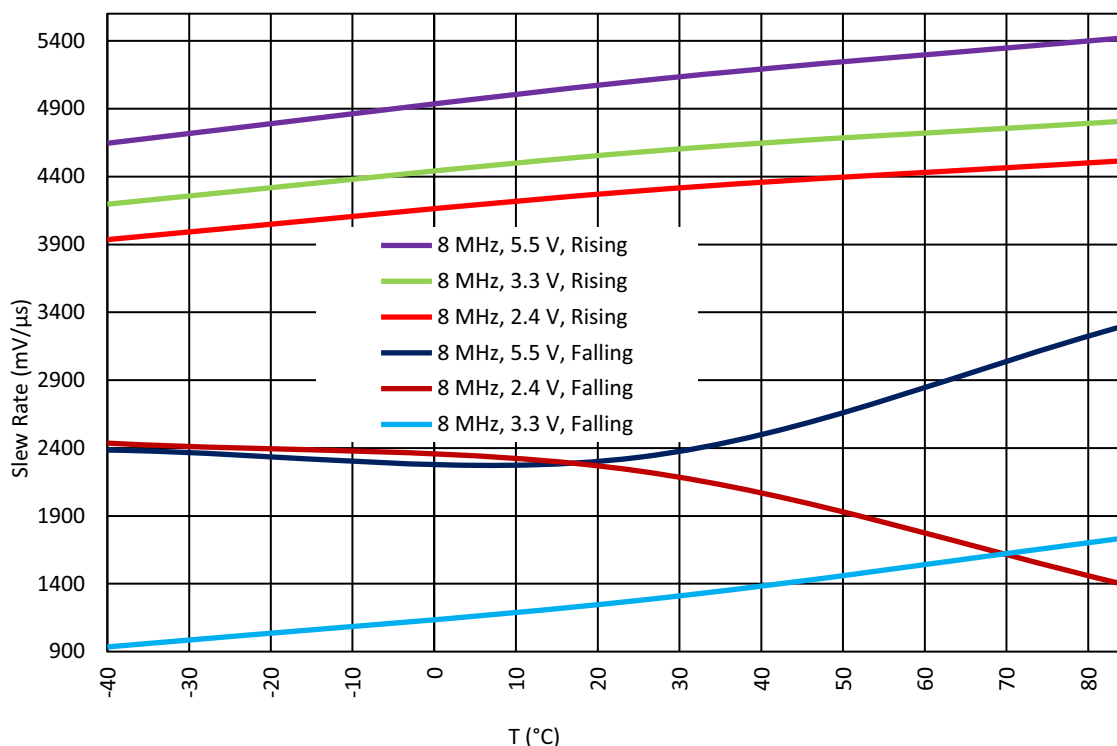


Figure 80: Slew Rate vs. Ambient Temperature $G = 1 \text{ V/V}$; $R_L = 50 \text{ k}\Omega$ for $BW = 8 \text{ MHz}$

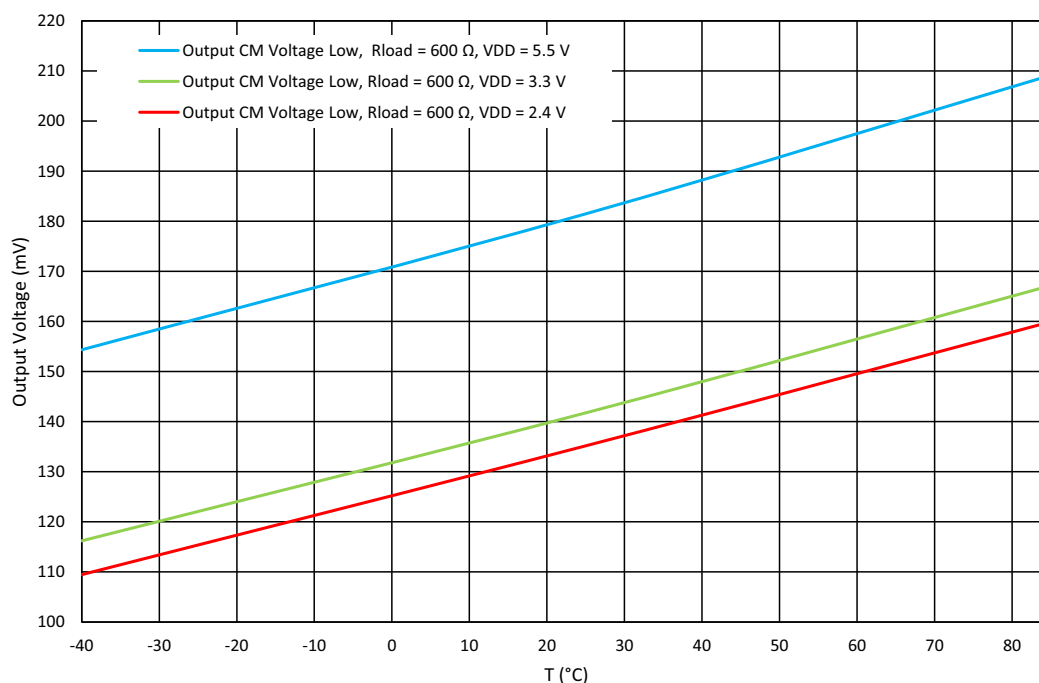


Figure 81: Output Voltage Low ($V_{OUT} - GND$) vs. Temperature at BW = 128 kHz, $R_{LOAD} = 600 \Omega$

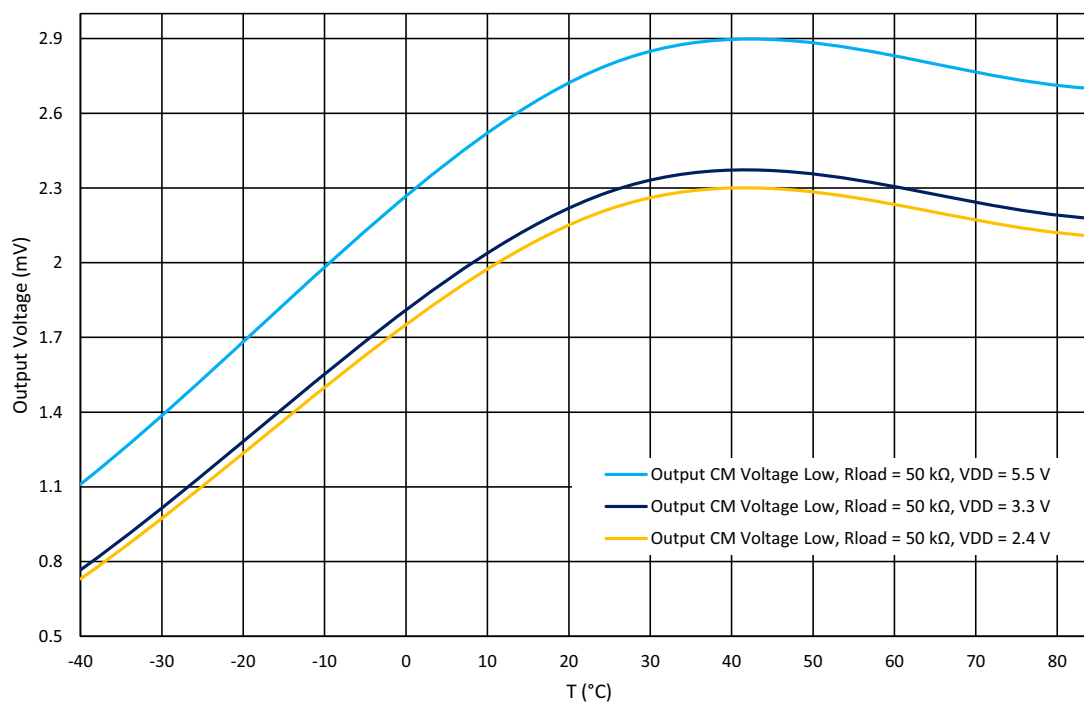


Figure 82: Output Voltage Low ($V_{OUT} - GND$) vs. Temperature at BW = 128 kHz, $R_{LOAD} = 50 k\Omega$

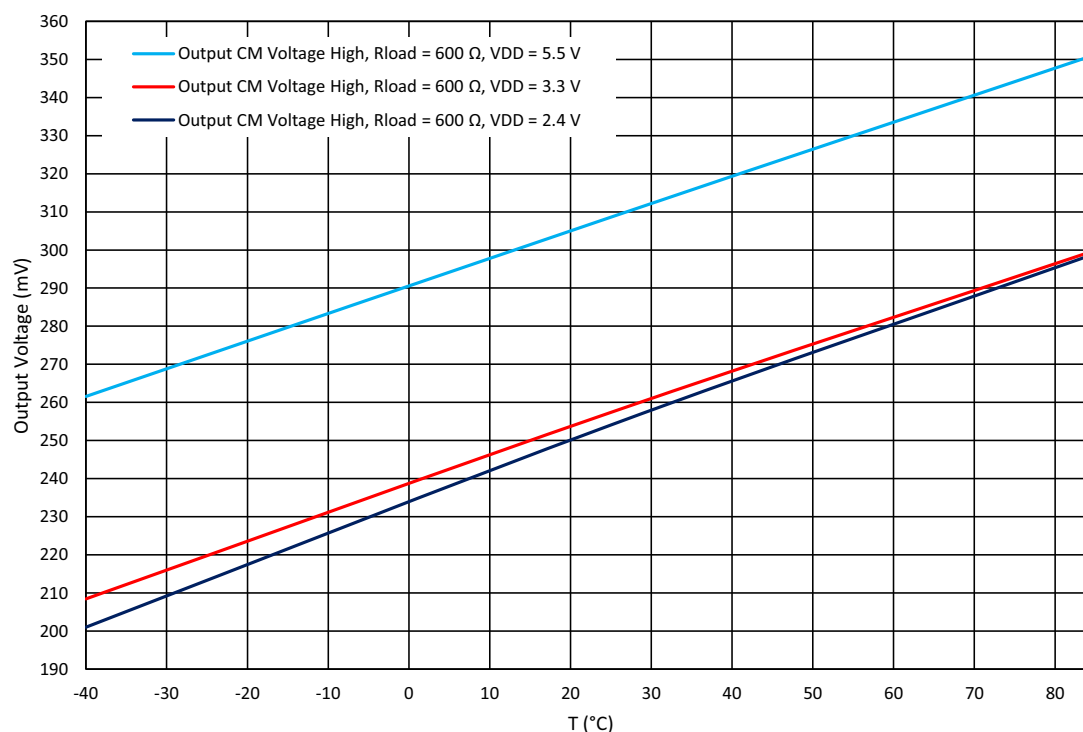


Figure 83: Output Voltage High ($V_{DDA} - V_{OUT}$) vs. Temperature at BW = 128 kHz, $R_{LOAD} = 600 \Omega$

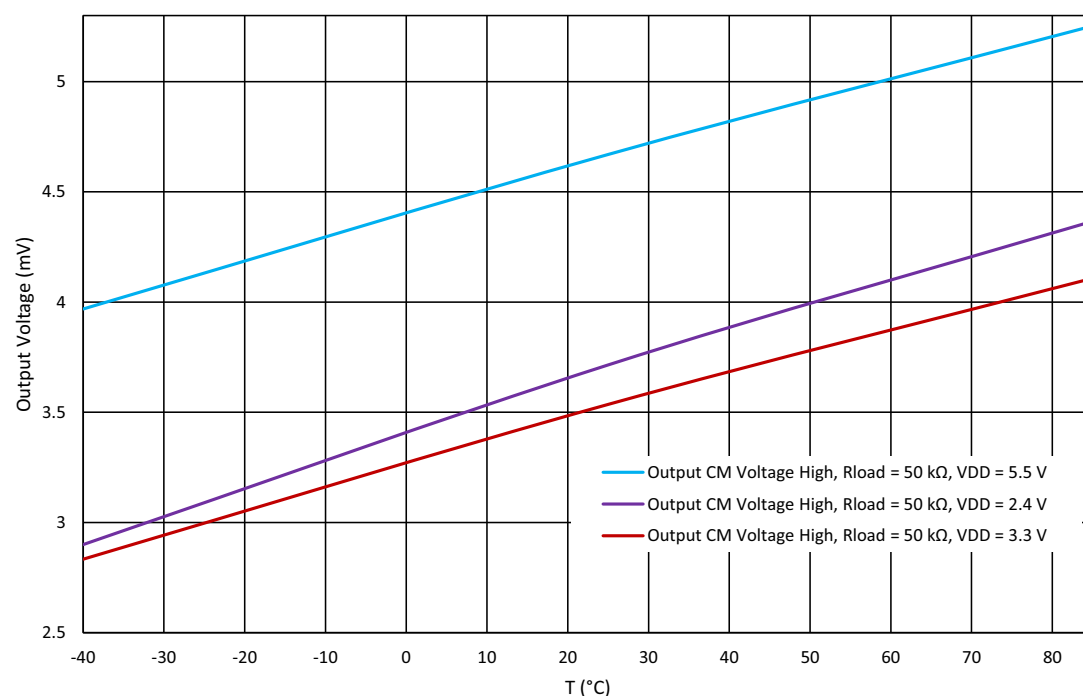
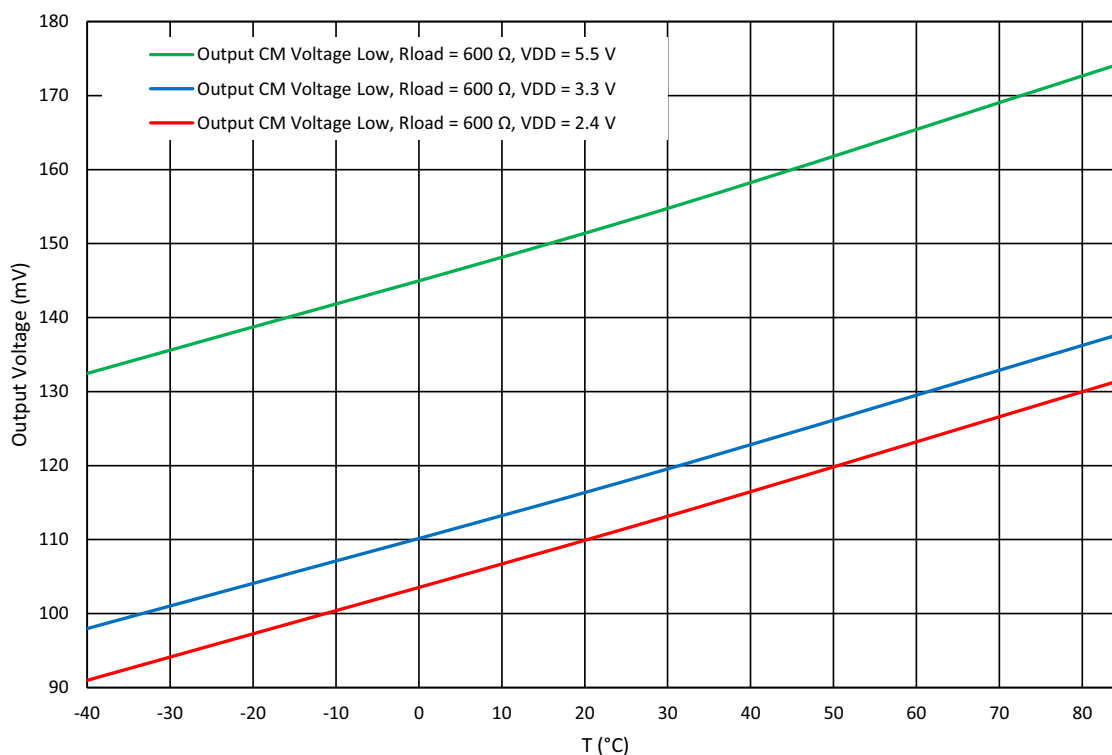
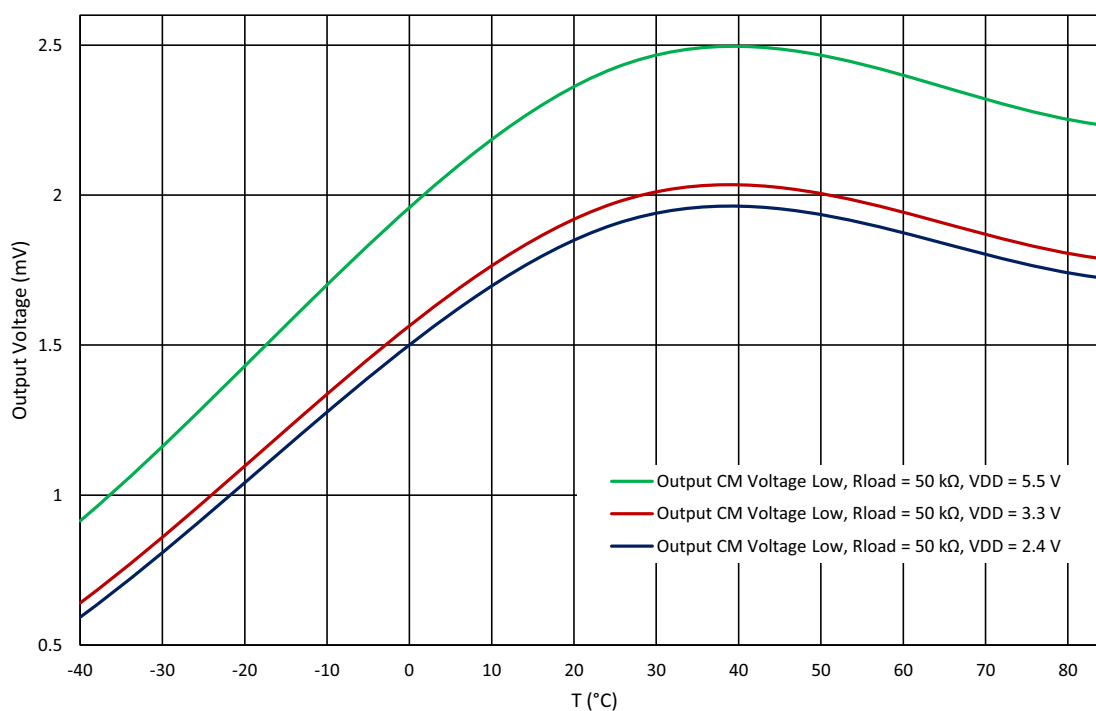


Figure 84: Output Voltage High ($V_{DDA} - V_{OUT}$) vs. Temperature at BW = 128 kHz, $R_{LOAD} = 50 k\Omega$


 Figure 85: Output Voltage Low ($V_{OUT} - GND$) vs. Temperature at BW = 512 kHz, $R_{LOAD} = 50\text{ k}\Omega$

 Figure 86: Output Voltage Low ($V_{OUT} - GND$) vs. Temperature at BW = 512 kHz, $R_{LOAD} = 50\text{ k}\Omega$

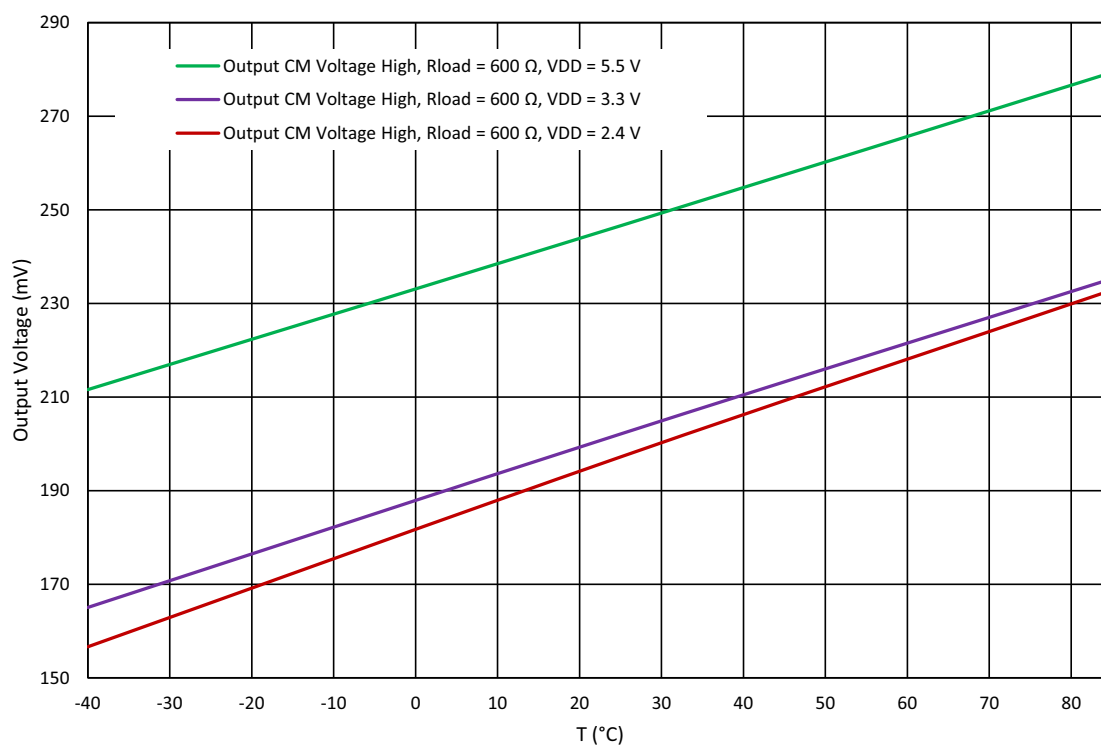


Figure 87: Output Voltage High ($V_{DDA} - V_{OUT}$) vs. Temperature at BW = 512 kHz, $R_{LOAD} = 600 \Omega$

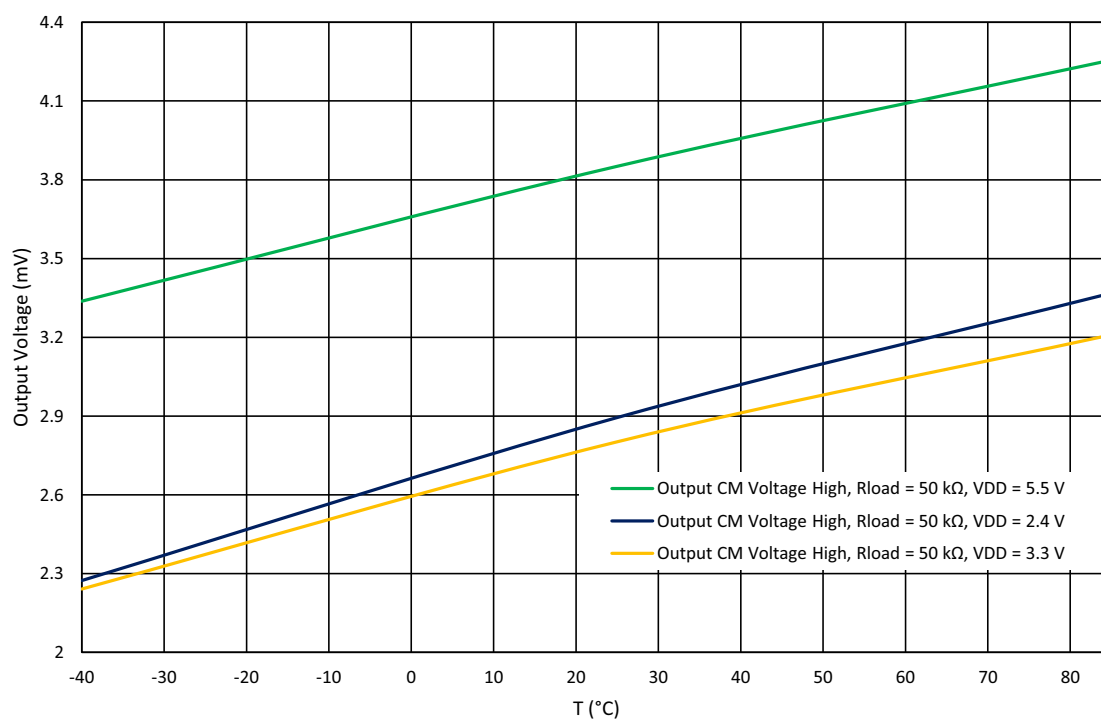


Figure 88: Output Voltage High ($V_{DDA} - V_{OUT}$) vs. Temperature at BW = 512kHz, $R_{LOAD} = 50 k\Omega$

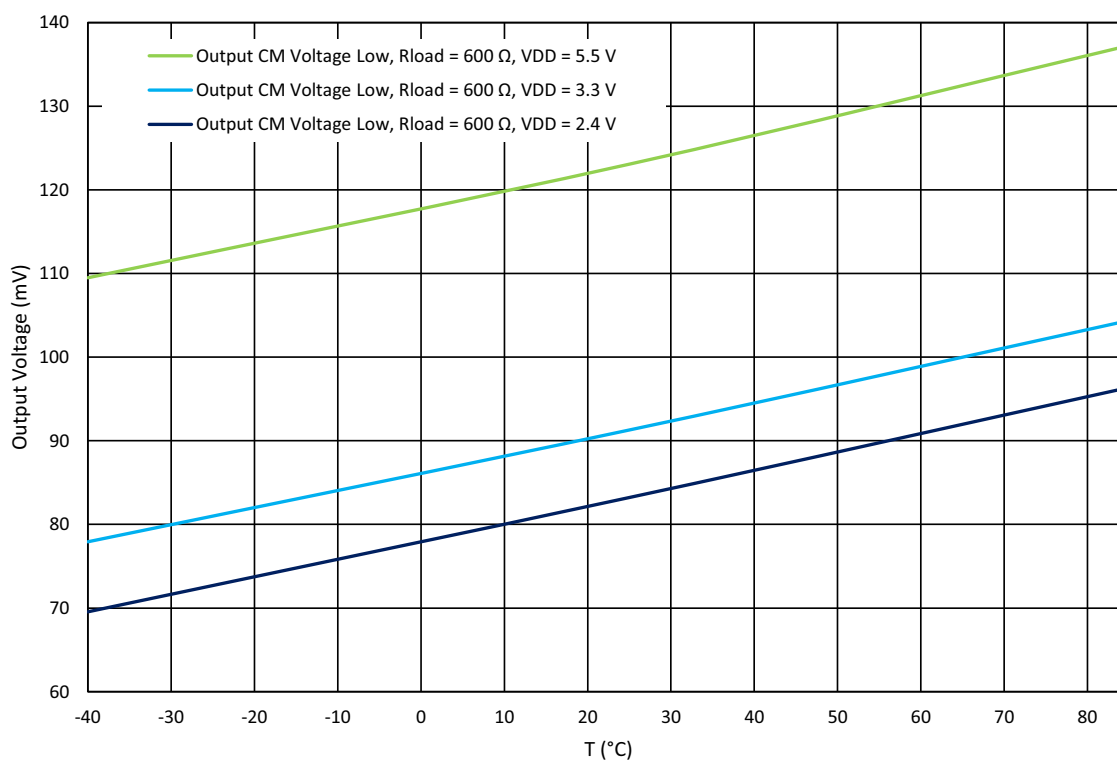


Figure 89: Output Voltage Low ($V_{OUT} - GND$) vs. Temperature at BW = 2 MHz, $R_{LOAD} = 600 \Omega$

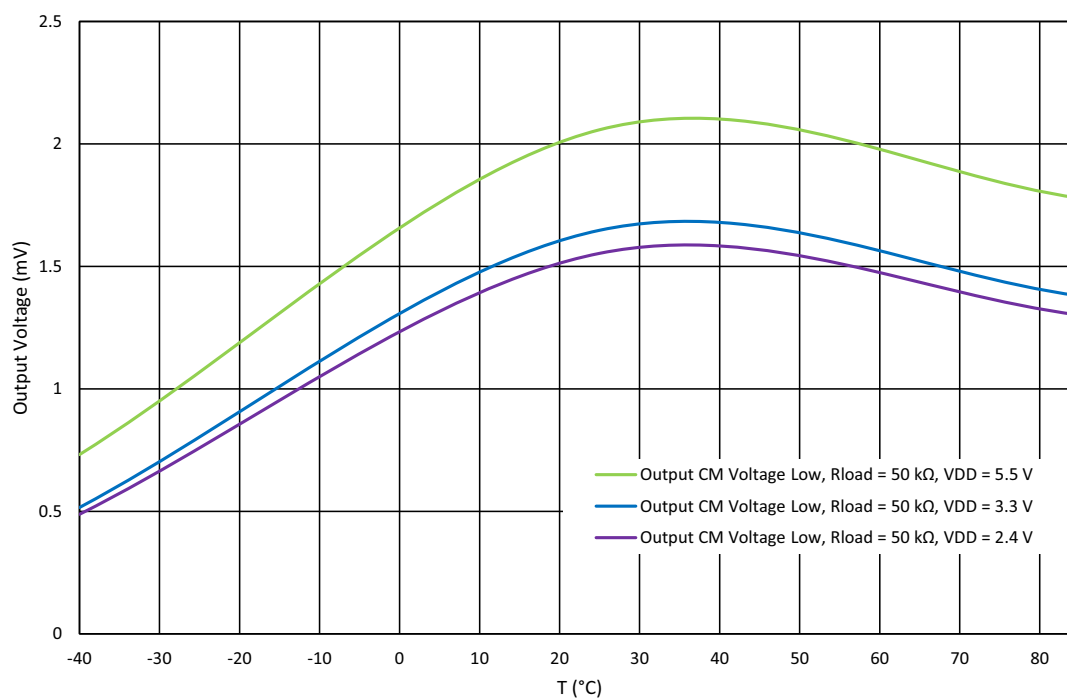


Figure 90: Output Voltage Low ($V_{OUT} - GND$) vs. Temperature at BW = 2 MHz, $R_{LOAD} = 50 k\Omega$

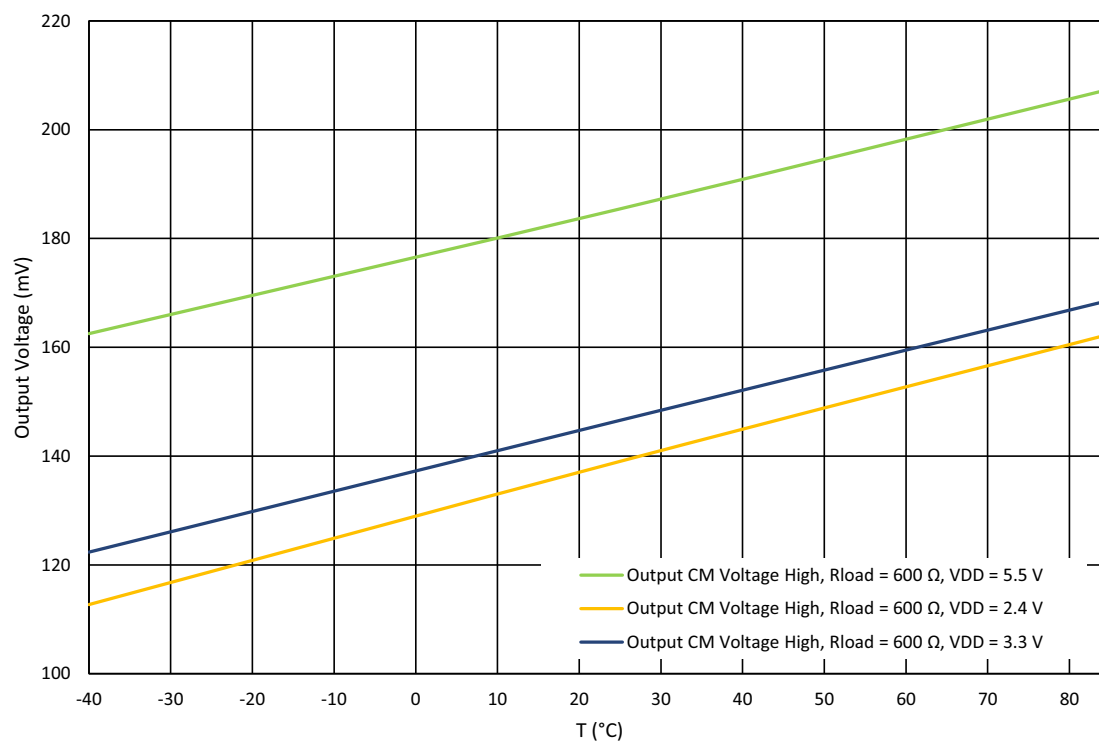


Figure 91: Output Voltage High ($V_{DDA} - V_{OUT}$) vs. Temperature at BW = 2 MHz, $R_{LOAD} = 600 \Omega$

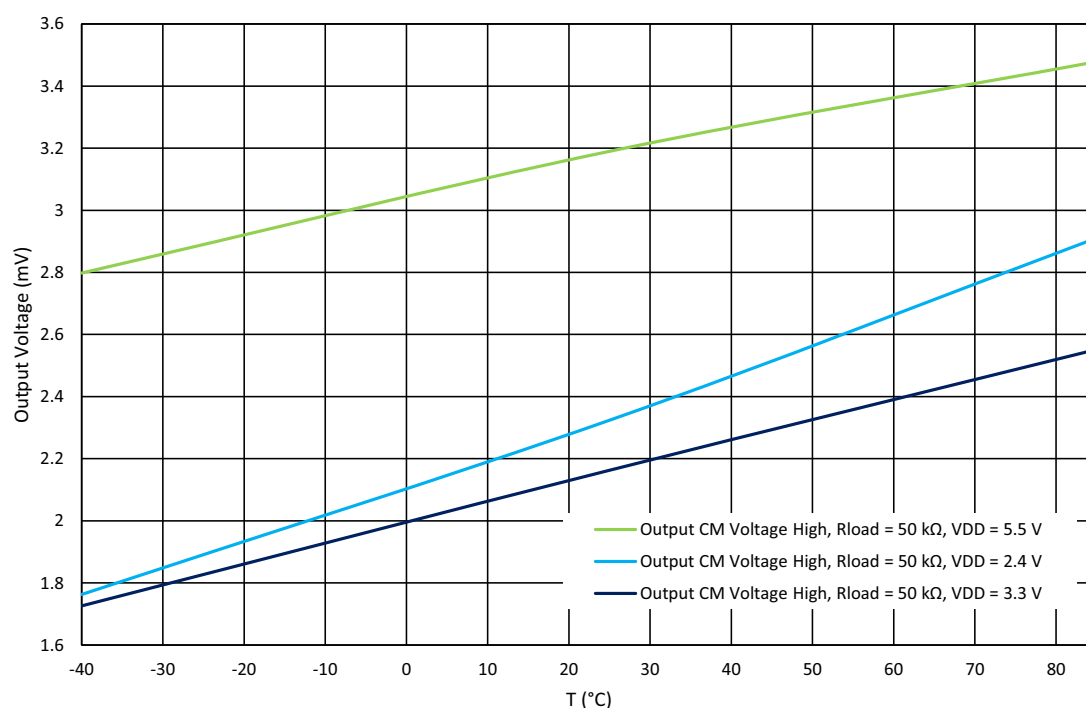


Figure 92: Output Voltage High ($V_{DDA} - V_{OUT}$) vs. Temperature at BW = 2 MHz, $R_{LOAD} = 50 k\Omega$

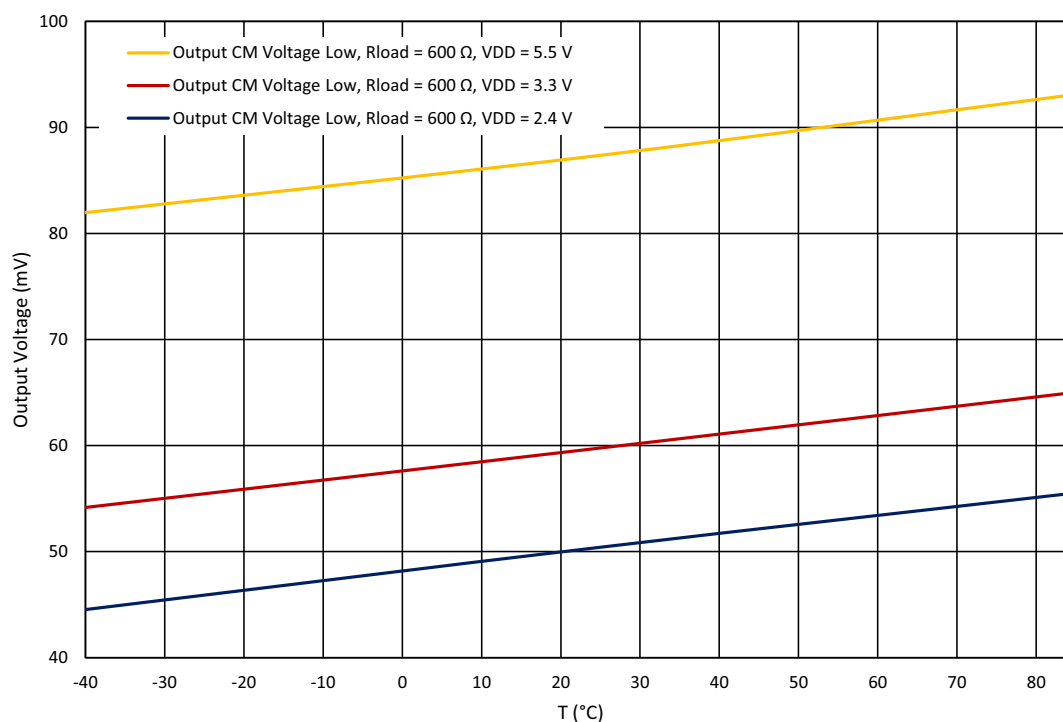


Figure 93: Output Voltage Low ($V_{OUT} - GND$) vs. Temperature at $BW = 8MHz$, $R_{LOAD} = 600 \Omega$

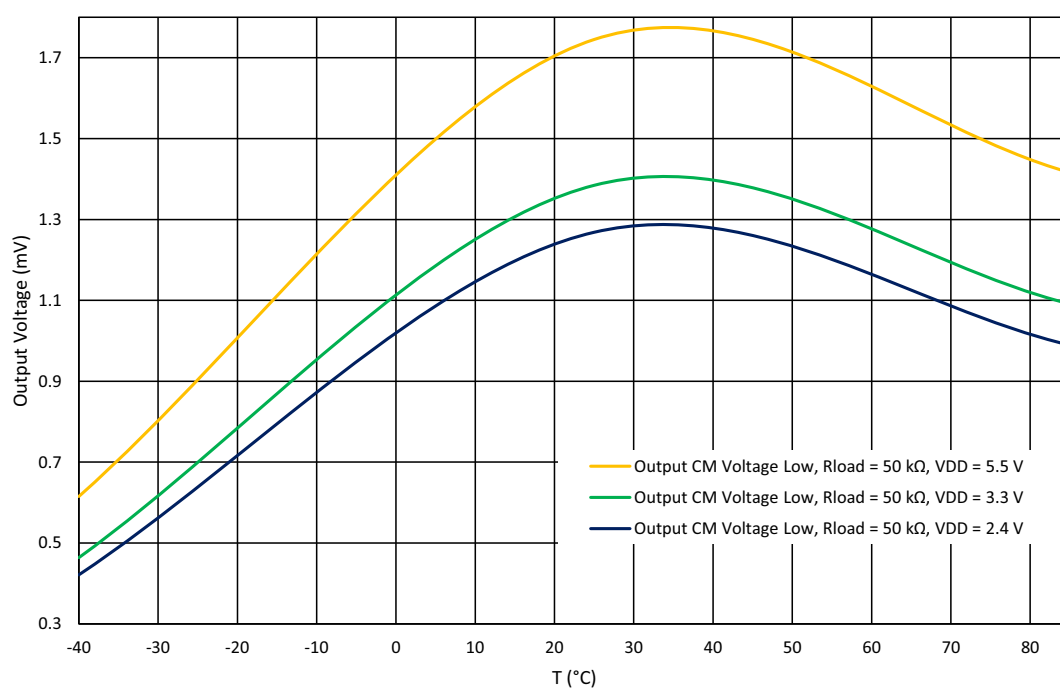
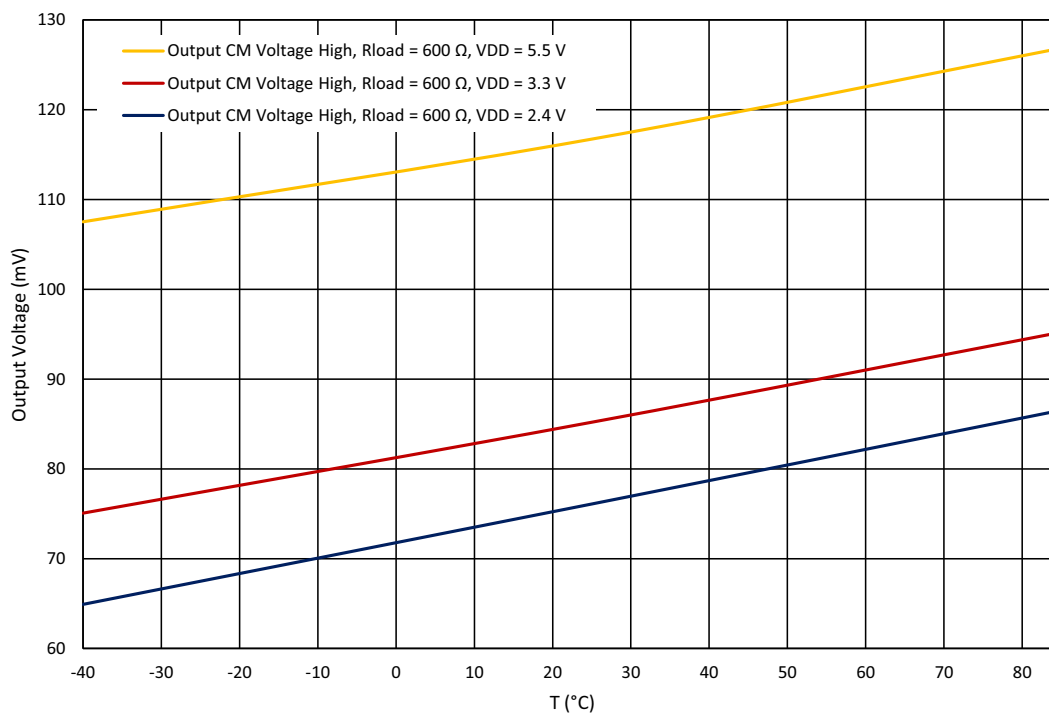
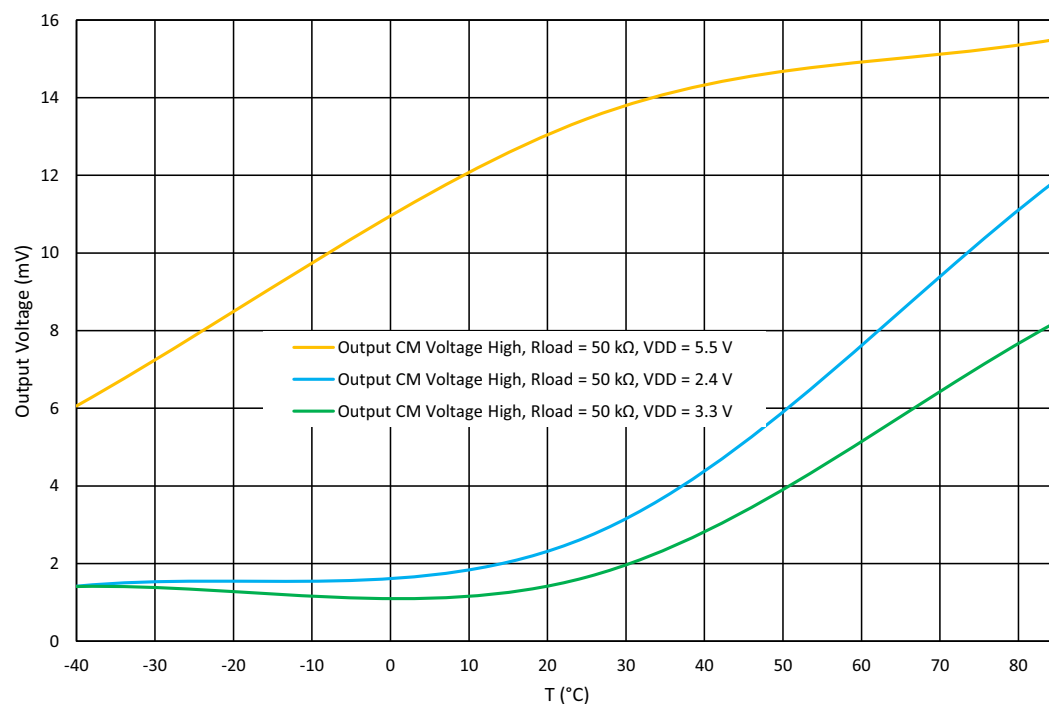
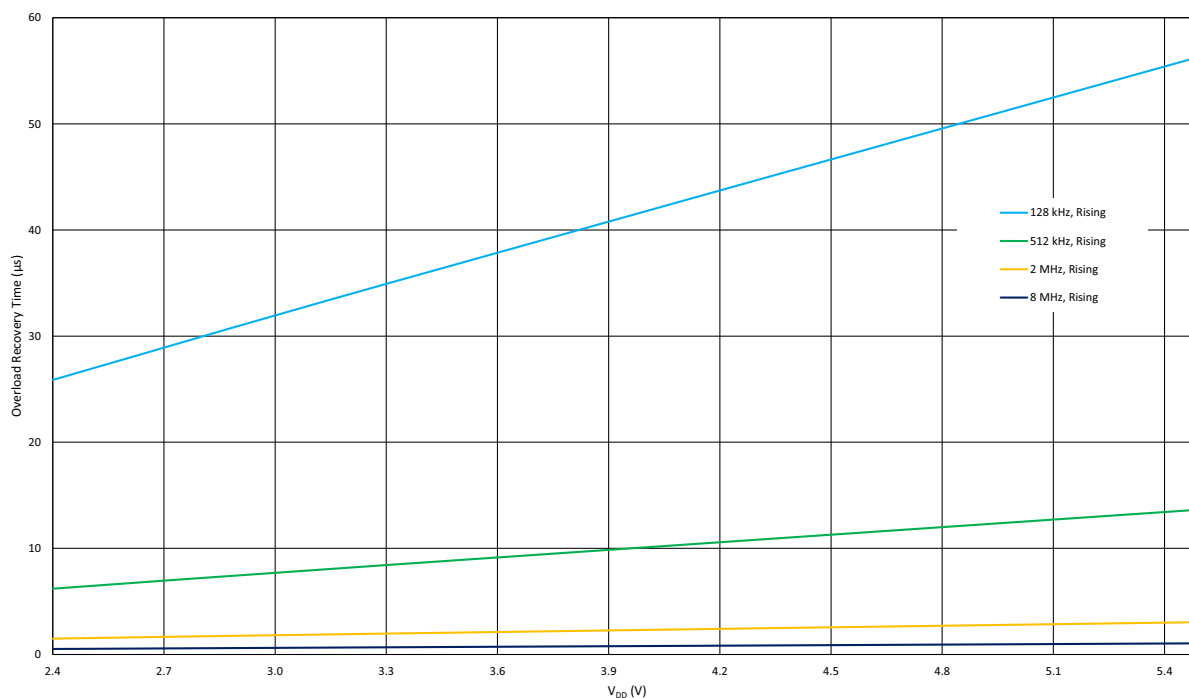
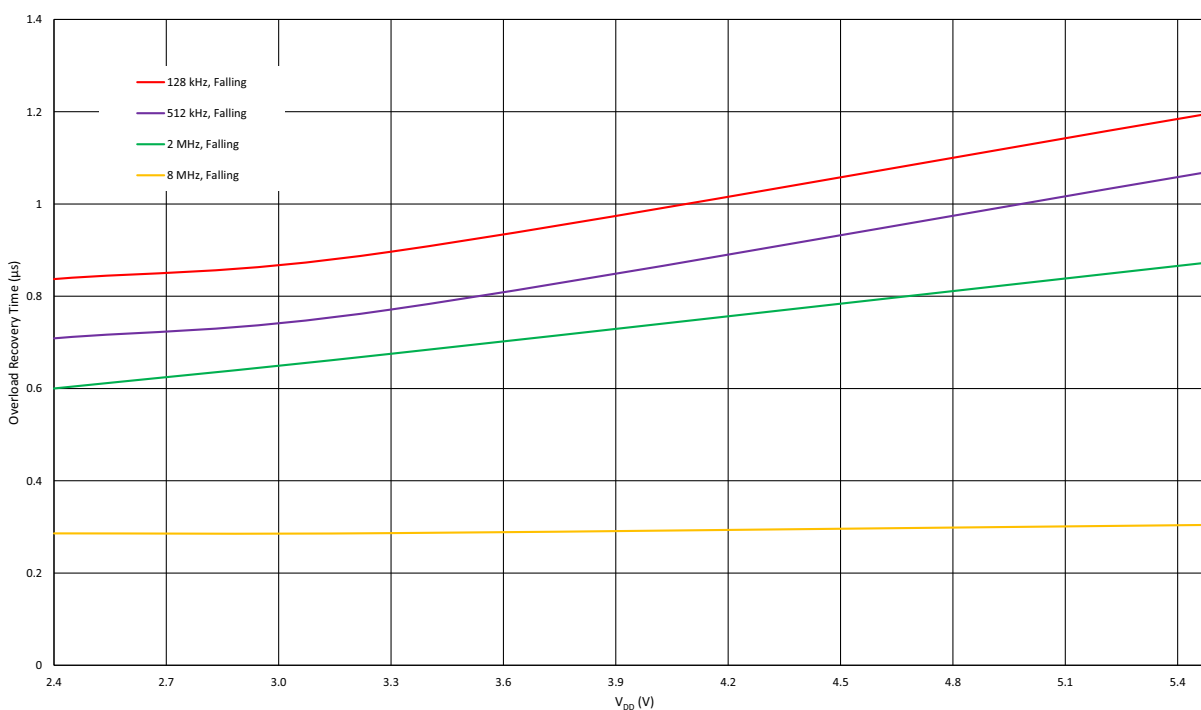


Figure 94: Output Voltage Low ($V_{OUT} - GND$) vs. Temperature at $BW = 8 MHz$, $R_{LOAD} = 50 k\Omega$


 Figure 95: Output Voltage High ($V_{DDA} - V_{OUT}$) vs. Temperature at BW = 8 MHz, $R_{LOAD} = 600 \Omega$

 Figure 96: Output Voltage High ($V_{DDA} - V_{OUT}$) vs. Temperature at BW = 8 MHz, $R_{LOAD} = 50 \text{ k}\Omega$


 Figure 97: Overload Recovery Time vs. Power Supply Voltage $R_L = 50\text{ k}\Omega$; $G = 1\text{ V/V}$, Rising

 Figure 98: Overload Recovery Time vs. Power Supply Voltage $R_L = 50\text{ k}\Omega$; $G = 1\text{ V/V}$, Falling

11 Analog Switch Macrocell

11.1 ANALOG SWITCH GENERAL DESCRIPTION

The SLG47004 contains two single-pole/single throw (SPST) normally open analog switches (AS). The structure of the Analog Switches is shown in [Figure 99](#) and [Figure 100](#).

Each analog switch can be controlled from the following sources:

- Connection matrix
- Operational Amplifier macrocell.

Small NMOS (small PMOS) of Analog Switch must be enabled when macrocell is controlled by logic signal from connection matrix. Otherwise, small NMOS (small PMOS) must be disabled when macrocell is controlled by op amp.

[Table 55](#) and [Table 56](#) show possible operation modes of analog switches.

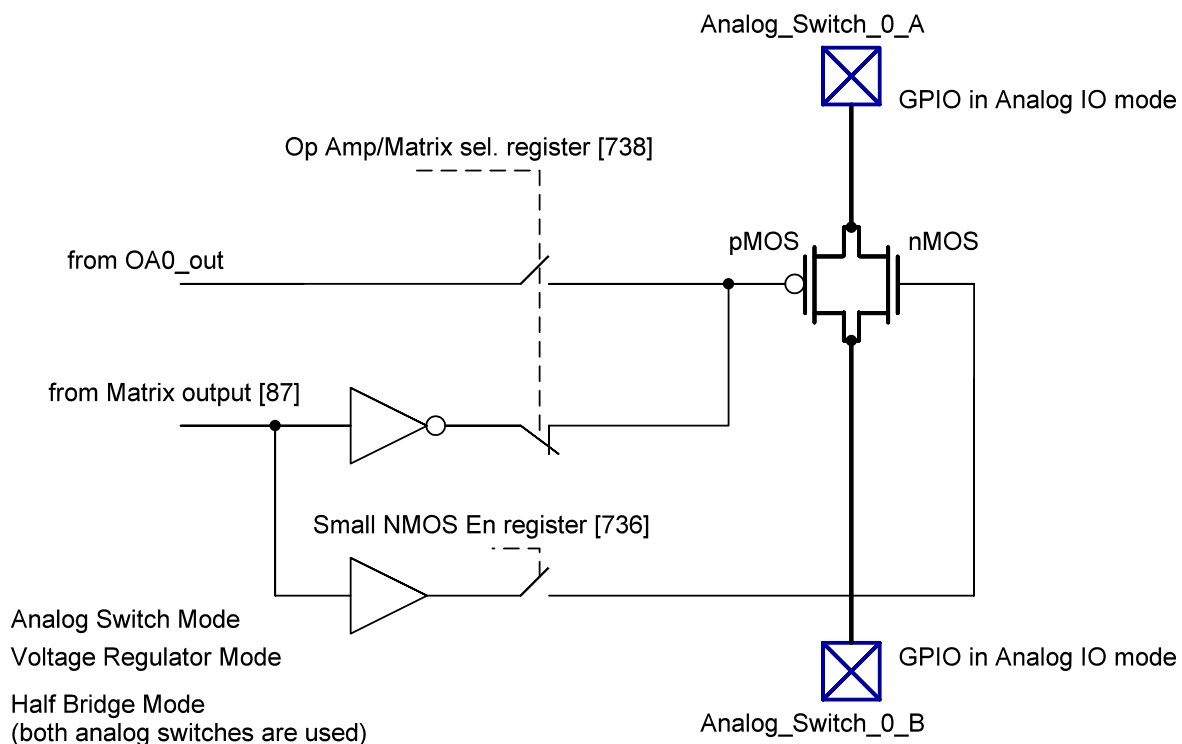


Figure 99: Analog Switch 0 Control Circuit

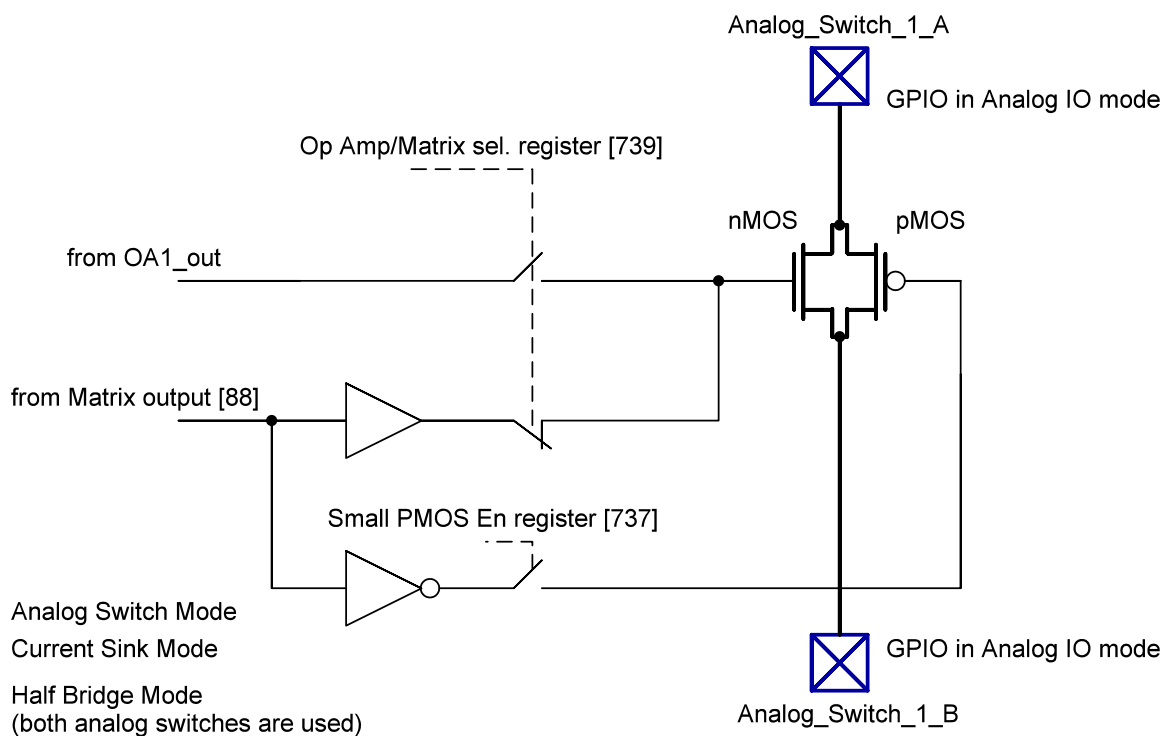


Figure 100: Analog Switch 1 Control Circuit

Table 55: Analog Switch 0 Modes of Operation

Mode of Operation	Half Bridge Mode Enable Register [740]	Matrix/Op Amp Control Register [738]	Small nMOS Enable Register [736]
Analog Switch mode with big pMOS only (control from connection matrix)	0	0	0
Analog Switch mode with all FETs enabled (control from connection matrix)	0	0	1
Voltage Regulator mode	0	1	0
Half Bridge mode with big pMOS only (control from connection matrix)	1	x	0
Half Bridge mode with all FETs enabled (control from connection matrix)	1	x	1

Table 56: Analog Switch 1 Modes of Operation

Mode of Operation	Half Bridge Mode Enable Register [740]	Matrix/Op Amp Control Register [739]	Small pMOS Enable Register [737]
Analog Switch mode with big nMOS only (control from connection matrix)	0	0	0
Analog Switch mode with all FETs enabled (control from connection matrix)	0	0	1
Current Sink mode	0	1	0
Half Bridge mode with big nMOS only (control from connection matrix)	1	x	0
Half Bridge mode with all FETs enabled (control from connection matrix)	1	x	1

11.2 HALF BRIDGE MODE

Two switches can be externally connected in series to create a half bridge. Please refer to tables [Table 55](#) and [Table 56](#) to enable half bridge mode. Additional logic will be connected to the analog switches to simplify control. [Figure 101](#) shows the half bridge structure with two analog switches.

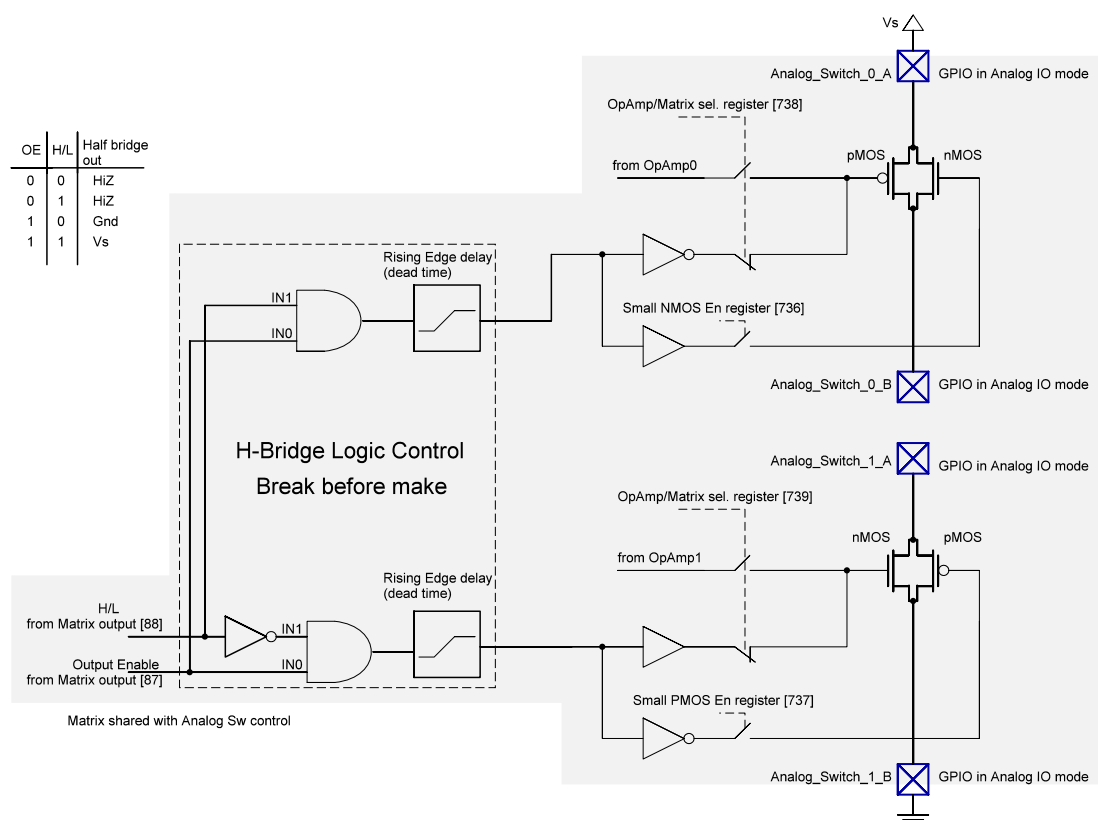


Figure 101: Structure of Half Bridge

12 Digital Rheostats and Programmable Trim Block

The SLG47004 contains two 10-bit Digital Rheostats. The structure of both macrocells is shown in [Figure 102](#). The range of digital code that corresponds to the rheostat resistance ranges from 0 to 1023 (1024 taps). Code 0 corresponds to the minimum resistance between the RHx_A and RHx_B terminals. As the code value increases, the resistance between the RHx_A and RHx_B terminals monotonically increases. Consequently, when the code value decreases, the resistance between the RH0_A and RH0_B terminals decreases as well (see [Section 12.2](#)). The voltage on any rheostat pin can be in the range from AGND to V_{DDA} , as well as be dynamically changed during operation.

To guarantee proper operation of digital rheostats charge pump must be turned on (matrix input [86] must be logic High). Optionally user can turn off rheostats charge pump to decrease energy consumption. But it's strongly recommended to use the charge pump if $V_{DD} < 4.5$ V.

It is possible to use the rheostat in the following different modes:

- Changing the Rheostat value using the I²C interface;
- Manually changing the rheostat value using clock and up/down signals, similar to the counter;
- Using the Built-in Auto-Trim mode, where the rheostat value change is done using a special logic based on the signal from the Chopper ACMP.

The Programmable Trim (PT) blocks of rheostats macrocell contain analog MUXs, digital MUXs, Chopper ACMP, and additional logic. The two analog MUXs (M1 and M2) and the Chopper ACMP are both shared between the two rheostats. All analog and digital MUXs are set by NVM bits and can be overwritten with I²C.

The M_CK0 and M_CK1 MUXs select the clock source from internal pre-dividers of the internal oscillators or from the connection matrix. The internal clock sources for the rheostats are OSC0, OSC0/8, OSC0/64, OSC0/512, OSC0/4096, OSC0/32768, OSC0/262144, OSC1, OSC1/8, OSC1/64, and OSC1/512. The PT blocks of the rheostat use the same clock scheme as Counter/Delay Macrocells (refer to [16.5](#)). M_CH0 and M_CH1 select the Chopper comparator or a matrix output as the signal source for the main rheostat up/down counter direction. The output of the Chopper ACMP is connected with the Up/Down inputs of the PT blocks by default. The output of the Chopper ACMP can be optionally inverted by setting register [882] to "1".

M1 MUX selects the input for the Chopper comparator to be connected either internally to one of the integrated op amps or externally to a PIN. M2 MUX is simplified symbol of Chopper ACMP reference selection blocks. The Chopper ACMP reference ("-" input) can be: analog signal from pin, divided internal Vref voltage (6-bit divider), or divide V_{DDA} voltage (6-bit divider). In Auto-Trim mode each of Rheostats has it own settings for Chopper ACMP inputs. For more information about Chopper ACMP Vref see [Section 9.2](#).

The power-up signal for the Chopper ACMP can be handled either by matrix output signal or Set0/Set1 signal from the PT macrocell. In Auto-Trim mode (Auto_Cal_Dis_RHx NVM bit = 0) additional internal logic enables the clocking of the corresponding PT macrocell counter and disables clocking when one of the stop conditions is reached. See a detailed description in [Section 12.4](#). In [Figure 102](#) when Auto_Cal_Dis_RHx NVM bit = 0 (Auto-Trim mode is enabled), the clocking pulses for the internal PT macrocell counter are under control of additional logic. When Auto_Cal_Dis_RHx NVM bit = 1 (Auto-Trim mode is disabled), all additional logics (Set signal, internal Set signal, Idle/Active signal) operate the same way, but clock pulses are always enabled and generated externally by the user. Calibration channel can be selected automatically (1st channel is channel 0, second channel is channel 1) or can be set manually by registers [893:892].

The inputs of Chopper ACMP can be reconfigured while operating in Auto-Trim mode. There is one configuration of inputs (M1, M2 configuration, [Figure 102](#)) for the case when Set0 signal is latched, and another configuration of M1, M2 MUXs when Set1 signal is latched. For example, M1 MUX can be configured to operate with In Amp out when Set0 is latched and Chopper_ACMP+ pin when Set1 is latched. The same way, M2 can be configured to work with any of M2 inputs when Set0 or Set1 are latched. Note that the default configuration is the configuration for Set0 signal. When Chopper ACMP operates as separate ACMP and Auto-Trim function is disabled, M1 and M2 MUXs operates with configuration for Set0 signal.

Keep in mind that two Auto-Trim processes cannot be done simultaneously. When the Auto-Trim process for one rheostat is active, all signals on the Set input for another rheostat will be ignored. See a detailed description in [12.4.1](#). The initial user defined value of Digital Rheostat resistance can be programmed into the NVM. The initial value will be loaded during the Power-On event and this value will be used as the initial rheostat resistance, as well as a starting point for count down or count up.

Both read and write operations are allowed for rheostat resistance value, stored in NVM. Also, both read and write operations are allowed for current rheostat resistance value. RH0 read operation - registers [1561:1552], write operation - registers [1545:1536]. RH1 read operation - registers [1689:1680], write operation - registers [1673:1664].

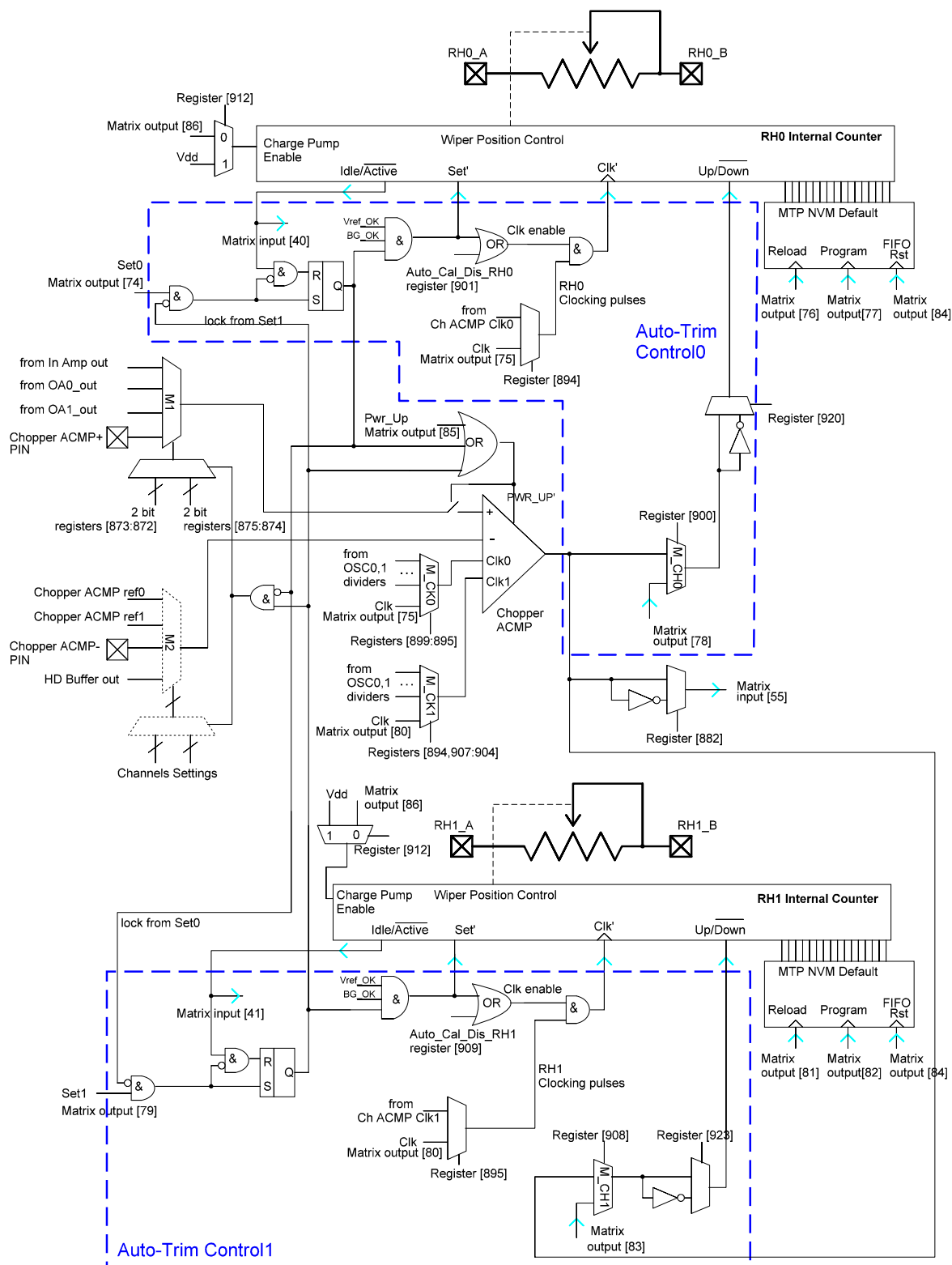


Figure 102: Programmable Trim Blocks and Digital Rheostat's Internal Circuit

PT macrocell signals:

- “Set”: external Set signal begins the Auto-Trim process when Auto_Cal_Dis_RHx bit is cleared (registers [901]). Otherwise, this signal has no effect. The behavior of the PT macrocell in Auto-Trim mode is described below.
- “Reload”: when Reload goes high the rheostat value stored in the MTP NVM will be loaded into the rheostat (Register and Counter) overwriting any current setting. This signal is edge sensitive. It has no effect while the Auto-Trim procedure is active. For detailed information see Section 12.3.
- “Program”: when Program goes high the Internal Counter value of the rheostat will be programmed into the MTP overwriting any current value in the NVM. This procedure can be done up to 1000 times. This signal is also edge sensitive. It has no effect while the Auto-Trim procedure is active. For detailed information see 12.3. To enable “Program” signal from connection matrix RH_PRB register must be cleared (RH_PRB [1796] = 0). If RH_PRB [1796] register is set to 1, the access to NVM is disabled for “Program” signal. Refer to Section 19.6 for more details.
- “Clock”: this input has the following options: the PT macrocell can be clocked internally or from matrix. When clocked internally, the clock is automatically enabled/disabled by the Set input logic in Auto-Trim mode. The internal clock is synchronized with the Chopper ACMP clock.
- “Up/Down”: the rheostat counter counts up when the signal is High and down when the signal is Low.
- “Idle/Active”: this is the connection matrix input, that is logic HIGH by default. It goes LOW with rising edge on SET input if Auto-Trim mode is enabled (Auto_Cal_Dis_RHx NVM bit = 0). After the end of Auto-Trim procedure (one of stop conditions occurs) this signal sets to logic HIGH again.
- “FIFO nReset”: low level at this input clears internal FIFO buffer for commands Reload and Program for both rheostats. User should provide high logic level at this input for the normal rheostat operation.

There is also an overflow protection option, for which the counter will stop counting up when the maximum value (0x3FF) is reached or stop counting down when the minimum value (0x00) is reached. The digital rheostat is initialized/powered in the first place. The rheostat value is Hi-Z (or highest resistance if it is impossible to disconnect the rheostat) during the Power-On sequence.

12.1 POTENTIOMETER MODE

This mode allows two 2-pin rheostats to work as one 3-pin potentiometer. When this mode is active (register [917] = 1), user changes the value of RH0 internal counter. In this mode, the value of RH1 counter is the inverted value of RH0 counter (Figure 103). Note that the RH0_B pin and the RH1_A pin must be connected externally. Also, note that the Auto-Trim function isn't allowed in Potentiometer Mode.

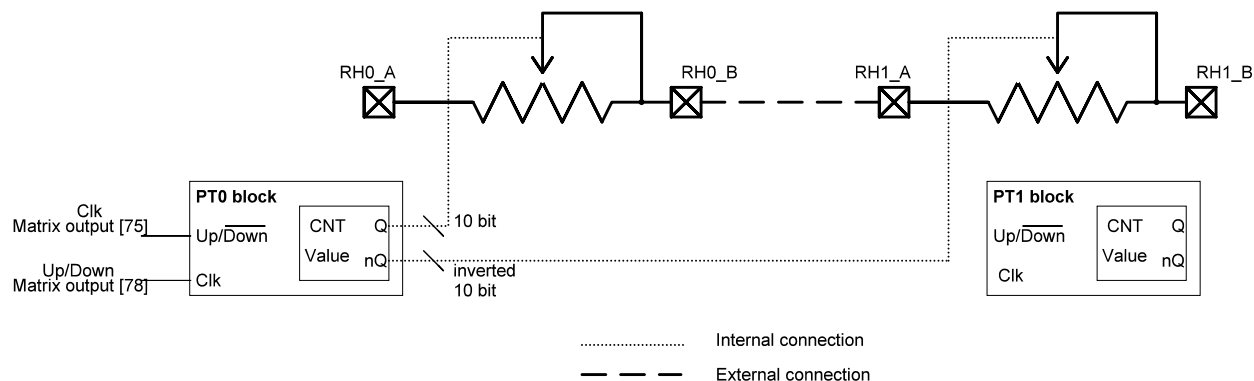
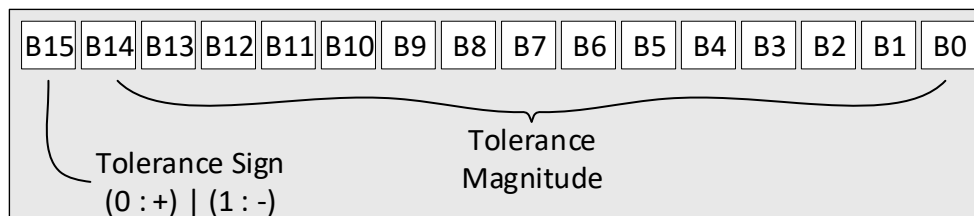


Figure 103: Rheostats in Potentiometer Mode

12.2 CALCULATING ACTUAL RESISTANCE

In applications where the absolute rheostat resistance is critical, the user can calculate it using the rheostat tolerance data, the minimum rheostat resistance, and the desired code.

The 16-bit tolerance data for both rheostats has been programmed into registers 0xE6 to 0xE9. These registers can be used to calculate the total rheostat resistance. The 16th bit defines the sign (0 = +, 1 = -) of the tolerance. The other fifteen bits correspond to the absolute value of the rheostat tolerances variation from 100 kΩ measured at 25 °C.


Figure 104: Rheostat Tolerance Registers

Note that the rheostat tolerance data is programmed into registers 0xE6 to 0xE9. To avoid losing this tolerance data, special attention must be paid when erasing and reprogramming page 14 in the NVM.

The rheostat value at a given code depends on the total digital rheostat resistance. The equations below can be used to calculate the rheostat resistance.

$$R_{Code} = (R_{DR} - R_{DR\ MIN}) \times (code/1023) + R_{DR\ MIN}$$

$$R_{DR} = 100 \times 10^3 + (sign_{RH_Tolerance} \times R_{RH_Tolerance})$$

where:

R_{Code} - Rheostat Resistance at a Given Code;

R_{DR} - Total Digital Rheostat Resistance;

$R_{DR\ MIN}$ - Minimum Rheostat Resistance;

$code$ - Rheostat Position Ranging from 0x000 to 0x3FF;

$sign_{RH_Tolerance}$ - the MSB of the Rheostat's Tolerance Data;

$R_{RH_Tolerance}$ - the 15 LSBs of the Rheostat's Tolerance Data.

For example, let's say that 0x2B67 has been written into the rheostat tolerance registers within the GreenPAK's NVM. B15 corresponds to a positive sign while B14:0 translates into a decimal value of 11111. R_{DR} calculates to approximately 111,111 Ω and can be used with the minimum rheostat resistance to calculate the resistance at a given code. Note that the minimum rheostat resistance must be measured to obtain precise results, but a range is provided in [Table 6](#).

12.3 DIGITAL RHEOSTAT VALUE SELF-PROGRAMMING INTO THE NVM

The current value of rheostat is stored in the Internal Counter. This value can be programmed into the MTP by setting logic HIGH at "Program" input. In this case, SLG47004 will generate a specific memory control sequence to rewrite a new value into the NVM. There is a separate NVM page that is dedicated for the Digital Rheostat value.

There is a dedicated bit RH_PRB, that enables/disables "Program" signal of PT block to change NVM rheostats resistance values. If RH_PRB[1796] = 0, "Program" signal is enabled. If RH_PRB[1796] = 1, "Program" signal is disabled. Note that RH_PRB bit has no effect on I²C access to NVM. To enable/disable I²C access to rheostat resistance value, stored in NVM, user must change NPRB0, NPRB1 bits. Refer to [Section 18.5](#).

SLG47004 can latch up to four "Program" and "Reload" signals of RH0 and RH1 (Reload RH0, Program RH0, Reload RH1, Program RH1). The same signal can't be latched second time, until it is processed. All latched signals will be processed in the order of arrival (FIFO buffer), since only one signal can access NVM at the same time. If Auto-Trim process of RH0 or RH1 is active and one or more "Reload", "Program" signals for corresponding rheostat come, SLG47004 will wait until the end of Auto-Trim process and then process will latch "Reload", "Program" signals. Set0 or Set1 signal can be latched at any time and processed when rheostat clocking isn't disabled by "Program" or "Reload" signals.

User can clear the FIFO buffer by setting low logic level at FIFO nReset input of PT blocks.

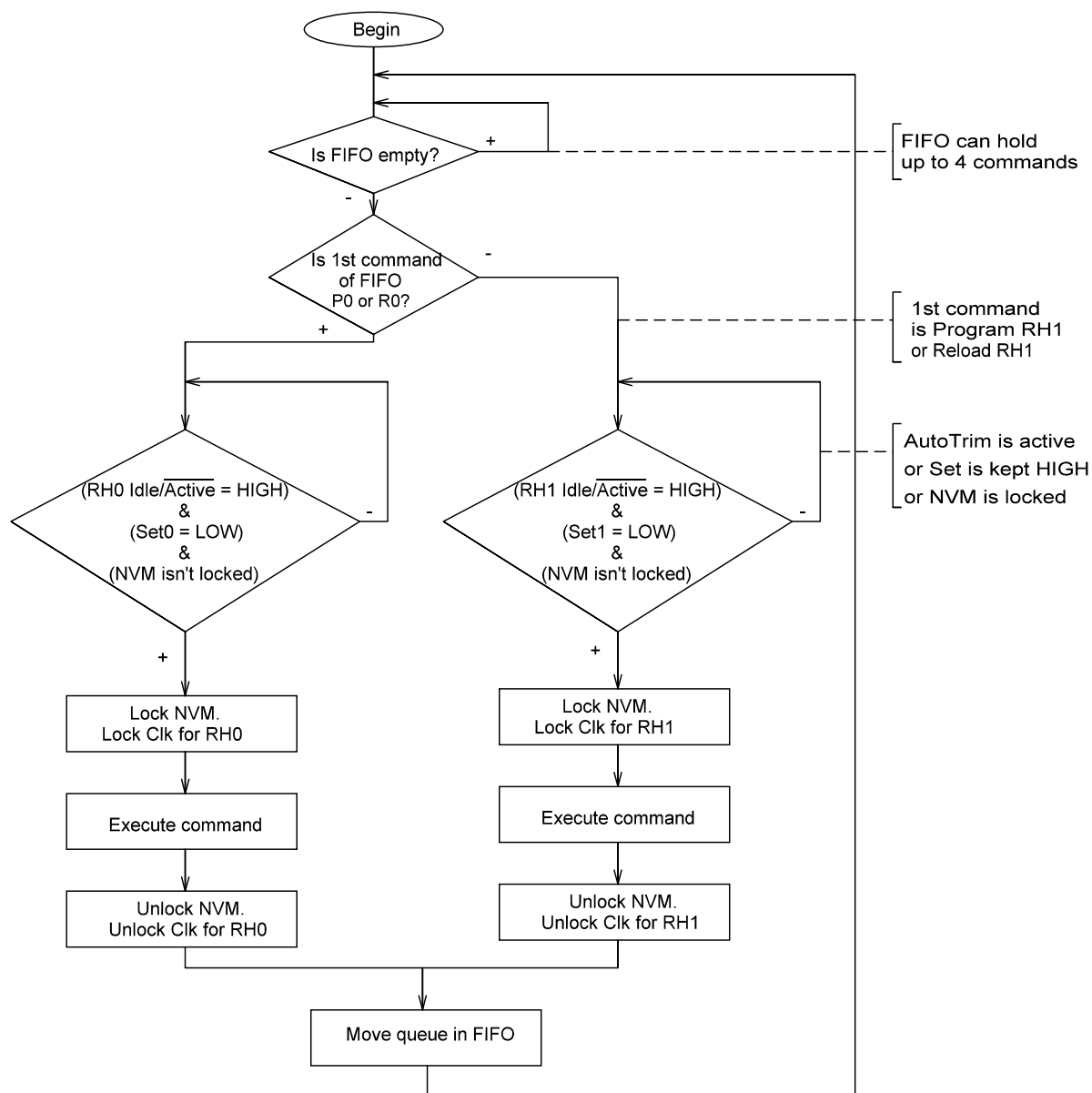


Figure 105: Flowchart of "Program" and "Reload" Signals

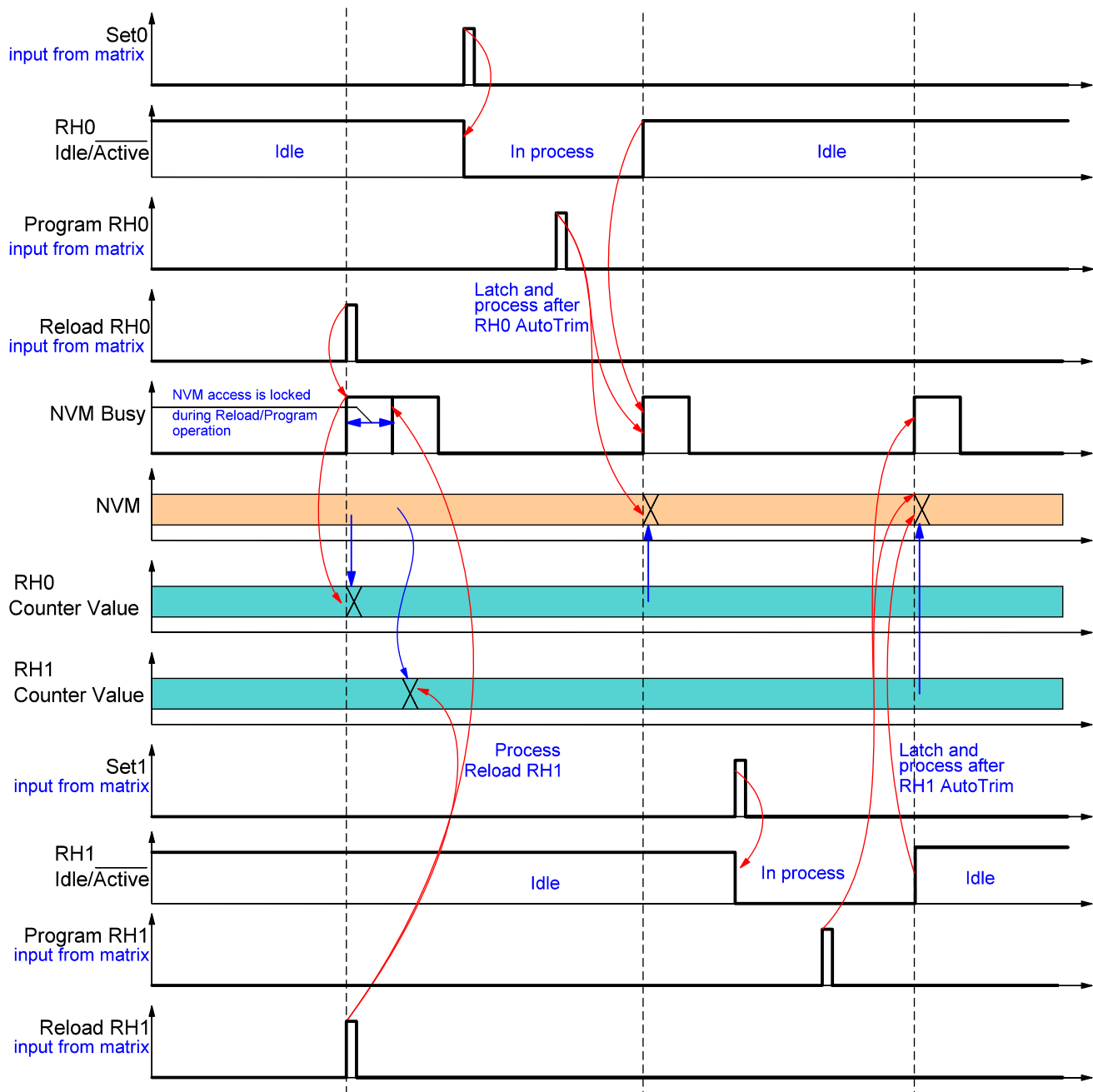


Figure 106: Example of Latching and Processing "Program" and "Reload" Signals

Since the access to the MTP NVM is disabled during NVM self-programming procedure, the device will not acknowledge it via I²C interface. This can be used to determine when the erase/programming cycle is completed (this feature can be used to maximize bus throughput). ACK polling can be used in this case.

If the device is still busy during the write cycle, then no ACK will be returned. If no ACK is returned, then the Start bit and control byte must be re-sent. Once the cycle is complete, then the device will return the ACK and the master can proceed with the next Read or Write command.

12.4 TRIMMING PROCESS USING PROGRAMMABLE TRIM BLOCK

There are several ways of implementing the trimming process using the PT block. One of the essential features of the PT macrocell is the Auto-Trim function described below. It allows the user to design simple calibration circuits for a wide variety of applications.

12.4.1 Trimming Process with Auto-Trim Option Enabled

For using the Auto-Trim function the following preliminary steps must be taken:

- Clear Auto_Cal_Dis_RHx NVM bit (0 is default value). This enables Auto-Trim function.
 - Configure M1 MUX (registers [875:872]). It can be user system voltage feedback. If Auto-Trim function is used for two rheostats, M1 MUX must be configured for both rheostats (for cases when Set0 is latched and when Set1 is latched).
 - Configure M2 MUX. It can be user desired set point threshold. If Auto-Trim function is used for two rheostats, M2 MUX must be configured for both rheostats (for cases when Set0 is latched and when Set1 is latched). Remember, that M2 MUX is simplified symbol of Chopper ACMP reference selection blocks.
 - Configure M_CH0 (M_CH1) MUX to work with Chopper ACMP (M_CH0,1 MUXs are configured to work with Chop ACMP by default).
 - Configure inverting or non-inverting Chopper ACMP output (registers [923], [920] and [882]);
 - Select clock source (internal clock from internal pre-dividers or from connection matrix). Note that in Auto-Trim mode clock source frequency for the PT Block is limited by the Chopper Comparator time response. Therefore, the clock source frequency must not be greater than $<f_{ChACMP}>$ kHz.
 - Start the Auto-Trim process by setting the Set0 (Set1) input of PT block to a High level. The Auto-Trim process stops if one of three stop conditions occur:
 - 1) 2nd time change on Up/Down input at the moment of rising edge on Clock input (see [Figure 107](#)).
 - 2) the value of rheostat reaches its maximum (1023).
 - 3) the value of rheostat reaches its minimum (0).Stop conditions result in a change of the Idle/Active signal, which resets the internal Auto-Trim logic.
- Note that the Set input is edge sensitive, but if the user keeps a High logic level at this input after reaching the set point, the PT block will continue to operate and continue to switch rheostat around the set point.
- To start new Auto-Trim process user should reapply a High level on Set input.

The detailed flow of Auto-Trim process is shown in [Figure 107](#), [Figure 108](#), [Figure 109](#).

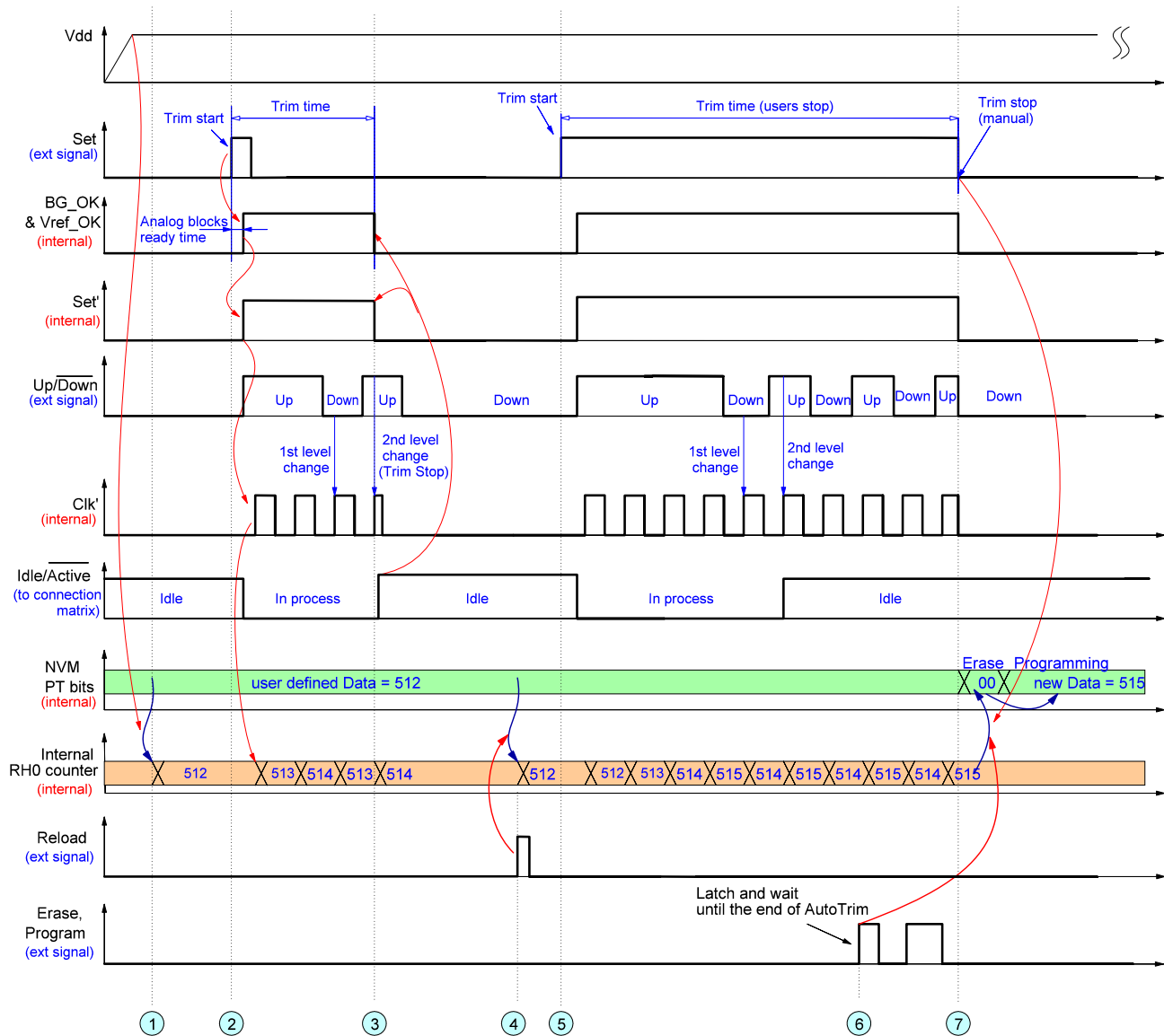


Figure 107: Example of Auto-Trim Process for a Single Rheostat

The key events of the Auto-Trim process are the following (see [Figure 107](#)):

1. During the startup event the SLG47004 loads the rheostat value from NVM to Internal Counter. In this example this value is 512.
2. The Trim process starts with a rising edge on Set input. This Set signal is latched until the end of the Auto-Trim process. The Set signal will enable the Chopper ACMP and the Vref, if they were not enabled earlier. After a ready signal from analog blocks (BG_OK & Vref_OK), the clock pulses for the internal counter are enabled. The counter starts to count up or down depending on the level at the Up/Down input. If user selected the "Internal Clock" option for Clock input, these clock pulses are generated automatically during trim time. Each rising edge of the Clock pulse changes the value of the counter and, consequently, the value of the rheostat.
3. There are three stop conditions for the Auto-Trim process:
 - 1) A subsequent change on Up/Down input at the moment of rising edge on Clock input.

- 2) The value of the rheostat reaches its maximum (1023).
- 3) The value of the rheostat reaches its minimum (0).

If the Set input signal is shorter than the trim time, the Auto-Trim process stops automatically after a stop condition occurs (event 3, [Figure 107](#)). However, if a stop condition comes and High logic level holds on the Set input, the rheostat value will be switched near the set point until a Low level on the Set input occurs (event 7, [Figure 107](#)). Note that the Idle/Active signal changes its level to High (Auto-Trim is done) even if the user keeps a High logic level at the Set input.

After the end of the Auto-Trim process, Chopper ACMP powers down and its output goes to a Low logic level.

4. After a rising edge at the “Reload” signal, the value from NVM is copied to the rheostat Internal Counter overwriting current rheostat settings.
5. During this event user starts Auto-Trim process, but holds High logic level at Set input for a time longer than Auto-Trim process.
6. A “Program” signal comes. The “Program” command is latched and will be executed at the end of the Auto-Trim process.
7. The Auto-Trim process stops when the signal at the Set input goes to Low level. Note that a logic High level at the Set input was held longer than the time that was needed for the Auto-Trim process. At the end of the Auto-Trim process, the SLG47004 starts the NVM self-programming routine to copy the rheostat value from Reg LATCH to MPT NVM.

[Figure 108](#) shows a similar Auto-Trim example. The only difference is that the user defined clock source as “External clock” from connection matrix. The clock pulses are present at the Clock input all the time, but have effect (rheostat value changes) during Trim time only. The stop condition for this case is the following: PT block reaches boundary value of 1023 and the logic level at change Set input is Low.

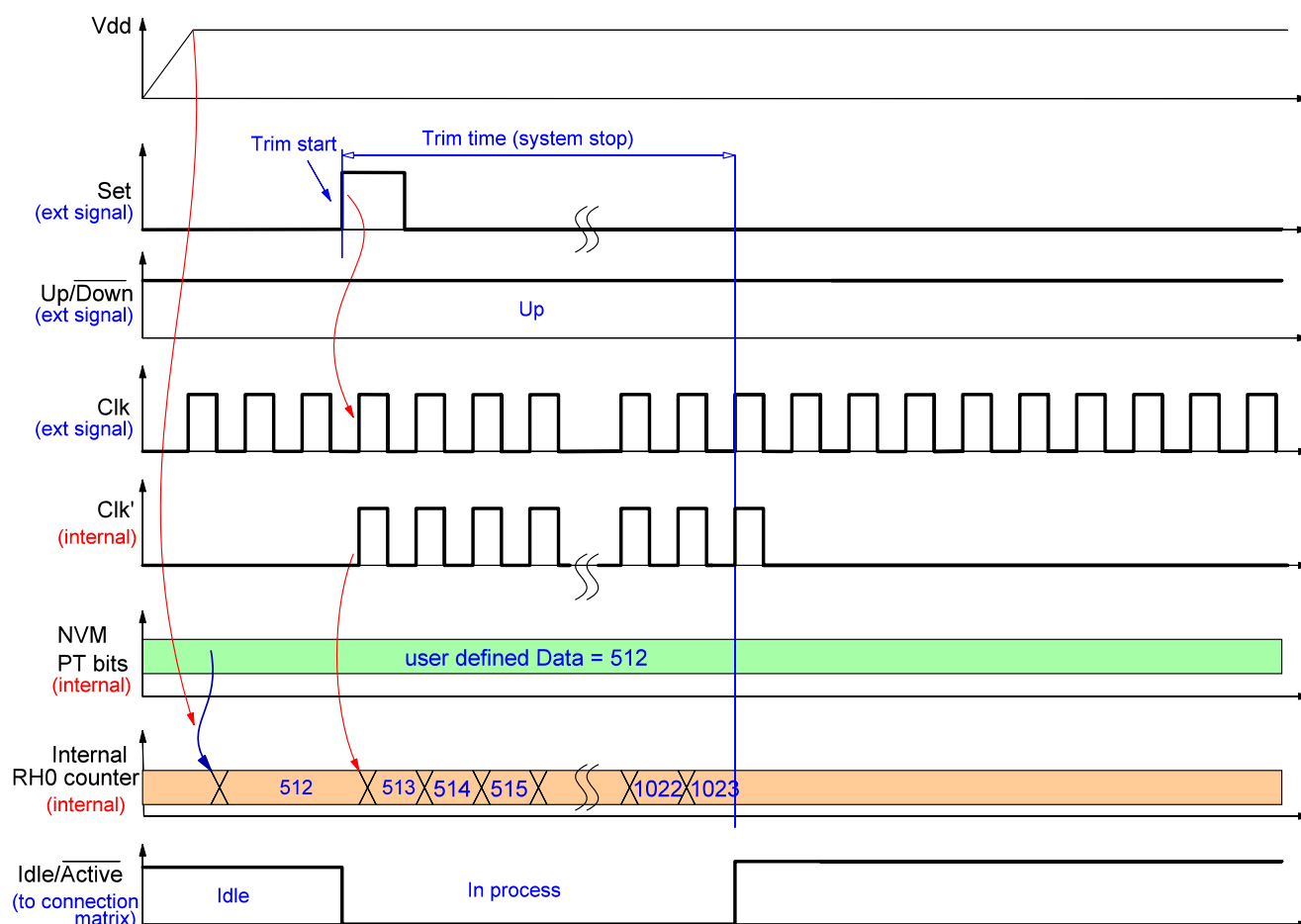


Figure 108: Example of Auto-Trim Process with External Clock Signal

Figure 109 shows Auto-Trim process flow for two rheostats.

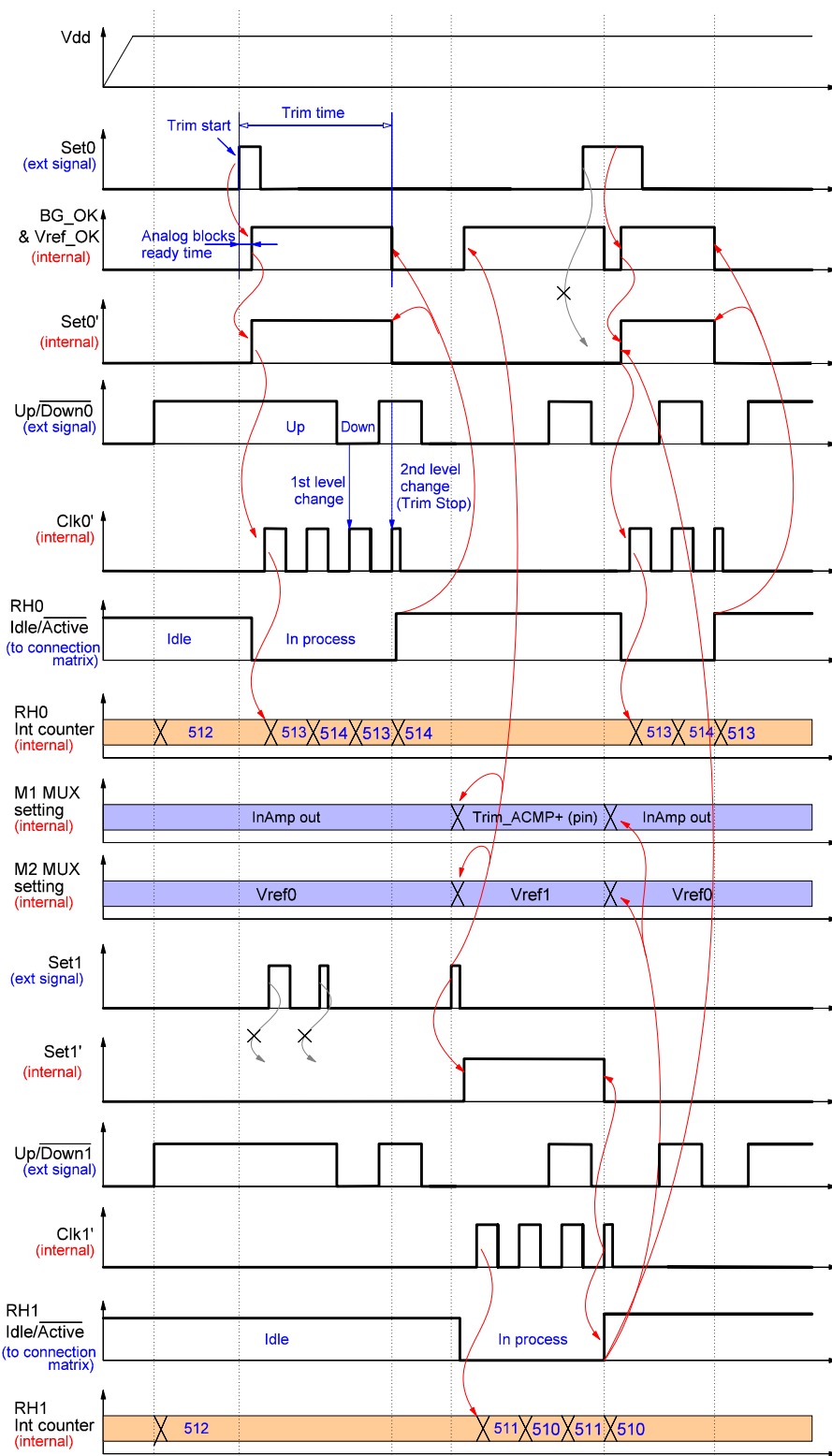


Figure 109: Example of Auto-Trim Process for Two Rheostats

12.4.2 I²C Controlled Trimming Process with Auto-Trim Option Enabled

It's possible to start the Auto-Trim process via I²C interface. In this case the user must configure the SLG47004 PT macrocell as described in Section 12.4.1. To start the Auto-Trim process via I²C interface the user can use I²C virtual inputs.

Also, an external I²C master device can force the SLG47004 to reload the rheostat value from NVM ("Reload" command) or to copy rheostat value to NVM ("Program" command) using I²C virtual inputs.

See Figure 110 for an example of the Auto-Trim process under external I²C master control.

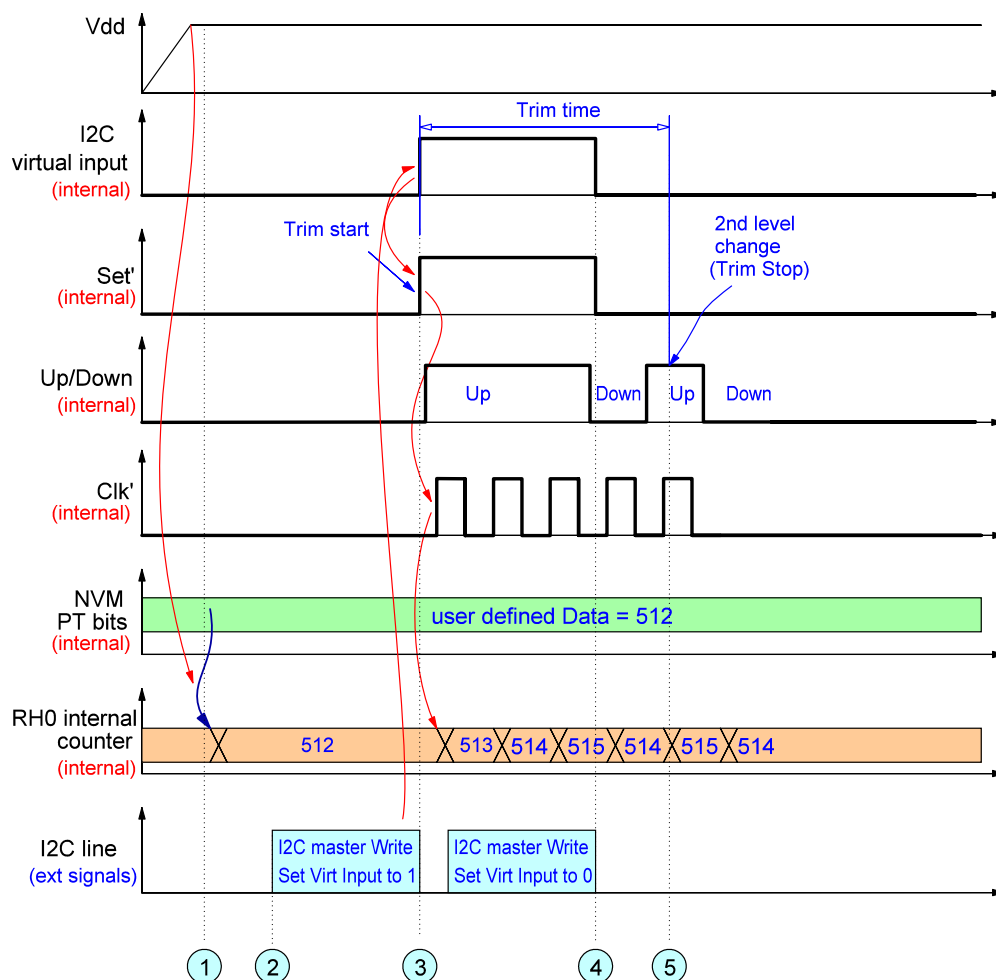


Figure 110: Example of Auto-Trim Process via I²C

The key events of the Auto-Trim process under external I²C master control are as follows:

1. During the startup event the SLG47004 loads the rheostat value from the NVM to the Internal Counter. In the example this value is 512.
2. I²C master sends the message to set High one of the I²C virtual inputs that is connected with Set input of the PT macrocell.
3. After the I²C message is received and processed, the I²C virtual input and the Set input will be at a High logic level. The Auto-Trim process begins.
4. I²C master clears the virtual input and, consequently, the Set input. The Auto-Trim process goes on until a trim stop condition occurs.

5. The Auto-Trim process ends. The stop condition in this example is a 2nd change on Up/Down input at the moment of rising edge on the Clock input and Low level at the Set input.

12.4.3 Changing Rheostat Value Directly via I²C

The user can perform their own trim algorithm setting the rheostat value directly via I²C interface. In the example below, a microcontroller uses a user defined trim algorithm to change SLG47004's rheostat via I²C interface (Figure 111). Note that during Auto-Trim process SLG47004 will return nACK, if master tries to get access (both read and write) to rheostats registers via I²C.

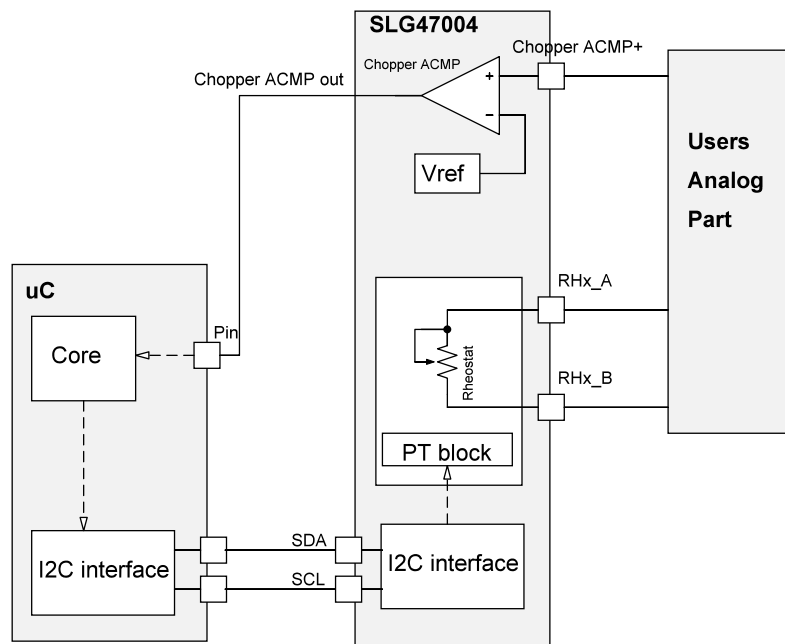


Figure 111: Example of Hardware Configuration

Note that the PT Registers are allowed to read and write via communication interface, if not protected.

The preliminary configuration of system shown in Figure 111 is the following:

- Auto_Cal_Dis_RHx bit is set to 1 (disable Auto-Trim mode);
- M1 MUX (registers [875:872]) is configured to work with user system voltage feedback (pin Chop_ACMP+);
- M2 MUX is configured to work with SLG47004 programmable Vref. Note that M2 MUX is simplified symbol of Chopper ACMP reference selection blocks (see Section 9.2);
- Chopper ACMP is powered up from connection matrix. Chopper ACMP out is connected to output pin;
- No Clock source for PT block.

The example of a system trim via I²C is shown in the figure below. In this example the I²C master uses a simple approximation algorithm for reaching the set point. Every next step the rheostat code is changed by $\pm(\text{Previous rheostat code step value}/2)$. The sign depends on the Chopper ACMP output. The algorithm steps are as follows:

- Set rheostat code to $1024/2 = 512$;
- Wait until the system settles down and check if Chopper ACMP output = 1, then $\text{Next_rheostat_code} = 512 + (512/2)$. If Chopper ACMP output = 0, then $\text{Next_rheostat_code} = 512 - (512/2)$;
- Repeat previous step until $\text{Next_rheostat_code} = \text{Prev_rheostat_code} \pm 1$;

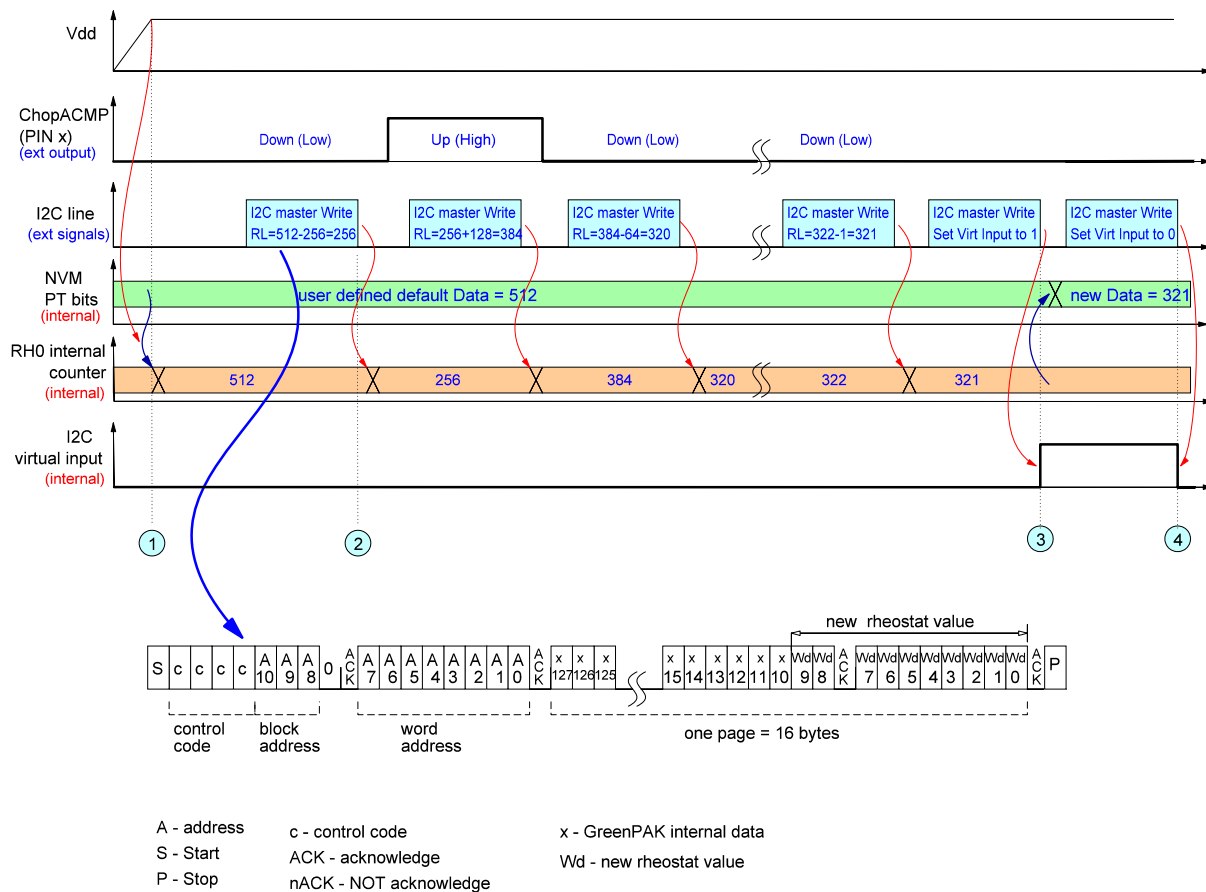


Figure 112: Example of User Specific Trimming Process under I²C Master Control

The key events of a user specific trimming process under I²C master control are as follows:

1. During the startup event the SLG47004 loads the rheostat value from NVM to Internal Counter. In the example this value is 512.
2. I²C master writes a new value to the Rheostat's Internal Counter according to Chopper ACMP output. Note that the minimum time for changing the rheostat code depends on the time response of the user system.
3. After the trim process is completed, the I²C master sets the I²C virtual input to logic "1". This input is connected to the "Reload" signal of the PT macrocell. The rising edge on this input starts the NVM self-programming routine.
4. The I²C master clears the I²C virtual input.

Additionally, the I^2C Master macrocell can use internal resources such as an ADC to read the system data, find the error, and then adjust the Rheostat value. Also, it is possible to change the Rheostat value for different conditions. For example, the I^2C Master macrocell can change the Rheostat value based on the temperature change to reduce the system error.

12.5 USING CHOPPER ACMP

When the Auto-Trim Function is disabled, the Chopper comparator can be used as a standalone analog comparator. Inputs of the Chopper ACMP are selected by the M1 and M2 analog MUXs. Output of the Chopper ACMP can be optionally inverted by register [882]. This comparator output is the input [55] of the connection matrix. In case of a disabled Auto-Trim Function, the power up source for the Chopper ACMP comes from connection matrix. Please refer to Section 9 for more details.

13 Programmable Delay/Edge Detector

The SLG47004 has a programmable time delay logic cell available, that can generate a delay that is selectable from one of four timings (time 2) configured in the GreenPAK Designer. The programmable time delay cell can generate one of four different delay patterns, rising edge detection, falling edge detection, both edge detection, and both edge delay. These four patterns can be further modified with the addition of delayed edge detection, which adds an extra unit of delay, as well as glitch rejection during the delay period. See Figure 114 for further information.

Note: The input signal must be longer than the delay, otherwise it will be filtered out.

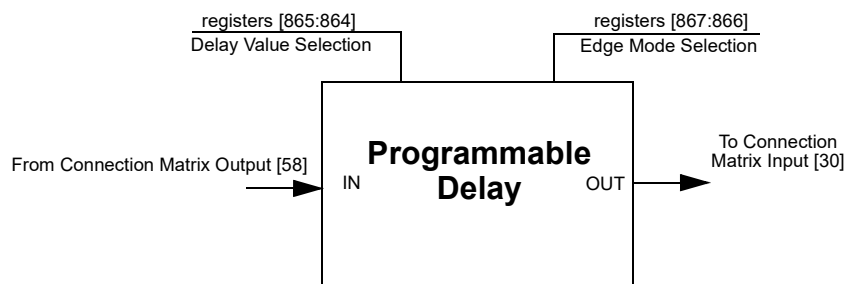


Figure 113: Programmable Delay

13.1 PROGRAMMABLE DELAY TIMING DIAGRAM - EDGE DETECTOR OUTPUT

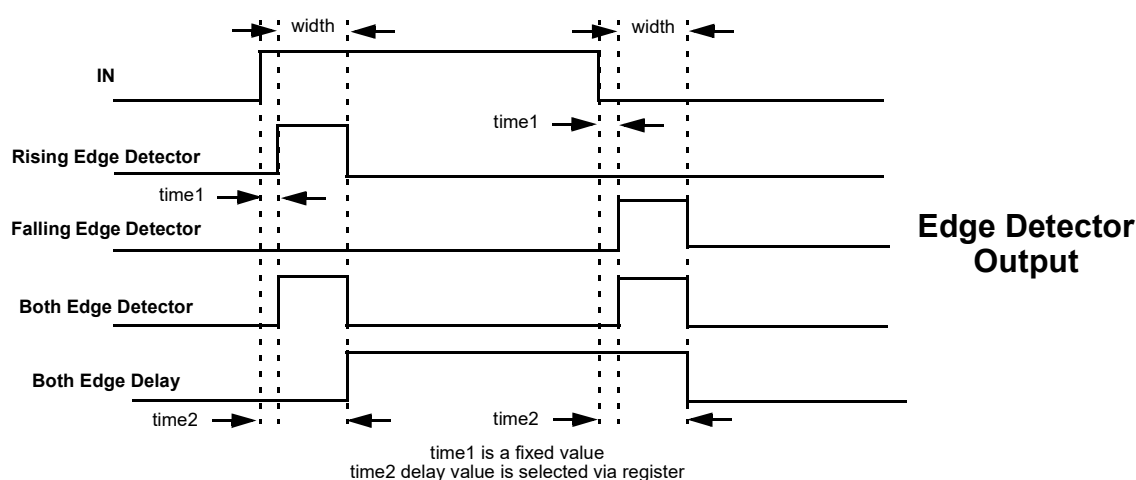


Figure 114: Edge Detector Output

Please refer to Table 11.

14 Additional Logic Function. Deglitch Filter

The SLG47004 has one Deglitch Filter macrocell with inverter function that is connected directly to the Connection Matrix inputs and outputs. In addition, this macrocell can be configured as an Edge Detector, with the following settings:

- Rising Edge Detector
- Falling Edge Detector
- Both Edge Detector
- Both Edge Delay

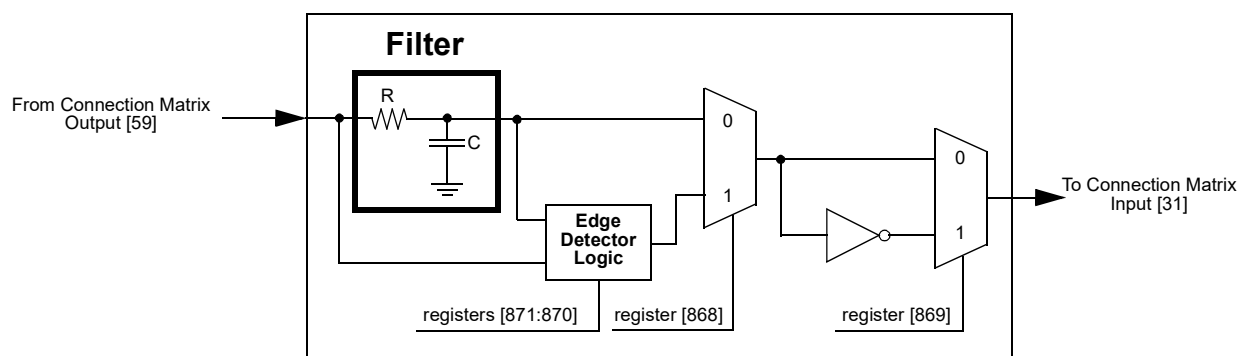


Figure 115: Deglitch Filter or Edge Detector

15 Voltage Reference

15.1 VOLTAGE REFERENCE OVERVIEW

The SLG47004 has a Voltage Reference (Vref) Macrocell to provide reference to analog comparators and operational amplifiers. The macrocell also has the option to output reference voltages on external pins (see Table 1). Vref0 and Vref1 share output buffers with Temperature sensor. Note that user can use any of output buffers, but Temperature sensor is calibrated for Vref1 output buffer. See Table 57 for the available selections for each analog comparator. Also, see Figure 116, Figure 117, and Figure 118, which show the reference output structure.

Also there is a high drive voltage reference macrocell called HD Buffer. The purpose of this macrocell is to provide stable voltage to the relatively high-power load (Please refer to the Table 18). HD Buffer has shared voltage reference source with the Op Amp0 Vref. User can select output voltage in the range from $V_{DD}/64$ to V_{DD} with a step $V_{DD}/64$, or output voltage in a range from 32 mV to 2.048 V with a step 32 mV (see Figure 118).

15.2 VREF SELECTION TABLE

Table 57: Vref Selection Table

SEL[5:0]	Vref	SEL[5:0]	Vref
0	0.032	33	1.088
1	0.064	34	1.12
2	0.096	35	1.152
3	0.128	36	1.184
4	0.16	37	1.216
5	0.192	38	1.248
6	0.224	39	1.28
7	0.256	40	1.312
8	0.288	41	1.344
9	0.32	42	1.376
10	0.352	43	1.408
11	0.384	44	1.44
12	0.416	45	1.472
13	0.448	46	1.504
14	0.48	47	1.536
15	0.512	48	1.568
16	0.544	49	1.6
17	0.576	50	1.632
18	0.608	51	1.664
19	0.64	52	1.696
20	0.672	53	1.728
21	0.704	54	1.76
22	0.736	55	1.792
23	0.768	56	1.824
24	0.8	57	1.856
25	0.832	58	1.888
26	0.864	59	1.92
27	0.896	60	1.952
28	0.928	61	1.984
29	0.96	62	2.016

Table 57: Vref Selection Table(Continued)

SEL[5:0]	Vref	SEL[5:0]	Vref
30	0.992	63	2.048
31	1.024	64	External
32	1.056		

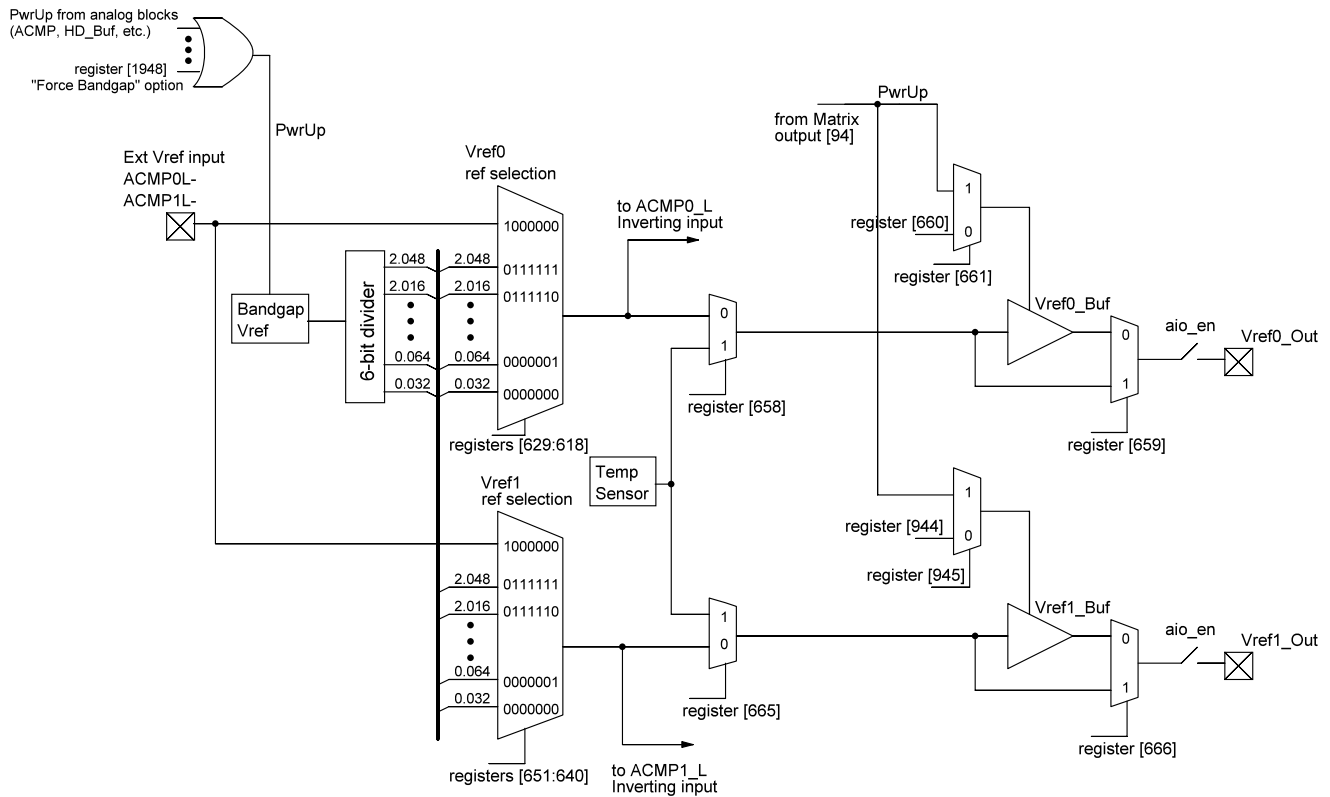


Figure 117: ACMP0L, ACMP1L Voltage Reference Block Diagram

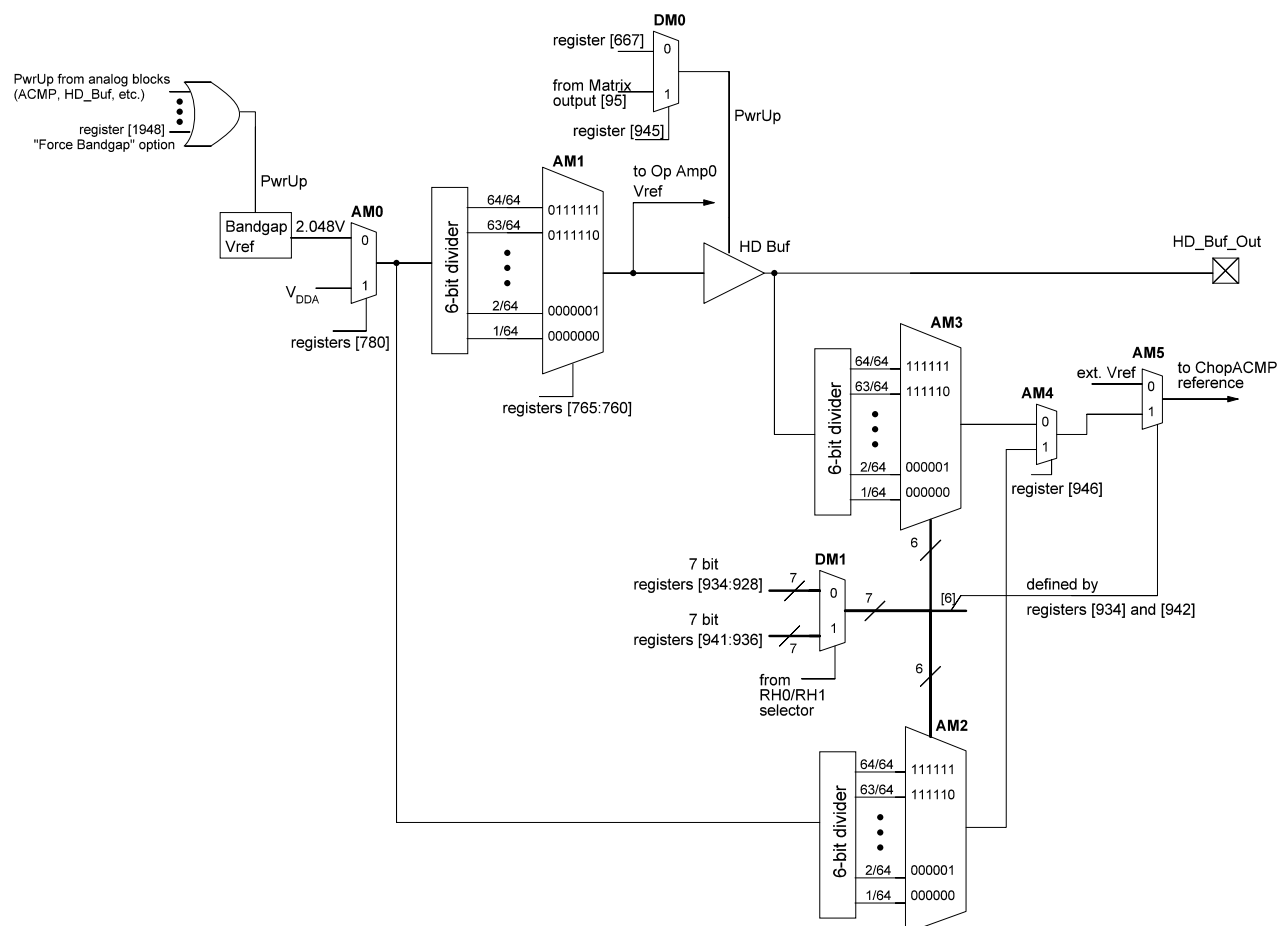
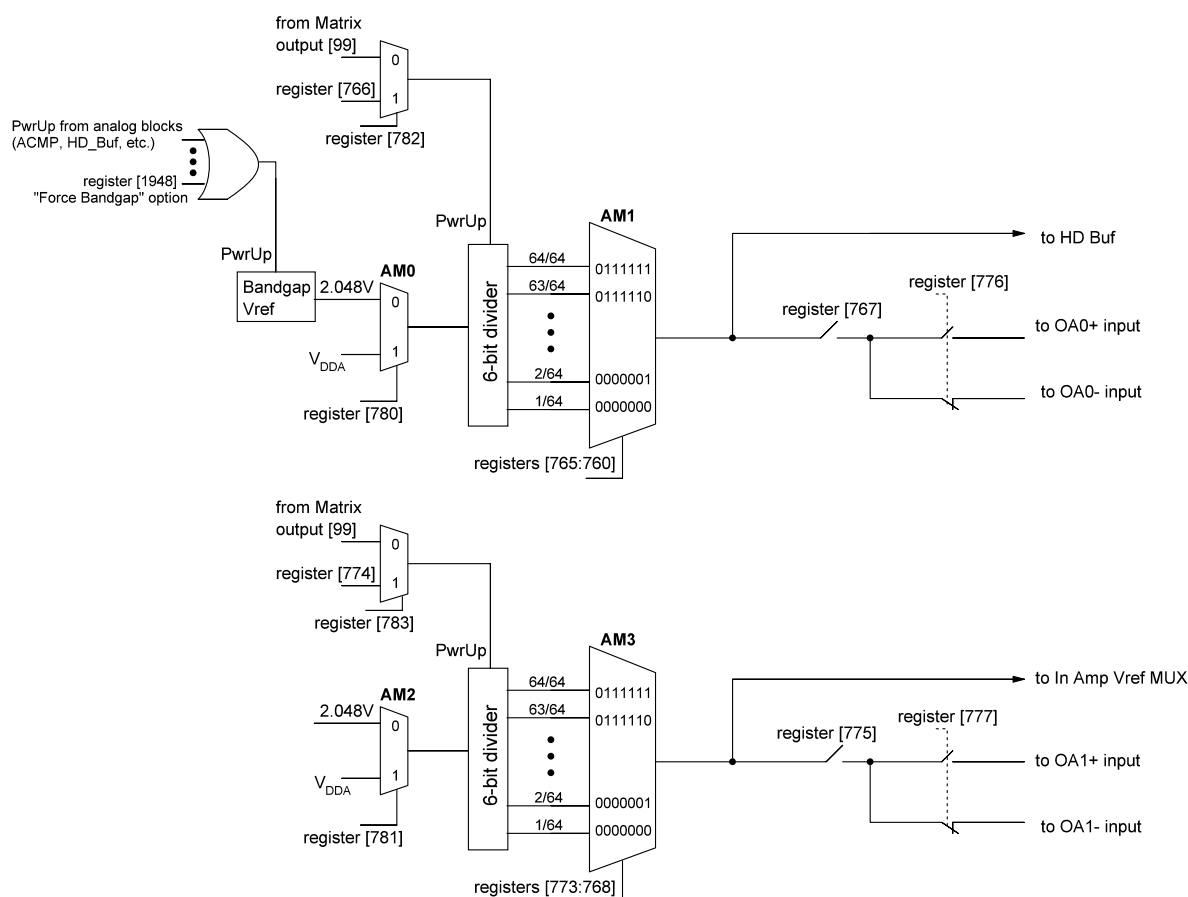


Figure 118: HD Buffer and Chopper ACMP Reference Block Diagram


Figure 119: Operational Amplifiers Voltage Reference Block Diagram

16 Clocking

16.1 OSC GENERAL DESCRIPTION

The SLG47004 has three internal oscillators to support a variety of applications:

- Oscillator0 (2.048 kHz)
- Oscillator1 (2.048 MHz)
- Oscillator2 (25 MHz)

There are two divider stages for each oscillator that give the user flexibility for introducing clock signals to connection matrix, as well as various other Macrocells. The pre-divider (first stage) for Oscillator allows the selection of /1, /2, /4, or /8 to divide down frequency from the fundamental. The second stage divider has an input of frequency from the pre-divider, and outputs one of eight different frequencies divided by /1, /2, /3, /4, /8, /12, /24, or /64 on Connection Matrix Input lines [52], [53], and [54]. Please see [Figure 123](#) for more details on the SLG47004 clock scheme.

Oscillator2 (25 MHz) has an additional function of 100 ns delayed startup, which can be enabled/disabled by register [713]. This function is recommended to use when analog blocks are used along with the Oscillator.

The Matrix Power-down/Force On function allows switching off or force on the oscillator using an external pin. The Matrix Power-down/Force On (Connection Matrix Output [91], [92], [93]) signal has the highest priority. The OSC operates according to the [Table 58](#).

Table 58: Oscillator Operation Mode Configuration Settings

POR	External Clock Selection	Signal From Connection Matrix	Register: Power-Down or Force On by Matrix Input	Register: Auto Power-On or Force On	OSC Enable Signal from CNT/DLY Macrocells	OSC Operation Mode
0	X	X	X	X	X	OFF
1	1	X	X	X	X	Internal OSC is OFF, logic is ON
1	0	1	0	X	X	OFF
1	0	1	1	X	X	ON
1	0	0	X	1	X	ON
1	0	0	X	0	CNT/DLY requires OSC	ON
1	0	0	X	0	CNT/DLY does not require OSC	OFF

Note 1 The OSC will run only when any macrocell that uses OSC is powered on.

16.2 OSCILLATOR0 (2.048 kHz)

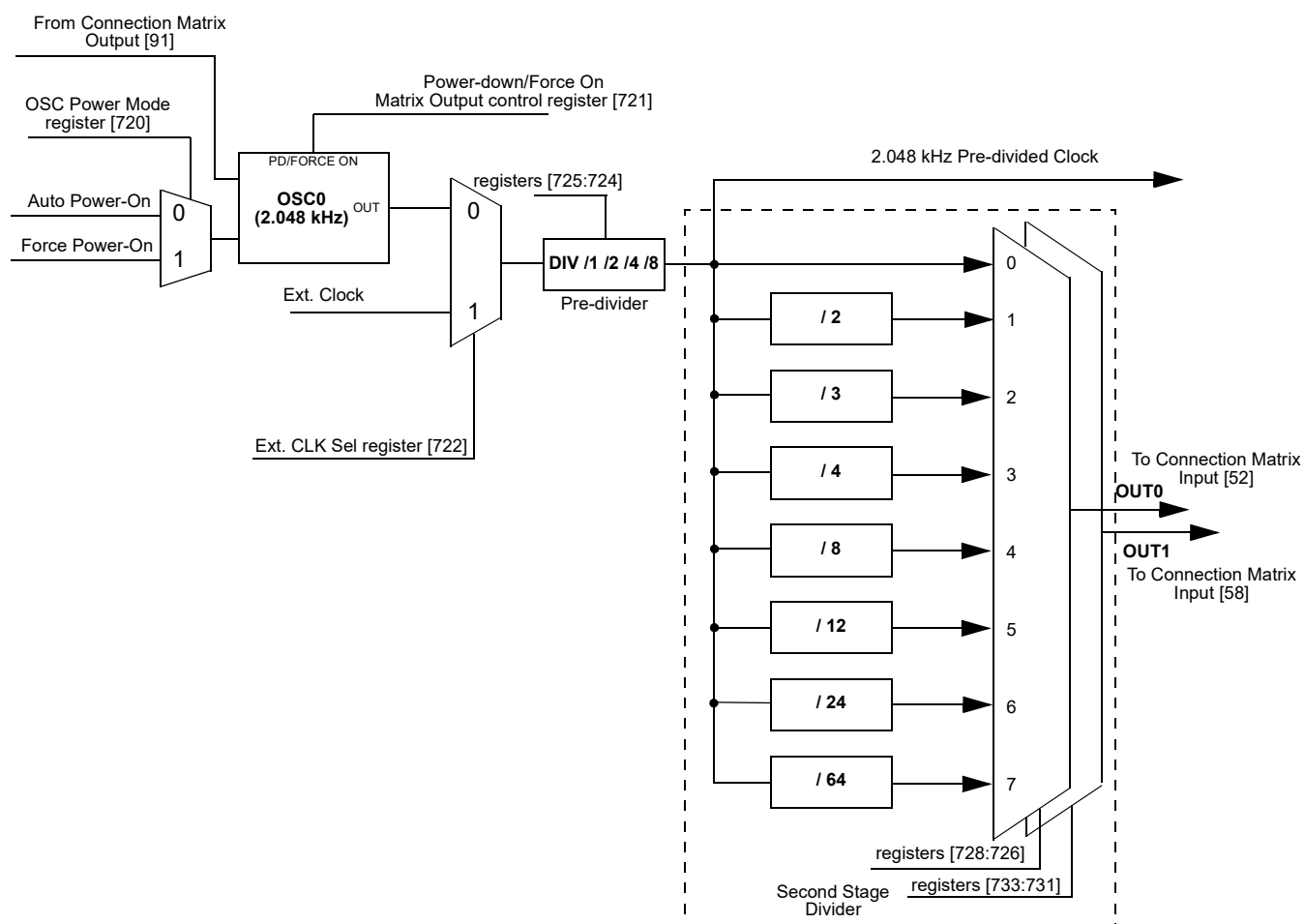


Figure 120: Oscillator0 Block Diagram

16.3 OSCILLATOR1 (2.048 MHZ)

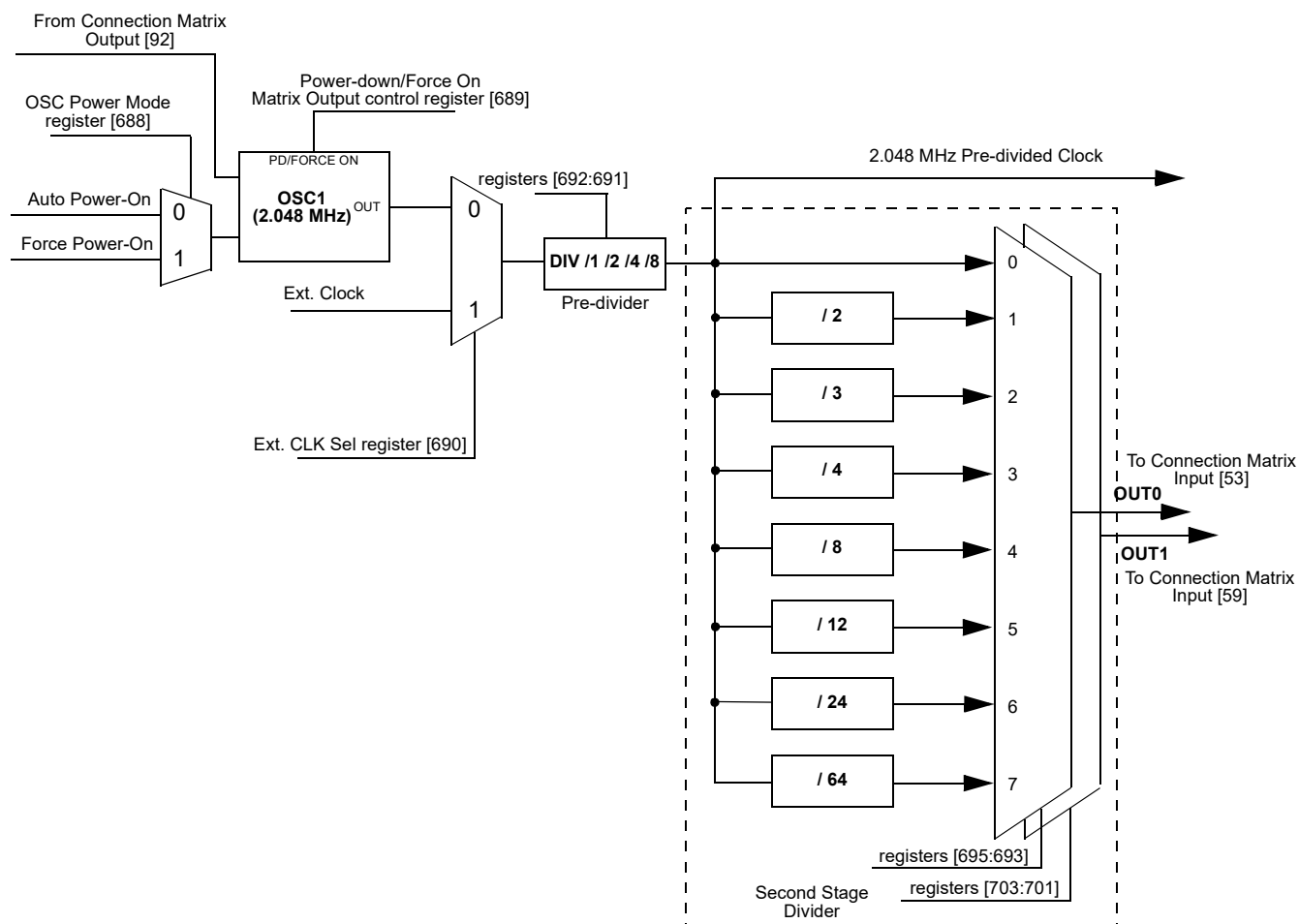


Figure 121: Oscillator1 Block Diagram

16.4 OSCILLATOR2 (25 MHZ)

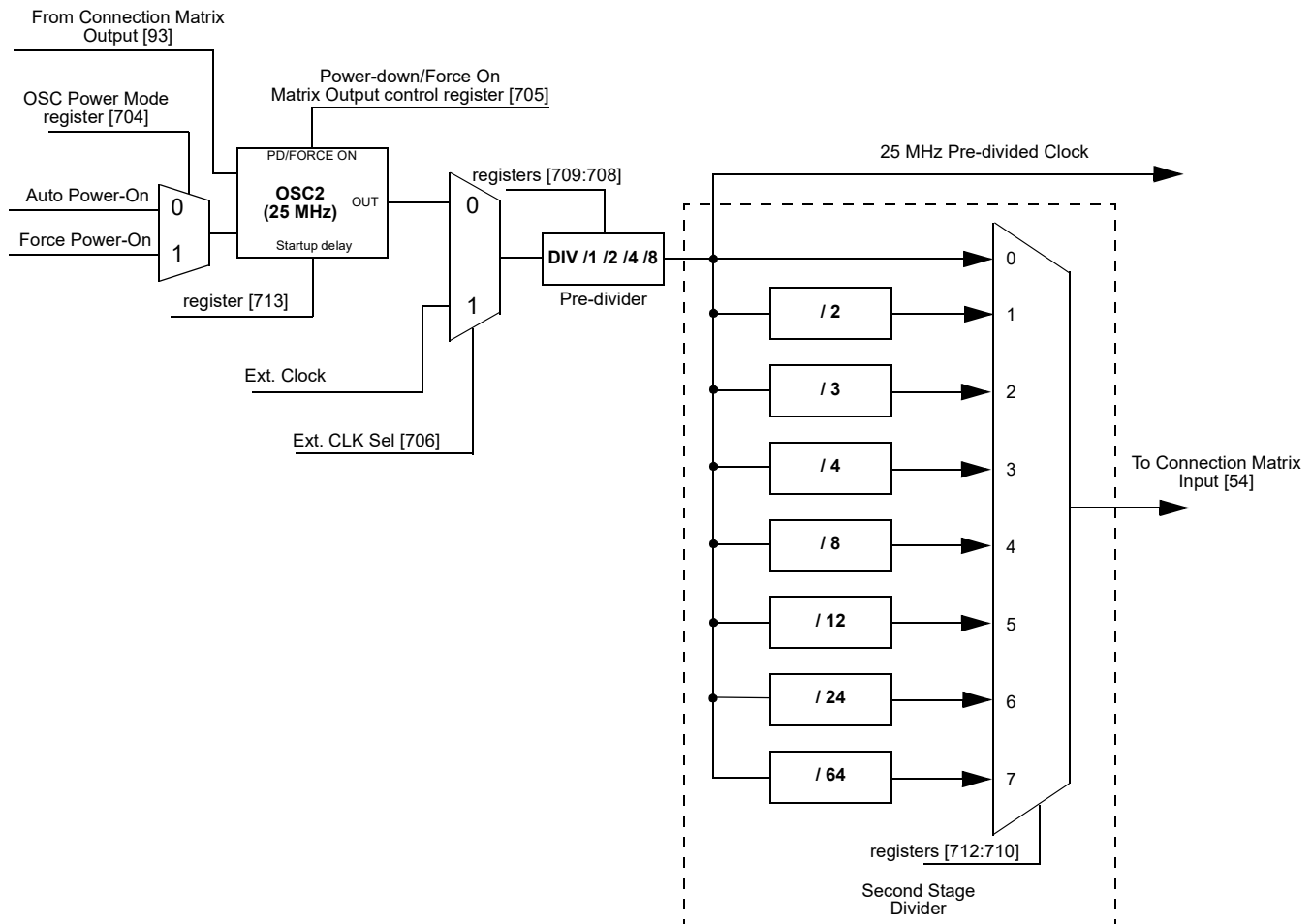


Figure 122: Oscillator2 Block Diagram

16.5 CNT/DLY CLOCK SCHEME

Each CNT/DLY within Multi-Function macrocell has its own additional clock divider connected to oscillators pre-divider. Available dividers are:

- OSC0/1, OSC0/8, OSC0/64, OSC0/512, OSC0/4096, OSC0/32768, OSC0/262144
- OSC1/1, OSC1/8, OSC1/64, OSC1/512
- OSC2/1, OSC2/4

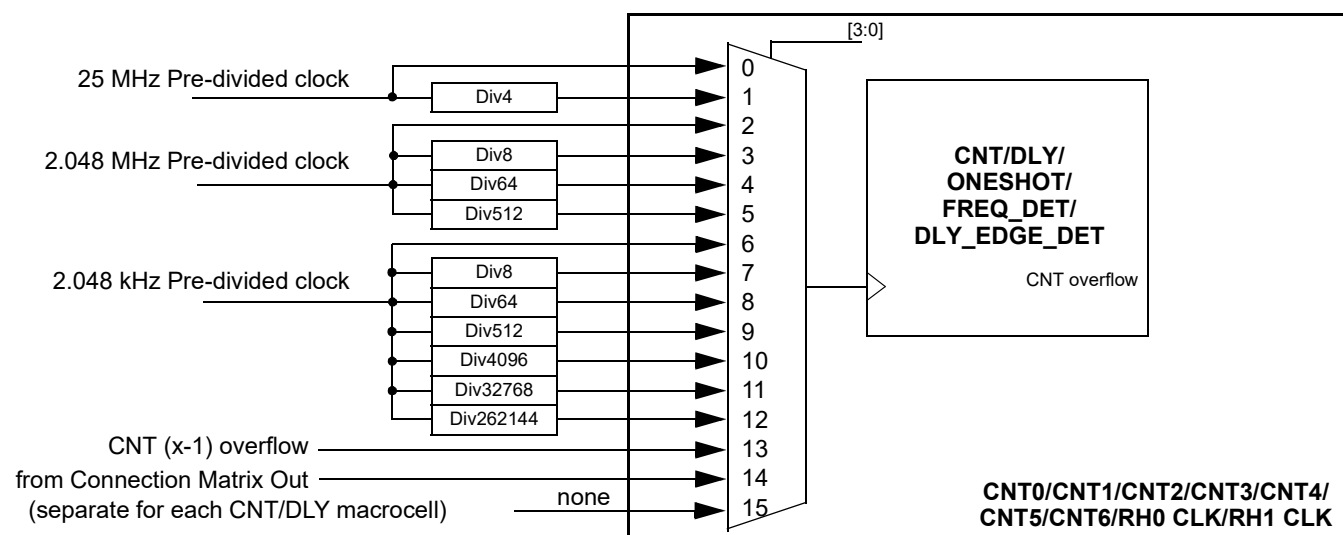


Figure 123: Clock Scheme

16.6 EXTERNAL CLOCKING

The SLG47004 supports several ways to use an external, higher accuracy clock as a reference source for internal operations.

16.6.1 IO1 Source for Oscillator0 (2.048 kHz)

When register [722] is set to 1, an external clocking signal on IO0 will be routed in place of the internal oscillator derived 2.048 kHz clock source. See Figure 120. The high and low limits for frequency that can be selected are 0 MHz and 10 MHz.

16.6.2 IO3 Source for Oscillator1 (2.048 MHz)

When register [690] is set to 1, an external clocking signal on IO1 will be routed in place of the internal oscillator derived 2.048 MHz clock source. See Figure 121. The high and low limits for frequency that can be selected are 0 MHz and 10 MHz.

16.6.3 IO2 Source for Oscillator2 (25 MHz)

When register [706] is set to 1, an external clocking signal on IO2 will be routed in place of the internal oscillator derived 25 MHz clock source. See Figure 122. The external frequency range is 0 MHz to 20 MHz at $V_{DD} = 2.4$ V, 0 MHz to 30 MHz at $V_{DD} = 3.3$ V, 0 MHz to 50 MHz at $V_{DD} = 5.0$ V.

16.7 OSCILLATORS POWER-ON DELAY

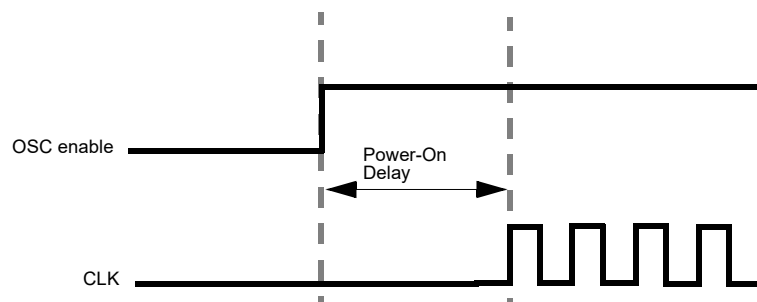


Figure 124: Oscillator Startup Diagram

Note 1 OSC power mode: “Auto Power-On”.

Note 2 “OSC enable” signal appears when any macrocell that uses OSC is powered on

16.8 OSCILLATORS ACCURACY

Note: OSC power setting: Force Power-On; Clock to matrix input - enable; Bandgap: turn on by register - enable.

Note: For more information see Section [3.6](#).

17 Power-On Reset

The SLG47004 has a Power-On Reset (POR) macrocell to ensure correct device initialization and operation of all macrocells in the device. The purpose of the POR circuit is to have consistent behavior and predictable results when the V_{DD} power is first ramping to the device, and also while the V_{DD} is falling during Power-down. To accomplish this goal, the POR drives a defined sequence of internal events that trigger changes to the states of different macrocells inside the device, and finally to the state of the IOs.

17.1 GENERAL OPERATION

The SLG47004 is guaranteed to be powered down and non-operational when the V_{DD} voltage (voltage on PIN13) is less than Power-Off Threshold (see in [Table 6](#)), but not less than -0.6 V. Another essential condition for the chip to be powered down is that no voltage higher (Note) than the V_{DD} voltage is applied to any other PIN. For example, if V_{DD} voltage is 0.3 V, applying a voltage higher than 0.3 V to any other PIN is incorrect, and can lead to incorrect or unexpected device behavior.

Note: There is a 0.6 V margin due to forward drop voltage of the ESD protection diodes.

To start the POR sequence in the SLG47004, the voltage applied on the V_{DD} should be higher than the Power-On Threshold (Note). The full operational V_{DD} range for the SLG47004 is 2.4 V to 5.5 V. This means that the V_{DD} voltage must ramp up to the operational voltage value, but the POR sequence will start earlier, as soon as the V_{DD} voltage rises to the Power-On Threshold. After the POR sequence has started, the SLG47004 will have a typical Startup Time (see in [Table 6](#)) to go through all the steps in the sequence, and will be ready and completely operational after the POR sequence is complete.

Note: The Power-On Threshold is defined in [Table 6](#).

To power down the chip, the V_{DD} voltage should be lower than the operational and to guarantee that chip is powered down, it should be less than Power-Off Threshold.

All PINs are in high impedance state when the chip is powered down and while the POR sequence is taking place. The last step in the POR sequence releases the IO structures from the high impedance state, at which time the device is operational. The pin configuration at this point in time is defined by the design programmed into the chip. Also, as it was mentioned before, the voltage on PINs can't be bigger than the V_{DD} , this rule also applies to the case when the chip is powered on.

17.2 POR SEQUENCE

The POR system generates a sequence of signals that enable certain macrocells. The sequence is shown in Figure 125.

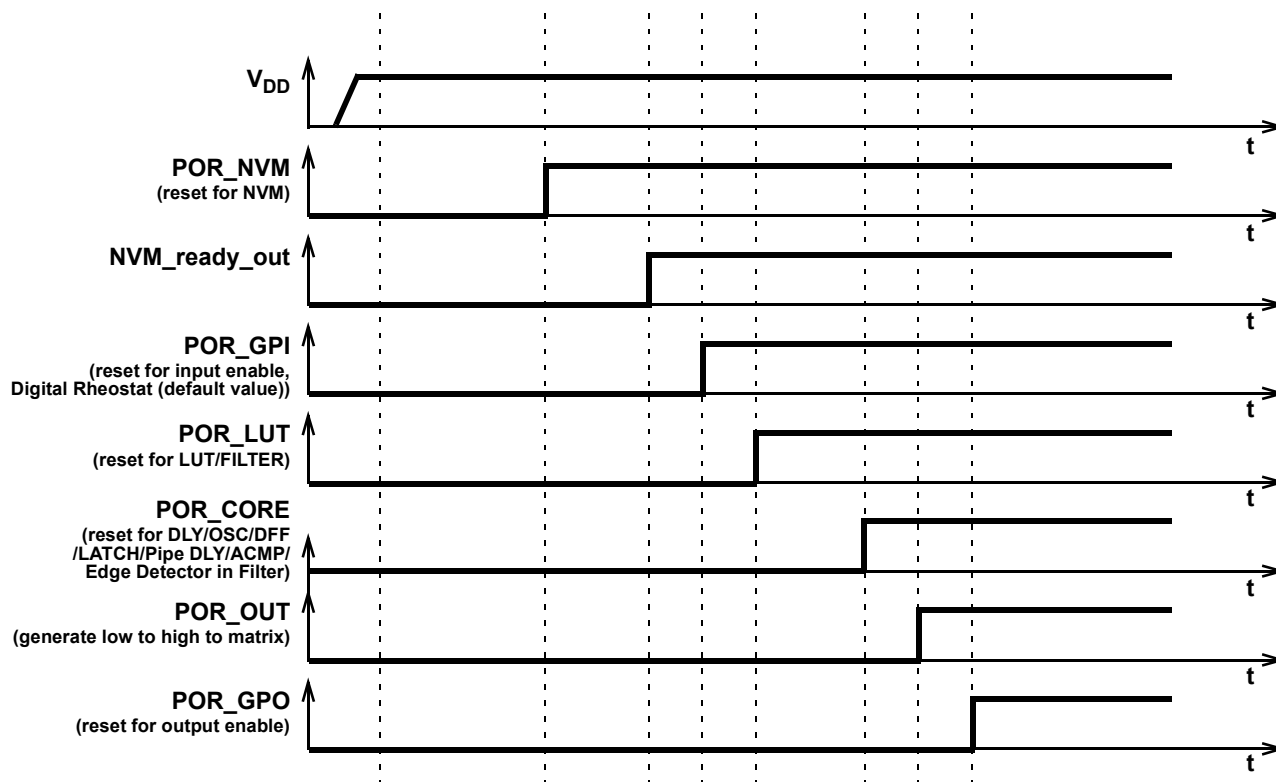


Figure 125: POR Sequence

As can be seen from Figure 125 after the V_{DD} has started ramping up and crossed the Power-On Threshold, first, the on-chip NVM memory is reset. Next, the chip reads the data from NVM and transfers this information to a CMOS LATCH, that serves to configure each macrocell, and the Connection Matrix, which routes signals between macrocells. The third stage causes the reset of the input pins, and then enables them. At that time Digital Rheostats value is set to its default value. After that, the LUTs are reset and become active. After LUTs, the Delay cells, OSCs, DFFs, LATCHES, and Pipe Delay are initialized. Only after all macrocells are initialized, internal POR signal (POR macrocell output) goes from LOW to HIGH (POR_OUT in Figure 125). The last portion of the device to be initialized is the output pins, which transition from high impedance to active at this point.

The typical time that takes to complete the POR sequence varies by device type in the GreenPAK family. It also depends on many environmental factors, such as: slew rate, V_{DD} value, temperature, and even will vary from chip to chip (process influence).

17.3 MACROCELLS OUTPUT STATES DURING POR SEQUENCE

To have a full picture of SLG47004 operation during powering and POR sequence refer to Figure 126, which describes the macrocell output states during the POR sequence.

First, before the NVM has been reset, all macrocells have their output set to logic LOW (except the output pins which are in high impedance state). On the next step, some of the macrocells start initialization: input pins output state becomes LOW; Digital Rheostats value is set to its default value; LUTs also output LOW. After that input pins are enabled. Next, only LUTs are configured. Then, all other macrocells are initialized. After macrocells are initialized, internal POR matrix signal switches from LOW to HIGH. The last are output pins that become active and determined by the input signals.

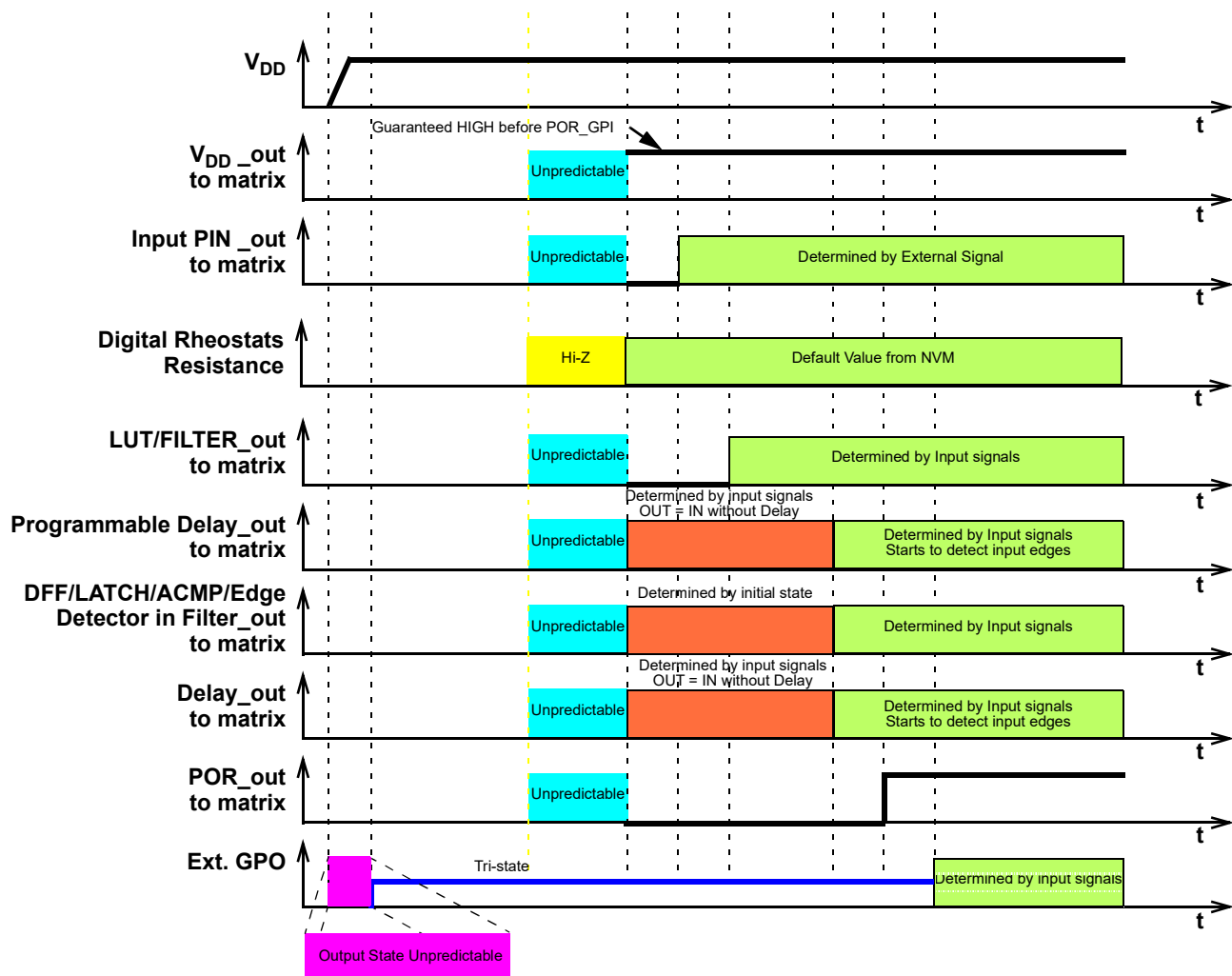


Figure 126: Internal Macrocell States During POR Sequence

17.3.1 Initialization

All internal macrocells by default have initial low level. Starting from indicated power-up time of 1.6 V to 2.07 V, macrocells in SLG47004 are powered on while forced to the reset state. All outputs are in Hi-Z and chip starts loading data from NVM. Then the reset signal is released for internal macrocells and they start to initialize according to the following sequence:

1. Input pins, Pull-up/down, Digital Rheostats, Op Amps.
2. LUTs.
3. DFFs, Delays/Counters, Pipe Delay, OSCs, ACMPs.
4. POR output to matrix.
5. Output pin corresponds to the internal logic.

The Vref output pin driving signal can precede POR output signal going high by 3 μ s to 5 μ s. The POR signal going high indicates the mentioned power-up sequence is complete.

Note: The maximum voltage applied to any pin should not be higher than the V_{DD} level. There are ESD Diodes between pin →

V_{DD} and pin $\rightarrow$ GND on each pin. Exceeding V_{DD} results in leakage current on the input pin, and V_{DD} will be pulled up, following the voltage on the input pin.

17.3.2 Power-Down

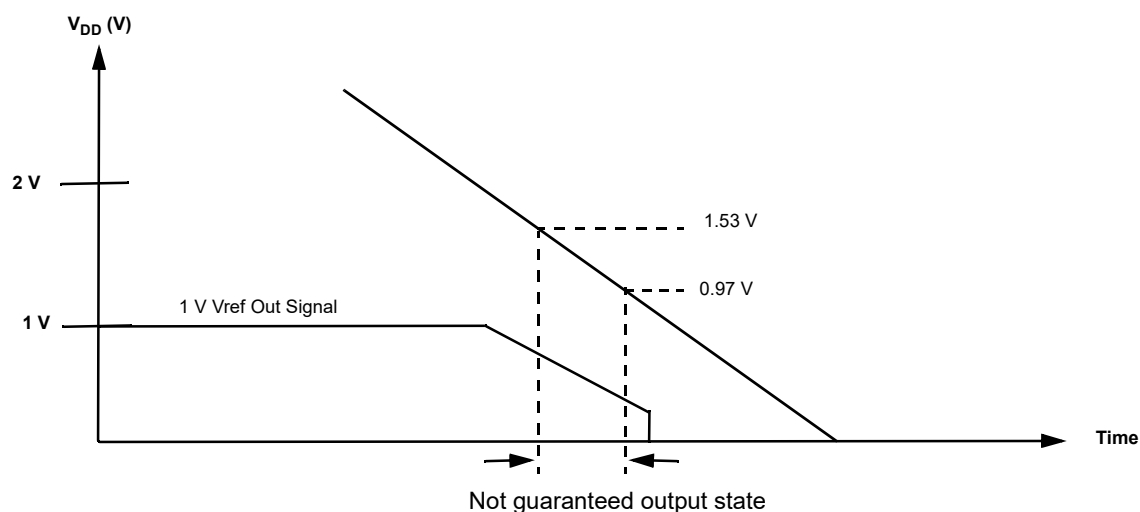


Figure 127: Power-Down

During Power-down macrocells in SLG47004 are powered off after V_{DD} falling down below Power-Off Threshold. Please note, that during a slow rampdown outputs can possibly switch state.

18 I²C Serial Communications Macrocell

18.1 I²C SERIAL COMMUNICATIONS MACROCELL OVERVIEW

In the standard use case for the GreenPAK devices, the configuration choices made by the user are stored as bit settings in the Non-Volatile Memory (NVM), and this information is transferred at startup time to volatile RAM registers that enable the configuration of the macrocells. Other RAM registers in the device are responsible for setting the connections in the Connection Matrix to route signals in the manner most appropriate for the user's application.

The I²C Serial Communications Macrocell in this device allows an I²C bus Master to read and write this information via a serial channel directly to the RAM registers, allowing the remote re-configuration of macrocells, and remote changes to signal chains within the device.

The I²C bus Master is also able to read and write other register bits that are not associated with NVM memory. As an example, the input lines to the Connection Matrix can be read as digital register bits. These are the signal outputs of each of the macrocells in the device, giving the I²C bus Master the capability to remotely read the current value of any macrocell.

The user has the flexibility to control read access and write access via registers bits registers [1795:1792]. See Section 19 for more details on I²C read/write memory protection.

18.2 I²C SERIAL COMMUNICATIONS DEVICE ADDRESSING

Each command to the I²C Serial Communications macrocell begins with a Control Byte. The bits inside this Control Byte are shown in Figure 128. After the Start bit, the first four bits are a control code. Each bit in a control code can be sourced independently from the register or by value defined externally by IO1, IO2, IO3, and IO4. The LSB of the control code is defined by the value of IO1, while the MSB is defined by the value of IO4. The address source (either register bit or PIN) for each bit in the control code is defined by registers [1019:1016]. This gives the user flexibility on the chip level addressing of this device and other devices on the same I²C bus. The default control code is 0001. The Block Address is the next three bits (A10, A9, A8), which will define the most significant bits in the addressing of the data to be read or written by the command. The last bit in the Control Byte is the R/W bit, which selects whether a read command or write command is requested, with a "1" selecting for a Read command, and a "0" selecting for a Write command. This Control Byte will be followed by an Acknowledge bit (ACK), which is sent by this device to indicate successful communication of the Control Byte data.

In the I²C-bus specification and user manual there are two groups of eight addresses (0000 xxx and 1111 xxx) that are reserved for the special functions, such as a system General Call address. If the user of this device chooses to set the Control Code to either "1111" or "0000" in a system with other slave device, please consult the I²C-bus specification and user manual to understand the addressing and implementation of these special functions, to ensure reliable operation.

In the read and write command address structure, there are a total of 11 bits of addressing, each pointing to a unique byte of information, resulting in a total address space of 2K bytes. The valid addresses are shown in the memory map in Figure 138.

With the exception of the Current Address Read command, all commands will have the Control Byte followed by the Word Address.

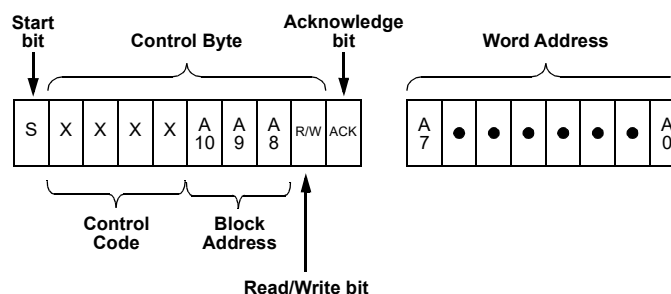


Figure 128: Basic Command Structure

18.3 I²C SERIAL GENERAL TIMING

General timing characteristics for the I²C Serial Communications macrocell are shown in Figure 129. Timing specifications can be found in the AC Characteristics, section 3.4.

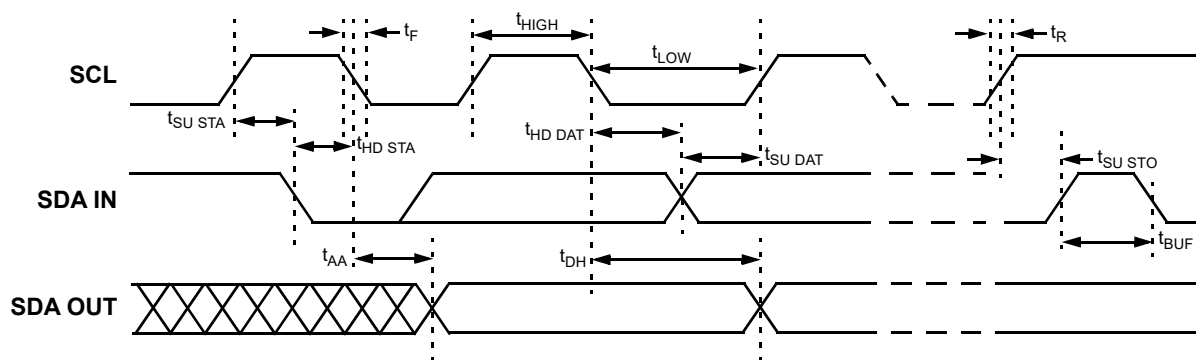


Figure 129: I²C General Timing Characteristics

18.4 I²C SERIAL COMMUNICATIONS COMMANDS

18.4.1 Byte Write Command

Following the Start condition from the Master, the Control Code [4 bits], the Block Address [3 bits], and the R/W bit (set to "0") are placed onto the I²C bus by the Master. After the SLG47004 sends an Acknowledge bit (ACK), the next byte transmitted by the Master is the Word Address. The Block Address (A10, A9, A8), combined with the Word Address (A7 through A0), together set the internal address pointer in the SLG47004, where the data byte is to be written. After the SLG47004 sends another Acknowledge bit, the Master will transmit the data byte to be written into the addressed memory location. The SLG47004 again provides an Acknowledge bit and then the Master generates a Stop condition. The internal write cycle for the data will take place at the time that the SLG47004 generates the Acknowledge bit.

It is possible to latch all IOs during I²C write command to the register configuration data (block address A10, A9, A8 = 000), register [985] = 1 - Enable. It means that IOs will remain their state until the write command is done.

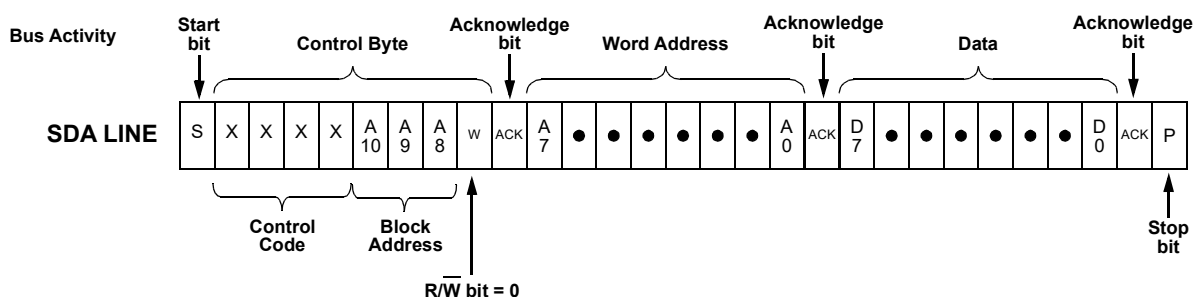


Figure 130: Byte Write Command, $R/\overline{W} = 0$

18.4.2 Sequential Write Command

The write Control Byte, Word Address, and the first data byte are transmitted to the SLG47004 in the same way as in a Byte Write command. However, instead of generating a Stop condition, the Bus Master continues to transmit data bytes to the SLG47004. Each subsequent data byte will increment the internal address counter, and will be written into the next higher byte in the command addressing. As in the case of the Byte Write command, the internal write cycle will take place at the time that the SLG47004 generates the Acknowledge bit.

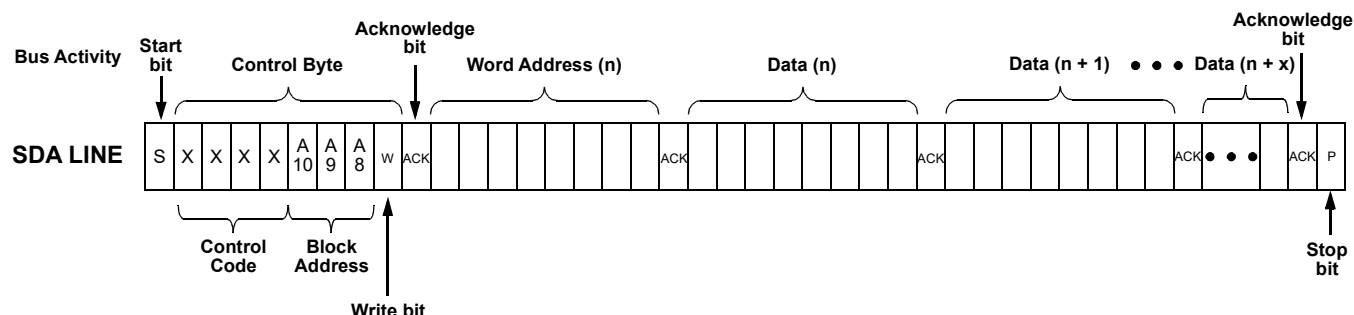


Figure 131: Sequential Write Command

18.4.3 Current Address Read Command

The Current Address Read Command reads from the current pointer address location. The address pointer is incremented at the first STOP bit following any write control byte. For example, if a Sequential Read command (which contains a write control byte) reads data up to address n , the address pointer would get incremented to $n + 1$ upon the STOP of that command. Subsequently, a Current Address Read that follows would start reading data at $n + 1$. The Current Address Read Command contains the Control Byte sent by the Master, with the R/W bit = "1". The SLG47004 will issue an Acknowledge bit, and then transmit eight data bits for the requested byte. The Master will not issue an Acknowledge bit, and follow immediately with a Stop condition.

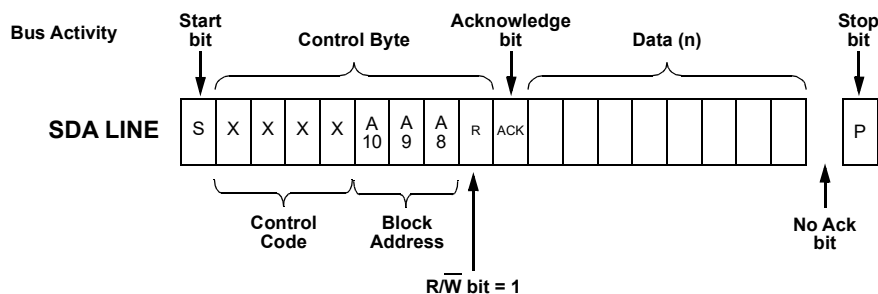


Figure 132: Current Address Read Command, $\overline{R/W} = 1$

18.4.4 Random Read Command

The Random Read command starts with a Control Byte (with R/W bit set to "0", indicating a write command) and Word Address to set the internal byte address, followed by a Start bit, and then the Control Byte for the read (exactly the same as the Byte Write command). The Start bit in the middle of the command will halt the decoding of a Write command, but will set the internal address counter in preparation for the second half of the command. After the Start bit, the Bus Master issues a second control byte with the R/W bit set to "1", after which the SLG47004 issues an Acknowledge bit followed by the requested eight data bits.

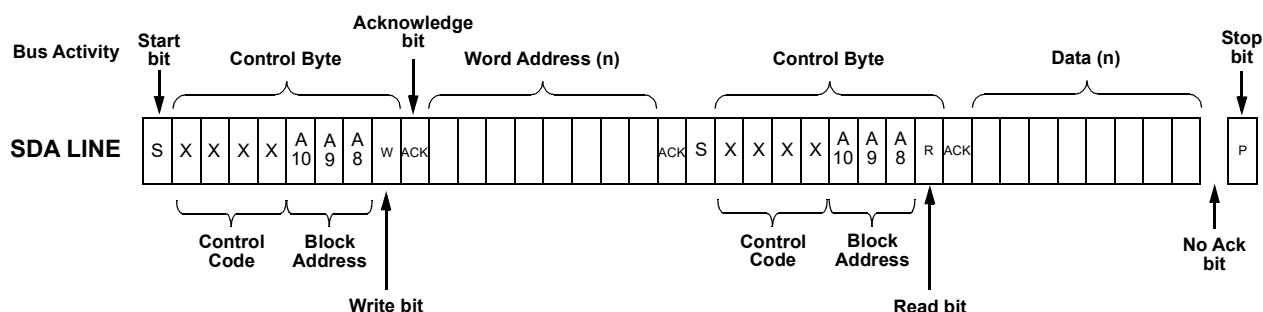


Figure 133: Random Read Command

18.4.5 Sequential Read Command

The Sequential Read command is initiated in the same way as a Random Read command, except that once the SLG47004 transmits the first data byte, the Bus Master issues an Acknowledge bit as opposed to a Stop condition in a random read. The Bus Master can continue reading sequential bytes of data, and will terminate the command with a Stop condition.

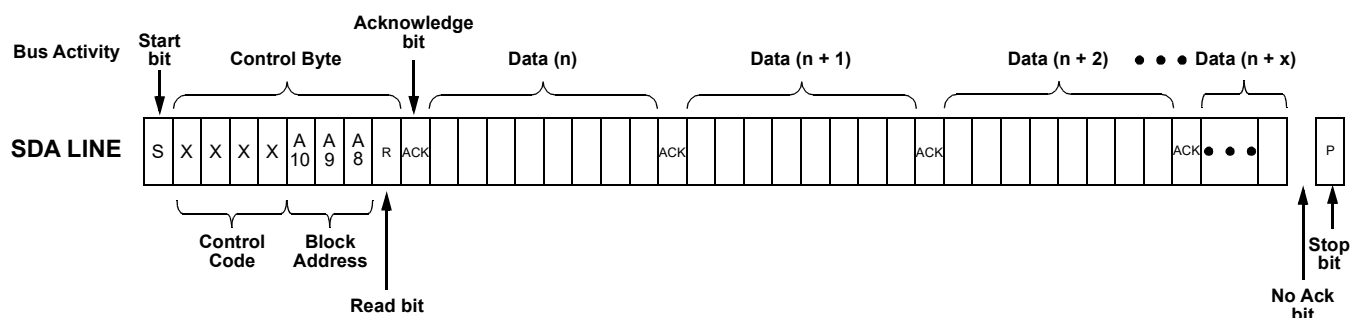


Figure 134: Sequential Read Command

18.4.6 I²C Serial Reset Command

If I²C serial communication is established with the device, it is possible to reset the device to initial power up conditions, including configuration of all macrocells and all connections provided by the Connection Matrix. This is implemented by setting register [984] I²C reset bit to "1", which causes the device to re-enable the Power-On Reset (POR) sequence, including the reload of all register data from NVM. During the POR sequence, the outputs of the device will be in tri-state. After the reset has taken place, the contents of register [984] will be set to "0" automatically. The [Figure 135](#) illustrates the sequence of events for this reset function.

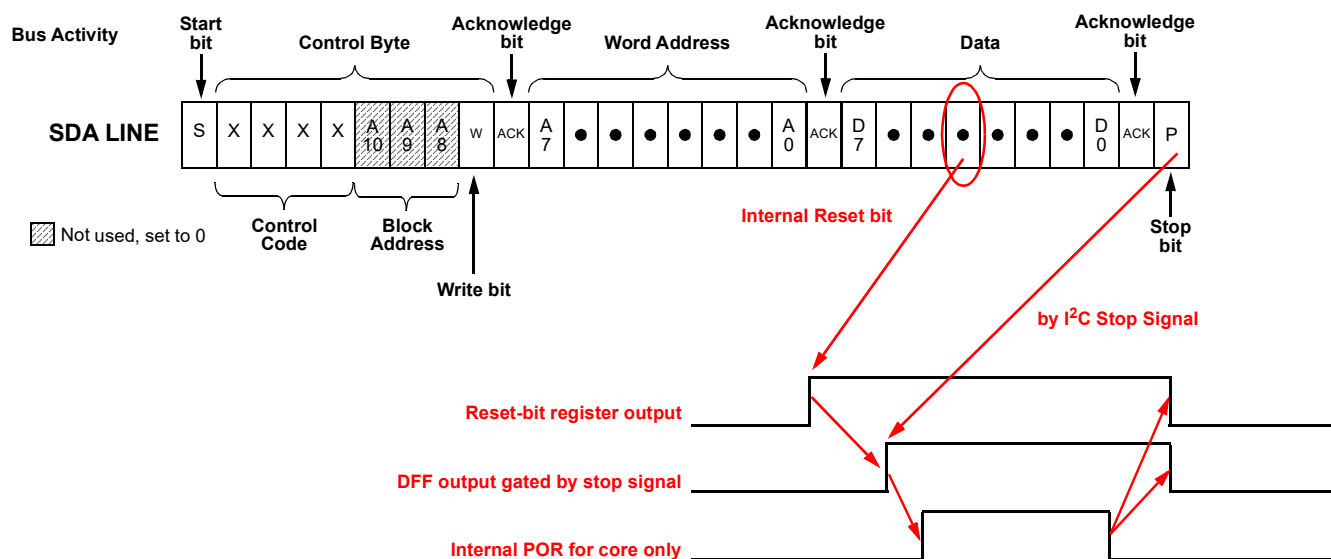


Figure 135: Reset Command Timing

18.5 CHIP CONFIGURATION DATA PROTECTION

The SLG47004 utilizes a scheme that allows a portion or the entire Register and NVM to be inhibited from being read or written/erased. There are two bytes that define the register and NVM access or change. The second byte NPR defines the chip NVM data configuration read and write protection. The first byte RPR defines the register read and write protection. If desired, the protection lock bit (PRL) can be set so that protection may no longer be modified, thereby making the current protection scheme permanent. The status of the RPR and NPR can be determined by following a Random Read sequence. Changing the state of the RPR and NPR is accomplished with a Byte Write sequence with the requirements outlined in this section.

Special care must be taken when NVM page 14 is rewritten (registers [1919:1792]). This page contains rheostats tolerance data that can be permanently lost during write/erase operation.

The RPR register is located on H'E0 address, while NPR is located on H'E1 address.

The RPR format is shown in Table 59, and the RPR bit functions are included in Table 60.

Table 59: RPR Format

	b7	b6	b5	b4	b3	b2	b1	b0
RPR				RH_PRB	RPRB3	RPRB2	RPRB1	RPRB0

Table 60: RPR Bit Function Description

Bit	Name		Type	Description
4	RH_PRB	--	R/W*	0: Program signal from connection matrix is enabled 1: Program signal from connection matrix is disabled
3:2	RPRB3	2k Register Write Selection Bits	R/W*	00: 2k register data is unprotected for write; 01: 2k register data is partly protected for write; Please refer to the Table 63. 10: 2k register data is fully protected for write.
	RPRB2		R/W*	

Table 60: RPR Bit Function Description(Continued)

Bit	Name		Type	Description
1:0	RPRB1	2k Register Read Selection Bits	R/W*	00: 2k register data is unprotected for read; 01: 2k register data is partly protected for read; Please refer to the Table 63 . 10: 2k register data is fully protected for read.
	RPRB0		R/W*	

* Becomes read only after PRL is high. The content is permanently locked for write and erase after PRL is high.

The NPR format is shown in [Table 61](#), and the NPR bit functions are included in [Table 62](#).

Table 61: NPR Format

	b7	b6	b5	b4	b3	b2	b1	b0
NPR							NPRB1	NPRB0

Table 62: NPR Bit Function Description

Bit	Name		Type	Description
1:0	NPRB1	2k NVM Configuration Selection Bits	R/W*	00: 2k NVM Configuration data is unprotected for read and write/erase; 01: 2k NVM Configuration data is fully protected for read; 10: 2k NVM Configuration data is fully protected for write/erase; 11: 2k NVM Configuration data is fully protected for read and write/erase.
	NPRB0		R/W*	

* Becomes read only after PRL is high. The content is permanently locked for write and erase after PRL is high.

The protection selection bits allow different levels of protection of the register and NVM Memory Array.

There is a dedicated bit RH_PRB, that enables/disables "Program" signal of PT block to change NVM rheostats resistance values. If RH_PRB [1796] = 0, "Program" signal is enabled. If RH_PRB [1796] = 1, "Program" signal is disabled. Note that RH_PRB bit has no effect on I²C access to NVM. To enable/disable I²C access to rheostat resistance value, stored in NVM, user must change NPRB0, NPRB1 bits.

The Protect Lock Bit (PRL) is used to permanently lock (for write and erase) the current state of the RPR and NPR, as well as EEPROM protection. A Logic 0 indicates that the protection byte can be modified, whereas a Logic 1 indicates the byte has been locked and can no longer be modified.

In this case it is impossible to erase the whole page E with protection bytes. The PRL is located at E4 address (register [1824]).

18.6 I²C SERIAL COMMAND REGISTER MAP

There are nine read/write protect modes for the design sequence from being corrupted or copied. See [Table 63](#) for details.

Table 63: Read/Write Register Protection Options

Configurations	Protection Modes Configuration									Test Mode	Register Address
	Unlock	Partly Lock Read	Partly Lock Write	Partly Lock Read/Write	Partly Lock Read & Lock Write	Lock Read & Partly Lock Write	Lock Read	Lock Write	Lock Read/Write		
RPR[1:0]	00	01	00	01	01	10	10	00	10		
RPR[3:2]	00	00	01	01	10	01	00	10	10		
I ² C Byte Write Bit Masking (section 18.7.2)	R/W	R/W	R/W	R/W	R	W	W	R	-	-	F6
I ² C Serial Reset Command (section 18.4.6)	R/W	R/W	R/W	R/W	R	W	W	R	-	-	7Bb'0
Outputs Latching During I ² C Write (section 18.7)	R/W	R/W	R/W	R/W	R	W	W	R	-	-	7Bb'1
Connection Matrix Virtual Inputs (section 6.3)	R/W	R/W	R/W	R/W	R	W	W	R	-	-	7C
Service page lock	R	R	R	R	R	R	R	R	R	R	F3b'0
RH0_CNT Data	R/W	R/W	R/W	R/W	R	W	W	R	-	-	C0,C1
RH1_CNT Data	R/W	R/W	R/W	R/W	R	W	W	R	-	-	D0,D1
Macrocells Output Values (Connection Matrix Inputs, section 6.3)	R	R	R	R	R	-	-	R	-	R	C4~CA
Counter Current Value	R	R	R	R	R	-	-	R	-	R	CB~CE
RH0_CNT Value	R	R	R	R	R	R	R	R	R	R	C2,C3
RH1_CNT Value	R	R	R	R	R	R	R	R	R	R	D2,D3
Protection Mode Selection (sections 18.6, 19.6)	R/W	R/W	R	R	R	R	R/W	R	R	R	E4'b0
Protect Mode Config (RH_PRB,RPR, NPR,WPR)	R/W*	R/W*	R/W*	R/W*	R/W*	R/W*	R/W*	R/W*	R/W*	R/W*	E0, E1, E2
I ² C Slave Address	R/W	R/W	R	R	R	R	R/W	R	R	R	7Fb'3~7Fb'0
Pin slave address select	R/W	R/W					R/W				7Fb'7~7Fb'4
RH0 Tolerance Data	R	R	R	R	R	R	R	R	R	R	E6,E7
RH1 Tolerance Data	R	R	R	R	R	R	R	R	R	R	E8,E9
Page Erase byte	W**	W**	W**	W**	W**	W**	W**	W**	W**	W**	E3
Macrocells Inputs Configuration (Connection Matrix Outputs)	R/W	W	R	-	-	-	W	R	-	-	

Table 63: Read/Write Register Protection Options(Continued)

Configurations	Protection Modes Configuration									Test Mode	Register Address
	Unlock	Partly Lock Read	Partly Lock Write	Partly Lock Read/Write	Partly Lock Read & Lock Write	Lock Read & Partly Lock Write	Lock Read	Lock Write	Lock Read/Write		
RPR[1:0]	00	01	00	01	01	10	10	00	10		
RPR[3:2]	00	00	01	01	10	01	00	10	10		
Configuration Bits for All Macrocells (IOs, ACMPs, Combination Function Macrocells, and others)	R/W	W	R	-	-	-	W	R	-	-	
Matrix Output Selection	R/W	W	R	-	-	-	W	R	-	-	00~4A (4B rev)

R/W	Allow Read and Write Data
W	Allow Write Data Only
W**	Pages that can be erased are defined by NVM write protection
R	Allow Read Data Only
-	The Data is protected for Read and Write

Note 1 R/W becomes read only if protection mode selection (lock bit) is set to 1.

Note 2 R/W Readable/writable depend on the "Trim mode enable" bit. If "Trim mode enable" bit value = 1, then trim bits are enable.

It is possible to read some data from macrocells, such as counter current value, connection matrix, and connection matrix virtual inputs. The I²C write will not have any impact on data in case data comes from macrocell output, except Connection Matrix Virtual Inputs. The silicon identification service bits allow identifying silicon family, its revision, and others.

R/W* - Becomes read only after PRL is high.

See Section 21 for detailed information on all registers.

18.7 I²C ADDITIONAL OPTIONS

When Output latching during I²C write to the register configuration data (block address A10, A9, A8 = 000), registers [985] = 1 allows all PINs output value to be latched while register content is changing. It will protect the output change due to configuration process during I²C write in case multiple register bytes are changed. Inputs and internal macrocells retain their status during I²C write.

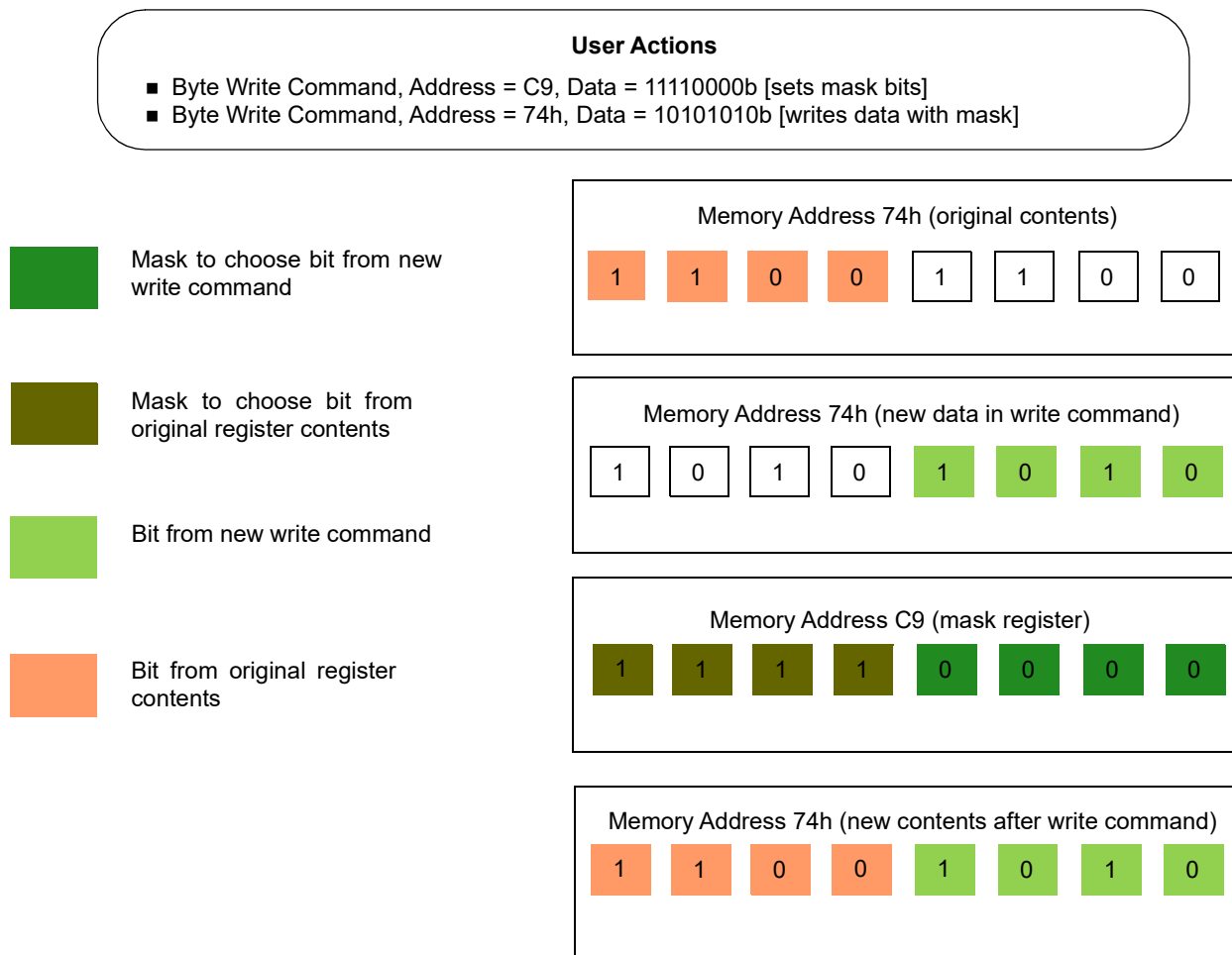
See Section 21 for detailed information on all registers.

18.7.1 Reading Counter Data via I²C

The current count value in three counters in the device can be read via I²C. The counters that have this additional functionality are 16-bit CNT0, and 8-bit counters CNT2 and CNT4.

18.7.2 I²C Byte Write Bit Masking

The I²C macrocell inside SLG47004 supports masking of individual bits within a byte that is written to the RAM memory space. This function is supported across the entire RAM memory space. To implement this function, the user performs a Byte Write Command (see Section 18.4.1 for details) on the I²C Byte Write Mask Register (address 0F6H) with the desired bit mask pattern. This sets a bit mask pattern for the target memory location that will take effect on the next Byte Write Command to this register byte. Any bit in the mask that is set to “1” in the I²C Byte Write Mask Register will mask the effect of changing that particular bit in the target register, during the next Byte Write Command. The contents of the I²C Byte Write Mask Register are reset (set to 00h) after valid Byte Write Command. If the next command received by the device is not a Byte Write Command, the effect of the bit masking function will be aborted, and the I²C Byte Write Mask Register will be reset with no effect. Figure 136 shows an example of this function.

Figure 136: Example of I²C Byte Write Bit Masking

19 Non-Volatile Memory

The SLG47004 provides 2,048 bits of Serial Electrically Erasable Configuration Register memory that is used for device configuration, and 2,048 bits Programmable Read-Only Memory (emulated EEPROM). Each of these memory spaces is internally organized as 16 pages of 16 bytes. The device features a Software Write Protection feature with five different programmable levels of protection for the emulated EEPROM array. The protection settings of the device can be made permanent if desired. The emulated EEPROM memory operates with a supply voltage ranging from 2.4 V to 5.5 V for Read and 2.5 V to 5.5 V for Write.

The emulated EEPROM inside the SLG47004 operates as a slave device and utilizes a simple I²C compatible 2-wire digital serial interface to communicate with a host controller commonly referred to as the bus Master. The Master initiates and controls all read and write operations to the Slave devices on the serial bus, and both the Master and the Slave devices can transmit and receive data on the bus.

Key features:

- Low-voltage Operation
 - for Read: VCC = 2.4 V to 5.5 V
 - for Write: VCC = 2.5 V to 5.5 V
- I²C-Compatible (2-Wire) Serial Interface
 - 100 kHz Standard Mode
 - 400 kHz Fast Mode (FM)
- Software Write Protection of the EEPROM Emulation Array
 - Five configuration options
 - Protection settings can be made permanent
- Low Current Consumption
 - Read Current 0.5 mA max
 - Page Write Current 3.0 mA max
 - Chip Erase Current 3.0 mA max
 - Standby Current (1.0 μ A max)
- 16-byte Page Write Mode
- Self-timed Write/Erase Cycle (20 ms max)
- Reliability
 - Endurance: 1,000 write cycles
 - Data retention: 10 years at 125 °C

19.1 SERIAL NVM WRITE OPERATIONS

Write access to the NVM is possible by setting A3, A2, A1, A0 to “0000”, which allows serial write data for a single page only. Upon receipt of the proper Control Byte and Word Address bytes, the SLG47004 will send an ACK. The device will then be ready to receive page data, which is 16 sequential writes of 8-bit data words. The SLG47004 will respond with an ACK after each data word is received. The addressing device, such as a bus Master, must then terminate the write operation with a Stop condition after all page data is written. At that time the device will enter an internally self-timed write cycle, which will be completed within t_{WR} (20 ms). While the data is being written into the NVM Memory Array, all inputs, outputs, internal logic, and I²C access to the Register data will be operational/valid. Please refer to [Figure 138](#) for the SLG47004 Memory Map.

Note: The 16 programmed bytes should be in the same page. Any I²C command that does not meet specific requirements will be ignored and NVM will remain unprogrammed.

Note: Special care must be taken when NVM page 14 is rewritten (registers [1919:1792]). This page contains rheostats tolerance data that can be permanently lost during write/erase operation.

SLG47004 will ignore the Serial NVM Write command in case the self-programming procedure for programming rheostat value into the NVM is in progress. The SLG47004 will respond with NACK in this case. Please refer to the Acknowledge Polling section for more details.

Data "1" cannot be re-programmed as data "0" without erasure. Each byte can only be programmed one time without erasure.

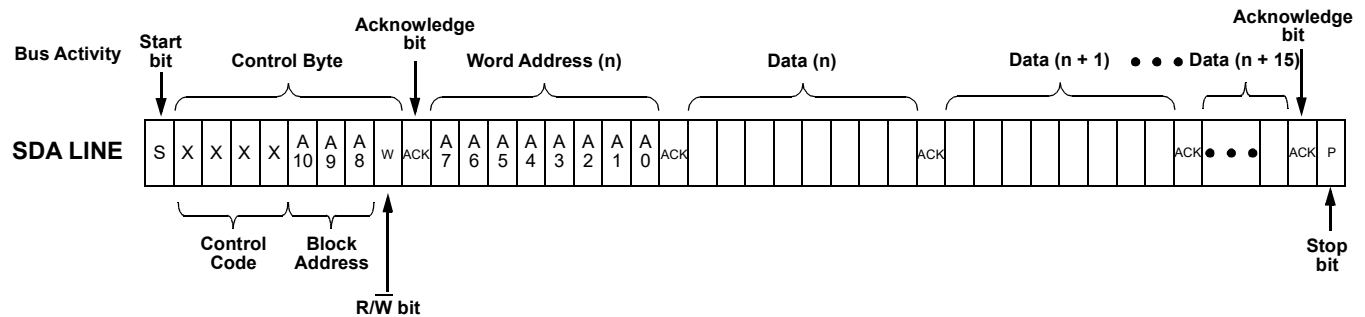


Figure 137: Page Write Command

A10 will be ignored during communication to SLG47004.

A9 = 1 will enable access to the NVM.

A9 = 1 and A8 = 0 corresponds to the 2K bits chip configuration NVM data.

A9 = 1 and A8 = 1 corresponds to the 2K bits of emulated EEPROM data.

A3, A2, A1, and A0 should be 0000 for the page write operation.

In a single page, if the data written to any byte is 00H, the contents of the matching byte in NVM memory will not be altered.

Lowest I ² C Address = 000h	I ² C Block Address			Memory Space
	A10 = 0	A9 = 0	A8 = 0	2 kbits Register Data Configuration
	A10 = 0	A9 = 0	A8 = 1	Not Used
	A10 = 0	A9 = 1	A8 = 0	2 kbits NVM Data Configuration
	A10 = 0	A9 = 1	A8 = 1	2 kbits EEPROM
	A10 = 1	A9 = X	A8 = X	Not Used
Highest I ² C Address = 7FFh				

Figure 138: I²C Block Addressing

19.2 SERIAL NVM READ OPERATIONS

There are three read operations:

- Current Address Read
- Random Address Read
- Sequential Read

Please refer to the Section 18 for more details.

19.3 SERIAL NVM ERASE OPERATIONS

The erase scheme allows a portion or the entire emulated EEPROM including the 2K bits NVM chip configuration to be erased by modifying the contents of the Erase Registers (ERSE <2:0>). Changing the state of the ERSE is accomplished with a Byte Write sequence with the requirements outlined in this section.

The ERSE registers are located on byte E3h.

The ERSE format is shown in [Table 64](#), and the ERSE bit functions are included in [Table 65](#).

Table 64: Erase Register Bit Format

	b7	b6	b5	b4	b3	b2	b1	b0
Page Erase Register	ERSE2	ERSE1	ERSE0	ERSEB4	ERSEB3	ERSEB2	ERSEB1	ERSEB0

Table 65: Erase Register Bit Function Description

Bit	Name	Type	Description
7	ERSE2	W	000: erase disable 110: cause the NVM erase: full NVM (4k bits) erase for ERSCHIP = 1 if DIS_ERCHIP = 0 or page erase for ERSCHIP = 0
6	ERSE1		
5	ERSE0		
4	ERSEB4	W	Define the page address, which will be erased: ERSB4 = 0 corresponds to the Upper 2K NVM used for chip configuration; ERSB4 = 1 corresponds to the 2-k emulated EEPROM
3	ERSEB3		
2	ERSEB2		
1	ERSEB1		
0	ERSEB0		

Upon receipt of the proper Device Address and Erase Registers Address, the SLG47004 will send an ACK. The device will then be ready to receive Erase Registers data. The SLG47004 will respond with an ACK after Erase Registers data word is received. The addressing device, such as a bus Master, must then terminate the write operation with a Stop condition. At that time the device will enter an internally self-timed erase cycle, which will be completed within t_{ER} ms. While the data is being written into the Memory Array, all inputs, outputs, internal logic, and I²C access to the Register data will be operational/valid.

After the erase has taken place, the contents of ERSE bits will be set to "0" automatically. The internal erase cycle will be triggered at the time the Stop Bit in the I²C command is received.

19.4 ACKNOWLEDGE POLLING

An Acknowledge Polling routine can be implemented to optimize time sensitive applications that would prefer not to wait the fixed maximum write cycle time (t_{WR}) or erase maximum cycle time (t_{ER}). This method allows the application to know immediately when the Serial EEPROM emulation write/erase cycle has completed, so a subsequent operation can be started. Once the internally self-timed write/erase cycle has started, an Acknowledge Polling routine can be initiated. This involves repeatedly sending a Start condition followed by a valid Device Address byte (NVM block address) with the R/W bit set at Logic 0. The device will not respond with an ACK while the write cycle is ongoing. Once the internal write/erase cycle has completed, emulated EEPROM will respond with an ACK, allowing a new read, erase, or write operation to be immediately initiated.

The same behavior will happen during the self-programming procedure when the rheostat value is written into the NVM.

The length of the self-timed write cycle (t_{WR}) and self-timed erase cycle (t_{ER}) is defined as the amount of time from the Stop condition that begins the internal write operation to the Start condition of the first Device Address byte that includes NVM address (A9 = 1; A8 = X) sent to the SLG47004, that it subsequently responds to with an ACK.

19.5 LOW POWER STANDBY MODE

Emulated EEPROM inside the SLG47004 has a low power standby mode which is enabled when any one of the following occurs:

- A valid power-up sequence is performed
- A Stop condition is received by the devices unless it initiates an internal write/erase cycle
- At the completion of an internal write/erase cycle
- An unsuccessful match of the device type identifier or hardware address in the Device Address byte occurs

19.6 EMULATED EEPROM WRITE PROTECTION

The SLG47004 utilizes a software scheme that allows a portion or the entire emulated EEPROM to be inhibited from being written or erased by modifying the contents of the Write Protection Register (WPR). If desired, the WPR can be set so that it may no longer be modified/erased, thereby making the current protection scheme permanent. The status of the WPR can be determined by following a Random Read sequence. Changing the state of the WPR is accomplished with a Byte Write sequence with the requirements outlined in this section.

The WPR register is located at E2 Address.

The WPR format is shown in [Table 66](#), and the WPR bit functions are included in [Table 67](#).

Table 66: Write/Erase Protect Register Format

	b7	b6	b5	b4	b3	b2	b1	b0
WPR						WPRE	WPB1	WPB0

Table 67: Write/Erase Protect Register Bit Function Description

Bit	Name		Type	Description
2	WPRE	Write Protect Register Enable	R/W	0: No Software Write Protection enabled (default) 1: Write Protection is set by the state of WPB [1:0] bits
1:0	WPB1	Write Protect Block Bits	R/W	00: Upper quarter of emulated EEPROM is write protected (default)
	WPB0		R/W	01: Upper half of emulated EEPROM is write protected 10: Upper 3/4 of emulated EEPROM is write protected. 11: Entire emulated EEPROM is write protected.

Write Protect Enable (WPRE): The Write Protect Enable Bit is used to enable or disable the device Software Write/Erase Protect. A Logic 0 in this position will disable Software Write/Erase Protection, and a Logic 1 will enable this function.

Write Protect Block Bits (WPB1:WPB0): The Write Protect Block bits allow four levels of protection of the Memory Array, provided that the WPRE bit is a Logic 1. If the WPRE bit is a Logic 0, the state of the WPB1:0 bits have no impact on device protection.

Protect Lock Bit (PRL): The Protect Lock Bit is used to permanently lock the current state of the WPR, as well as RPR and NPR (see [Section 18.5](#)). A Logic 0 indicates that the WPR, RPR, and NPR can be modified, whereas a Logic 1 indicates the WPR, RPR, and NPR has been locked and can no longer be modified. The PRL register bit is located at register [1824] address.

20 Analog Temperature Sensor

The SLG47004 has an Analog Temperature sensor (TS) with an output voltage linearly-proportional to the Centigrade temperature. The TS cell shares buffer with Vref 0, so it is impossible to use both cells simultaneously, its output can be connected directly to the IO0 or IO1 or the ACPM1_L positive input. Using buffer causes low-output impedance, linear output and makes interfacing to readout or control circuitry especially easy. Vref0 and Vref1 share output buffers with Temperature sensor. Note, that user can use any of output buffers, but Temperature sensor is calibrated for Vref1 output buffer. The TS is rated to operate over a -40 °C to 85 °C temperature range. The error in the whole temperature range does not exceed $\pm 1.76\%$. For more details refer to Section 3.10.

$$V_{TS1} = -2.3 \times T + 907.4$$

$$V_{TS2} = -2.8 \times T + 1095.4$$

where:

V_{TS1} (mV) - TS Output Voltage, range 1

V_{TS2} (mV) - TS Output Voltage, range 2

T (°C) - Temperature

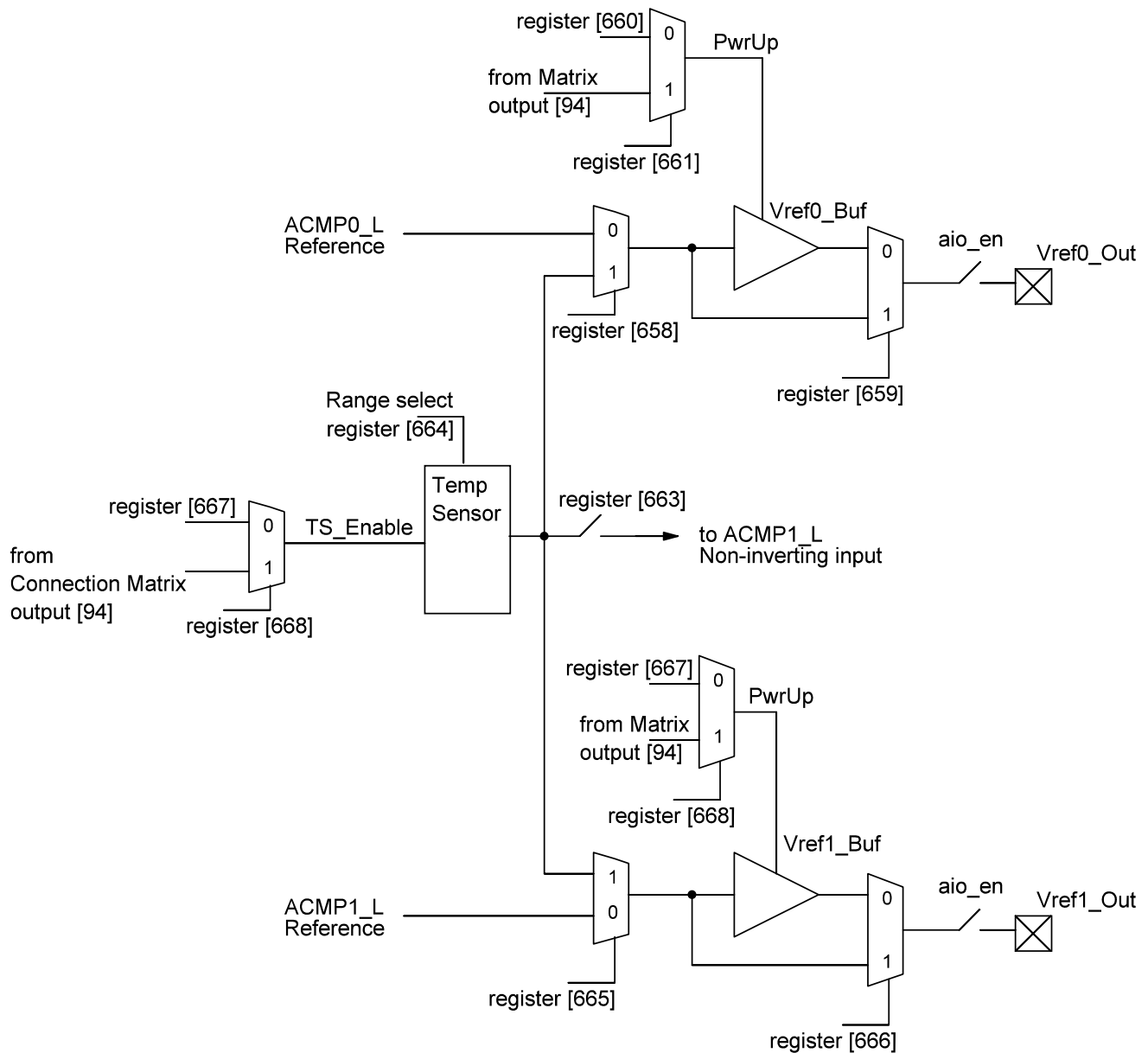
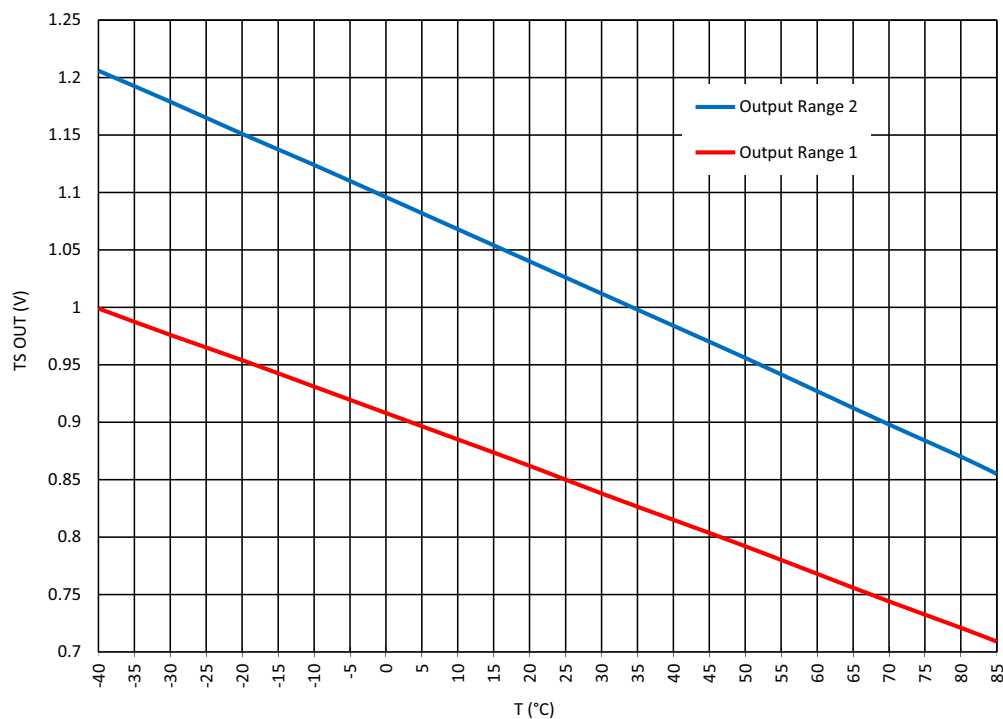


Figure 139: Analog Temperature Sensor Structure Diagram

Figure 140: TS Output vs. Temperature, $V_{DD} = 3.3\text{ V}$

21 Register Definitions

21.1 REGISTER MAP

Table 68: Register Map

Address		Signal Function	Register Bit Definition	I ² C Interface		
Byte	Register Bit			Read	Write	
Matrix Output						
0	0	LUT2_0 & DFF0	OUT0: IN0 of LUT2_0 or Clock Input of DFF0			
	1					
	2					
	3					
	4					
	5					
	6					
	7					
1	8	LUT2_1 & DFF1	OUT1: IN1 of LUT2_0 or Data Input of DFF0			
	9					
	10					
	11					
	12					
	13					
	14					
	15					
2	16	LUT2_1 & DFF1	OUT2: IN0 of LUT2_1 or Clock Input of DFF1			
	17					
	18					
	19					
	20			OUT3: IN1 of LUT2_1 or Data Input of DFF1		
	21					
	22					
	23					
3	24	LUT2_2 & DFF2	OUT4: IN0 of LUT2_2 or Clock Input of DFF2			
	25					
	26					
	27					
	28					
	29					
	30					
	31					
4	32	LUT2_3 & PGen	OUT5: IN1 of LUT2_2 or Data Input of DFF2			
	33					
	34					
	35					
	36					
	37			OUT6: IN0 of LUT2_3 or Clock Input of PGen		
	38					
	39					

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface		
Byte	Register Bit			Read	Write	
5	40	LUT2_3 & PGen	OUT6: IN0 of LUT2_3 or Clock Input of PGen			
	41					
	42		OUT7: IN1 of LUT2_3 or nRST of PGen			
	43					
	44					
	45					
	46					
	47					
6	48	LUT3_0 & DFF3	OUT8: IN0 of LUT3_0 or CLK Input of DFF3			
	49					
	50					
	51					
	52					
	53					
	54					
	55					
7	56		OUT9: IN1 of LUT3_0 or Data Input of DFF3			
	57					
	58					
	59					
	60			OUT10: IN2 of LUT3_0 or nRST (nSET) of DFF3		
	61					
	62					
	63					
8	64		LUT3_1 & DFF4	OUT11: IN0 of LUT3_1 or CLK Input of DFF4		
	65					
	66					
	67					
	68					
	69					
	70					
	71					
9	72	OUT12: IN1 of LUT3_1 or Data Input of DFF4				
	73					
	74					
	75					
	76			OUT13: IN2 of LUT3_1 or nRST (nSET) of DFF4		
	77					
	78					
	79					
A	80	OUT13: IN2 of LUT3_1 or nRST (nSET) of DFF4				
	81					
	82					
	83					

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
A	84	LUT3_2 & DFF5	OUT14: IN0 of LUT3_2 or CLK Input of DFF5		
	85				
	86				
	87				
B	88		OUT15: IN1 of LUT3_2 or Data Input of DFF5		
	89				
	90				
	91				
	92				
	93				
	94				
	95				
C	96		OUT16: IN2 of LUT3_2 or nRST (nSET) of DFF5		
	97				
	98				
	99				
	100				
	101				
	102				
	103				
D	104	LUT3_3 & DFF6	OUT17: IN0 of LUT3_3 or CLK Input of DFF6		
	105				
	106				
	107				
	108		OUT18: IN1 of LUT3_3 or Data Input of DFF6		
	109				
	110				
	111				
E	112		OUT19: IN2 of LUT3_3 or nRST (nSET) of DFF6		
	113				
	114				
	115				
	116				
	117				
	118				
	119				
F	120	LUT3_4 & DFF7	OUT20: IN0 of LUT3_4 or CLK Input of DFF7		
	121				
	122				
	123				
	124		OUT21: IN1 of LUT3_4 or Data Input of DFF7		
	125				
	126				
	127				

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
10	128	LUT3_4 & DFF7	OUT21: IN1 of LUT3_4 or Data Input of DFF7		
	129				
	130				
	131		OUT22: IN2 of LUT3_4 or nRST (nSET) of DFF7		
	132				
	133				
	134				
11	135	LUT3_5 & DFF8	OUT23: IN0 of LUT3_5 or CLK Input of DFF8		
	136				
	137				
	138				
	139				
	140				
	141				
12	142	LUT3_6 & DFF9	OUT24: IN1 of LUT3_5 or Data Input of DFF8		
	143				
	144				
	145				
	146				
	147				
	148				
13	149	LUT3_6 & DFF9	OUT25: IN2 of LUT3_5 or nRST (nSET) of DFF8		
	150				
	151				
	152				
	153				
	154				
	155				
14	156	LUT3_6 & DFF9	OUT26: IN0 of LUT3_6 or CLK Input of DFF9		
	157				
	158				
	159				
	160				
	161				
	162				
15	163	LUT3_6 & DFF9	OUT27: IN1 of LUT3_6 or Data Input of DFF9		
	164				
	165				
	166				
	167				
	168				
	169				
15	170	LUT3_6 & DFF9	OUT28: IN2 of LUT3_6 or nRST (nSET) of DFF9		
	171				
	172				
	173				
	174				

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface		
Byte	Register Bit			Read	Write	
15	174	Multi_function1	OUT29: IN0 of LUT3_7 or CLK Input of DFF11 Delay1 Input (or Counter1 nRST Input)			
	175					
16	176					
	177					
	178					
	179					
	180					
	181					
	182		OUT30: IN1 of LUT3_7 or nRST (nSET) of DFF11 Delay1 Input (or Counter1 nRST Input)			
183						
17	184					
	185					
	186					
	187			OUT31: IN2 of LUT3_7 or Data of DFF11 Delay1 Input (or Counter1 nRST Input)		
	188					
	189					
	190					
191						
18	192	Multi_function2	OUT32: IN0 of LUT3_8 or CLK Input of DFF12 Delay2 Input (or Counter2 nRST Input)			
	193					
	194					
	195					
	196					
	197					
	198					
199	OUT33: IN1 of LUT3_8 or nRST (nSET) of DFF12 Delay2 Input (or Counter2 nRST Input)					
19			200			
			201			
			202			
			203			
			204	OUT34: IN2 of LUT3_8 or Data of DFF12 Delay2 Input (or Counter2 nRST Input)		
			205			
	206					
207						
1A	208	Multi_function3	OUT35: IN0 of LUT3_9 or CLK Input of DFF13 Delay3 Input (or Counter3 nRST Input)			
	209					
	210					
	211					
	212					
	213					
	214					
215						

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
1B	216	Multi_function3	OUT36: IN1 of LUT3_9 or nRST (nSET) of DFF13 Delay3 Input (or Counter3 nRST Input)		
	217				
	218				
	219				
	220				
	221				
	222				
1C	223	Multi_function3	OUT37: IN2 of LUT3_9 or Data of DFF13 Delay3 Input (or Counter3 nRST Input)		
	224				
	225				
	226				
	227				
	228				
	229				
1D	230	Multi_function4	OUT38: IN0 of LUT3_10 or CLK Input of DFF14 Delay4 Input (or Counter4 nRST Input)		
	231				
	232				
	233				
	234				
	235				
	236				
1E	237	Multi_function4	OUT39: IN1 of LUT3_10 or nRST (nSET) of DFF14 Delay4 Input (or Counter4 nRST Input)		
	238				
	239				
	240				
	241				
	242				
	243				
1F	244	Multi_function5	OUT40: IN2 of LUT3_10 or Data of DFF14 Delay4 Input (or Counter4 nRST Input)		
	245				
	246				
	247				
	248				
	249				
	250				
20	251	Multi_function5	OUT41: IN0 of LUT3_11 or CLK Input of DFF15 Delay5 Input (or Counter5 nRST Input)		
	252				
	253				
	254				
	255				
	256				
	257				
20	258	Multi_function5	OUT42: IN1 of LUT3_11 or nRST (nSET) of DFF15 Delay5 Input (or Counter5 nRST Input)		
	259				
	260				
	261				
	262				
	263				
	263				
20	260	Multi_function5	OUT43: IN2 of LUT3_11 or Data of DFF15 Delay5 Input (or Counter5 nRST Input)		
	261				
	262				
	263				
	263				
	263				
	263				

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface		
Byte	Register Bit			Read	Write	
21	264	Multi_function6	OUT44: IN0 of LUT3_12 or CLK Input of DFF16 Delay6 Input (or Counter6 nRST Input)			
	265					
	266					
	267					
	268					
	269					
	270					
22	271					
	272		OUT45: IN1 of LUT3_12 or nRST (nSET) of DFF16 Delay6 Input (or Counter6 nRST Input)			
	273					
	274					
	23		275	OUT46: IN2 of LUT3_12 or Data of DFF16 Delay6 Input (or Counter6 nRST Input)		
			276			
			277			
24		278	OUT47: IN0 of LUT3_13 or Input of Pipe Delay or UP signal of RIPP CNT			
		279				
		280				
		281				
	282					
	283					
	284					
25	285	OUT48: IN1 of LUT3_13 or nRST of Pipe Delay or nSET of RIPP CNT				
	286					
	287					
	288					
	289					
	290					
	291					
26	292	OUT49: IN2 of LUT3_13 or Clock of Pipe Delay_RIPP CNT				
	293					
	294					
	295					
	296					
	297					
	298					
27	299	OUT50: IN0 of LUT4_0 or CLK Input of DFF10				
	300					
	301					
	302					
	303					
	304					
	305					
28	306	OUT51: IN1 of LUT4_0 or Data of DFF10				
	307					
	308					
	309					
	310					
	311					
	312					

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
27	312	LUT4_DFF10	OUT52: IN2 of LUT4_0 or nRST (nSET) of DFF10		
	313				
	314				
	315				
	316				
	317				
	318				
28	319	LUT4_DFF10	OUT53: IN3 of LUT4_0		
	320				
	321				
	322				
	323				
	324				
	325				
29	326	Multi_function0	OUT54: IN0 of LUT4_1 or CLK Input of DFF17 Delay0 Input (or Counter0 nRST Input)		
	327				
	328				
	329				
	330				
	331				
	332				
2A	333	Multi_function0	OUT55: IN1 of LUT4_1 or nRST of DFF17 Delay0 Input (or Counter0 nRST Input) Delay/Counter0 External CLK source		
	334				
	335				
	336				
	337				
	338				
	339				
2B	340	Multi_function0	OUT56: IN2 of LUT4_1 or nSET of DFF17 Delay0 Input (or Counter0 nRST Input) Delay/Counter0 External CLK source KEEP Input of FSM0		
	341				
	342				
	343				
	344				
	345				
	346				
2C	347	Filter/Edge detector	OUT57: IN3 of LUT4_1 or Data of DFF17 Delay0 Input (or Counter0 nRST Input) UP Input of FSM		
	348				
	349				
	350				
	351				
	352				
	353				
2C	354	Filter/Edge detector	OUT58: Programmable delay/edge detect input		
	355				
	356				
	357				
	358				
	359				
	359				

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface		
Byte	Register Bit			Read	Write	
2D	360	IO0	OUT60: IO0 DOUT			
	361					
	362					
	363					
	364					
	365					
	366					
	367					
2E	368		OUT61: IO0 DOUT OE			
	369					
	370					
	371					
	372			OUT62: IO1 DOUT		
	373					
	374					
	375					
2F	376	IO1	OUT63: IO1 DOUT OE			
	377					
	378					
	379					
	380					
	381					
	382					
	383					
30	384	IO2	OUT64: IO2 DOUT			
	385					
	386					
	387					
	388					
	389					
	390					
	391			OUT65: IO2 DOUT OE		
31	392	IO2				
	393					
	394					
	395					
	396	OUT66: IO3 DOUT				
	397					
	398					
	399					
32	400		IO3	OUT67: IO3 DOUT OE		
	401					
	402					
	403					
	404					
	405					
	406					
	407					

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
33	408	IO4	OUT68: IO4 DOUT		
	409				
	410				
	411				
	412				
	413				
	414				
34	415		OUT69: IO4 DOUT OE		
	416				
	417				
	418				
	419				
	420				
	421				
35	422	IO5	OUT70: IO5 DOUT		
	423				
	424				
	425				
	426				
	427				
	428				
36	429		OUT71: IO5 DOUT OE		
	430				
	431				
	432				
	433				
	434				
	435				
37	436	IO6	OUT72: IO6 DOUT		
	437				
	438				
	439				
	440				
	441				
	442				
38	443		OUT73: IO6 DOUT OE		
	444				
	445				
	446				
	447				
	448				
	449				
39	450	Programmable Trim Block0	OUT74: set0 of Auto Calibration		
	451				
	452				
	453				
	454				
	455				
40			OUT75: clock0 of Auto Calibration		

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
39	456	Programmable Trim Block0	OUT76: reload0 of Auto Calibration		
	457				
	458				
	459				
	460				
	461				
	462				
3A	463	Digital Rheostat	OUT77: program0 of Auto Calibration		
	464				
	465				
	466				
	467				
	468				
	469				
3B	470	Digital Rheostat	OUT78: Rheostat Counter0 up/down 0: down, 1: up. (register [920] = 0) 0: up, 1: down. (register [920] = 1)		
	471				
	472				
	473				
	474				
	475				
	476				
3C	477	Programmable Trim Block1	OUT79: set1 of Auto Calibration		
	478				
	479				
	480				
	481				
	482				
	483				
3D	484	Digital Rheostat	OUT80: clock1 of Auto Calibration		
	485				
	486				
	487				
	488				
	489				
	490				
3E	491	Digital Rheostat	OUT81: reload1 of Auto Calibration		
	492				
	493				
	494				
	495				
	496				
	497				
3F	498	Digital Rheostat	OUT82: program1 of Auto Calibration		
	499				
	500				
	501				
	502				
	503				
	504				

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
3F	504	FIFO Reset of PT blocks	OUT84: FIFO nRST of the control logic of re-load0/reload1/auto program0/auto program1		
	505				
	506				
	507				
	508				
	509				
	510				
	511				
40	512	Chopper ACMP	OUT85: Chopper ACMP Power Up		
	513				
	514				
	515				
	516	Digital Rheostat	OUT86: Rheostat Charge pump enable		
	517				
	518				
	519				
41	520	Analog Switch0	OUT87: ASW0 enable/Half bridge enable		
	521				
	522				
	523				
	524				
	525				
	526				
	527				
42	528	Analog Switch1	OUT88: ASW1 enable/Half bridge data		
	529				
	530				
	531				
	532				
	533				
	534				
	535				
43	536	ACMP0	OUT89: ACMP0 Power Up		
	537				
	538				
	539				
	540	ACMP1	OUT90: ACMP1 Power Up		
	541				
	542				
	543				
44	544	OSC0	OUT91: OSC0 ENABLE		
	545				
	546				
	547				
	548				
	549				
	550				
	551				

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
45	552	OSC1	OUT92: OSC1 ENABLE		
	553				
	554				
	555				
	556				
	557				
	558				
46	559	OSC2	OUT93: OSC2 ENABLE		
	560				
	561				
	562				
	563				
	564				
	565				
47	566	Temperature Sensor	OUT94: VREFO TEMPSSEN/VREFO Power Up		
	567				
	568				
	569				
	570				
	571				
	572				
48	573	HDBUF	OUT95: HDBUF ENABLE		
	574				
	575				
	576				
	577				
	578				
	579				
49	580	Op Amp0	OUT96: OP0(Op Amp ACMP0) Power Up		
	581				
	582				
	583				
	584				
	585				
	586				
4A	587	Op Amp1	OUT97: OP1(Op Amp ACMP1) Power Up		
	588				
	589				
	590				
	591				
	592				
	593				
4A	594	Op amps	OUT98: OP2 Power Up (In Amp Mode)		
	595				
	596				
	597				
	598				
	599				
	599				

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
4B	600	Reserved			
	601	Reserved			
	602	Reserved			
	603	Reserved			
	604	Reserved			
	605	Reserved			
	606	Reserved			
	607	Reserved			
ACMP0					
4C	608	ACMP Low Energy Power Up enable (ACMP power after bg_ok)	1: enable		
	609	ACMP input path LPF enable	1: enable		
	610	ACMP sampling mode enable	1: enable		
	611	ACMP short time wake sleep mode disable	0: short time wake sleep enable 1: short time wake sleep disable		
	612	ACMP wake sleep function enable	1: enable		
	613	ACMP Vref path LPF enable (when ACMP hysteresis > 196 mV)	1: enable		
	614	ACMP input divider selection	00: 1 01: 0.5 10: 1/3 11: 1/4		
	615				
4D	616	ACMP input mux selection	00: OP0 output 01: from Pin 10: tie VDD		
	617				
	618	ACMP Low to High Vref selection	000000-111111: 32 mV ~2.048 V/step = 32 mV		
	619				
	620				
	621				
	622				
	623				
4E	624	ACMP High to Low Vref selection	000000-111111: 32 mV ~2.048 V/step = 32 mV		
	625				
	626				
	627				
	628				
	629				
ACMP1					
4E	630	ACMP Low Energy Power Up enable (ACMP power after bg_ok)	1: enable		
	631	ACMP input path LPF enable	1: enable		
4F	632	ACMP sampling mode enable	1: enable		
	633	ACMP short time wake sleep mode disable	0: short time wake sleep enable 1: short time wake sleep disable		
	634	ACMP wake sleep function enable	1: enable		
	635	ACMP Vref path LPF enable (when ACMP hysteresis > 196 mV)	1: enable		
	636	ACMP input divider selection	00: 1 01: 0.5 10: 1/3 11: 1/4		
	637				

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
4F	638	ACMP input mux selection	00: OP1 output 01: from Pin 10: ACMP0 input mux output 11: VrefO1 Temp sensor output		
	639				
50	640	ACMP Low to High Vref selection	000000-111111: 32 mV ~2.048 V/step = 32 mV		
	641				
	642				
	643				
	644				
	645				
	646				
51	647	ACMP High to Low Vref selection	000000-111111: 32 mV ~2.048 V/step = 32 mV		
	648				
	649				
	650				
	651				
Vref					
51	652	Reserved			
	653	Reserved			
	654	Reserved			
	655	Reserved			
52	656	Reserved			
	657	Reserved			
	658	VREFO0 input source selection	0: ACMP0 VREF 1: Temp Sensor		
	659	VREFO0 output buffer enable	1: enable		
	660	VREFO0 register Power Up	VREFO0 register power on signal		
	661	VREFO0 Power Up selection	0: Power Up from reg 1: from matrix		
	662	Reserved	no use		
53	663	VREFO1's temp sensor to ACMP1 input path enable	Temp Sensor output to ACMP1 enable 1: enable		
	664	VREFO1's temp sensor range selection	0:1V; 1:1.2V		
	665	VREFO1 input source selection	0: ACMP1 Vref 1: TS		
	666	VREFO1 output buffer enable	1: enable		
	667	VREFO1 register Power Up	VrefO1 register power on signal		
	668	VREFO1 Power Up selection	0: Power Up from reg 1: from matrix		
	669	ACMP Vrefs source selection	ACMP Vref gen source selection (0: VBG, 1: V _{DD})		
	670	ACMP0 external Vref enable	1:enable		
	671	ACMP1 external Vref enable	1:enable		
54	672	Reserved			
54	673	Reserved			
	674	Reserved			

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
54	675	Reserved			
	676				
	677				
	678	Reserved			
	679	Reserved			
55	680	Reserved			
	681	Reserved			
	682	Reserved			
	683	Reserved			
	684	Reserved			
	685	Reserved			
	686	Reserved			
	687	Reserved			
OSC1					
56	688	OSC1 turn on by register	when matrix output enable/pd control signal = 0: 0: auto on by delay cells 1: always on		
	689	OSC1 matrix power down or on select	0: matrix down 1: matrix on		
	690	OSC1 external clock source enable	0: internal OSC1 1: external clock from PAD15		
	691	OSC1 post divider ratio control	00: div 1 01: div 2 10: div 4 11: div8		
	692				
	693	OSC1 matrix divider ratio control	000: /1 001: /2 010: /4 011: /3 100: /8 101: /12 110: /24 111: /64		
	694				
	695				
57	696	OSC1 matrix out enable	0: disable 1: enable		
	697	Reserved			
	698	Reserved			
	699	Reserved			
	700	OSC1 2nd output to matrix enable	0: disable 1: enable		
	701	OSC1 2nd matrix divider ratio control	000: /1 001: /2 010: /4 011: /3 100: /8 101: /12 110: /24 111: /64		
	702				
57	703				
OSC2					

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
58	704	OSC2 turn on by register	when matrix output enable/pd control signal = 0: 0: auto on by delay cells 1: always on		
	705	OSC2 matrix power down or on select	0: matrix down 1: matrix on		
	706	OSC2 external clock source enable	0: internal OSC2 1: external clock from IO2		
	707	OSC2 matrix out enable	0: disable 1: enable		
	708	OSC2 post divider ratio control	00: div 1 01: div 2 10: div 4 11: div8		
	709				
	710				
59	711	OSC2 matrix divider ratio control	000: /1 001: /2 010: /4 011: /3 100: /8 101: /12 110: /24 111: /64		
	712				
	713				
	714				
	715				
	716				
	717				
5A	718	Op Amp0 sr boost for OP 8 MHz	0: enable, 1: disable		
	719	Op Amp1 sr boost for OP 8 MHz	0: enable, 1: disable		
	720	Op Amp2 sr boost for OP 8 MHz	0: enable, 1: disable		
	721	Reserved			
	722	Reserved			
	723	Reserved			
	724	Reserved			
5B	725	OSC0 turn on by register	when matrix output enable/pd control signal = 0: 0: auto on by delay cells 1: always on		
	726	OSC0 matrix power down or on select	0: matrix down 1: matrix on		
	727	OSC0 external clock source enable	0: internal OSC0 1: external clock from IO0		
	728	OSC0 matrix out enable	0: disable 1: enable		
	729	OSC0 post divider ratio control	00: div 1 01: div 2 10: div 4 11: div8		
	730				
	731				
5C	732	OSC0 matrix divider ratio control	000: /1 001: /2 010: /4 011: /3 100: /8 101: /12 110: /24 111: /64		
	733				
	734				
	735				
	736				
	737				
	738				

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
5B	729	enable OSC0 output gating by wake_sleep signal (note: the wake_sleep clock is separated path, so it is not gated)	0: no gating 1: enable		
	730	OSC0 2nd output to matrix enable	0: disable 1: enable		
	731	OSC0 2nd matrix divider ratio control	000: /1 001: /2 010: /4 011: /3 100: /8 101: /12 110: /24 111: /64		
	732				
	733				
	734	Reserved			
	735	Reserved			
Analog Switch					
5C	736	ASW0 small NMOS enable selection	0: small NMOS disable 1: small NMOS enable by matrix87		
	737	ASW1 small PMOS enable selection	0: small PMOS disable 1: small PMOS enable by matrix88		
	738	ASW0 big PMOS control selection	0: control by matrix87 1: control by Op Amp0		
	739	ASW1 big NMOS control selection	0: control by matrix88 1: control by Op Amp1		
	740	ASW half bridge mode enable	0: analog switch mode 1: half bridge (enable from matrix87; data from matrix88)		
	741	ASW half bridge dead time select	00: bypass 01: 20ns 10: 100ns 11: 500ns		
	742				
	743	Reserved			
Op Amp0/1/2					
5D	744	Op Amp0 bandwidth selection	00: 128 kHz 01: 512 kHz 10: 2 MHz 11: 8 MHz		
	745				
	746	Op Amp1 bandwidth selection	00: 128 kHz 01: 512 kHz 10: 2 MHz 11: 8 MHz		
	747				
	748	Op Amp2 bandwidth selection	00: 128 kHz 01: 512 kHz 10: 2 MHz 11: 8 MHz		
	749				
	750	ACMP/Op Amp0 mode	0: Op amp mode 1: ACMP mode		
	751	ACMP/Op Amp1 mode	0: Op amp mode 1: ACMP mode		
5E	752	Op Amp0 charge pump disable	0: Op amp input common voltage higher than V _{DD} -1.5V, enable CP 1: Op amp input common voltage lower than V _{DD} -1.5V, disable CP		

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
5E	753	Op Amp1 charge pump disable	0: Op amp input common voltage higher than $V_{DD}-1.5V$, enable CP; 1: Op amp input common voltage lower than $V_{DD}-1.5V$, disable CP		
	754	Op Amp2 charge pump disable	0: Op amp input common voltage higher than $V_{DD}-1.5V$, enable CP 1: Op amp input common voltage lower than $V_{DD}-1.5V$, disable CP		
	755	Path between Op Amp0/1 and Op Amp2	0: path on (for normal function) 1: path off (for trim function)		
	756	Op Amp2's Vref buffer bypass control	0: without buffer 1: with buffer		
	757	Supporting blocks for Op Amp0 on/off	0: on/off follows op amp 1: always on except input common voltage of op amp lower than $V_{DD}-1.5V$		
	758	Supporting blocks for Op Amp1 on/off	0: on/off follows op amp 1: always on except input common voltage of op amp lower than $V_{DD}-1.5V$		
	759	Supporting blocks for Op Amp2 on/off	0: on/off follows op amp 1: always on except input common voltage of op amp lower than $V_{DD}-1.5V$		
5F	760	Op amp ACMP Vref0 output selection[0]	000000-111111: 32 mV ~2.048 V/step = 32 mV		
	761	Op amp ACMP Vref0 output selection[1]			
	762	Op amp ACMP Vref0 output selection[2]			
	763	Op amp ACMP Vref0 output selection[3]			
	764	Op amp ACMP Vref0 output selection[4]			
	765	Op amp ACMP Vref0 output selection[5]			
	766	Op amp ACMP Vref0 register enable (select by register [782])	0: dynamic on/off 1: Vref enable		
	767	Vref0 to op amp/ACMP input enable	0:disable; 1: enable		
60	768	Op amp ACMP Vref1 output selection[0]	000000-111111: 32 mV ~2.048 V/step = 32 mV		
	769	Op amp ACMP Vref1 output selection[1]			
	770	Op amp ACMP Vref1 output selection[2]			
	771	Op amp ACMP Vref1 output selection[3]			
	772	Op amp ACMP Vref1 output selection[4]			
	773	Op amp ACMP Vref1 output selection[5]			
	774	Op amp ACMP Vref1 register enable (select by register [783])	0: dynamic on/off 1: Vref enable		
	775	Vref1 to op amp/ACMP input enable	0:disable; 1: enable		
61	776	Op amp ACMP Vref0 output selection	0: Vref to ACMP negative input 1: Vref to ACMP positive input		
	777	Op amp ACMP Vref1 output selection	0: Vref to ACMP negative input 1: Vref to ACMP positive input		
	778	Op amp Vref0 LPF enable	0: disable 1: enable		
	779	Op amp Vref1 LPF enable	0: disable 1: enable		
	780	Op amp ACMP Vref0 input voltage selection	0: 2.048 V 1: V_{DD}		
	781	Op amp ACMP Vref1 input voltage selection	0: 2.048 V 1: V_{DD}		
	782	Op amp ACMP vref0 enable selection	0: from register [766] 1: from matrix99		

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
61	783	Op amp ACMP vref1 enable selection	0: from register [774] 1: from matrix99		
LUT3_2/DFF5					
62	784	LUT3_2_DFF5 setting	<2:0>: LUT3_2 <2:0>		
	785				
	786				
	787		<3>:LUT3_2 <3>/DFF5 Active level selection for RST/SET 0: Active low level reset/set, 1: Active high level reset/set		
	788		<4>:LUT3_2 <4>/DFF5 0: RSTB from Matrix Output, 1: SETB from Matrix Output		
	789		<5>:LUT3_2 <5>/DFF5 Initial Polarity Select 0: Low, 1: High		
	790		<6>:LUT3_2 <6>/DFF5 Output Select 0: Q output, 1: QB output		
	791		<7>:LUT3_2 <7>/DFF5 or Latch Select 0: DFF function, 1: Latch function		
LUT3_3/DFF6					
63	792	LUT3_3_DFF6 setting	<2:0>: LUT3_3 <2:0>		
	793				
	794				
	795		<3>:LUT3_3 <3>/DFF6 Active level selection for RST/SET 0: Active low level reset/set, 1: Active high level reset/set		
	796		<4>:LUT3_3 <4>/DFF6 0: RSTB from Matrix Output, 1: SETB from Matrix Output		
	797		<5>:LUT3_3 <5>/DFF6 Initial Polarity Select 0: Low, 1: High		
	798		<6>:LUT3_3 <6>/DFF6 Output Select 0: Q output, 1: QB output		
	799		<7>:LUT3_3 <7>/DFF6 or Latch Select 0: DFF function, 1: Latch function		
LUT3_4/DFF7					
64	800	LUT3_4_DFF7 setting	<2:0>: LUT3_4 <2:0>		
	801				
	802				
	803		<3>:LUT3_4 <3>/DFF7 Active level selection for RST/SET 0: Active low level reset/set, 1: Active high level reset/set		
	804		<4>:LUT3_4 <4>/DFF7 0: RSTB from Matrix Output, 1: SETB from Matrix Output		
	805		<5>:LUT3_4 <5>/DFF7 Initial Polarity Select 0: Low, 1: High		
	806		<6>:LUT3_4 <6>/DFF7 Output Select 0: Q output, 1: QB output		

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
64	807	LUT3_4_DFF7 setting	<7>:LUT3_4 <7>/DFF7 or Latch Select 0: DFF function, 1: Latch function		
LUT3_5/DFF8					
65	808	LUT3_5_DFF8 setting	<2:0>: LUT3_5 <2:0>		
	809				
	810				
	811		<3>:LUT3_5 <3>/DFF8 Active level selection for RST/SET 0: Active low level reset/set, 1: Active high level reset/set		
	812		<4>:LUT3_5<4>/DFF8 0: RSTB from Matrix Output, 1: SETB from Matrix Output		
	813		<5>:LUT3_5 <5>/DFF8 Initial Polarity Select 0: Low, 1: High		
	814		<6>:LUT3_5 <6>/DFF8 Output Select 0: Q output, 1: QB output		
	815		<7>:LUT3_5 <7>/DFF8 or Latch Select 0: DFF function, 1: Latch function		
LUT3_6/DFF9					
66	816	LUT3_6_DFF9 setting	<2:0>: LUT3_6 <2:0>		
	817				
	818				
	819		<3>:LUT3_6 <3>/DFF9 Active level selection for RST/SET 0: Active low level reset/set, 1: Active high level reset/set		
	820		<4>:LUT3_6<4>/DFF9 0: RSTB from Matrix Output, 1: SETB from Matrix Output		
	821		<5>:LUT3_6 <5>/DFF9 Initial Polarity Select 0: Low, 1: High		
	822		<6>:LUT3_6 <6>/DFF9 Output Select 0: Q output, 1: QB output		
	823		<7>:LUT3_6 <7>/DFF9 or Latch Select 0: DFF function, 1: Latch function		
67	824	LUT3_2 or DFF5 Select	0: LUT3_2 1: DFF5		
	825	LUT3_3 or DFF6 Select	0: LUT3_3 1: DFF6		
	826	LUT3_4 or DFF7 Select	0: LUT3_4 1: DFF7		
	827	LUT3_5 or DFF8 Select	0: LUT3_5 1: DFF8		
	828	LUT3_6 or DFF9 Select	0: LUT3_5 1: DFF8		
	829	LUT4_0 or DFF10 Select	0: LUT4_0 1: DFF10		
	830	Reserved			
	831	Reserved			
LUT4_0/DFF10					

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
68	832	LUT4_0_DFF10 setting	<9:0>: LUT4_0 <9:0>		
	833				
	834				
	835				
	836				
	837				
	838				
	839				
69	840				
	841				
	842		<10>:LUT4_0 <10>/DFF10 stage selection 0: Q of first DFF; 1 Q of second DFF		
	843		<11>:LUT4_0 <11>/DFF10 Active level selection for RST/SET 0: Active low level reset/set, 1: Active high level reset/set		
	844		<12>:LUT4_0 <12>/DFF10 0: RSTB from Matrix Output, 1: SETB from Matrix Output		
	845		<13>:LUT4_0 <13> /DFF10 Initial Polarity Select 0: Low, 1: High		
	846		<14>:LUT4_0 <14>/DFF10 Output Select 0: Q output, 1: QB output		
847	<15>:LUT4_0 <15>/DFF10 or Latch Select 0: DFF function, 1: Latch function				
LUT3_13/Pipe Delay (RIPP CNT)					
6A	848	LUT value or pipe delay out sel or nSET/END value	at LUT/pipe delay mode bit<7:4>: LUT3_13 <7:4> / REG_S1<3:0> pipe delay out1 sel bit<3:0>: LUT3_13 <3:0> / REG_S0<3:0> pipe delay out0 sel at RIPP CNT mode bit<2:0> is the nSET value. bit<5:3> is the END value bit<6> is the range control: 0: full cycle, 1: range cycle bit<7> No used		
	849				
	850				
	851				
	852				
	853				
	854				
6B	855				
	856	Active level selection for RST/SET 0: Active low level reset/set 1: Active high level reset/set			
	857	Out of LUT3_13 or Out0 of Pipe Delay/RIPP CNT Select 0: LUT3_13 1: OUT0 of Pipe Delay or RIPP CNT			
	858	PIPE_RIPP_CNT_S 0: Pipe delay mode selection 1: Ripple Counter mode selection			
	859	Pipe Delay OUT1 Polarity Select 0: Non-inverted 1: Inverted			
	860	Reserved			
	861	Reserved			
	862	Reserved			
863	Reserved				

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
Programmable Delay					
6C	864	Delay Value Select for Programmable Delay & Edge Detector	00: 125ns 01: 250ns 10: 375ns 11: 500ns		
	865				
	866	Select the Edge Mode of Programmable Delay & Edge Detector	00: Rising Edge Detector 01: Falling Edge Detector 10: Both Edge Detector 11: Both Edge Delay		
	867				
Filter/Edge Detector					
6C	868	Filter or Edge Detector selection	0: filter 1: edge detect		
	869	Output Polarity Select	0: output non-invert 1: output invert		
	870	Select the edge mode	00: Rising Edge Detect 01: Falling Edge Detect 10: Both Edge Detect 11: Both Edge DLY		
	871				
Chopper ACMP					
6D	872	Chopper ACMP positive input selection for calibration channel0	00: from In Amp out 01: from Op Amp0 out 10: from Op Amp1 out 11: IO1		
	873				
	874	Chopper ACMP positive input selection for calibration channel1	00: from In Amp out 01: from Op Amp0 out 10: from Op Amp1 out 11: IO1		
	875				
	876	Reserved			
	877	Reserved			
	878	Reserved			
	879	Reserved			
6E	880	Reserved			
	881	Reserved			
	882	Output Polarity Select	0: output non-invert 1: output invert		
	883	Reserved			
	884				
	885				
	886				
6F	887				
	888	Reserved			
	889				
	890	Reserved			
891	Reserved				
Calibration					

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
6F	892	auto calibration channel selection by register	0: calibration channel0 1: calibration channel1		
	893	auto calibration channel selection source selection	0: calibration channel auto selection 1: from register [892]		
	894	RH_CNT1 clock source selection	0: From Chopper ACMP (Chopper ACMP changes one time per rheostat clock) 1: from matrix directly		
	895	RH_CNT0 clock source selection	0: From Chopper ACMP (Chopper ACMP changes one time per rheostat clock) 1: from matrix directly		
70	896	Calibration0 clock divider	0000: OSC1 0001: OSC1/8 0010: OSC1/64 0011: OSC1/512 0100: OSC0 0101: OSC0/8 0110: OSC0/64 0111: OSC0/512 1000: OSC0/4096 1001: OSC0/32768 1010: OSC0/262144 1011/1100/1101/1110: GND 1111: EXTCLK		
	897				
	898				
	899				
	900	Up/down selection	0: chopper ACMP 1: matrix83		
	901	auto_calibration disable	0: auto calibration enable 1: disable		
	902	Reserved			
	903	Reserved			
71	904	Calibration1 clock divider	0000: OSC1 0001: OSC1/8 0010: OSC1/64 0011: OSC1/512 0100: OSC0 0101: OSC0/8 0110: OSC0/64 0111: OSC0/512 1000: OSC0/4096 1001: OSC0/32768 1010: OSC0/262144 1011/1100/1101/1110: GND 1111: EXTCLK		
	905				
	906				
	907				
	908	Up/down selection	0: chopper ACMP 1: matrix83		
	909	auto_calibration disable	0: auto calibration enable 1: disable		
	910	Reserved			
	911	Reserved			
Digital Rheostats					

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
72	912	POTCP0 turn on by register	0: control by matrix86 1: on		
	913	POTCP1 turn on by register	0: control by matrix86 1: on		
	914	POTCP0/1 clock source selection	0: from LPBG chopper OSC 1: from OSC1		
	915	POTCP0/1 clock source select from register	0: by register [914] 1: calibration auto on		
	916	Reserved			
	917	Reserved			
	918	Reserved			
73	919	Reserved			
	920	Polarity selection of RH_CNT0 UP signal	0: default (up = 0 down mode, up = 1 up mode) 1: (up = 0 up mode, up = 1 down mode)		
	921	Reserved			
	922	Reserved			
	923	Polarity selection of RH_CNT1 UP signal	0: default (up = 0 down mode, up = 1 up mode) 1: (up = 0 up mode, up = 1 down mode)		
	924	Reserved			
	925	Reserved			
74	926	Reserved			
	927	Reserved			
HD Buffer					
74	928	Chop ACMP Vref selection for calibration channel 0	000000-111111: 1/64 ~ 64/64 (divider input select by register [946])		
	929				
	930				
	931				
	932				
	933				
	934	Chop ACMP calibration channel0 external Vref selection	0: external Vref (pin18) 1: internal Vref		
75	935	Reserved			
	936	Chop ACMP Vref selection for calibration channel 1	000000-111111: 1/64 ~ 64/64 (divider input select by register [946])		
	937				
	938				
	939				
	940				
	941				
	942	Chop ACMP calibration channel1 external Vref selection	0: external Vref (pin18) 1: internal Vref		
	943	Reserved			

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
76	944	HD buffer register enable (select by register [945])	0: disable 1: enable		
	945	HD buffer enable selection	0: from register [944] 1: from matrix95		
	946	Chop ACMP Vref divider input selection	0: from HD buffer output 1: from op amp Vref voltage (2.048/V _{DD} selection register in Vref block)		
	947	Reserved			
	948	Reserved			
	949	Reserved			
	950	Reserved			
	951	Reserved			
CP OSC/Regulator					
77	952	CPOSC single or multiple mode select	0: multiple OSC mode 1: single OSC mode		
	953	Reserved			
	954	CPOSC0 frequency select	00: 250 kHz 01: 1 MHz 10: 4 MHz 11: 8 MHz		
	955				
	956	Reserved			
	957	Reserved			
	958	Reserved			
78	959	Reserved			
	960	Reserved			
	961	Reserved			
	962	CPOSC1 frequency select	00: 250 kHz 01: 1 MHz 10: 4 MHz 11: 8 MHz		
	963				
	964	Reserved			
	965	Reserved			
79	966	Reserved			
	967	Reserved			
	968	Reserved			
	969	Reserved			
	970	CPOSC2 frequency select	00: 250 kHz 01: 1 MHz 10: 4 MHz 11: 8 MHz		
	971				
	972	Reserved			
	973	Reserved			
	974	Reserved			
	975	Reserved			

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
7A	976	Buffer Vref select	00: none		
	977		01: internal Vref 10: Rheostat Vref 11: external Vref		
	978	Reserved			
	979	Reserved			
	980	Reserved			
	981	Reserved			
	982	Reserved			
	983	Reserved			
7B	984	I ² C soft reset	0: Keep existing condition 1: Reset execution, reload NVM to registers		
	985	IO latch enable during I ² C write	0: disable 1: enable		
	986	Reserved			
	987	Reserved			
	988	Reserved			
	989	Reserved			
	990	Reserved			
	991	Reserved			
7C	992	Matrix Input 32	I ² C_virtual_0 Input		
	993	Matrix Input 33	I ² C_virtual_1 Input		
	994	Matrix Input 34	I ² C_virtual_2 Input		
	995	Matrix Input 35	I ² C_virtual_3 Input		
	996	Matrix Input 36	I ² C_virtual_4 Input		
	997	Matrix Input 37	I ² C_virtual_5 Input		
	998	Matrix Input 38	I ² C_virtual_6 Input		
	999	Matrix Input 39	I ² C_virtual_7 Input		
7D	1000	Reserved			
	1001				
	1002				
	1003				
	1004				
	1005				
	1006				
	1007				
7E	1008	Reserved			
	1009				
	1010				
	1011				
	1012				
	1013				
	1014				
	1015				

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
7F	1016	I ² C slave address			
	1017				
	1018				
	1019				
	1020	slave address selection bit0	0: from register [1016] 1: from PAD15		
	1021	slave address selection bit1	0: from register [1017] 1: from PAD16		
	1022	slave address selection bit2	0: from register [1018] 1: from PAD17		
	1023	slave address selection bit3	0: from register [1019] 1: from PAD18		
80	1024	Power sequence byte A5	A5 fixed		
	1025				
	1026				
	1027				
	1028				
	1029				
	1030				
	1031				
81	1032	Reserved			
	1033				
	1034				
	1035				
	1036				
	1037				
	1038	Reserved			
	1039	Reserved			
82	1040	Reserved			
	1041				
	1042				
	1043				
	1044				
	1045				
	1046	Reserved			
	1047	Reserved			
83	1048	Reserved			
	1049				
	1050				
	1051				
	1052				
	1053				
	1054	Reserved			
	1055	Reserved			

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
84	1056	Reserved			
	1057				
	1058				
	1059				
	1060	Reserved			
	1061				
	1062				
85	1063	Reserved			
	1064				
	1065				
	1066				
	1067	Reserved			
	1068				
	1069				
86	1070	Reserved			
	1071				
	1072				
	1073				
	1074	Reserved			
	1075				
	1076				
87	1077	Reserved			
	1078				
	1079				
	1080				
	1081	Reserved			
	1082				
	1083				
88	1084	Reserved			
	1085				
	1086				
	1087				
	1088	Reserved			
	1089				
	1090				
	1091	Reserved			
	1092				
	1093				
	1094				
	1095				

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
89	1096	Reserved			
	1097				
	1098				
	1099				
	1100	Reserved			
	1101				
	1102				
8A	1103	Reserved			
	1104				
	1105				
	1106				
	1107	Reserved			
	1108				
	1109				
8B	1110	Reserved			
	1111				
	1112				
	1113				
	1114	Reserved			
	1115				
	1116				
8C	1117	Reserved			
	1118				
	1119				
	1120				
	1121	Reserved			
	1122				
	1123				
8D	1124	Reserved			
	1125				
	1126				
	1127				
	1128	Reserved			
	1129				
	1130				
8E	1131	Reserved			
	1132				
	1133				
	1134				
	1135	Reserved			
	1136				
	1137				
	1138				
	1139	Reserved			
	1140				

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
8E	1141	Reserved			
	1142				
	1143				
8F	1144	Reserved			
	1145				
	1146				
	1147				
	1148	Reserved			
	1149				
	1150				
	1151	Reserved			
SCL/SDA					
90	1152	input mode configuration	00: digital without Schmitt trigger 01: digital with Schmitt trigger 10: low voltage digital in 11: analog IO		
	1153				
	1154	Reserved			
	1155	I ² C mode selection	0: I ² C fast mode + 1: I ² C standard/fast mode		
IO0					
90	1156	input mode configuration	00: digital without Schmitt Trigger 01: digital with Schmitt Trigger 10: low voltage digital in 11: analog IO		
	1157				
	1158	output mode configuration	00: Push-Pull 1x 01: Push-Pull 2x 10: 1x Open-Drain 11: 2x Open-Drain		
	1159				
91	1160	Pull-up/down resistance selection	00: floating 01: 10k 10: 100k 11: 1M		
	1161				
	1162	Pull-up/down selection	0: Pull-down 1: Pull-up		
IO1					
91	1163	input mode configuration	00: digital without Schmitt Trigger 01: digital with Schmitt Trigger 10: low voltage digital in 11: analog IO		
	1164				
	1165	output mode configuration	00: Push-Pull 1x 01: Push-Pull 2x 10: 1x Open-Drain 11: 2x Open-Drain		
	1166				
	1167		00: floating 01: 10K 10: 100K 11: 1M		
92	1168	Pull-up/down resistance selection	0: Pull-down 1: Pull-up		
	1169	Pull-up/down selection			
IO2					

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
92	1170	input mode configuration	00: digital without Schmitt Trigger		
	1171		01: digital with Schmitt Trigger		
			10: low voltage digital in		
			11: analog IO		
	1172	output mode configuration	00: Push-Pull 1x		
	1173		01: Push-Pull 2x		
			10: 1x Open-Drain		
			11: 2x Open-Drain		
	1174	Pull-up/down resistance selection	00: floating		
			01: 10K		
	1175		10: 100K		
			11: 1M		
93	1176	Pull-up/down selection	0: Pull-down 1: Pull-up		
IO3					
93	1177	input mode configuration	00: digital without Schmitt Trigger		
	1178		01: digital with Schmitt Trigger		
			10: low voltage digital in		
			11: analog IO		
	1179	output mode configuration	00: Push-Pull 1x		
	1180		01: Push-Pull 2x		
			10: 1x Open-Drain		
			11: 2x Open-Drain		
	1181	Pull-up/down resistance selection	00: floating		
			01: 10K		
	1182		10: 100K		
			11: 1M		
	1183	Pull-up/down selection	0: Pull-down 1: Pull-up		
IO4					
94	1184	input mode configuration	00: digital without Schmitt Trigger		
	1185		01: digital with Schmitt Trigger		
			10: low voltage digital in		
			11: analog IO		
	1186	output mode configuration	00: Push-Pull 1x		
	1187		01: Push-Pull 2x		
			10: 1x Open-Drain		
			11: 2x Open-Drain		
	1188	Pull-up/down resistance selection	00: floating		
			01: 10K		
	1189		10: 100K		
			11: 1M		
	1190	Pull-up/down selection	0: Pull-down 1: Pull-up		
IO5					

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
94	1191	input mode configuration	00: digital without Schmitt Trigger 01: digital with Schmitt Trigger 10: low voltage digital in 11: analog IO		
95	1192				
	1193	output mode configuration	00: Push-Pull 1x 01: Push-Pull 2x 10: 1x Open-Drain 11: 2x Open-Drain		
	1194				
	1195	Pull-up/down resistance selection	00: floating 01: 10K 10: 100K 11: 1M		
	1196				
	1197	Pull-up/down selection	0: Pull-down 1: Pull-up		
IO6					
95	1198	input mode configuration	00: digital without Schmitt Trigger 01: digital with Schmitt Trigger 10: low voltage digital in 11: analog IO		
	1199				
96	1200	output mode configuration	00: Push-Pull 1x 01: Push-Pull 2x 10: 1x Open-Drain 11: 2x Open-Drain		
	1201				
	1202	Pull-up/down resistance selection	00: floating 01: 10K 10: 100K 11: 1M		
	1203				
	1204	Pull-up/down selection	0: Pull-down 1: Pull-up		
IO					
96	1205	input mode configuration	00: digital without Schmitt Trigger 01: digital with Schmitt Trigger 10: low voltage digital in 11: analog IO		
	1206				
	1207	IO fast Pull-up/down enable	0: disable 1: enable		
97	1208	Reserved			
	1209	Reserved			
	1210	Reserved			
	1211	Reserved			
	1212	Reserved			
	1213	Reserved			
	1214	Reserved			
	1215	Reserved			

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
98	1216	Multi0 register configure	multit_function selection		
	1217				
	1218		dly2lut selection		
	1219				
	1220		output selection of LUT4_1/DFF17: 0: LUT4_1 1: DFF17		
	1221				
	1222		external clock selection		
99	1223				
	1224	DLY/CNT0 Mode Selection	00: DLY 01: one shoot 10: frequency detect 11: CNT register [1238] = 0		
	1225	DLY/CNT0 edge Mode Selection	00: both edge 01: falling edge 10: rising edge 11: High Level Reset (only in CNT mode)		
	1226				
	1227	DLY/CNT0 Clock Source Select	Clock source sel[3:0] 0000: 25M(OSC2) 0001: 25M/4 0010: 2M(OSC1) 0011: 2M/8 0100: 2M/64 0101: 2M/512 0110: 2K(OSC0) 0111: 2K/8 1000: 2K/64 1001: 2K/512 1010: 2K/4096 1011: 2K/32768 1100: 2K/262144 1101: CNT6_END 1110: External 1111: Not used		
	1228				
	1229				
	1230				
	1231				
	1231	FSM0 SET/RST Selection	0: Reset to 0 1: Set to data		
	1232	wake sleep mode selection	0: Default Mode, 1: Wake Sleep Mode (registers [1224:1223] = 11)		
9A	1233	Wake sleep power down state selection	0: low 1: high		
	1234	Keep signal sync selection	0: bypass 1: after two DFF		
	1235	UP signal sync selection	0: bypass 1: after two DFF		
	1236	CNT0 CNT mode SYNC selection	0: bypass 1: after two DFF		
	1237	CNT0 output pol selection	0: Default Output 1: Inverted Output		
	1238	CNT0 DLY EDET FUNCTION Selection	0: normal 1: DLY function edge detection (registers [1224:1223] = 00)		
	1239	Reserved			

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
9B	1240	Multi1 register configure	multit_function selection		
	1241				
	1242		dly2lut selection		
	1243				
	1244		output selection of LUT3_7/DFF11: 0: LUT3_7 1: DFF11		
	1245	CNT1 DLY EDET FUNCTION Selection	0: normal 1: DLY function edge detection (registers [1251:1248] = 0000/0001/0010)		
	1246	CNT1 CNT mode SYNC selection	0: bypass 1: after two DFF		
	1247	CNT1 output pol selection	0: Default Output 1: Inverted Output		
9C	1248	CNT1 function and edge mode selection	0000: both edge Delay		
	1249		0001: falling edge delay		
	1250		0010: rising edge delay		
	1251		0011: both edge One Shot 0100: falling edge One Shot 0101: rising edge One Shot 0110: both edge freq detect 0111: falling edge freq detect 1000: rising edge freq detect 1001: both edge detect 1010: falling edge detect 1011: rising edge detect 1100: both edge reset CNT 1101: falling edge reset CNT 1110: rising edge reset CNT 1111: high level reset CNT		
	1252	DLY/CNT1 Clock Source Select	Clock source sel[3:0]		
	1253		0000: 25M(OSC2)		
	1254		0001: 25M/4		
	1255		0010: 2M(OSC1) 0011: 2M/8 0100: 2M/64 0101: 2M/512 0110: 2K(OSC0) 0111: 2K/8 1000: 2K/64 1001: 2K/512 1010: 2K/4096 1011: 2K/32768 1100: 2K/262144 1101: CNT0_END 1110: External 1111: Not used		

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
9D	1256	Multi2 register configure	multit_function selection		
	1257				
	1258		dly2lut selection		
	1259				
	1260	CNT2 DLY EDET FUNCTION Selection	output selection of LUT3_8/DFF12: 0: LUT3_8 1: DFF12		
	1261		0: normal 1: DLY function edge detection (registers [1267:1264] = 0000/0001/0010)		
	1262		0: bypass 1: after two DFF		
	1263		0: Default Output 1: Inverted Output		
9E	1264	CNT2 function and edge mode selection	0000: both edge Delay 0001: falling edge delay 0010: rising edge delay 0011: both edge One Shot 0100: falling edge One Shot 0101: rising edge One Shot 0110: both edge freq detect 0111: falling edge freq detect 1000: rising edge freq detect 1001: both edge detect 1010: falling edge detect 1011: rising edge detect 1100: both edge reset CNT 1101: falling edge reset CNT 1110: rising edge reset CNT 1111: high level reset CNT		
	1265				
	1266				
	1267				
9E	1268	DLY/CNT2 Clock Source Select	Clock source sel[3:0] 0000: 25M(OSC2) 0001: 25M/4 0010: 2M(OSC1) 0011: 2M/8 0100: 2M/64 0101: 2M/512 0110: 2K(OSC0) 0111: 2K/8 1000: 2K/64 1001: 2K/512 1010: 2K/4096 1011: 2K/32768 1100: 2K/262144 1101: CNT1_END 1110: External 1111: Not used		
	1269				
	1270				
	1271				

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
9F	1272	Multi3 register configure	multit_function selection		
	1273				
	1274		dly2lut selection		
	1275				
	1276		output selection of LUT3_9/DFF13: 0: LUT3_9 1: DFF13		
	1277	CNT3 DLY EDET FUNCTION Selection	0: normal 1: DLY function edge detection(registers [1283:1280] = 0000/0001/0010)		
	1278	CNT3 CNT mode SYNC selection	0: bypass; 1: after two DFF		
	1279	CNT3 output pol selection	0: Default Output, 1: Inverted Output		
A0	1280	CNT3 function and edge mode selection	0000: both edge Delay		
	1281		0001: falling edge delay		
	1282		0010: rising edge delay		
	1283		0011: both edge One Shot 0100: falling edge One Shot 0101: rising edge One Shot 0110: both edge freq detect 0111: falling edge freq detect 1000: rising edge freq detect 1001: both edge detect 1010: falling edge detect 1011: rising edge detect 1100: both edge reset CNT 1101: falling edge reset CNT 1110: rising edge reset CNT 1111: high level reset CNT		
	1284	DLY/CNT3 Clock Source Select	Clock source sel[3:0]		
	1285		0000: 25M(OSC2)		
	1286		0001: 25M/4		
	1287		0010: 2M(OSC1) 0011: 2M/8 0100: 2M/64 0101: 2M/512 0110: 2K(OSC0) 0111: 2K/8 1000: 2K/64 1001: 2K/512 1010: 2K/4096 1011: 2K/32768 1100: 2K/262144 1101: CNT2_END 1110: External 1111: Not used		

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
A1	1288	Multi4 register configure	multit_function selection		
	1289				
	1290		dly2lut selection		
	1291				
	1292		output selection of LUT3_10/DFF14: 0: LUT3_10 1: DFF14		
	1293	CNT4 DLY EDET FUNCTION Selection	0: normal 1: DLY function edge detection (registers [1299:1296] = 0000/0001/0010)		
	1294	CNT4 CNT mode SYNC selection	0: bypass 1: after two DFF		
	1295	CNT4 output pol selection	0: Default Output 1: Inverted Output		
A2	1296	CNT4 function and edge mode selection	0000: both edge Delay		
	1297		0001: falling edge delay		
	1298		0010: rising edge delay		
	1299		0011: both edge One Shot 0100: falling edge One Shot 0101: rising edge One Shot 0110: both edge freq detect; 0111: falling edge freq detect 1000: rising edge freq detect 1001: both edge detect 1010: falling edge detect 1011: rising edge detect 1100: both edge reset CNT 1101: falling edge reset CNT 1110: rising edge reset CNT 1111: high level reset CNT		
	1300	DLY/CNT4 Clock Source Select	Clock source sel[3:0]		
	1301		0000: 25M(OSC2)		
	1302		0001: 25M/4		
	1303		0010: 2M(OSC1)		
			0011: 2M/8		
			0100: 2M/64		
			0101: 2M/512		
			0110: 2K(OSC0)		
			0111: 2K/8		
			1000: 2K/64		
			1001: 2K/512		
			1010: 2K/4096		
			1011: 2K/32768		
			1100: 2K/262144		
			1101: CNT3_END		
			1110: External		
			1111: Not used		

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
A3	1304	Multi5 register configure	multit_function selection		
	1305				
	1306		dly2lut selection		
	1307				
	1308		output selection of LUT3_11/DFF15: 0: LUT3_11 1: DFF15		
	1309	CNT5 DLY EDET FUNCTION Selection	0: normal 1: DLY function edge detection (registers [1315:1312] = 0000/0001/0010)		
	1310	CNT5 CNT mode SYNC selection	0: bypass 1: after two DFF		
	1311	CNT5 output pol selection	0: Default Output 1: Inverted Output		
A4	1312	CNT5 function and edge mode selection	0000: both edge Delay		
	1313		0001: falling edge delay		
	1314		0010: rising edge delay		
	1315		0011: both edge One Shot 0100: falling edge One Shot 0101: rising edge One Shot 0110: both edge freq detect 0111: falling edge freq detect 1000: rising edge freq detect 1001: both edge detect 1010: falling edge detect 1011: rising edge detect 1100: both edge reset CNT 1101: falling edge reset CNT 1110: rising edge reset CNT 1111: high level reset CNT		
	1316	DLY/CNT5 Clock Source Select	Clock source sel[3:0]		
	1317		0000: 25M(OSC2)		
	1318		0001: 25M/4		
	1319		0010: 2M(OSC1) 0011: 2M/8 0100: 2M/64 0101: 2M/512 0110: 2K(OSC0) 0111: 2K/8 1000: 2K/64 1001: 2K/512 1010: 2K/4096 1011: 2K/32768 1100: 2K/262144 1101: CNT4_END 1110: External 1111: Not used		

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
A5	1320	Multi6 register configure	multit_function selection		
	1321				
	1322		dly2lut selection		
	1323				
	1324		output selection of LUT3_12/DFF16: 0: LUT3_12 1: DFF16		
	1325	CNT6 DLY EDET FUNCTION Selection	0: normal 1: DLY function edge detection (registers [1331:1328] = 0000/0001/0010)		
	1326	CNT6 CNT mode SYNC selection	0: bypass 1: after two DFF		
	1327	CNT6 output pol selection	0: Default Output 1: Inverted Output		
A6	1328	CNT6 function and edge mode selection	0000: both edge Delay		
	1329		0001: falling edge delay		
	1330		0010: rising edge delay		
	1331		0011: both edge One Shot 0100: falling edge One Shot 0101: rising edge One Shot 0110: both edge freq detect 0111: falling edge freq detect 1000: rising edge freq detect 1001: both edge detect 1010: falling edge detect 1011: rising edge detect 1100: both edge reset CNT 1101: falling edge reset CNT 1110: rising edge reset CNT 1111: high level reset CNT		
	1332	DLY/CNT6 Clock Source Select	Clock source sel[3:0]		
	1333		0000: 25M(OSC2)		
	1334		0001: 25M/4		
	1335		0010: 2M(OSC1) 0011: 2M/8 0100: 2M/64 0101: 2M/512 0110: 2K(OSC0) 0111: 2K/8 1000: 2K/64 1001: 2K/512 1010: 2K/4096 1011: 2K/32768 1100: 2K/262144 1101: CNT5_END 1110: External 1111: Not used		

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
A7	1336	CNT0 initial value selection	00: bypass the initial 01: initial 0 10: initial 1 11: initial 1		
	1337				
	1338				
	1339				
	1340	CNT6 initial value selection	00: bypass the initial 01: initial 0 10: initial 1 11: initial 1		
	1341				
	1342	Reserved			
	1343	Reserved			
A8	1344	CNT2 initial value selection	00: bypass the initial 01: initial 0 10: initial 1 11: initial 1		
	1345				
	1346	CNT3 initial value selection	00: bypass the initial 01: initial 0 10: initial 1 11: initial 1		
	1347				
	1348	CNT4 initial value selection	00: bypass the initial 01: initial 0 10: initial 1 11: initial 1		
	1349				
	1350	CNT5 initial value selection	00: bypass the initial 01: initial 0 10: initial 1 11: initial 1		
	1351				
A9	1352	Multi0_LUT4_DFF setting	<12:0>:LUT4_1 <12:0>		
	1353				
	1354				
	1355				
	1356				
	1357				
	1358				
	1359				
AA	1360		<13>:LUT4_1 <13>/DFF17 Initial Polarity Select 0: Low, 1: High		
	1361				
	1362				
	1363				
	1364		<14>:LUT4_1 <14>/DFF17 Output Se- lect 0: Q output, 1: QB output		
	1365				
	1366		<15>:LUT4_1 <15>/DFF17 or Latch Se- lect 0: DFF function, 1: Latch function		
	1367				

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
AB	1368	REG_CNT0_D<15:0>	Data[15:0]		
	1369				
	1370				
	1371				
	1372				
	1373				
	1374				
	1375				
AC	1376				
	1377				
	1378				
	1379				
	1380				
	1381				
	1382				
	1383				
AD	1384	Multi1_LUT3_DFF setting	<3:0>:LUT3_7 <3:0>		
	1385				
	1386				
	1387				
	1388		<4>:LUT3_7 <4>/DFF11 Initial Polarity Select 0: Low, 1: High		
	1389		<5>:LUT3_7 <5>/DFF11 0: RSTB from Matrix Output, 1: SETB from Matrix Output		
	1390		<6>:LUT3_7 <6>/DFF11 Output Select 0: Q output, 1: QB output		
	1391		<7>:LUT3_7 <7>/DFF11 or Latch Select 0: DFF function, 1: Latch function		
Multi1_CNT1					
AE	1392	REG_CNT1_D<7:0>	Data[7:0]		
	1393				
	1394				
	1395				
	1396				
	1397				
	1398				
	1399				

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
AF	1400	Multi2_LUT3_DFF setting	<3:0>:LUT3_8 <3:0>		
	1401				
	1402				
	1403				
	1404		<4>:LUT3_8 <4>/DFF12 Initial Polarity Select 0: Low, 1: High		
	1405		<5>:LUT3_8 <5>/DFF12 0: RSTB from Matrix Output, 1: SETB from Matrix Output		
	1406		<6>:LUT3_8 <6>/DFF12 Output Select 0: Q output, 1: QB output		
	1407		<7>:LUT3_8 <7>/DFF12 or Latch Select 0: DFF function, 1: Latch function		
B0	1408	REG_CNT2_D<7:0>	Data[7:0]		
	1409				
	1410				
	1411				
	1412				
	1413				
	1414				
	1415				
B1	1416	Multi3_LUT3_DFF setting	<3:0>:LUT3_9 <3:0>		
	1417				
	1418				
	1419				
	1420		<4>:LUT3_9 <4>/DFF13 Initial Polarity Select 0: Low, 1: High		
	1421		<5>:LUT3_9 <5>/DFF13 0: RSTB from Matrix Output, 1: SETB from Matrix Output		
	1422		<6>:LUT3_9 <6>/DFF13 Output Select 0: Q output, 1: QB output		
	1423		<7>:LUT3_9 <7>/DFF13 or Latch Select 0: DFF function, 1: Latch function		
B2	1424	REG_CNT3_D<7:0>	Data[7:0]		
	1425				
	1426				
	1427				
	1428				
	1429				
	1430				
	1431				

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
B3	1432	Multi4_LUT3_DFF setting	<3:0>:LUT3_10 <3:0>		
	1433				
	1434				
	1435				
	1436		<4>:LUT3_10 <4>/DFF14 Initial Polarity Select 0: Low, 1: High		
	1437		<5>:LUT3_10 <5>/DFF14 0: RSTB from Matrix Output, 1: SETB from Matrix Output		
	1438		<6>:LUT3_10 <6>/DFF14 Output Select 0: Q output, 1: QB output		
	1439		<7>:LUT3_10 <7>/DFF14 or Latch Select 0: DFF function, 1: Latch function		
B4	1440	REG_CNT4_D<7:0>	Data[7:0]		
	1441				
	1442				
	1443				
	1444				
	1445				
	1446				
	1447				
B5	1448	Multi5_LUT3_DFF setting	<3:0>:LUT3_11<3:0>		
	1449				
	1450				
	1451				
	1452		<4>:LUT3_11<4>/DFF15 Initial Polarity Select 0: Low, 1: High		
	1453		<5>:LUT3_11 <5>/DFF15 0: RSTB from Matrix Output, 1: SETB from Matrix Output		
	1454		<6>:LUT3_11 <6>/DFF15 Output Select 0: Q output, 1: QB output		
	1455		<7>:LUT3_11 <7>/DFF15 or Latch Select 0: DFF function, 1: Latch function		
B6	1456	REG_CNT5_D<7:0>	Data[7:0]		
	1457				
	1458				
	1459				
	1460				
	1461				
	1462				
	1463				

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
B7	1464	Multi6_LUT3_DFF setting	<3:0>:LUT3_12 <3:0>		
	1465				
	1466				
	1467				
	1468		<4>:LUT3_12 <4>/DFF16 Initial Polarity Select 0: Low, 1: High		
	1469		<5>:LUT3_12 <5>/DFF16 0: RSTB from Matrix Output, 1: SETB from Matrix Output		
	1470		<6>:LUT3_12 <6>/DFF16 Output Select 0: Q output, 1: QB output		
	1471		<7>:LUT3_12 <7>/DFF16 or Latch Select 0: DFF function, 1: Latch function		
B8	1472	REG_CNT6_D<7:0>	Data[7:0]		
	1473				
	1474				
	1475				
	1476				
	1477				
	1478				
	1479				
B9	1480	LUT2_0/DFF0 setting	<0>:LUT2_0 <0>		
	1481		<1>:LUT2_0 <1>/DFF0 Initial Polarity Select 0: Low, 1: High		
	1482		<2>:LUT2_0 <2>/DFF0 Output Select 0: Q output, 1: QB output		
	1483		<3>:LUT2_0 <3>/DFF0 or Latch Select 0: DFF function, 1: Latch function		
	1484	LUT2_1/DFF1 setting	<0>:LUT2_0 <0>		
	1485		<1>:LUT2_0 <1>/DFF0 Initial Polarity Select 0: Low, 1: High		
	1486		<2>:LUT2_0 <2>/DFF0 Output Select 0: Q output, 1: QB output		
	1487		<3>:LUT2_0 <3>/DFF0 or Latch Select 0: DFF function, 1: Latch function		

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
BA	1488	LUT2_2/DFF2 setting	<0>:LUT2_0 <0>		
	1489		<1>:LUT2_0 <1>/DFF0 Initial Polarity Select 0: Low, 1: High		
	1490		<2>:LUT2_0 <2>/DFF0 Output Select 0: Q output, 1: QB output		
	1491		<3>:LUT2_0 <3>/DFF0 or Latch Select 0: DFF function, 1: Latch function		
	1492	LUT2_0 or DFF0 Select	0: LUT2_0 1: DFF0		
	1493	LUT2_1 or DFF1 Select	0: LUT2_1 1: DFF1		
	1494	LUT2_2 or DFF2 Select	0: LUT2_2 1: DFF2		
	1495	Reserved			
BB	1496	PGen data	PGen Data[15:0]		
	1497				
	1498				
	1499				
	1500				
	1501				
	1502				
	1503				
BC	1504				
	1505				
	1506				
	1507				
	1508				
	1509				
	1510				
	1511				
BD	1512	LUT2_3_VAL or PGen_data	LUT2_3<3:0> or PGen 4bit counter data<3:0>		
	1513				
	1514				
	1515				
	1516	LUT2_3 or PGen Select	0: LUT2_3 1: PGen		
	1517	Active level selection for RST/SET	0: Active low level reset/set 1: Active high level reset/set		
	1518	LUT3_0 or DFF3 Select	0: LUT3_0 1: DFF3		
	1519	LUT3_1 or DFF4 Select	0: LUT3_1 1: DFF4		

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
BE	1520	LUT3_0_DFF3 setting	<1:0>: LUT3_0 <1:0>		
	1521				
	1522		<2>:LUT3_0 <2>/DFF3 stage selection 0: Q of first DFF; 1: Q of second DFF		
	1523		<3>:LUT3_0 <3>/DFF3 Active level selection for RST/SET 0: Active low level reset/set, 1: Active high level reset/set		
	1524		<4>:LUT3_0 <4>/DFF3 0: RSTB from Matrix Output, 1: SETB from Matrix Output		
	1525		<5>:LUT3_0 <5>/DFF3 Initial Polarity Select 0: Low, 1: High		
	1526		<6>:LUT3_0 <6>/DFF3 Output Select 0: Q output, 1: QB output		
	1527		<7>:LUT3_0 <7>/DFF3 or Latch Select 0: DFF function, 1: Latch function		
BF	1528	LUT3_1_DFF4 setting	<2:0>: LUT3_1 <2:0>		
	1529				
	1530				
	1531		<3>:LUT3_1 <3>/DFF4 Active level selection for RST/SET 0: Active low level reset/set, 1: Active high level reset/set		
	1532		<4>:LUT3_1 <4>/DFF4 0: RSTB from Matrix Output, 1: SETB from Matrix Output		
	1533		<5>:LUT3_1 <5>/DFF4 Initial Polarity Select 0: Low, 1: High		
	1534		<6>:LUT3_1 <6>/DFF4 Output Select 0: Q output, 1: QB output		
	1535		<7>:LUT3_1 <7>/DFF4 or Latch Select 0: DFF function, 1: Latch function		
C0	1536	Rheostat0 data selection	0000000000: 0 ~ 1111111111:100k		
	1537				
	1538				
	1539				
	1540				
	1541				
	1542				
	1543				
C1	1544	Reserved			
	1545				
	1546				
	1547				
	1548				
	1549				
	1550				
	1551				

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
C2	1552	Rheostat0 current value (read only)			
	1553				
	1554				
	1555				
	1556				
	1557				
	1558				
	1559				
C3	1560				
	1561				
	1562	Reserved			
	1563	Reserved			
	1564	Reserved			
	1565	Reserved			
	1566	Reserved			
	1567	Reserved			
C4	1568	Matrix Input 0			
	1569	Matrix Input 1			
	1570	Matrix Input 2			
	1571	Matrix Input 3			
	1572	Matrix Input 4			
	1573	Matrix Input 5			
	1574	Matrix Input 6			
	1575	Matrix Input 7			
C5	1576	Matrix Input 8			
	1577	Matrix Input 9			
	1578	Matrix Input 10			
	1579	Matrix Input 11			
	1580	Matrix Input 12			
	1581	Matrix Input 13			
	1582	Matrix Input 14			
	1583	Matrix Input 15			
C6	1584	Matrix Input 16			
	1585	Matrix Input 17			
	1586	Matrix Input 18			
	1587	Matrix Input 19			
	1588	Matrix Input 20			
	1589	Matrix Input 21			
	1590	Matrix Input 22			
	1591	Matrix Input 23			
C7	1592	Matrix Input 24			
	1593	Matrix Input 25			
	1594	Matrix Input 26			
	1595	Matrix Input 27			
	1596	Matrix Input 28			
	1597	Matrix Input 29			
	1598	Matrix Input 30			
	1599	Matrix Input 31			

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
C8	1600	Matrix Input 40			
	1601	Matrix Input 41			
	1602	Matrix Input 42			
	1603	Matrix Input 43			
	1604	Matrix Input 44			
	1605	Matrix Input 45			
	1606	Matrix Input 46			
	1607	Matrix Input 47			
C9	1608	Matrix Input 48			
	1609	Matrix Input 49			
	1610	Matrix Input 50			
	1611	Matrix Input 51			
	1612	Matrix Input 52			
	1613	Matrix Input 53			
	1614	Matrix Input 54			
	1615	Matrix Input 55			
CA	1616	Matrix Input 56			
	1617	Matrix Input 57			
	1618	Matrix Input 58			
	1619	Matrix Input 59			
	1620	Matrix Input 60			
	1621	Matrix Input 61			
	1622	Matrix Input 62			
	1623	Matrix Input 63			
CB	1624	CNT0_Q			
	1625				
	1626				
	1627				
	1628				
	1629				
	1630				
	1631				
CC	1632				
	1633				
	1634				
	1635				
	1636				
	1637				
	1638				
	1639				
CD	1640	CNT5_Q			
	1641				
	1642				
	1643				
	1644				
	1645				
	1646				
	1647				

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
CE	1648	CNT6_Q			
	1649				
	1650				
	1651				
	1652				
	1653				
	1654				
	1655				
CF	1656	Reserved			
	1657	Reserved			
	1658	Reserved			
	1659	Reserved			
	1660	Reserved			
	1661	Reserved			
	1662	Reserved			
	1663	Reserved			
D0	1664	Rheostat1 data selection	0000000000: 0 ~ 1111111111:100k		
	1665				
	1666				
	1667				
	1668				
	1669				
	1670				
	1671				
D1	1672	Reserved			
	1673				
	1674				
	1675				
	1676				
	1677				
	1678				
	1679				
D2	1680	Rheostat1 current value (read only)			
	1681				
	1682				
	1683				
	1684				
	1685				
	1686				
	1687				
D3	1688	Reserved			
	1689				
	1690				
	1691				
	1692				
	1693				
	1694				
	1695				

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
D4	1696	Reserved			
	1697	Reserved			
	1698	Reserved			
	1699	Reserved			
	1700	Reserved			
	1701	Reserved			
	1702	Reserved			
	1703	Reserved			
D5	1704	Reserved			
	1705	Reserved			
	1706	Reserved			
	1707	Reserved			
	1708	Reserved			
	1709	Reserved			
	1710	Reserved			
	1711	Reserved			
D6	1712	Reserved			
	1713	Reserved			
	1714	Reserved			
	1715	Reserved			
	1716	Reserved			
	1717	Reserved			
	1718	Reserved			
	1719	Reserved			
D7	1720	Reserved			
	1721	Reserved			
	1722	Reserved			
	1723	Reserved			
	1724	Reserved			
	1725	Reserved			
	1726	Reserved			
	1727	Reserved			
D8	1728	Reserved			
	1729	Reserved			
	1730	Reserved			
	1731	Reserved			
	1732	Reserved			
	1733	Reserved			
	1734	Reserved			
	1735	Reserved			
D9	1736	Reserved			
	1737	Reserved			
	1738	Reserved			
	1739	Reserved			
	1740	Reserved			
	1741	Reserved			
	1742	Reserved			
	1743	Reserved			

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
DA	1744	Reserved			
	1745	Reserved			
	1746	Reserved			
	1747	Reserved			
	1748	Reserved			
	1749	Reserved			
	1750	Reserved			
	1751	Reserved			
DB	1752	Reserved			
	1753	Reserved			
	1754	Reserved			
	1755	Reserved			
	1756	Reserved			
	1757	Reserved			
	1758	Reserved			
	1759	Reserved			
DC	1760	Reserved			
	1761	Reserved			
	1762	Reserved			
	1763	Reserved			
	1764	Reserved			
	1765	Reserved			
	1766	Reserved			
	1767	Reserved			
DD	1768	ID[24]: Reserved			
	1769	ID[25]: Reserved	Reserved for NVM Power-Up Check Pattern Status (A55A match from Flag)		
	1770	ID[27:26]: Reserved for Silicon Identification Service Bits (metal hard code)			
	1771				
	1772				
	1773	ID[31:28]: Production family ID (metal hard code)	0000: 47004		
	1774				
	1775				
DE	1776				
	1777				
	1778				
	1779	ID[15:8]: Metal revision ID (metal hard code)	0x00: Rev Z		
	1780				
	1781				
	1782				
	1783				

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
DF	1784	ID[7:0]: Base Die ID (metal hard code)	0x86		
	1785				
	1786				
	1787				
	1788				
	1789				
	1790				
	1791				
E0	1792	RPR<1:0> (2k register read selection bits)	00: 2k register data is unprotected for read 01: 2k register data is partly protected for read 10: 2k register data is fully protected for read 11: reserved		
	1793				
	1794	RPR<3:2> (2k register write selection bits)	00: 2k register data is unprotected for write 01: 2k register data is partly protected for write 10: 2k register data is fully protected for write 11: reserved		
	1795				
	1796	RH_PRB	0: Rheostat Program Input from matrix enabled 1: Rheostat Program Input from matrix disabled		
	1797	Reserved			
	1798	Reserved			
	1799	Reserved			
E1	1800	NPR<1:0> (2k NVM configuration selection bits)	00: 2k NVM Configuration data is unprotected for read and write/erase 01: 2k NVM Configuration data is fully protected for read 10: 2k NVM Configuration data is fully protected for write/erase 11: 2k NVM Configuration data is fully protected for read and write/erase		
	1801				
	1802	NPR<3:2> (Rheosta0 NVM configuration selection bits)	00: Rheosta0 NVM Configuration data is unprotected for read and write/erase 01: Rheosta0 NVM Configuration data is fully protected for read 10: Rheosta0 NVM Configuration data is fully protected for write/erase 11: Rheosta0 NVM Configuration data is fully protected for read and write/erase		
	1803				
	1804	NPR<5:4> (Rheosta1 NVM configuration selection bits)	00: Rheosta1 NVM Configuration data is unprotected for read and write/erase 01: Rheosta1 NVM Configuration data is fully protected for read 10: Rheosta1 NVM Configuration data is fully protected for write/erase 11: Rheosta1 NVM Configuration data is fully protected for read and write/erase		
	1805				
	1806	Reserved			
	1807	Reserved			

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
E2	1808	WPR<1:0> (EEPROM Write protect block bits range: page31~16)	00: Upper 1/4 (page16~19) of EEPROM is write protected (default)		
	1809		01: Upper 2/4 (page16~23) of EEPROM is write protected		
			10: Upper 3/4 (page16~27) of EEPROM is write protected		
			11: Entire (page16~31) EEPROM is write protected		
	1810	WPRE (EEPROM Write protect register enable)	0: No Software Write Protection enabled (default) 1: Write Protection is set by the state of the WPR<1:0> bits		
	1811	Reserved			
	1812	Reserved			
	1813	Reserved			
E3	1814	Reserved			
	1815	Reserved			
	1816	ERSE<4:0> (Page selection for erase)	Define the page address which will be erased ERSE<4> = 0 corresponds to the upper 2k NVM used for chip configuration ERSE<4> = 1 corresponds to the 2k EEPROM		
	1817				
	1818				
	1819				
	1820	ERSE <2:0> (Erase enable)	000/001/010/011/100/101/111: erase disable 110: cause the NVM erase: full NVM (4k bits) erase for ERSCHIP = 1 if DIS_ERCHIP=0 or page erase for ERSCHIP=0.		
	1821				
	1822				
E4	1823				
	1824	PRL (Protection lock)	0: RPR/WPR/NPR setting can be changed 1: RPR/WPR/NPR setting cannot be changed		
	1825	Reserved			
	1826	Reserved			
	1827	Reserved			
	1828	Reserved			
	1829	Reserved			
	1830	Reserved			
E5	1831	Reserved			
	1832	Reserved			
	1833				
	1834				
	1835				
	1836				
	1837				
	1838				
	1839				

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
E6	1840	Rheostat0 tolerance data <0>			
	1841	Rheostat0 tolerance data <1>			
	1842	Rheostat0 tolerance data <2>			
	1843	Rheostat0 tolerance data <3>			
	1844	Rheostat0 tolerance data <4>			
	1845	Rheostat0 tolerance data <5>			
	1846	Rheostat0 tolerance data <6>			
	1847	Rheostat0 tolerance data <7>			
E7	1848	Rheostat0 tolerance data <8>			
	1849	Rheostat0 tolerance data <9>			
	1850	Rheostat0 tolerance data <10>			
	1851	Rheostat0 tolerance data <11>			
	1852	Rheostat0 tolerance data <12>			
	1853	Rheostat0 tolerance data <13>			
	1854	Rheostat0 tolerance data <14>			
	1855	Sign of Rheostat0 tolerance data	0: "+" 1: "-"		
E8	1856	Rheostat1 tolerance data <0>			
	1857	Rheostat1 tolerance data <1>			
	1858	Rheostat1 tolerance data <2>			
	1859	Rheostat1 tolerance data <3>			
	1860	Rheostat1 tolerance data <4>			
	1861	Rheostat1 tolerance data <5>			
	1862	Rheostat1 tolerance data <6>			
	1863	Rheostat1 tolerance data <7>			
E9	1864	Rheostat1 tolerance data <8>			
	1865	Rheostat1 tolerance data <9>			
	1866	Rheostat1 tolerance data <10>			
	1867	Rheostat1 tolerance data <11>			
	1868	Rheostat1 tolerance data <12>			
	1869	Rheostat1 tolerance data <13>			
	1870	Rheostat1 tolerance data <14>			
	1871	Sign of Rheostat1 tolerance data	0: "+"; 1: "-"		
EA	1872	Reserved			
	1873				
	1874				
	1875				
EA	1876	Reserved			
	1877				
	1878				
	1879				

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
EB	1880	Reserved			
	1881				
	1882				
	1883				
	1884	Reserved			
	1885	Reserved			
	1886	Reserved			
	1887	Reserved			
EC	1888	Reserved			
	1889	Reserved			
	1890	Reserved			
	1891	Reserved			
	1892	Reserved			
	1893	Reserved			
	1894	Reserved			
	1895	Reserved			
ED	1896	Reserved			
	1897	Reserved			
	1898	Reserved			
	1899	Reserved			
	1900	Reserved			
	1901	Reserved			
	1902	Reserved			
	1903	Reserved			
EE	1904	Reserved			
	1905	Reserved			
	1906	Reserved			
	1907	Reserved			
	1908	Reserved			
	1909	Reserved			
	1910	Reserved			
	1911	Reserved			
EF	1912	Reserved			
	1913	Reserved			
	1914	Reserved			
	1915	Reserved			
	1916	Reserved			
	1917	Reserved			
	1918	Reserved			
	1919	Reserved			

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
F0	1920	Reserved			
	1921				
	1922				
	1923				
	1924				
	1925				
	1926				
	1927				
F1	1928	Lot #			
	1929				
	1930				
	1931				
	1932				
	1933				
	1934				
	1935				
F2	1936	Date Code			
	1937				
	1938				
	1939				
	1940				
	1941				
	1942				
	1943				
F3	1944	Service page lock bit	0: Service page can be changed 1: Service page is locked		
	1945	BG Chopper off	0: chopper enable 1: chopper off		
	1946	Reserved			
	1947	Reserved			
	1948	BG register power down	0: power on 1: power off		
	1949	Reserved			
	1950	Reserved			
	1951	Reserved			

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
F4	1952	Reserved			
	1953	Reserved			
	1954	Reserved			
	1955	Reserved			
	1956	DIS_ERCHIP (Disable full chip erase)	Permanently disable the full Chip Erase. After bit DIS_ERCHIP = 1, ERCHIP bit does not have any impact. When writing to an ERCHIP bit for DIS_ERCHIP = 1, the device will ACK, but the erase will abort. 0: ERCHIP 1: DIS_ERCHIP (permanent disable)		
	1957	ERCHIP (Full chip selection for erase)	Select Full NVM Erase (4K bits) ERCHIP = 1 Full NVM Erase (4K bits); ERCHIP = 0 Page Erase		
	1958	CHIP_PROG_EN (Chip program enable)	0: page program 1: chip program		
F5	1959	Reserved			
	1960	Reserved			
	1961	Reserved			
	1962	Reserved			
	1963	Reserved			
	1964	Reserved			
	1965	Reserved			
F6	1966	Reserved			
	1967	Reserved			
	1968	I ² C write mask bits	0: overwrite; 1: mask the bit which set to high		
	1969				
	1970				
	1971				
	1972				
	1973				
	1974				
F7	1975	Reserved			
	1976				
	1977				
	1978				
	1979				
	1980				
	1981				
F8	1982	Reserved			
	1983				
	1984				
	1985				
	1986				
	1987				
	1988				
	1989	Reserved			
	1990				
	1991				

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
F9	1992	Reserved			
	1993				
	1994				
	1995				
	1996				
	1997				
	1998				
	1999	Reserved			
FA	2000	Reserved			
	2001				
	2002				
	2003				
	2004				
	2005	Reserved			
	2006	Reserved			
	2007	Reserved			
FB	2008	Reserved			
	2009				
	2010				
	2011				
	2012				
	2013	Reserved			
	2014	Reserved			
	2015	Reserved			
FC	2016	Reserved			
	2017				
	2018				
	2019				
	2020				
	2021	Reserved			
	2022	Reserved			
	2023	Reserved			
FD	2024	Reserved			
	2025				
	2026				
	2027				
	2028				
	2029	Reserved			
	2030	Reserved			
	2031	Reserved			

Table 68: Register Map (Continued)

Address		Signal Function	Register Bit Definition	I ² C Interface	
Byte	Register Bit			Read	Write
FE	2032	Reserved			
	2033				
	2034				
	2035				
	2036				
	2037	Reserved			
	2038	Reserved			
	2039	Reserved			
FF	2040	Reserved			
	2041	Reserved			
	2042	Reserved			
	2043	Reserved			
	2044	Reserved			
	2045	Reserved			
	2046	Reserved			
	2047	Reserved			

22 Package Top Marking System Definition

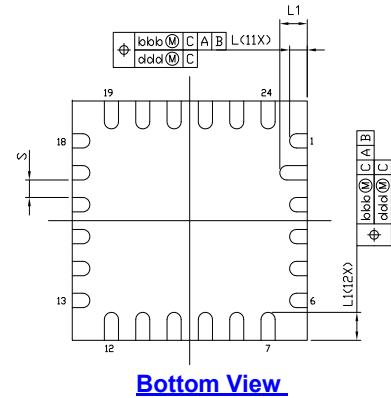
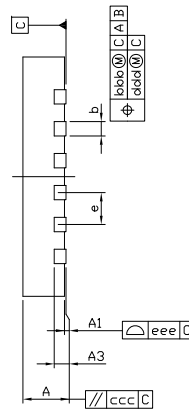
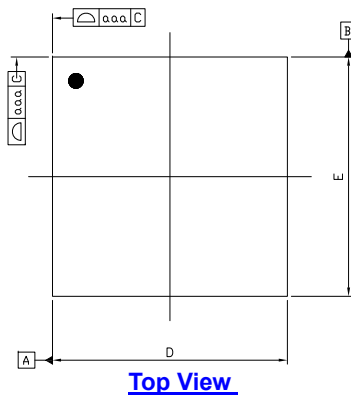
22.1 STQFN-24L 3 MM X 3 MM X 0.55 MM, 0.4P FCD PACKAGE

Part Code	PPPPP	
Date Code	WWNNN	S/N Code
Pin 1 Identifier	● ARR	Assembly House Code + Revision Code

23 Package Information

23.1 PACKAGE OUTLINES FOR STQFN 24L 3 MM X 3 MM X 0.55 MM 0.4P GREEN PACKAGE

JEDEC MO-220



PKG CODE	UQFN					
	MILLIMETER			INCH		
SYMBOLS	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.50	0.55	0.60	0.020	0.022	0.024
A1	0.00	0.02	0.05	0.000	0.001	0.002
A3	0.10	0.15	0.20	0.004	0.006	0.008
b	0.13	0.18	0.23	0.005	0.007	0.009
D	2.95	3.00	3.05	0.116	0.118	0.120
E	2.95	3.00	3.05	0.116	0.118	0.120
e	0.40 BSC			0.016 BSC		
L	0.175	0.225	0.275	0.007	0.009	0.011
L1	0.30	0.35	0.40	0.012	0.014	0.016
S	0.22 REF.			0.009 REF.		
aaa	0.07			0.003		
bbb	0.07			0.003		
ccc	0.10			0.004		
ddd	0.05			0.002		
eee	0.08			0.003		

A1 MAX LEAD COPLANARITY 0.05mm
STANDARD TOLERANCE : ±0.05

PAD SIZE	LEAD FINISH		JEDEC CODE
	Pure Tin	PPF	
	V	X	N/A

NOTES :

- ALL DIMENSIONS ARE IN MILLIMETERS.
- DIMENSION b APPLIES TO METALLIZED TERMINAL AND IS MEASURED BETWEEN 0.15mm AND 0.30mm FROM THE TERMINAL TIP. IF THE TERMINAL HAS THE OPTIONAL RADIUS ON THE OTHER END OF THE TERMINAL, THE DIMENSION b SHOULD NOT BE MEASURED IN THAT RADIUS AREA.
- BILATERAL COPLANARITY ZONE APPLIES TO THE EXPOSED HEAT SINK SLUG AS WELL AS THE TERMINALS.

23.2 STQFN HANDLING

Be sure to handle STQFN package only in a clean, ESD-safe environment. Tweezers or vacuum pick-up tools are suitable for handling. Do not handle STQFN package with fingers as this can contaminate the package pins and interface with solder reflow.

23.3 SOLDERING INFORMATION

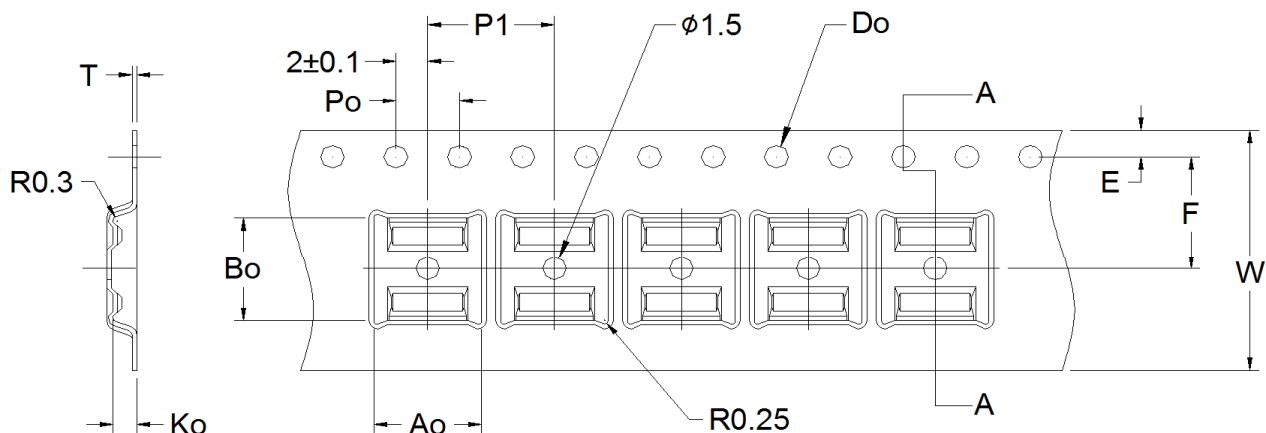
Please see IPC/JEDEC J-STD-020: for relevant soldering information. More information can be found at www.jedec.org.

24 Ordering Information

Part Number	Type
SLG47004V	24-pin STQFN
SLG47004ATR	24-pin STQFN - Tape and Reel (3k units)

24.1 TAPE AND REEL SPECIFICATIONS

Package Type	# of Pins	Nominal Package Size (mm)	Max Units		Reel & Hub Size (mm)	Leader (min)		Trailer (min)		Tape Width (mm)	Part Pitch (mm)
			per Reel	per Box		Pockets	Length (mm)	Pockets	Length (mm)		
STQFN 24L 3 mm x 3 mm 0.4P FCD	24	3 x 3 x 0.55	4,000	4,000	330 / 100	42	336	42	336	16	8



SECTION A-A

Refer to EIA-481 specification

Note: Orientation in carrier: Pin1 is at upper left corner (Quadrant1).

25 Layout Guidelines

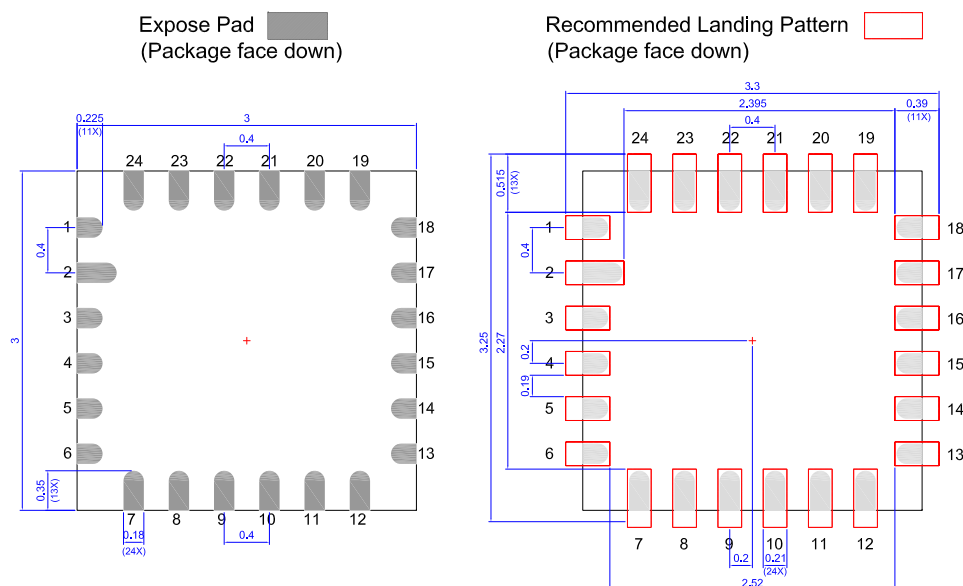
SLG47004 has two analog supply pins and two ground pins: V_{DD} , V_{DDA} , GND and AGND. Separating analog supply voltage from digital one helps to minimize noise generated by the digital part of IC.

Analog supply voltage domain: operational amplifiers, charge pumps for op amps, charge pumps for Oscillators, bias generators and regulators for op amps, digital rheostats, Chopper ACMP, HD Buffer, Vref of op amp and HD Buffer, Low Power Bandgap.

Digital supply voltage domain: ACMPs, Vref of ACMPs, Vref output buffers, Oscillator 0, Oscillator 1, Oscillator 2, I²C macrocell, NVM logic, Multi-function and Combination Function macrocells.

Analog and digital grounds must be connected together on the PCB board. The place of connection depends on users schematic. For application cases with low digital current of SLG47004, both AGND and GND should be connected to analog ground plane.

25.1 STQFN 24L 3 MM X 3 MM X 0.55 MM 0.4P GREEN PACKAGE



Glossary

A

ACK	Acknowledge bit
ACMP	Analog Comparator
ACMPH	Analog Comparator High Speed
ACMPL	Analog Comparator Low Power
AS	Analog Switch

B

BG	Bandgap
----	---------

C

CLK	Clock
CMO	Connection matrix output
CNT	Counter

D

DFF	D Flip-Flop
DLY	Delay
DNL	Differential Non-Linearity
DR	Digital Rheostat

E

EC	Electrical Characteristics
ERSE	Erase Enable
ERSR	Erase Register
ESD	Electrostatic discharge
EV	End Value

F

FSM	Finite State Machine
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G

GPI	General Purpose Input
GPIO	General Purpose Input/Output
GPO	General Purpose Output

I

IN	Input
In Amp	Instrumentation Amplifier
DNL	Differential Non-Linearity

INL Integral Non-Linearity

IO Input/Output

L

LPF Low Pass Filter

LSB Least Significant Bit

LUT Look Up Table

LV Low Voltage

M

MSB Most Significant Bit

MTP Multiple-Time-Programmable

MUX Multiplexer

N

NPR Non-Volatile Memory Read/Write/Erase Protection

nRST Reset

NVM Non-Volatile Memory

O

OA Operational Amplifier

OD Open-Drain

OE Output Enable

Op Amp Operational Amplifier

OSC Oscillator

OUT Output

P

PD Power-down

PGen Pattern Generator

POR Power-On Reset

PP Push-Pull

PRL Protect Lock Bit

PT Programmable Trim

PWR Power

P DLY Programmable Delay

R

RPR Register Read/Write Protection

RPRB Register Read/Write Protection Bit

RPRL Register Protection Read/Write/Erase Lock

R/W Read/Write

S

SCL I²C Clock Input
SDA I²C Data Input/Output
SLA Slave Address
SMT With Schmitt Trigger
SPST Single-pole/Single throw
SV nSET Value

T

TS Temperature Sensor

V

Vref Voltage Reference

W

WOSMT Without Schmitt Trigger
WPB Write Protect Bit
WPR Write Protection Register
WPRE Write Protect Enable
WS Wake and Sleep Controller

Revision History

Revision	Date	Description
2.1	13-Nov-2020	Removed TSSOP Package
2.0	9-Nov-2020	Preliminary version

Status Definitions

Revision	Datasheet Status	Product Status	Definition
1.<n>	Target	Development	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
2.<n>	Preliminary	Qualification	This datasheet contains the specifications and preliminary characterization data for products in pre-production. Specifications may be changed at any time without notice in order to improve the design.
3.<n>	Final	Production	This datasheet contains the final specifications for products in volume production. The specifications may be changed at any time in order to improve the design, manufacturing and supply. Major specification changes are communicated via Customer Product Notifications. Datasheet changes are communicated via www.dialog-semiconductor.com .
4.<n>	Obsolete	Archived	This datasheet contains the specifications for discontinued products. The information is provided for reference only.

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